intel

Intel[®] 830 Chipset Family: 82830 Graphics and Memory Controller Hub (GMCH-M)

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Revision History

Rev.	Description	Date
001	Initial Release	July 2001
002	 Updates include: Added design specifications for 830M and 830MG Chipset Added Mobile Intel[®] Celeron[®] Processors support information 	October 2001
003	 Updates include: Better differentiation between 830 SKUs (830MP, 830M, and 830MG) Added Ball-out diagrams and signal list for each SKUs (830MP, 830M, and 830MG) Updated Intel Reserved signals Removed local memory support Removed Sections 5.4.8.3 and 5.4.8.4 	January 2002

Intel[®] 830MP Chipset

Product Features

- Mobile Processor/Host Bus Support
 - Optimized for Mobile Intel[®] Pentium[®] III Processor-M /Mobile Intel[®] Celeron[®] Processors¹ at 133-MHz host bus frequency
 - --- Supports 32-bit host bus addressing

 - -Supports dual ended AGTL termination
- System Memory SDRAM Controller
 - Single Data Rate (SDR) SDRAM Support — Supports PC133 only
 - Four integrated 133- MHz System Memory Clocks
 - Supports 64-Mb, 128-Mb, 256-Mb, and 512-Mb technologies
 - --- Maximum of 1.0 GB of System Memory using 512-Mb technology
 - -Supports LVTTL signaling interface
- Hub Interface
 - Proprietary interconnect between GMCH-M and ICH3-M

- Accelerated Graphics Port (AGP) Interface
 Supports a single AGP or PCI-66 device
 - AGP Support
 - Supports AGP 2.0 including 4x AGP data transfers
 - —AGP 1.5-V Signaling only
 - -Fast Writes
 - -PCI Support
 - 66-MHz PCI 2.2 Specification compliant with the following exceptions: 1.5V but not 3.3-V safe, AGP 2.0 specification electricals
- Power Management
 - APM Rev 1.2 compliant power management
 - ACPI 1.0b and 2.0 Support
 System states: S0, S1, S3, S4, S5
 CPU states: C0, C1, C2, C3
- Package
- —625 PBGA
- IO Device Support

 $^{^1}$ The 830 Chipset family is optimized for the Mobile Intel[®] Pentium[®] III Processor-M, the Mobile Intel[®] Celeron[®] Processor (0.13 μ) in Micro-FCBGA and Micro-FCPGA Packages, and the Mobile Intel[®] Celeron[®] Processor (.18 μ) in Micro-FCBGA and Micro-FCPGA Packages (hereafter referred to as Mobile Intel Celeron Processors)

Intel 830MP Chipset Interface Block Diagram



Intel[®] 830M Chipset

Product Features

- Mobile Processor/Host Bus Support
 - Optimized for Mobile Intel[®] Pentium[®] III Processor-M /Mobile Intel[®] Celeron[®] Processors² at 133-MHz host bus frequency
 - -Supports 32-bit host bus addressing
 - -1.25-V AGTL bus driver technology (gated AGTL receivers for reduced power)
 - Supports dual ended AGTL termination
- System Memory SDRAM Controller
 - --- Single Data Rate (SDR) SDRAM Support
 - -Supports PC133 only
 - -Four integrated 133- MHz System Memory Clocks
 - -Supports 64-Mb, 128-Mb, 256-Mb, and 512-Mb technologies
 - -Maximum of 1.0 GB of System Memory using 512-Mb technology
 - -Supports LVTTL signaling interface
- Accelerated Graphics Port (AGP) Interface

 - —AGP Support
 - -Supports AGP 2.0 including 4x AGP data transfers
 - AGP 1.5-V Signaling only
 - -Fast Writes
 - -PCI Support
 - 66-MHz PCI 2.2 Specification compliant with the following exceptions: 1.5-V but not 3.3-V safe, AGP specification electricals.
- Hub Interface
 - Proprietary interconnect between GMCH-M and ICH3-M
- Graphics Features
 - -Core Frequency up to 166 MHz
 - -High Performance 3D Setup and Render Engine
 - --- Setup capable of delivering Mobile Intel Pentium III Processor-M / Mobile Celeron Processors Performance
 - -Triangles list, Strips, and Fans Support
 - —D3D Vertex Formats
 - -Pixel Accurate Fast Scissoring and Clipping Operation
 - -Backface Culling Support
 - -Support D3D and OGL Pixelization Rules
 - -Sprite Points Support
 - -High Quality / Performance Texture Engine
 - -Per Pixel Perspective Corrected Texture Mapping

 $^{^2}$ The 830 Chipset family is optimized for the Mobile Intel[®] Pentium[®] III Processor-M, the Mobile Intel[®] Celeron[®] Processor (0.13µ) in Micro-FCBGA and Micro-FCPGA Packages, and the Mobile Intel[®] Celeron[®] Processor (.18µ) in Micro-FCBGA and Micro-FCPGA Packages (hereafter referred to as <u>Mobile</u> Intel Celeron Processors)

intel

- -Single Pass Texture Compositing
- —12 Level of Details MIP Map Sizes from 1x1 to 2Kx2K
- -All texture formats including 32-bit RGBA and 8-bit paletted
- Alpha and Luminance Maps
- Texture ColorKeying / ChromaKeying
- -Bilinear, Trilinear, and Anisotropic MIP-Mapped Filtering
- -Cubic Environment Reflection Mapping
- -Embossed and Environment Reflection Mapping
- --- Embossed and Environment Bump-Mapping
- -D3D (DXTn) Texture Decompression
- 3D Graphics Rasterization Enhancements
 - -Flat & Gouraud Shading
 - -Color Alpha Blending For Transparency
 - --- Vertex and Programmable Pixel Fog and Atmospheric Effects
 - -Color Specular Lighting
 - -Line and Full-Scene Anti-aliasing
 - —16-bit and 24-bit Z Buffering
 - -16-bit and 24-bit W Buffering
 - 8-bit Stencil Buffering
 - -Double and Triple Render Buffer Support
 - —16-bit and 32-bit Color
 - —Destination Alpha
 - -Fast Clear Support
- 2D Graphics
 - -256-bit pattern fill and BLT Engine Performance
 - -Programmable 3-Color Transparent Cursor
 - -Color Space Conversion
 - -GDI+ Feature Support
 - -Anti-aliased Lines
 - -Alpha Blended Cursor
 - -Anti-aliased Text
 - Alpha Stretch Blitter
 - -8-bit, 16-bit and 32-bit Color
 - -ROP Support
- -Video
- Dynamic Bob and Weave Support for Video Streams
- -Supports 720 x 480 DVD Quality encoding
- -MPEG2 HWMC decoding support
- -Video Overlay
- -Single High Quality Scalable Overlay
- -Multiple Overlay Functionality provided via Stretch Blitter
- --- Independent Gamma Correction
- --- Independent Brightness / Contrast / Saturation
- --- Independent Tint / Hue Support
- -Destination Colorkeying
- Source Chromakeying
- Display
 - Analog Display Support
 - -350-MHz Integrated 24-bit RAMDAC
 - -Hardware Color Cursor Support
 - -DDC2B Compliant

INte

- Dual display options with FP/ digital display
 - -Concurrent: Different images and native display timings on each display device
 - -Simultaneous: Same images and native display timings on each display device
- DVO support
 - -3 DVO interfaces supported
 - 165-MHz dot clock with 12-bit interface
 - -Supports Hot Plug Display
 - --- Supports a variety of DVO devices
- Dedicated DVO (DVOA) interface
 - 165-MHz dot clock 12-bit interface
- Multiplexed DVO (DVOB and DVOC) interface
 - -Two channels multiplexed with AGP
 - -Can combine two 12-bits channels to form one 24-bit interface
- Supports larger display resolutions
- Supports one additional flat panel display and / or one TV
- Power Management
 - APM Rev 1.2 compliant power management
 - -ACPI 1.0b and 2.0 Support
- Package
 - —625 PBGA
- IO Device Support

Intel 830M Chipset Interface Block Diagram



Intel[®] 830MG Chipset

Product Features

- Mobile Processor/Host Bus Support
 - Optimized for Mobile Intel Pentium III Processor-M / Mobile Intel Celeron Processors ³at 133-MHz host bus frequency
 - -Supports 32-bit host bus addressing
 - -1.25-V AGTL bus driver technology (gated AGTL receivers for reduced power)
 - -Supports dual ended AGTL termination
- System Memory SDRAM Controller
 - -Single Data Rate (SDR) SDRAM Support
 - -Supports PC133 only
 - -Four integrated 133- MHz System Memory Clocks
 - -Supports 64-Mb, 128-Mb, 256-Mb, and 512-Mb technologies
 - -Maximum of 1.0 GB of System Memory using 512-Mb technology
 - -Supports LVTTL signaling interface
- Hub Interface
 - Proprietary interconnect between GMCH-M and ICH3-M
- Graphics Features
 - -Core Frequency up to 166 MHz
 - -High Performance 3D Setup and Render Engine
 - --- Setup capable of delivering Mobile Intel Pentium III Processor-M / Mobile Celeron Processors Performance
 - Triangles list, Strips, and Fans Support
 - —D3D Vertex Formats
 - -Pixel Accurate Fast Scissoring and Clipping Operation
 - -Backface Culling Support
 - Support D3D and OGL Pixelization Rules
 - -Sprite Points Support
 - -High Quality / Performance Texture Engine
 - -Per Pixel Perspective Corrected Texture Mapping
 - -Single Pass Texture Compositing
 - -12 Level of Details MIP Map Sizes from 1x1 to 2Kx2K
 - -All texture formats including 32-bit RGBA and 8-bit paletted
 - Alpha and Luminance Maps
 - Texture ColorKeying / ChromaKeying
 - -Bilinear, Trilinear, and Anisotropic MIP-Mapped Filtering
 - -Cubic Environment Reflection Mapping
 - Embossed and Environment Reflection Mapping
 - -Embossed and Environment Bump-Mapping
 - -D3D (DXTn) Texture Decompression
 - 3D Graphics Rasterization Enhancements

³ The 830 Chipset family is optimized for the Mobile Intel Pentium III Processor-M, the Mobile Intel Celeron[®] Processor (0.13 μ) in Micro-FCBGA and Micro-FCPGA Packages, and the Mobile Intel Celeron[®] Processor (.18 μ) in Micro-FCBGA and Micro-FCPGA Packages (hereafter referred to as <u>Mobile</u> Intel Celeron Processors).

intel

- -Flat & Gouraud Shading
- -Color Alpha Blending For Transparency
- --- Vertex and Programmable Pixel Fog and Atmospheric Effects
- -Color Specular Lighting
- -Line and Full-Scene Anti-aliasing
- -16-bit and 24-bit Z Buffering
- -16-bit and 24-bit W Buffering
- -8-bit Stencil Buffering
- -Double and Triple Render Buffer Support
- —16-bit and 32-bit Color
- -Destination Alpha
- -Fast Clear Support
- -2D Graphics
 - -256-bit pattern fill and BLT Engine Performance
 - -Programmable 3-Color Transparent Cursor
 - -Color Space Conversion
 - -GDI+ Feature Support
 - -Anti-aliased Lines
 - Alpha Blended Cursor
 - -Anti-aliased Text
 - -Alpha Stretch Blitter
- -ROP Support
- —Video
- -Dynamic Bob and Weave Support for Video Streams
- -Supports 720 x 480 DVD Quality encoding
- MPEG2 HWMC decoding support
- -Video Overlay
- -Single High Quality Scalable Overlay
- -Multiple Overlay Functionality provided via Stretch Blitter
- -Independent Gamma Correction
- --- Independent Brightness / Contrast / Saturation
- Independent Tint / Hue Support
- Destination Colorkeying
- Source Chromakeying
- Display
 - Analog Display Support
 - 350-MHz Integrated 24-bit RAMDAC
 - -Hardware Color Cursor Support
 - -DDC2B Compliant
 - Dual display options with FP/ digital display
 - -Concurrent: Different images and native display timings on each display device
 - -Simultaneous: Same images and native display timings on each display device
 - DVO support
 - -3 DVO interfaces supported
 - 165-MHz dot clock with 12-bit interface
 - Supports Hot Plug Display
 - Dedicated DVO (DVOA) interface
 - 165-MHz dot clock 12-bit interface
 - Multiplexed DVO (DVOB & DVOC) interface
 - -Two channels multiplexed with AGP

- -Can combine two 12-bits channels to form one 24-bit interface
- ---Supports one additional flat panel and / or one TV
- Power Management
 - -APM Rev 1.2 compliant power management
 - ACPI 1.0b and 2.0 Support
 - —System states: S0, S1, S3, S4, S5
 - -CPU states: C0, C1, C2, C3
- Package 625 DI
 - 625 PBGA
- IO Device Support — 82801CAM (I/O Controller Hub)

Intel 830MG Chipset Interface Block Diagram



1 Introduction

This document provides the external design specifications for notebook computer manufacturers.

1.1 Document References

- *Mobile Intel[®] Pentium[®] III Processor-M Datasheet* (298340-003): Contact <u>http://developer.intel.com/design/mobile/datashts/298340.htm</u>
- Mobile Intel[®] Celeron[®] Processor (0.18µ) in Micro-FCBGA and Micro-FCPGA Packages Datasheet (298514-001): Contact http://developer.intel.com/design/mobile/datashts/298514.htm
- Mobile Intel[®] Celeron[®] Processor (0.13µ) in Micro-FCBGA and Micro-FCPGA Packages Datasheet (298517-001): Contact http://developer.intel.com/design/mobile/datashts/298517.htm
- PCI Local bus Specification 2.2: Contact <u>www.pcisig.com</u>
- Intel[®] 82801CAM I/O Controller Hub 3 (ICH3-M) Datasheet (290716-002): Contact http://developer.intel.com/design/chipsets/datashts/290716.htm
- Intel[®] 830 Chipset Family Design Guide (298339-003): Contact http://developer.intel.com/design/chipsets/designex/298339.htm
- Advanced Graphic Port (AGP) 2.0 Specification: Contact <u>ftp://download.intel.com/technology/agp/downloads/agp20.pdf</u>
- Advanced Configuration and Power Management (ACPI) Specification 1.0b & 2.0: Contact http://www.teleport.com/~acpi/
- Advanced Power Management (APM) Specification 1.2: Contact http://www.microsoft.com/hwdev/busbios/amp_12.htm
- Write Combing Memory Implementation Guideline: Contact <u>http://developer.intel.com/design/PentiumII/applnots/244422.htm</u>
- *IA-32 Intel Architecture Software Developer Manuel Volume 3: System Programming Guide:* Contact <u>http://developer.intel.com/design/Pentium4/manuals/24547203.pdf</u>
- Intel Graphics Software PC 10.0 Product Requirements: Contact you Intel Field Representative.

2 Overview



Figure 1. Intel 830MP Chipset Interface Block Diagram

HA[31:3]# ← HD[63:0]# ← ADS# ← BNR# ← → VSYNC → HSYNC → RED → GREEN Display GREEN BLUE REFSET Interface BPRI# ◀ DBSY# ◀ + DBSY# ← DEFER# ← DRDY# ← HIT# ← HLOCK# HREQ[4:0]# ← HTRDY# ← CPURST# ← CPURST# ← Host Interface ٠ [RED,GREEN,BLUE# SBA[7:0] PIPE# ST[2:0] RBF# WBF# -Þ * AD_STB[1:0], AD_STB[1:0]# SB_STB, SB_STB# AGPRCOMP • GTL_RCOMP • AGP • G_FRAME# G_IRDY# G_TRDY# SM_RCLn SM_OCLK ← SM_MA[12:0] ← SM_BA[1:0] ← SM_MD[63:0] ← CM_ECC[7:0] ← * Interface **→** G_STOP# G_DEVSEL# G_REQ# • System Memory SM_ECC[7:0] G_GNT# G_AD[31:0] G_C/BE[3:0]# G_PAR ⇒ (Single Data Rate) SM_CS[5:0]# SM_RAS# SM_CAS# SM_CAS# SM_WE# * SM_CKE[5:0] ← SM_RCOMP ← DVOB_CLK/DVOB_CLK DVOB_D[11:0] DVOB_HSYNC DVOB_VSYNC DVOB_BLANK# DVOBC_CLKINT DVOBC_CLKINT Digital • • Video Out B HL[10:0] ← HLSTRB, HLSTRB# ← HL_RCOMP ← • Hub -(DVOB) Interface DVOB_FLD/STL DVOA_CLK/DVOA_C DVOA_D[11:0] DVOA_HSYNC DVOA_VSYNC DVOA_CALANK# DVOA_RCANK# DVOA_RCOMP DVOA_CLKINT DVOA_CLKINT DVOA_FLD/STL DVOC_CLK/DVOC_CLK DVOC_D[11:0] DVOC_HSYNC DVOC_VSYNC DVOC_BLANK# DVOBC_INTR# DVOC_FLD/STL Digital Multiplexed with AGE * Video (either AGP or Digital Out A (DVOA) these functions) Video Out C • • (DVOC) → MDDC_DATA → MDDC_CLK → MI2C_DATA → MI2C_CLK DDC2 DATA Multiplexed^{*} DDC2_DA DDC2_CLK I2C_DATA I2C_CLK DDC1_DATA DDC1_CLK . GPIO • GPIO → DQ_A[7:0] [Reserved] → DQ_B[7:0] [Reserved] → RQ[7:0] [Reserved] → CTM, CTM# [Reserved] → CFM, CFM# [Reserved] → SCK [Reserved] → SIO [Reserved] → SIO [Reserved] • Graphics GTL_REF[B:A]-RAM_REF[B:A]-AGPREF -Direct RDRAM AGPREF — HLREF — VCCA_HPLL, VSSA_HPLL VCCA_CPLL, VSSA_CPLL VCCA_DPLL, VSSA_DPLL VCCCMOS — Channel Voltage Refernce, (Reserved) PLL Power GN_RCLK [Reserved] — GM_RCLK [Reserved] — HTCLK, HTCLK# → GBOUT — GBIN VCCQ AGP Clocks VCCQSM • and → GM_GCLK [Reserved] → DREFCLK → RESET# VSS SM_REF[B:A] Reset Note: Dashed lines indicated multiplexed functions

Figure 2. Intel 830M Chipset Interface Block Diagram

intel



Figure 3. Intel 830MG Chipset Interface Block Diagram

int_{el}.

2.1 Terminology

82830MP Graphics and Memory Controller Hub (GMCH-M)	The Intel 830MP Graphics and Memory Controller Hub-Mobile component, which contains the CPU interface, system SDRAM controller and AGP interface. It communicates with the ICH3-M over a proprietary interconnect called the hub interface.
82830M Graphics and Memory Controller Hub (GMCH-M)	The Intel 830M Graphics and Memory Controller Hub-Mobile component which contains the CPU interface, system SDRAM controller, AGP interface, and Integrated Graphics Device (IGD). It communicates with the ICH3-M over a proprietary interconnect called the hub interface.
82830MG Graphics and Memory Controller Hub (GMCH-M)	The Intel 830MG Graphics and Memory Controller Hub-Mobile component which contains the CPU interface, system SDRAM controller, and Integrated Graphics Device (IGD). It communicates with the ICH3-M over a proprietary interconnect called the hub interface.
Intel 830 Chipset Family	Intel 830 Chipset family SKU consists of the following 3 defined SKUs: 82830MP, 82830M, 82830MG and will be referred to as the Intel 830 Chipset Family
Discrete AGP Graphics Interface	The Intel 830M and 830MP Graphics and Memory Controller Hub-Mobile (GMCH-M) components which implements an external graphics solution (AGP) will be referred to as Intel 830M and 830MP discrete AGP graphics Interface
Internal Graphics device	PCI Device #2 of the Intel 830M and 830MG Graphics and Memory Controller Hub-Mobile (GMCH-M) component which implements the Intel Graphics solution will be referred to as the Intel graphics device
82801CAM I/O Controller Hub (ICH3-M)	The ICH3-M is connected to the GMCH-M through a proprietary interconnect called the hub interface. This is the I/O Controller Hub or ICH component that contains the primary PCI interface, LPC interface, USB1.1, ATA-100 and other IO functions.
Hub Interface	The proprietary interconnect between the GMCH-M and the ICH3-M. In this document, hub interface cycles originating from or destined for the ICH3-M are generally referred to as hub interface cycles. Hub cycles originating from or destined for the primary PCI interface on the ICH3-M are sometimes referred to as Hub Interface/PCI cycles.
DVO Port	Digital Video Out Port. Refers to the Intel 830M and 830MG Chipset's digital display channels. The Intel 830M Chipset has one dedicated DVO and two DVOs that are multiplexed with AGP. The Intel 830MG Chipset has three dedicated DVO.
AGP	Accelerated Graphics Port. Refers to the AGP/PCI interface that is in the Intel 830MP and 830M Chipset SKUs. It supports a 1.5V AGP 4X component. PIPE# and SBA cycles are generally referred to as AGP transactions. FRAME# cycles are generally referred to as AGP/PCI transactions.
AGP/PCI1	The physical bus that is driven directly by the AGP/PCI1 Bridge (Device #1) in the 830MP and 830M SKUs. This is the primary AGP bus.
Primary PCI	The primary physical PCI (PCI0) bus that is driven directly by the ICH3-M component. It supports a 3.3V interface and is 5.0V tolerant, 33 MHz PCI 2.2 compliant components. Interaction between PCI0 and GMCH-M occurs over the hub interface. Note that even though the Primary PCI bus is referred to as PCI0 it is not PCI Bus #0 from a configuration standpoint.
Secondary PCI	The secondary physical PCI (PCI1) interface that is a subset of the AGP bus driven directly by the GMCH-M. It supports a subset of 1.5V, 66 MHz PCI 2.2 compliant components. Note that even though the Secondary PCI bus is referred to as PCI1 it may not be configured as PCI Bus #1.
Direct AGP	Integrated AGP interface.
UMA	Unified Memory Architecture. Graphics memory for the IGD that is located in system memory
IGD	Integrated Graphics Device. The Graphics Device that is internal to the GMCH-M
DVMT	Direct Video Memory Technology

2.2 Intel 830 Chipset Family System Architecture

The Intel 830 Chipset family (consists of the three different SKUs: 82830M, 82830MP, 82830MG) is a highly integrated hub that provides the CPU interface to a Mobile Intel[®] Pentium[®] III Processor-M / Mobile Intel Celeron Processor, the SDRAM system memory interface, a hub link interface to the 82801CAM I/O Controller Hub (ICH3-M), and is optimized for Mobile Intel Pentium III Processor-M /Mobile Intel Celeron Processor configurations at 133-MHz PSB.

2.2.1 Intel 830MP Chipset

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The Intel 830MP Chipset supports Mobile Intel Pentium III Processor-M / Mobile Intel Celeron Processors with an external AGP 4X graphics solution.

- 1.25-V AGTL host bus supporting 32-bit host addressing
- System SDRAM supports PC133 (LVTTL) SDRAM
- Supports up to 1.0 GB of system SDRAM
- AGP interface with 1x/2x/4x SBA/Data Transfer and 2x/4x Fast Write capability
- Hub interface to ICH3-M

2.2.2 Intel 830M Chipset

The Intel 830M Chipset has integrated graphics capabilities as well as external AGP support. Its dedicated multimedia engines deliver high performance 3D, 2D, video, and display capabilities. The Intel 830M Chipset provides the flexibility of an external graphics solution with the AGP port.

- 1.25-V AGTL host bus supporting 32-bit host addressing
- System SDRAM supports PC133 (LVTTL) SDRAM
- Supports up to 1.0 GB of system SDRAM
- AGP interface with 1x/2x/4x SBA/Data Transfer and 2x/4x Fast Write capability
- Hub interface to ICH3-M
- Integrated graphics capabilities, including 3D rendering acceleration and 2D hardware acceleration
- Integrated 350-MHz RAMDAC
- A variety of display device protocols (TV, DVI, LVDS) are supported through Digital Video Out Ports (one dedicated and two muxed with AGP) connected to external devices

2.2.3 Intel 830MG Chipset

The Intel 830MG Chipset has integrated graphics capabilities. Its dedicated multimedia engines deliver high performance 3D, 2D, video, and display capabilities. 1.25-V AGTL host bus supporting 32-bit host addressing:

- 1.25-V AGTL host bus supporting 32-bit host addressing
- System SDRAM supports PC133 (LVTTL) SDRAM
- Supports up to 1.0 GB of system SDRAM
- Hub interface to ICH3-M

- Integrated graphics capabilities, including 3D rendering acceleration and 2D hardware acceleration
- Integrated 350-MHz RAMDAC
- A variety of display device protocols (TV, DVI, LVDS) are supported through three Digital Video Out Ports (DVOs) connected to external devices

2.3 Intel 830 Chipset Family Host Interface¹

The Intel 830 Chipset family is optimized for the Mobile Intel Pentium III Processor-M /Mobile Intel Celeron Processors. Each member of the Intel 830 Chipset family supports a PSB frequency of 133 MHz using 1.25-V AGTL signaling. Dual ended termination AGTL is supported for single processor configurations. It supports 32-bit host addressing, decoding up to 4 GB of the CPU's memory address space. Host initiated I/O cycles are decoded to AGP/PCI1, Hub interface, or GMCH-M configuration space. Host initiated memory cycles are decoded to AGP/PCI1, Hub interface, or system SDRAM. All memory accesses from the Host interface that hit the graphics aperture are translated using an AGP address translation table. GMCH-M accesses to graphics memory and AGP/PCI1 device accesses to non-cacheable system memory are not snooped on the host bus. Memory accesses initiated from AGP/PCI1 using PCI semantics and from Hub interface to system SDRAM will be snooped on the host bus.

Note: Discrete AGP support is available only with the Intel 830MP and 830M Chipset.

2.4 Intel 830 Chipset Family System Memory Interface

The Intel 830 Chipset family integrates a system memory SDRAM controller with a 64-bit wide interface. The Intel 830 Chipset family supports Single Data Rate (SDR) SDRAM for system memory. Consequently, the GMCH-M system memory buffers support LVTTL signal interfaces.

Configured for SDRAM, the GMCH-M memory interface includes support for the following:

- Up to 1.0 GB of 133-MHz SDR SDRAM using 512-Mb technology
- PC133 SO-DIMMs
- Maximum of two SO-DIMMs, single-sided and/or double-sided
- The Intel 830M Chipset only supports four bank memory technologies.
- Four Integrated Clock buffers

2.5 Intel 830M / 830MP Discrete AGP Interface

GMCH-M has the capability to support a single AGP or PCI-66 component using the Intel 830M and 830MP AGP interface via an AGP 2.0 interface. High bandwidth access to data is provided through the system memory ports. GMCH-M can access AGP memory located in system memory with a peak bandwidth of 1.0 GB/s. Actual AGP throughput may vary depending on application running and system memory throttling mechanism applied. Please consult Section 5.7.11.2 for a discussion on throttling management.

The 830M/830MP AGP port supports a 1.5-V interface and is not 3.3-V safe. This mode is compliant with the AGP 2.0 spec.

The AGP/PCI1 interface supports up to 4x AGP signaling and up to 4x Fast Writes. AGP semantic cycles to system SDRAM are not snooped on the host bus. PCI semantic cycles to system SDRAM are snooped on the host bus. The GMCH-M supports PIPE# or SBA[7:0] AGP address mechanisms, but not both simultaneously. Either the PIPE# or the SBA[7:0] mechanism must be selected during system initialization. The GMCH-M contains a 32-deep AGP request queue. High priority accesses are supported.

2.6 Intel 830M / 830MG Internal Graphics Introduction

The Intel 830M and 830MG Chipset IGD provide a highly integrated graphics accelerator delivering high performance 3D, 2D, and video capabilities. The GMCH-M contains an extensive set of instructions for 3D operations, BLT and Stretch BLT operations, motion compensation, overlay, and display control. GMCH-M supports a UMA architecture using DVMT configuration. With its interfaces to analog display and flat panel display (through an accompanying LVDS transmitter/scaler), the GMCH-M provides a complete graphics solution.

High bandwidth access to data is provided through the system memory ports. The GMCH-M uses tiling architecture to increase memory efficiency and thus maximize effective rendering bandwidth. The GMCH-M uses Intel's Direct Memory Execution model to fetch textures from system memory at 1.0 GB/s. GMCH-M includes a cache controller to avoid frequent memory fetches of recently used texture data.

The GMCH-M also provides 2D hardware acceleration for block transfers of data (BLTs). The BLT engine provides the ability to copy a source block of data to a destination and perform raster operations (e.g., ROP1, ROP2, and ROP3) on the data using a pattern, and/or another destination. Performing these common tasks in hardware reduces CPU load, and thus improves performance.

2.7 Intel 830M / 830MG Internal Graphics Display Interface

The Intel 830M and 830MG IGD SKU have four display ports, one analog and three digital. This provides support for a progressive scan analog monitor, a dedicated DVO port (DVOA) and dual DVO ports. Each port can transmit data according to one or more protocols. The DVO ports are connected to an external device that converts one protocol to another. Examples of this are TV encoders, external DACs, LVDS transmitters, and TMDS transmitters. Each display port has control signals that may be used to control, configure and/or determine the capabilities of an external device. The data that is sent out the display port is selected from one of the two possible sources; pipe A or pipe B.

2.7.1 Intel 830M and 830MG Analog Display Port

The Intel <u>830M and</u> 830MG Chipset has an integrated 350-MHz RAMDAC that can directly drive a progressive scan analog monitor up to a resolution of 1800 x 1440 pixels.

2.7.2 Intel 830M and 830MG DVO interfaces

The Intel 830M and 830MG Chipset provides digital display channels that are capable of driving a 165-MHz pixel clock. GMCH-M is compliant with DVI Specification 1.0. When combined with a DVI compliant external device and connector, the Intel 830M and 830MG Chipset has a high-speed interface to a digital display (e.g. flat panel or digital CRT).

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2.7.2.1 Intel 830M and 830MG Dedicated DVOA Interface

The Intel 830M and 830MG supports DVO devices that can drive pixel clocks up to 165 MHz. The dedicated DVOA interface can support a variety of TV-Out and TMDS transmitters.

2.7.2.2 Intel 830M and 830MG DVOB and DVOC Interfaces

The Intel 830MG Chipset has dedicated interfaces (DVOB and DVOC). Each interface is capable to drive pixel clocks up to 165 MHz. The DVO interface can support a variety of TV-Out and TMDS transmitters. The DVOB and DVOC interfaces may be used independently or combined to support higher resolutions and refresh rates.

Similar to the Intel 830MG Chipset, the Intel 830M Chipset can use DVOB and DVOC interfaces independently or combined for higher resolutions and refresh rates. Furthermore, the Intel 830M Chipset supports a discrete AGP graphics device by multiplexing an AGP interface with the DVOB and DVOC interfaces.

3 Signal Description

This section provides a detailed description of the Intel 830 Chipset family GMCH-M signals. The signals are arranged in functional groups according to their associated interface.

The "#" symbol at the end of a signal name indicates that the active, or asserted state occurs when the signal is at a low voltage level. When "#" is not present after the signal name the signal is asserted when at the high voltage level.

When not otherwise specified, "set" refers to changing a bit to its asserted state (a logical 1). Clear refers to changing a bit to its negated state (a logical 0). The following notations are used to describe the signal type:

The following notations are used to describe the signal type:

I	Input pin			
0	Output pin			
I/O	Bi-directional Input/Output pin			
s/t/s	Sustained Tristate. This pin is driven to its inactive state prior to tri-stating.			
as/t/s	Active Sustained Tristate. This applies to some of the Hub interface signals. This pin is weekly driven to its last driven value.			
The signal description also includes the type of buffer used for the particular signal:				
AGTL	Open Drain 1.25-V AGTL interface signal. Refer to the AGTL I/O Specification for complete details. AGTL signals are "inverted bus" style where a low voltage represents a logical "1".			
AGP/1.5V	Signals used for AGP or 1.5V interfaces. AGP signals are compatible with AGP 2.0 1.5-V Signaling Environment DC and AC Specifications. The buffers are not 3.3-V tolerant.			
LVTTL	Low Voltage TTL compatible signals. These are also 3.3-V outputs.			
CMOS	CMOS buffers.			

Note that CPU address and data bus signals are logically inverted signals. In other words, the actual values are inverted of what appears on the CPU bus. This must be taken into account and the addresses and data bus signals must be inverted inside the GMCH-M. All CPU control signals follow normal convention. A 0 indicates an active level (low voltage) if the signal is followed by # symbol and a 1 indicates an active level (high voltage) if the signal has no # suffix.

Table 1 shows the Vtt/Vdd and Vref levels for the various interfaces.

Table 1. Signal Voltage Levels

Interface	Vtt/Vdd (nominal)	Vref
AGTL	1.25 V	2/3 * Vtt
1.5 V/AGP	1.5 V	0.5 * Vdd
LVTTL	3.3 V	Vddq * 0.5
RSL [Reserved]	1.8 V	1.4 V
Hub Interface	1.8 V	0.5 * Vdd

3.1 Common Signals for the Intel 830 Chipset Family

This section describes the common signals that apply to the entire Intel 830 Chipset family. The Intel 830 Chipset family common signals consist of: Host Interface signals, System Memory signals, Hub Interface signals, and Clock and Reset Signals.

3.1.1 Host Interface Signals

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Table 2. Host Interface Signal Descriptions

Signal Name	Туре	Description
CPURST#	O AGTL	CPU Reset . The CPURST# pin is an output from the GMCH-M. The GMCH-M asserts CPURST# while RESET# (PCIRST# from ICH3-M) is asserted and for approximately 1 ms after RESET# is deasserted. The CPURST# allows the CPUs to begin execution in a known state.
		Note that the ICH3-M must provide CPU strap set-up and hold times around CPURST#. This requires strict synchronization between GMCH-M CPURST# deassertion and ICH3-M driving the straps.
HA[31:3]#	I/O AGTL	Host Address Bus : HA[31:3]# connect to the CPU address bus. During CPU cycles the HA[31:3]# are inputs. The GMCH-M drives HA[31:3]# during snoop cycles on behalf of hub interface and AGP/Secondary PCI initiators. Note that the address bus is inverted on the CPU bus.
HD[63:0]#	I/O AGTL	Host Data: These signals are connected to the CPU data bus. Note that the data signals are inverted on the CPU bus.
ADS#	I/O AGTL	Address Strobe: The CPU bus owner asserts ADS# to indicate the first of two cycles of a request phase.
BNR#	I/O AGTL	Block Next Request : Used to block the current request bus owner from issuing a new request. This signal is used to dynamically control the CPU bus pipeline depth.
BPRI#	O AGTL	Priority Agent Bus Request : The GMCH-M is the only Priority Agent on the CPU bus. It asserts this signal to obtain the ownership of the address bus. This signal has priority over symmetric bus requests and will cause the current symmetric owner to stop issuing new transactions unless the HLOCK# signal was asserted.
DBSY#	I/O AGTL	Data Bus Busy : Used by the data bus owner to hold the data bus for transfers requiring more than one cycle.
DEFER#	O AGTL	Defer : GMCH-M will generate a deferred response as defined by the rules of the GMCH-M's dynamic defer policy. The GMCH-M will also use the DEFER# signal to indicate a CPU retry response.
DRDY#	I/O AGTL	Data Ready: Asserted for each cycle that data is transferred.
HIT#	I/O AGTL	Hit : Indicates that a caching agent holds an unmodified version of the requested line. Also, driven in conjunction with HITM# by the target to extend the snoop window.
HITM#	I/O AGTL	Hit Modified : Indicates that a caching agent holds a modified version of the requested line and that this agent assumes responsibility for providing the line. Also, driven in conjunction with HIT# to extend the snoop window.
HLOCK#	I AGTL	Host Lock : All CPU bus cycles sampled with the assertion of HLOCK# and ADS#, until the negation of HLOCK# must be atomic, i.e. no hub interface or AGP/PCI snoopable access to SDRAM is allowed when HLOCK# is asserted by the CPU.

HREQ[4:0]#	I/O AGTL	Host Request Command : Asserted during both clocks of request phase. In the first clock, the signals define the transaction type to a level of detail that is sufficient to begin a snoop request. In the second clock, the signals carry additional information to define the complete transaction type. The transactions supported by the GMCH-M Host Bridge are defined in the Host Interface section of this document.	
HTRDY#		Host Target Ready: Indicates that the target of the CPU transaction is able to enter the data transfer phase.	
	AGIL		
RS[2:0]#	I/O	Response Signals: Indicates type of response according to the following table:	
	AGTL	RS[2:0] Response type	
		000 Idle state 001 Retry response	
		010 Deterred response	
		100 Hard Eailure (not driven by GMCH-M)	
		101 No data response	
		110 Implicit Writeback	
		111 Normal data response	
GTL_RCOMP	I/O	GTL Compensation : Used to calibrate the GTL interface buffers to match the board. This pin should be connected to an 80- Ω simple resistor to ground.	

Total pins for this section: 113.
3.1.2 System Memory Interface

Table 3. System Memory Interface Signal Descriptions

Signal Name	Туре	Description
SM_MA[12:0]	O LVTTL	Memory Address : SM_MA[12:0] are used to provide the multiplexed row and column address to SDRAM.
SM_BA[1:0]	O LVTTL	Memory Bank Address : These signals define the banks that are selected within each SDRAM row. The SM_MA and SM_BA signals combine to address every possible location within a SDRAM device.
SM_MD[63:0]	1/0 1 VTTI	Memory Data: These signals are used to interface to the SDRAM data bus.
SM_DQM[7:0]	O LVTTL	Input/Output Data Mask : These pins act as synchronized output enables during read cycles and as byte enables during write cycles.
SM_CS[3:0]#	O LVTTL	Chip Select : For the memory rows configured with SDRAM, these pins perform the function of selecting the particular SDRAM components during the active state. Note: There is one SM_CS per SDRAM row. These signals can be toggled on every rising System Memory Clock edge.
SM_RAS#	O LVTTL	SDRAM Row Address Strobe : A table of the SDRAM commands supported by the Intel 830 Chipset family is given in the SDRAM section. SM_RAS# may be heavily loaded and requires 2 SDRAM clock cycles for setup time to the SDRAMs.
SM_CAS#	O LVTTL	SDRAM Column Address Strobe : A table of the SDRAM commands supported by the Intel 830 Chipset family is given in the SDRAM section. SM_CAS# may be heavily loaded and requires 2 SDRAM clock cycles for setup time to the SDRAMs.
SM_WE#	O LVTTL	Write Enable Signal : SM_WE# is asserted during writes to SDRAM. Refer to truth table of the SDRAM commands supported by the Intel 830 Chipset family, given in the SDRAM section. SM_WE# may be heavily loaded and requires 2 SDRAM clock cycles for setup time to the SDRAMs.
SM_CKE[3:0]	O LVTTL	Clock Enable : These signals are used to signal a self-refresh or power down command to a SDRAM array when entering system suspend. SM_CKE is also used to dynamically power down inactive SDRAM rows. There is one SM_CKE per SDRAM row. These signals can be toggled on every rising SM_CLK Clock edge.
SM_OCLK	O LVTTL	System Memory Output Clock : This signal delivers a synchronized clock to the SM_RCLK pin.
SM_RCLK	I LVTTL	System Memory Return Clock : This signal receives the synchronized clock from SM_OCLK.
SM_CLK [3:0]	O LVTTL	System Memory Clock : These signals deliver a synchronized clock to the SDRAMs.
SM_RCOMP	I/O	System Memory RCOMP: Used to calibrate the system memory I/O buffers. This pin should be connected to a $27.5-\Omega$ resistor tied to Vss.

Total pins for System Memory Section: 105.

3.1.3 Hub Interface Signals

Table 4. Hub Interface Signal Descriptions

Signal Name	Туре	Description
HL[10:0]	I/O (as/t/s) CMOS	HL[10:0] Hub Interface Signals. Signals used for the hub interface.
HLSTRB; HLSTRB#	I/O (as/t/s) CMOS	HLSTRB; HLSTRB# Hub Interface Strobe/Complement. The two differential strobe signals used to transmit or receive packet data.
HL_RCOMP	I/O	HL_RCOMP Hub Interface Compensation: Used to calibrate the hub I/O buffers. This signal has an external 55-ohm pull-down resistor.

Total pins for this section: 14.

3.1.4 Clocking and Reset

Table 5. Clocking and Reset Signal Descriptions

Signal Name	Туре	Description
HTCLK; HTCLK#	I CMOS	Host Clock In : These pins receive a buffered host clock from the external clock synthesizer. This clock is used by all of the GMCH-M. The clock is also the reference clock for the graphics core PLL. This is a low voltage differential input.
GBOUT	0 LVTTL	AGP/Hub Clock Reference Output: This clock goes to the external AGP/Hub/PCI buffer.
GBIN	I LVTTL	AGP/Hub Input Clock : 66 MHz, 3.3-V input clock from external buffer AGP/Hub-link interface.
GM_GCLK; GM_RCLK	O CMOS	Graphics Memory Clock Out: (Reserved) These signals should leave as NC ("Not Connected").
DCLKREF	I LVTTL	Display Clock Input: This pins provides a 48-MHz input clock to the Display PLL that is used for 2D/Video/Flat Panel and DAC. The signal needs pull down if ext graphics solution is implemented.
RESET#	I LVTTL	Reset In : When asserted, this signal will asynchronously reset the GMCH-M logic. This signal is connected to the PCIRST# output of the ICH3-M. The ICH3-M drives this to 3.3 V. All AGP/PCI output and bi-directional signals will also tri-state compliant to PCI rev 2.2 specifications. This input should have a Schmidt trigger to avoid spurious resets. Note that this input needs to be 3.3-V tolerant.

Total pins for Clocks/Resets section: 8.

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3.1.5 Reserved Signals

Table 6. Intel Reserved Signals

Signal Name	Туре	Description
DQ_A[7:0]		Intel Reserved. Should be left NC ("Not Connected")
DQ_B[7:0]		Intel Reserved. Should be left NC ("Not Connected")
RQ[7:0]		Intel Reserved. Should be left NC ("Not Connected")
CTM;CTM#		Intel Reserved . Requires pull down.
CFM;CFM#		Intel Reserved. Should be left NC ("Not Connected")
CMD		Intel Reserved. Should be left NC ("Not Connected")
SCK		Intel Reserved. Should be left NC ("Not Connected")
SIO		Intel Reserved. Should be left NC ("Not Connected")

Total reserved pins: 31.

3.2 Common Signals for 830M and 830MP Chipset Discrete AGP Graphics Implementation

The Intel 830M and 830MP Chipset support an external AGP graphics solution. The following signals apply only when an external AGP graphics solution is implemented. Please consult Section 3.3 for internal graphics implementation with the Intel 830M and 830MG Chipset. For signal multiplexing information between AGP and DVO/Display signals, please refer to Sections 3.3.3.1 and 3.3.5.2. Please see *Intel*[®] 830 Chipset Family Design Guide for design recommendations required for pins where NO functionality is defined for the chosen SKU.

3.2.1 AGP Addressing Signals

Table 7. AGP Addressing Signal Descriptions

Signal Name	Туре	Description
PIPE#	I AGP	Pipelined Read : This signal is asserted by the current master to indicate a full width address is to be queued by the target. The master queues one request each rising clock edge while PIPE# is asserted. When PIPE# is deasserted no new requests are queued across the AD bus. PIPE# is a sustained tri-state signal from the master (graphics controller) and is an input to the GMCH-M.
SBA[7:0]	l AGP	Sideband Address : This bus provides an additional bus to pass address and command to the GMCH-M from the AGP master.

The above table contains two mechanisms to queue requests by the AGP master. Note that the master can only use one mechanism. When PIPE# is used to queue addresses, the master is not allowed to queue addresses using the SBA bus. For example, during configuration time, if the master indicates that it can use either mechanism, the configuration software will indicate which mechanism the master will use. Once this choice has been made, the master will continue to use the mechanism selected until the master is reset (and reprogrammed) to use the other mode. This change of modes is not a dynamic mechanism but rather a static decision when the device is first being configured after reset.

3.2.2 AGP Flow Control Signals

Table 8. AGP Flow Control Signal Descriptions

Signal Name	Туре	Description
RBF#	I AGP	Read Buffer Full : Indicates if the master is ready to accept previously requested low priority read data.
		When RBF# is asserted, the GMCH-M is not allowed to return low priority read data to the AGP master on the first block. RBF# is only sampled at the beginning of a cycle. If the AGP master is always ready to accept return read data, it is not required to implement this signal.
WBF#	I AGP	Write Buffer Full: Indicates if the master is ready to accept fast write data from the GMCH-M.
		When WBF# is asserted, the GMCH-M is not allowed to drive fast write data to the AGP master. WBF# is only sampled at the beginning of a cycle. If the AGP master is always ready to accept fast write data, it is not required to implement this signal.

3.2.3 AGP Status Signals

Table 9. AGP Status Signal Descriptions

Signal Name	Туре	Description
ST[2:0]	O AGP	Status : Provides information from the arbiter to the AGP Master on what it may do.
		ST[2:0] only have meaning to the master when its GNT# is asserted. When GNT# is deasserted these signals have no meaning and must be ignored.
		000 Indicates that previously requested low priority read data is being returned.
		001 Indicates that previously requested high priority read data is being returned.
		010 Indicates that the master is to provide low priority write data for a previously queued write command.
		011 Indicates that the master is to provide high priority write data for a previously queued write command.
		100 Reserved
		101 Reserved
		110 Reserved
		111 Indicates that the master has been given permission to start a bus transaction. The master may queue AGP requests by asserting PIPE# or start a PCI transaction by asserting FRAME#. ST[2:0] are always an output from the GMCH-M and an input to the master.
AGP_RCOMP	I/O	AGP RCOMP: Used to calibrate AGP I/O buffers for 830M and 830MP discrete AGP interface
		Please refer to the Intel [®] 830 Chipset Family Design Guide for pull down resistor value.

3.2.4 AGP Clocking Signals – Strobes

Table 10. AGP Clock Signal-Strobe Descriptions

Signal Name	Туре	Description
AD_STB0	I/O (s/t/s) AGP	AD Bus Strobe-0 : Provides timing for 2x and 4x clocked data on AD[15:0] and C/BE[1:0]#. The agent that is providing data drives this signal.
AD_STB0#	I/O (s/t/s) AGP	AD Bus Strobe-0 Complement : The differential complement to the AD_STB0 signal. It is used to provide timing for 4x clocked data.
AD_STB1	I/O (s/t/s) AGP	AD Bus Strobe-1 : Provides timing for 2x and 4x clocked data on AD[31:16] and C/BE[3:2]#. The agent that is providing data drives this signal.
AD_STB1#	I/O (s/t/s) AGP	AD Bus Strobe-1 Complement : The differential complement to the AD_STB1 signal. It is used to provide timing for 4x clocked data.
SB_STB	l AGP	Sideband Strobe : Provides timing for 2x and 4x clocked data on the SBA[7:0] bus. The AGP master drives it after the system has been configured for 2x or 4x clocked sideband address delivery.
SB_STB#	l AGP	Sideband Strobe Complement : The differential complement to the SB_STB signal. It is used to provide timing for 4x clocked data.

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3.2.5 PCI Signals - AGP Semantics

PCI signals are redefined when used in AGP transactions that are carried using AGP protocol extension. For transactions on the AGP interface that are carried using PCI protocol, these signals completely preserve PCI 2.2 semantics. The exact roles of all PCI signals during AGP transactions are defined below.

Table 11. PCI Signals – AGP Semantics Signal Descriptions

Signal Name	Туре	Description
G_FRAME#	I/O	Not used during an AGP pipelined transaction.
	s/t/s	G_FRAME# is an output from the GMCH-M during Fast Writes.
	AGP	
G_IRDY#	I/O s/t/s	G_IRDY# indicates the AGP compliant master is ready to provide all write data for the current transaction.
	AGP	Once IRDY# is asserted for a write operation, the master is not allowed to insert wait states. The assertion of IRDY# for reads indicates that the master is ready to transfer to a subsequent block (32 bytes) of read data. The master is never allowed to insert a wait state during the initial data transfer (32 bytes) of a read transaction. However, it may insert wait states after each 32-byte block is transferred. (There is no G_FRAME# G_IRDY# relationship for AGP transactions.)
		For Fast Write transactions, G_IRDY# is driven by the GMCH-M to indicate when the write data is valid on the bus. The GMCH-M deasserts this signal to insert wait states on block boundaries.
G_TRDY#	I/O s/t/s AGP	G_TRDY# indicates the AGP compliant target is ready to provide read data for the entire transaction (when the transfer size is less than or equal to 32 bytes) or is ready to transfer the initial or subsequent block (32 bytes) of data when the transfer size is greater than 32 bytes.
		transferred on both read and write transactions.
		For Fast Write transactions, the AGP master uses this signal to indicate when it is willing to transfer a subsequent block.
G_STOP#	I/O	G_STOP# Not used during an AGP transaction.
	s/t/s AGP	For Fast Write transactions G_STOP# is used to signal Disconnect or Target Abort terminations.
G_DEVSEL#	I/O	G_DEVSEL# Not used during an AGP transaction.
	s/t/s AGP	For Fast Write transactions, it is used when the transaction cannot complete during the block.
G_REQ#	l AGP	G_REQ# Used to request access to the bus to initiate a PCI or AGP request.
G_GNT#	O AGP	G_GNT# Same meaning as PCI but additional information is provided on ST[2:0].
		The additional information indicates that the selected master
		 Is the recipient of previously requested read data (high or normal priority) Is to provide write data (high or normal priority), for a previously queued write command or
		Has been given permission to start a bus transaction (AGP or PCI).
G_AD[31:0]	I/O	G_AD[31:0] Same as PCI.

	AGP	
G_C/BE[3:0]#	I/O	G_C/BE[3:0]# Slightly different meaning.
	AGP	 Provides command information (different commands than PCI) when requests are being queued when using PIPE#.
		 Provide valid byte information during AGP write transactions and are not used during the return of read data.
G_PAR	I/O AGP	G_PAR Same as PCI. Not used on AGP transactions but used during PCI transactions as defined by the PCI specification.

NOTES:

- PCIRST# from the ICH3-M is connected to RESET# and is used to reset AGP interface logic within the GMCH-M. The AGP agent will also use PCIRST# provided by the as an input to reset its internal logic.
 LOCK# signal is not supported on the AGP interface (even for PCI operations).
 The SERR# and PERR# signals are not supported on the AGP interface.

Total pins for AGP section: 66.

3.2.6 **PCI Pins During PCI Transactions on AGP Interface**

PCI signals described in a previous table behave according to PCI 2.2 specifications when used to perform PCI transactions on the AGP Interface.

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3.3 Common Signals for 830M and 830MG Chipset Internal Graphics Implementation

An internal graphics device is available with the Intel 830M and 830MG Chipset. The following signals apply when the internal graphics device is chosen. The internal graphics device has support for Dedicated Digital Video Port (DVOA), Dual DVOB and DVOC ports, and Analog Display. Please consult Section 3.2 for discrete AGP implementation with 830M or 830MP Chipset. Also see Sections 3.3.3.1 and 3.3.5.2 for signal mapping information between discrete AGP and DVO/Display signals for the 830M SKU. Please refer to the *Intel*[®] 830 Chipset Family Design Guide regarding design recommendations for pins where no functionality is defined for the chosen SKU.

Table 12. Internal Graphics Status Signal Descriptions

Signal Name	Туре	Description
AGP_BUSY#	OD	AGP_BUSY# : Output of the Intel 830M or 830MG GMCH-M graphics controller to the ICH3-M, which indicates that certain internal graphics (IGD) activity is taking place. Assertion indicates to the ACPI software to not enter the C3 state. Assertion also causes a C3 exit if C3 was being entered, or was already entered when AGP_BUSY# went active. AGP_BUSY# will be inactive when the graphics controller is in any ACPI state other than D0.
		AGP_BUSY# must be pulled up to a voltage rail which turned off in the ACPI S3-S5 stages.

3.3.1 Dedicated Digital Video Port (DVOA)

Table 13. Dedicated Digital Video Port (DVOA) Signal Descriptions

Name	Туре	Description
DVOA_CLK; DVOA_CLK#	0 1.5 V	 DVO Clock Output: These pins provide a differential pair reference clock that can run up to 165 MHz. DVOA_CLK (DVOCLKOUT0) (AJ24) corresponds to the primary clock out. DVOA_CLK# (DVOCLKOUT1) (AG24) corresponds to the primary clock out. DVOA_CLK and DVOA_CLK# need to be pulled up if: i) The signals are NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DVOA_D[11:0]	0 1.5 V	 DVO Data: This data bus is used to drive 12-bit RGB data on each edge of DVOA_CLKOUT. This provides 24-bits of data per clock. DVOA_D[11:0] should be left as NC (not connected) if: i) The signals are NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DVOA_HSYNC	0 1.5 V	 Horizontal Sync: HSYNC signal for the DVO interface. The active polarity of the signal is programmable. DVOA_HYSNC should be left as NC (not connected) if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DVOA_VSYNC	0 1.5V	 Vertical Sync: VSYNC signal for the DVO interface. The active polarity of the signal is programmable. DVOA_VSYNC should be left as NC (not connected) if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DVOA_BLANK#	0 1.5 V	 Flicker Blank or Border Period Indication: DVOA_BLANK# is a programmable output pin driven by the GMCH-M. When programmed as a blank period indication, this pin indicates active pixels excluding the border. When programmed as a border period indication, this pin indicates active pixel including the border pixels. DVOA_BLANK# should be left as NC (not connected) if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DVOA_RCOMP	I/O	DVO Compensation : Used to calibrate the DVOA I/O buffers. This signal needs to be pulled down to ground through an external resistor (resistance is based on board impedance).
DVOA_INTR#	l 1.5 V	 DVO Interrupt: This pin is used to signal an interrupt, typically used to indicate a hot plug or unplug of a digital display. DVOA_INTR# needs to be pulled up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DVOA_CLKINT	l 1.5 V	DVO Pixel Clock Input/Interrupt input pin can be programmed to be either a reference input to a dot clock PLL (DPLL) or to be a second interrupt input. DVO Pixel Clock Input : When used as a pixel clock input, this signal may be selected as a reference input for an external TV encoder.

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		DVO Interrupt: When used as an interrupt input, the signal is internally ANDed with the DVOA_INTR# signal inside the GMCH-M.
		DVOA_CLKINT needs to be pulled up if:
		i) The signal is NOT used when using internal graphics device, or
		ii) Discrete AGP device is implemented.
DVOA_FLD/STL	I	DVOA_FLD/STL input pin can be programmed to be either a TV Field input
	1.5 V	from the TV encoder or Stall input from the flat panel.
		DVOA TV Field Stall Signal . When used as a Field input, it synchronizes the overlay field with the TV encoder field when the overlay is displaying an interleaved source.
		DVOA Flat Panel Stall Signal . When used as the Stall input, it indicates that the pixel pipeline should stall one horizontal line. The signal changes during horizontal blanking. This is used by the panel fitting logic when expanding the image vertically.
		DVOA_FLD/STL needs to be pulled down if:
		i) The signal is NOT used when using internal graphics device, or
		ii) Discrete AGP device is implemented.

Total pins for DVOA section: 21.

3.3.2 Multiplexed Digital Video Port B (DVOB)

Table 14. Multiplexed DVOB (DVOB) Signal Descriptions

Name	Туре	Description	
DVOB_CLK; DVOB_CLK#	O AGP	DVO Clock Output : These pins provide a differential pair reference clock that can run up to 165 MHz. DVOB_CLK (DVOCLKOUT0) corresponds to the primary clock out. DVOB_CLK# (DVOCLKOUT1) corresponds to the primary clock out. DVOB_CLK and DVOB_CLK# should be left as NC ("Not Connected") if the signals are NOT used when using internal graphics device.	
DVOB_D[11:0]	O AGP	DVO Data : This data bus is used to drive 12-bit RGB data on each edge of DVOB_CLKOUT. This provides 24-bits of data per clock. DVOB_D[11:0] should be left as left as NC ("Not Connected") if the signal are NOT used when using internal graphics device.	
DVOB_HSYNC	O AGP	Horizontal Sync: HSYNC signal for the DVO interface. The active polarity of the signal is programmable. DVOB_HSYNC should be left as left as NC ("Not Connected") if the signal is NOT used when using internal graphics device.	
DVOB_VSYNC	O AGP	Vertical Sync: VSYNC signal for the DVO interface. The active polarity of the signal is programmable. DVOB_VSYNC should be left as left as NC ("Not Connected") if the signal is NOT used when using internal graphics device.	
DVOB_BLANK#	O AGP	Flicker Blank or Border Period Indication: DVOB_BLNK# is a programmable output pin driven by the GMCH-M.When programmed as a blank period indication, this pin indicates active pixels excluding the border.When programmed as a border period indication, this pin indicates active pixel including the border pixels.DVOB_BLANK# should be left as left as NC ("Not Connected") if the signal is NOT used when using internal graphics device.	
DVOBC_CLKINT	I AGP	 DVOBC Pixel Clock Input/Interrupt: This signal may be selected as the reference input to either dot clock PLL (DPLL) or may be configured as an interrupt input. DVOBC Pixel Clock Input: When selected as the dot clock PLL (DPLL) reference input, this clock reference input supports SSC clocking for DVO LVDS devices. DVOBC Interrupt: When configured as an interrupt input, this interrupt can support for either of the DVOB or DVOC. DVOBC_CLKINT needs to be pulled up if the signal is NOT used when using internal graphics device. 	
DVOB_FLD/STL	I AGP	 TV Field and Flat Panel Stall Signal. This input can be programmed to either be a TV Field input from the TV encoder or Stall input from the flat panel. DVOB TV Field Signal: When used as a Field input, it synchronizes the overlay field with the TV encoder field when the overlay is displaying an interleaved source. DVOB Flat Panel Stall Signal: When used as the Stall input, it indicates that the pixel pipeline should stall one horizontal line. The signal changes during horizontal blanking. This is used by the panel fitting logic when expanding the image vertically. 	

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DVOB_FLD/STL needs to be pulled down if the signal is NOT used when using internal graphics device.

Total multiplexed pins for DVOB (and DVOC) section: 19.

3.3.3 Multiplexed Digital Video Port (DVOC)

Table 15. Multiplexed Digital Video port C (DVOC) Signal Descriptions

Name	Туре	Description	
DVOC_CLK; DVOC_CLK#	O AGP	DVO Clock Output : These pins provide a differential pair reference clock that can run up to 165 MHz.	
	_	DVOC_CLK (DVOCLKOUT0) corresponds to the primary clock out. DVOC_CLK# (DVOCLKOUT1) corresponds to the primary clock out.	
		DVOC_CLK and DVOC_CLK# should be left as NC ("Not Connected") if the signal are NOT used when using internal graphics device.	
DVOC_D[11:0]	O AGP	DVO Data : This data bus is used to drive 12-bit RGB data on each edge of DVOC_CLKOUT. This provides 24-bits of data per clock.	
		DVOC_D[11:0] should be left as NC ("Not Connected") if the signals are NOT used when using internal graphics device.	
DVOC_HSYNC	O AGP	Horizontal Sync: HSYNC signal for the DVO interface. The active polarity of the signal is programmable.	
		DVOC_HSYNC should be left as NC ("Not Connected") if the signal is NOT used when using internal graphics device.	
DVOC_VSYNC	O AGP	Vertical Sync : VSYNC signal for the DVO interface. The active polarity of the signal is programmable.	
		DVOC_VSYNC should be left as NC ("Not Connected") if the signal is NOT used when using internal graphics device.	
DVOC_BLANK#	O AGP	Flicker Blank or Border Period Indication: DVOC_BLNK# is a programmable output pin driven by the GMCH-M.	
	_	When programmed as a blank period indication, this pin indicates active pixels excluding the border.	
		When programmed as a border period indication, this pin indicates active pixel including the border pixels.	
		DVOC_BLANK# should be left as NC ("Not Connected") if the signal is NOT used when using internal graphics device.	
DVOBC_INTR#/	l AGP	DVOBC Interrupt : This pin is used to signal an interrupt, typically used to indicate a hot plug or unplug of a digital display.	
		DMPS_CLK : When internal graphics is used, this signal is needed to provide the necessary clock source for D1/S1 state support.	
DVOC_FLD/STL	I AGP	TV Field and Flat Panel Stall Signal . This input can be programmed to either be a TV Field input from the TV encoder or Stall input from the flat panel.	
		DVOC TV Field Signal: When used as a Field input, it synchronizes the overlay field with the TV encoder field when the overlay is displaying an interleaved source.	
		DVOC Flat Panel Stall Signal : When used as the Stall input, it indicates that the pixel pipeline should stall one horizontal line.	
		DVOC_FLD/STL needs to be pulled down if the signal is NOT used when using internal graphics device.	

Total multiplexed pins for DVOB (and DVOC) section: 19.

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3.3.3.1 DVOBC to AGP Pin Mapping

Table 16. Multiplexed DVOBC to AGP Pin Mapping Information

DVO Signal Name	AGP Signal Name	DVO Signal Name	AGP Signal Name
DVOB_D0	AD3	DVOC_D0	AD19
DVOB_D1	AD2	DVOC_D1	AD20
DVOB_D2	AD5	DVOC_D2	AD21
DVOB_D3	AD4	DVOC_D3	AD22
DVOB_D4	AD7	DVOC_D4	AD23
DVOB_D5	AD6	DVOC_D5	CBE3#
DVOB_D6	AD8	DVOC_D6	AD25
DVOB_D7	CBE0#	DVOC_D7	AD24
DVOB_D8	AD10	DVOC_D8	AD27
DVOB_D9	AD9	DVOC_D9	AD26
DVOB_D10	AD12	DVOC_D10	AD29
DVOB_D11	AD11	DVOC_D11	AD28
DVOB_CLK	ADSTB0	DVOC_CLK	ADSTB1
DVOB_CLK#	ADSTB0#	DVOC_CLK#	ADSTB1#
DVOB_HSYNC	AD0	DVOC_HSYNC	AD17
DVOB_VSYNC	AD1	DVOC_VSYNC	AD16
DVOB_BLANK#	CBE1#	DVOC_BLANK#	AD18
DVOBC_CLKINT#	AD13	DVOBC_INTR#/DPMS_CLK	AD30
DVOB_FLD/STL	AD14	DVOC_FLD/STL	AD31
DVOBC_RCOMP	AGP_RCOMP		

3.3.3.2 DVO Miscellaneous Signals

Signal Name	Туре	Description
DVOBC_RCOMP	I/O	DVOBC RCOMP: Used to calibrate DVOBC I/O buffer 830M and 830MG internal graphics device. Please refer to the Intel 830 Chipset Family Design Guide for pull down resistor value.
DVO_DETECT	I/O AGP	DVO_DETECT Used for strapping option for the muxed DVO interface. Please see design guide for requirement.

3.3.4 Analog Display

Table 17. Analog Display Signal Descriptions

Pin Name	Туре	Description
VSYNC	O LVTTL	CRT Vertical Synchronization : This signal is used as the vertical sync (polarity is programmable) or "VSYNC Interval". VSYNC should be left as NC ("Not Connected") if discrete AGP device is implemented.
HSYNC	O LVTTL	CRT Horizontal Synchronization: This signal is used as the horizontal sync (polarity is programmable). HSYNC should be left as NC ("Not Connected") if discrete AGP device is implemented.
RED	O Analog	Red (Analog Video Output) : This signal is a CRT Analog video output from the internal color palette DAC. The DAC is designed for a 37.5 W equivalent load on each pin (e.g., 75-W resistor on the board, in parallel with the 75-W CRT load). RED can be left as NC ("Not Connected") if discrete AGP device is implemented.
GREEN	O Analog	Green (Analog Video Output) : This signal is a CRT analog video output from the internal color palette DAC. The DAC is designed for a 37.5 W equivalent load on each pin (e.g., 75-W resistor on the board, in parallel with the 75-W CRT load). GREEN can be left as NC ("Not Connected") if discrete AGP device is implemented.
BLUE	O Analog	Blue (Analog Video Output) : This signal is a CRT Analog video output from the internal color palette DAC. The DAC is designed for a 37.5 W equivalent load on each pin (e.g., 75-W resistor on the board, in parallel with the 75-W CRT load). BLUE can be left as NC ("Not Connected") if discrete AGP device is implemented.
REFSET	I NA	Resistor Set : Set point resistor for the internal color palette DAC. A 255-W 1% resistor is required between REFSET and VSSA. RESET can be left as NC ("Not Connected") if discrete AGP device is implemented.
RED#	O Analog	Red#(Analog Output) : This signal is an analog video output from the internal color palette DAC connected to a 37.5-ohm resistor to ground. This is used to provide noise immunity. Please refer to the <i>Intel®</i> 830 Chipset Family Design Guide. RED# can be left as NC ("Not Connected") if discrete AGP device is implemented.
GREEN#	O Analog	Green# (Analog Output): This signal is an analog video output from the internal color palette DAC connected to a 37.5-ohm resistor to ground This is used to provide noise immunity. Please refer to the <i>Intel® 830 Chipset Family Design Guide</i> . GREEN# can be left as NC ("Not Connected") if discrete AGP device is implemented.
BLUE#	O Analog	Blue# (Analog Output) : This signal is an analog video output from the internal color palette DAC connected to a 37.5 ohm resistor to ground. This is used to provide noise immunity. Please refer to the <i>Intel® 830 Chipset Family Design Guide</i> . BLUE# can be left as NC ("Not Connected") if discrete AGP device is implemented.

Total pins for Display section: 9.

3.3.5 Display Control Signals

Table 18. Display Control Signal Descriptions

Pin Name	Туре	Description
DDC1_CLK	I/O LVTTL	 DDC1_CLK: The specific function is DDC_CLK for CRT/analog display. This signal is tri-stated during a hard reset. DDC1_CLK needs to be pulled up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DDC1_DATA	I/O LVTTL	 DDC1_DATA: The specific function is DDC_DATA for CRT/analog display. This signal is tri-stated during a hard reset. DDC1_DATA needs to be pulled up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
I2C_CLK	I/O LVTTL	 I2C_CLK: The specific function is I2C CLK. This signal can be used as GMBUS bus for DVOA/B/C device. This signal is tri-stated during a hard reset. I2C_CLK needs to be pulled up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
I2C_DATA	I/O LVTTL	 I2C_DATA: The specific function is I2C_DATA. This signal can be used as GMBUS bus for DVOA/B/C device. This signal is tri-stated during a hard reset. I2C_DATA needs to pull up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DDC2_CLK	I/O LVTTL	 DDC2_CLK: The specific function is DDC_CLK for digital display, EDID info or as GMBUS bus for DVOA/B/C device. This signal is tri-stated during a hard reset. DDC2_CLK needs to be pull up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.
DDC2_DATA	I/O LVTTL	 DDC2_DATA: The specific function is DDC_DATA for digital display, EDID info or as GMBUS bus for DVOA/B/C device. This signal is tri-stated during a hard reset. DDC2_DATA needs to be pull up if: i) The signal is NOT used when using internal graphics device, or ii) Discrete AGP device is implemented.

Total pins for this section: 6.

3.3.5.1 DVO Display Control Signals

Table 19. DVO Display Control Signals Descriptions

Pin Name	Туре	Description
M_I2C_CLK	I/O	M_I2C_CLK: The specific function is I2C_CLK for the muxed DVOs.
	1.5 V	M_I2C_CLK needs to be pulled up if:
		i) The signal is NOT used when using internal graphics device.
M_I2C_DATA		M_I2C_DATA: The specific function is I2C_DATA for the muxed DVOs.
		M_I2C_DATA needs to be pulled up if:
	1.5 V	i) The signal is NOT used when using internal graphics device.
M_DDC1_CLK		M_DDC1_CLK : The specific function is DDC1_CLK for the muxed DVOs.
		M_DDC1_CLK needs to be pulled up if:
	1.5 V	i) The signal is NOT used when using internal graphics device.
M_DDC1_DATA		M_DDC1_DATA: The specific function is DDC1_DATA for the muxed DVOs.
		M_DDC1_DATA needs to be pulled up if:
	1.5 V	i) The signal is NOT used when using internal graphics device.

Total multiplexed pins for this section: 4.

3.3.5.2 Display Control Signals to AGP Pin Mapping

Table 20. Display Signals to AGP Pin Mapping Signal Descriptions

GPIO Signal Name	AGP Signal Name	GPIO Signal Name	AGP Signal Name
M_I2C_Clk	IRDY#	M_DDC1_CLK	G_TRDY#
M_I2C_data	DEVSEL#	M_DDC1_DATA	G_FRAME#

3.4 Intel 830 Chipset Family Voltage References, PLL Power

Table 21. Voltage References, PLL Power Signal Descriptions

Signal Name	Number	Description
GTL_REF[B:A]	2	GTL Reference : Reference voltage input for the Host AGTL interface. GTLREF is 2/3 * VTT. VTT is nominally 1.25 V.
VTT	9	Host Voltage: VTT is nominally 1.25 V for host signals.
AGPREF/ DVOBC_REF	1	AGP Reference: Reference voltage input for the AGP interface. AGPREF is 0.5 * Vagpdd when Vdd=1.5 V. DVO BC interface: DVOBC_REF is 0.5 * Vagpdd when Vdd=1.5 V.
VCC_AGP	8	AGP Voltage: VDD is nominally 1.5 V for AGP.
VCCQ_AGP	2	AGP Quiet Voltage: Quiet voltage for AGP interface is also 1.5 V.
HLREF	1	Hub Interface Reference: Reference voltage input for the hub interface. HLREF is 0.5 * Vdd.
VCC_HUB	2	Hub Interface Voltage: VCC supplies for the hub interface are 1.8 V.
SM_REF[B:A]	2	System Memory Reference : Reference voltage input for system memory is VCC_SM/6 = .55 V.
VCC_SM	14	System Memory Voltage: VCC supplies for system memory are 3.3 V.
VCCQ_SM	5	System Memory Quiet Voltage : Quiet VCC for the system memory interface is 3.3 V.
VCC_GPIO	2	GPIO Voltage: VCC supplies for general purpose I/O signals are 3.3 V.
VCC_DVO	3	DVO Voltage: VCC supplies for digital video output signals are 1.5 V.
VCCA_DAC; VSSA_DAC	21	DAC Voltage : VCCA and VSSA supplies for the DAC. VCCA_DAC is 1.8 V.
RAM_REF[B:A]	2	Reserved(Rambus* Reference) : Reference voltage input for the Rambus RSL interface. RAMREF is approximately 1.4 V. Rambus no longer supported.
VCC_CMOS; VSS_CMOS	43	Reserved(Graphics Memory CMOS Voltage) : VCC and VSS supplies for local memory CMOS signals. VCC_CMOS is 1.8 V. Local memory no longer supported.
VCC_LM	9	Reserved(VCC Graphics Memory Voltage): VCC supplies for local memory. VCC_LM is 1.8 V. Local memory no longer supported.
VDD_LM	7	Reserved(VDD Graphics Memory Voltage) : VDD supplies for local memory. VDD_LM is 1.25V. Local memory no longer supported.
VCCA_CPLL; VSSA_CPLL	11	Graphics Core PLL Voltage : VCCA and VSSA supplies for core PLL. VCCA_CPLL is 1.25 V.
VCCA_HPLL; VSSA_HPLL	11	Host/Memory/Hub/AGP PLL Voltage: VCCA and VSSA supplies for host PLL. VCCA_HPLL is 1.25 V.
VCCA_DPLL[1:0]; VSSA_DPLL[1:0]	22	Display PLL Voltage : VCCA and VSSA supplies for display PLL. VCCA_DPLL is 1.25 V.
VCC	24	Core VCC: 1.25 V.



VSS 140 Ground pins.

3.5 Intel 830 Chipset Family Strap Signals

Table 22 indicates the strap options invoked by various Intel 830 Chipset family GMCH-M signal pins.

Table 22. Bootup Strap Signal Descriptions

Signal Name	Description	
DVOA_D [5]	Desktop/Mobile Selection . The state of this pin on the rising edge of RESET# selects whether the GMCH-M is desktop or mobile.	
	DVOA_D [5] Desktop/Mobile Part	
	0 = Desktop Part (Default)	
	1= Mobile Part	
DVOA_D[7]	XOR Chain. The state of this pin on the rising edge of RESET# select whether to invoke the XOR chain test mode for checking the IO buffer connectivity.	
	DVOA_D[7] XOR Chain Test Mode	
	0 = Default (normal operation; XOR Chain test mode is NOT invoked)	
	1 = XOR chain test mode	
	To invoke the XOR chain test mode, pull up this signal through an external resistor to 1.5 V.	
DVOA_D[8]	All Z. The state of this pin on the rising edge of RESET# select whether to tri-states all GMCH output when ICH3-M is in XOR Chain mode.	
	DVOA_D[8] All Z	
	0 = Default (do NOT tri-states GMCH output)	
	1 = All Z	
	To invoke this strap, pull up this signal through an external resistor to 1.5 V.	

4 **Register Description**

This section details register access and provides PCI register address maps.

4.1 Conceptual Overview of the Platform Configuration Structure

The Intel 830 Chipset family GMCH-M and the ICH3-M are physically connected with the Hub interface. From a configuration standpoint the Hub interface connecting the GMCH-M and the ICH3-M is logically PCI bus #0. All devices internal to the GMCH-M and ICH3-M appear to be on PCI bus #0. The system's primary PCI expansion bus is physically attached to the ICH3-M, and from a configuration standpoint appears as a hierarchical PCI bus behind a PCI-to-PCI bridge. The primary PCI expansion bus connected to the ICH3-M has a programmable PCI Bus number. Note that even though the primary PCI bus is referred to as PCI0 in this document it is not PCI bus #0 from a configuration standpoint.

The GMCH-M contains three PCI devices within a single physical component. The configuration registers for Device 0 and 1 are mapped as devices residing on PCI bus #0.

- Device 0: Host-Hub Interface Bridge/SDRAM Controller. Logically, this appears as a PCI device residing on PCI bus #0. Physically, Device 0 contains the standard PCI registers, AGP capabilities registers¹, SDRAM registers, the Graphics Aperture controller, and other GMCH-M specific registers. Device 0 applies to the entire 830 Chipset family.
- **Device 1: Host-AGP Bridge**. Logically, this appears as a "virtual" PCI-to-PCI bridge residing on PCI bus #0. Physically, Device 1 contains the standard PCI-to-PCI bridge registers and the standard AGP/PCI1 configuration registers (including the AGP I/O and memory address mapping). Device 1 applies to both the Intel 830MP and 830M Chipset.
- Device 2: Integrated Graphics Device (IGD). Logically, this appears as a PCI device residing on PCI bus #0. Physically, Device 2 contains the standard registers of a PCI Graphics Controller Device. Device 2 applies to both the Intel 830M and 830MG Chipset.
- *Note:* ¹AGP capabilities registers are applicable when discrete AGP graphics solution (Intel 830MP/ Intel 830M Chipset) is used.

Logically, the ICH3-M appears as two PCI devices within a single physical component also residing on PCI bus #0. One of the ICH3-M devices residing on PCI Bus #0 is a PCI-to-PCI bridge. Logically, the primary side of the bridge resides on PCI bus #0 while the secondary side is the standard PCI expansion bus (PCI0). Also within the ICH3-M is another PCI Device, the LAN Controller, which resides on the standard PCI expansion bus (PCI0) down from the PCI-to-PCI bridge.

Note that a physical PCI bus #0 does not exist and that Hub Interface and the internal devices in the GMCH-M and ICH3-M logically constitute PCI Bus #0 to configuration software. This is shown in Figure 4, Figure 5, and Figure 6 for the Intel 830MP, Intel 830M, and Intel 830MG Chipsets respectively.



Figure 4. Intel 830MP Chipset Logical Bus Structure During PCI Configuration

Figure 5. Intel 830M Chipset Logical Bus Structure During PCI Configuration



NOTE: Intel 830M Chipset can support the use of either the discrete AGP interface or the internal graphics device.

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Figure 6. 830MG Chipset Logical Bus Structure During PCI Configuration

4.2 Routing Configuration Accesses to PCI0 or AGP/PCI

The Intel 830 Chipset family GMCH-M supports two bus interfaces: Hub Interface and AGP/PCI. PCI configuration cycles are selectively routed to both interfaces. The GMCH-M is responsible for routing PCI configuration cycles to the proper interface. PCI configuration cycles to ICH3-M internal devices and Primary PCI (including downstream devices) are routed to the ICH3-M via Hub Interface. AGP/PCI1 configuration cycles are routed to AGP. The AGP/PCI1 interface is treated as a separate PCI bus from the configuration point of view. Routing of configuration accesses to AGP/PCI1 is controlled via the standard PCI-PCI bridge mechanism using information contained within the PRIMARY BUS NUMBER, the SECONDARY BUS NUMBER, and the SUBORDINATE BUS NUMBER registers of the Host-AGP/PCI1 (device #1).

Note: AGP is only available with 830M and 830MP Chipset; internal graphics device is available with 830M and 830MG Chipset.

4.2.1 Intel 830 Chipset Family GMCH-M Configuration Cycle Flow Charts

Figure 7. Configuration Cycle Flow Chart



A detailed description of the mechanism for translating CPU I/O bus cycles to configuration cycles on one of the two buses is described in Figure 7 above.

4.2.2 PCI Bus Configuration Mechanism

The PCI Bus defines a slot based "configuration space" that allows each device to contain up to 8 functions with each function containing up to 256, 8-bit configuration registers. The PCI specification defines two bus cycles to access the PCI configuration space: Configuration Read and Configuration Write. Memory and I/O spaces are supported directly by the CPU. Configuration space is supported by a mapping mechanism implemented within the GMCH-M. The PCI specification defines two mechanisms to access configuration space, Mechanism #1 and Mechanism #2. The GMCH-M supports only Mechanism #1 for PCI configuration accesses.

The configuration access mechanism makes use of the CONFIG_ADDRESS Register and CONFIG_DATA Register. To reference a configuration register, a Dword I/O write cycle is used to place a value into CONFIG_ADDRESS that specifies the PCI bus, the device on that bus, the function within the device, and a specific configuration register of the device function being accessed. CONFIG_ADDRESS[31] must be first to enable a configuration cycle. CONFIG_DATA then becomes

a window into the four bytes of configuration space specified by the contents of CONFIG_ADDRESS. Any read or write to CONFIG_DATA will result in the Intel 830 Chipset family GMCH-M translating the CONFIG_ADDRESS into the appropriate configuration cycle. The GMCH-M is responsible for translating and routing the CPU's I/O accesses to the CONFIG_ADDRESS and CONFIG_DATA registers to internal GMCH-M configuration registers, Hub Interface, or AGP/PCI1 (applicable when discrete AGP is used with Intel 830M and 830MP Chipset).

4.2.3 PCI Bus #0 Configuration Mechanism

The Intel 830 Chipset family GMCH-M decodes the Bus Number (bits 23:16) and the Device Number fields of the CONFIG_ADDRESS register. If the Bus Number field of CONFIG_ADDRESS is 0 the configuration cycle is targeting a PCI Bus #0 device. The Host-Hub Interface Bridge entity within the GMCH-M is hardwired as Device #0 on PCI Bus #0 (applicable to the entire 830 Chipset family). The Host-AGP/PCI1 Bridge entity within the GMCH-M is hardwired as Device #1 on PCI Bus #0 (applicable only to the 830M and 830MP Chipset). The Integrated Graphics entity within the GMCH-M is hardwired as Device #2 on PCI Bus#0 (applicable to 830M and 830MG Chipset). Configuration cycles to any of the GMCH-M's internal devices are confined to the GMCH-M and not sent over Hub Interface. Accesses to devices #3 to #31 will be forwarded over Hub Interface as Type 0 Configuration Cycles (see Hub Interface spec). A[1:0] of the Hub Interface Request Packet for the Type 0 configuration cycle will be "00". Bits 15:2 of the CONFIG_ADDRESS register will be translated to the A[15:2] field of the Hub Interface Request Packet of the configuration cycle as shown the figure below. The ICH3-M decodes the Type 0 access and generates a configuration access to the selected internal device.

Figure 8. Hub Interface Type 0 Configuration Address Translation



4.2.4 Primary PCI and Downstream Configuration Mechanism

If the Bus Number in the CONFIG_ADDRESS is non-zero, and is less than the value programmed into the Intel 830 Chipset family GMCH-M's device #1 SECONDARY BUS NUMBER register or greater than the value programmed into the SUBORDINATE BUS NUMBER Register, the GMCH-M will generate a Type 1 Hub Interface Configuration Cycle. A[1:0] of the Hub Interface Request Packet for the Type 1 configuration cycle will be "01". Bits 31:2 of the CONFIG_ADDRESS register will be translated to the A[31:2] field of the Hub Interface Request Packet of the configuration cycle as shown in the figure below. The ICH3-M compares the non-zero Bus Number with the SECONDARY BUS NUMBER and SUBORDINATE BUS NUMBER registers of its P2P bridges to determine if the configuration cycle is meant for Primary PCI, one of the ICH3-M's Hub Interfaces, or a downstream PCI bus.



Figure 9. Hub Interface Type 1 Configuration Address Translation

4.2.5 Intel 830M and 830MP Chipset AGP/PCI1 Bus Configuration Mechanism

From the chipset configuration perspective, AGP/PCI1 is seen as another PCI bus interface residing on a Secondary Bus side of the "virtual" PCI-PCI bridge referred to as the Intel 830M and 830MP Chipset GMCH-M Host-AGP/PCI1 bridge. On the Primary bus side, the "virtual" PCI-PCI Bridge is attached to PCI Bus #0. Therefore, the PRIMARY BUS NUMBER register is hardwired to "0". The "virtual" PCI-PCI bridge entity converts Type #1 PCI Bus Configuration cycles on PCI Bus #0 into Type 0 or Type 1 configuration cycles on the AGP/PCI1 interface. Type 1 configuration cycles on PCI Bus #0 that have a BUS NUMBER that matches the SECONDARY BUS NUMBER of the GMCH-M's "virtual" PCI-PCI Bridge will be translated into Type 0 configuration cycles on the AGP/PCI1 interface. The GMCH-M will decode the Device Number field [15:11] and assert the appropriate GAD signal as an IDSEL in accordance with the PCI-to-PCI Bridge Type 0 configuration mechanism. For PCI-to-PCI Bridge translation one of 16 IDSELs are generated (as opposed to one of 21 for Host-to-PCI bridges).

When bit [15] = 0, bits [14:11] are decoded to assert a single AD[31:16] IDSEL. If bit [15] = 1, AD[31:16] are 0000h. The remaining address bits will be mapped as described in Figure 10.

Figure 10. Mechanism #1 Type 0 Configuration Address to PCI Address Mapping



intel

Config Address AD[15:11]	AGP GAD[31:16] IDSEL
00000	0000 0000 0000 0001
00001	0000 0000 0000 0010
00010	0000 0000 0000 0100
00011	0000 0000 0000 1000
00100	0000 0000 0001 0000
00101	0000 0000 0010 0000
00110	0000 0000 0100 0000
00111	0000 0000 1000 0000
01000	0000 0001 0000 0000
01001	0000 0010 0000 0000
01010	0000 0100 0000 0000
01011	0000 1000 0000 0000
01100	0001 0000 0000 0000
01101	0010 0000 0000 0000
01110	0100 0000 0000 0000
01111	1000 0000 0000 0000
1xxxx	0000 0000 0000 0000

Table 23. AGP/PCI1 Config Address Remapping

If the Bus Number is non-zero, greater than the value programmed into the SECONDARY BUS NUMBER register and less than or equal to the value programmed into the SUBORDINATE BUS NUMBER register, the configuration cycle is targeting a PCI bus downstream of AGP/PCI1. The 830M and 830MP GMCH-M will generate a Type 1 PCI configuration cycle on AGP/PCI1. The address bits will be mapped as described in figure below.

Figure 11. Mechanism #1 Type 1 Configuration Address to PCI Address Mapping



To prepare for mapping of the configuration cycles on AGP/PCI1 the initialization software will go through the following sequence:

- 1. Scan all devices residing on the PCI Bus #0 using Type 0 configuration accesses.
- 2. For every device residing at bus #0 which implements PCI-PCI bridge functionality, it will configure the secondary bus of the bridge with the appropriate number and scan further down the hierarchy. This process will include the configuration of the "virtual" PCI-PCI Bridge within the 830M and 830MP GMCH-M used to map the AGP address space in a software specific manner.
- *Note:* Although initial AGP platform implementations will not support hierarchical buses residing below AGP, this specification still must define this capability in order to support PCI-66 compatibility. Note also that future implementations of the AGP devices may support hierarchical PCI or AGP-like buses coming out of the root AGP device.

4.2.6 Intel 830 Chipset Family Internal GMCH-M Configuration Register Access Mechanism

Accesses decoded as PCI Bus #0/Device #0 (Host-Hub Interface Bridge/SDRAM Controller), PCI Bus #0/Device #1 (Host-AGP Bridge¹), or PCI Bus #0/Device#2 (Integrated Graphics Device¹) are sequenced as Type 0 PCI Configuration Cycle accesses on Bus #0 to Device #0/Function #0, Device #1/Function #0, and Device #2/Function #0/1. Note that since GMCH-M device #0 and #1 are not multi-function devices, the function number should always be '0'. If the function number is not '0' for accesses to Device #0 or #1, the GMCH-M will not claim the configuration cycle and it will be forwarded to the Hub Interface where it should be master aborted (by the ICH3-M) in the same way as transactions to other unimplemented PCI configuration targets.

Note: AGP is available only with the Intel 830MP and 830M Chipset. Internal graphics device is available only with the Intel 830M and 830MG Chipset.

4.3 Intel 830 Chipset Family GMCH-M Register Introduction

The Intel 830 Chipset family GMCH-M contains two sets of software accessible registers, accessed via the Host CPU I/O address space:

- 1. Control registers I/O mapped into the CPU I/O space, which control access to PCI and AGP configuration space (see section entitled I/O Mapped Registers).
- 2. Internal configuration registers residing within the GMCH-M that are partitioned into three logical device register sets ("logical" since they reside within a single physical device). The first register set is dedicated to Host-Hub Interface Bridge functionality (controls PCI Bus #0 i.e. SDRAM configuration, other chip-set operating parameters and optional features). The second register block is dedicated to Host-AGP/PCI1 Bridge functions (controls AGP/PCI1 interface configurations and operating parameters). The third register block is dedicated to the Integrated Graphics Device (IGD) function.
- *Note:* AGP is only available with 830M and 830MP Chipset; internal graphics device is available with 830M and 830MG Chipset
- *Note:* This configuration scheme is necessary to accommodate the existing and future software configuration model supported by Microsoft* where the Host Bridge functionality will be supported and controlled via a dedicated specific driver. Virtual PCI-PCI Bridge functionality will be supported via standard PCI bus enumeration configuration software. The term "virtual" is used to designate that no real physical embodiment of the PCI-PCI Bridge functionality exists within the GMCH-M, but that GMCH-M's

internal configuration register sets are organized in this particular manner to create that impression to the standard configuration software.

The GMCH-M supports PCI configuration space accesses using the mechanism denoted as Configuration Mechanism #1 in the PCI specification. The GMCH-M internal registers (both I/O Mapped and Configuration registers) are accessible by the Host CPU. The registers can be accessed as Byte, Word (16-bit), or Dword (32-bit) quantities, with the exception of CONFIG_ADDRESS that can only be accessed as a Dword. All multi-byte numeric fields use "little-endian" ordering (i.e., lower addresses contain the least significant parts of the field).

Some of the GMCH-M registers described in this section contain reserved bits. These bits are labeled "Reserved". Software must deal correctly with fields that are reserved. On reads, software must use appropriate masks to extract the defined bits and not rely on reserved bits being any particular value. On writes, software must ensure that the values of reserved bit positions are preserved. That is, the values of reserved bit positions must first be read, merged with the new values for other bit positions and then written back. Note the software does not need to perform read, merge, and write operations for the configuration address register.

In addition to reserved bits within a register, the GMCH-M contains address locations in the configuration space of the Host-Hub Interface Bridge entity that are marked either "Reserved" or "Intel Reserved". The GMCH-M responds to accesses to "Reserved" address locations by completing the host cycle. When a "Reserved" register location is read, a zero value is returned. ("Reserved" registers can be 8-, 16-, or 32-bit in size). Writes to "Reserved" registers have no effect on the GMCH-M. Registers that are marked as "Intel Reserved" must not be modified by system software. Writes to "Intel Reserved" registers may cause system failure. Reads to "Intel Reserved" registers may return a non-zero value.

Upon Reset, the GMCH-M sets all of its internal configuration registers to predetermined default states. Some register values at reset are determined by external strapping options. The default state represents the minimum functionality feature set required to successfully bring up the system. Hence, it does not represent the optimal system configuration. It is the responsibility of the system initialization software (usually BIOS) to properly determine the SDRAM configurations, operating parameters and optional system features that are applicable, and to program the GMCH-M registers accordingly.

4.4 Intel 830 Chipset Family I/O Mapped Registers

The Intel 830 Chipset family GMCH-M contains a set of registers that reside in the CPU I/O address space - the Configuration Address (CONFIG_ADDRESS) Register and the Configuration Data (CONFIG_DATA) Register. The Configuration Address Register enables/disables the configuration space and determines what portion of configuration space is visible through the Configuration Data window.

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4.4.1 CONFIG_ADDRESS - Configuration Address Register

0CF8
0000
Read
32 bi

0CF8h Accessed as a Dword 00000000h Read/Write 32 bits

CONFIG_ADDRESS is a 32-bit register accessed only when referenced as a Dword. A Byte or Word reference will "pass through" the Configuration Address Register and Hub Interface onto the PCI0 bus as an I/O cycle. The CONFIG_ADDRESS register contains the Bus Number, Device Number, Function Number, and Register Number for which a subsequent configuration access is intended.



Bit	Descriptions
31	Configuration Enable (CFGE) . When this bit is set to 1, accesses to PCI configuration space are enabled. If this bit is reset to 0, accesses to PCI configuration space are disabled.
30:24	Reserved (These bits are read only and have a value of 0).
23:16	Bus Number . When the Bus Number is programmed to 00h the target of the Configuration Cycle is either the GMCH-M or the ICH3-M. The Configuration Cycle is forwarded to hub interface if the Bus Number is programmed to 00h and no device internal to the GMCH-M is the target.
	If the Bus Number is non-zero and matches the value programmed into the SECONDARY BUS NUMBER Register of the AGP/PCI1 bridge, a Type 0 PCI configuration cycle will be generated on AGP/PCI1.
	If the Bus Number is non-zero, greater than the value in the SECONDARY BUS NUMBER register of the AGP/PCI1 bridge, and less than or equal to the value programmed into the SUBORDINATE BUS NUMBER Register, a Type 1 PCI configuration cycle will be generated on AGP/PCI1.
	If the Bus Number is non-zero, and is less than the value programmed into the SECONDARY BUS NUMBER Register of the AGP/PCI1 bridge, or is greater than the value programmed into the SUBORDINATE BUS NUMBER Register, a Type 1 hub interface Configuration Cycle is generated.
15:11	Device Number . This field selects one agent on the PCI bus selected by the Bus Number. When the Bus Number field is "00" the GMCH-M decodes the Device Number field. The GMCH-M is always Device #0 for the Host-hub interface bridge entity, Device #1 for the Host-AGP/PCI1 entity, and Device #2 for the Integrated Graphics Device entity. Therefore, when the Bus Number = 0 and the Device Number = 0, 1, or 2, the internal GMCH-M devices are selected.
	If the Bus Number is non-zero and matches the value programmed into the SECONDARY BUS NUMBER Register of the AGP/PCI1 bridge, a Type 0 PCI configuration cycle will be generated on AGP/PCI1. The Device Number field is decoded and the GMCH-M asserts one and only one GADxx signal as an IDSEL. GAD11 is asserted to access Device #0, GAD12 for Device #1, and so forth up to Device #20 for which will assert GAD31. All device numbers higher than 20 cause a type 0 configuration access with no IDSEL asserted, which will result in a Master Abort reported in the GMCH-M's "virtual" PCI-PCI bridge registers.

	For Bus Numbers resulting in AGP/PCI1 Type 1 Configuration cycles, the Device Number is propagated as GAD[15:11].
10:8	Function Number . This field is mapped to GAD[10:8] during AGP/PCI1 Configuration cycles. This allows the configuration registers of a particular function in a multi-function device to be accessed. The GMCH-M ignores configuration cycles to Devices 1 if the function number is not equal to 0.
7:2	Register Number . This field selects one register within a particular Bus, Device, and Function as specified by the other fields in the Configuration Address Register. This field is mapped to GAD[7:2] during AGP/PCI1 Configuration cycles.
1:0	Reserved

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4.4.2 CONFIG_DATA - Configuration Data Register

I/O Address:0CFChDefault Value:0000000hAccess:Read/WriteSize:32 bits

CONFIG_DATA is a 32-bit read/write window into configuration space. The portion of configuration space that is referenced by CONFIG_DATA is determined by the contents of CONFIG_ADDRESS.



Bit	Descriptions
31:0	Configuration Data Window (CDW) . If bit 31 of CONFIG_ADDRESS is 1, any I/O access to the CONFIG_DATA register will be mapped to configuration space using the contents of CONFIG_ADDRESS.

4.5 Intel 830 Chipset Family GMCH-M Internal Device Registers

Table 24 below shows the nomenclature of access attributes for the configuration space of each device.

Table 24. Nomenclature for Access Attributes

RO	Read Only. If a register is read only, writes to this register have no effect.
R/W	Read/Write. A register with this attribute can be read and written
R/WC	Read/Write Clear . A register bit with this attribute can be read and written. However, a write of a 1 clears (sets to 0) the corresponding bit and a write of a 0 has no effect.
R/WO	Read/Write Once . A register bit with this attribute can be written to only once after power up. After the first write, the bit becomes read only.
L	Lock. A register bit with this attribute becomes Read Only after a lock bit is set.

4.5.1 SDRAM Controller/Host-hub Interface Device Registers -Device #0

Table 25 shows the GMCH-M configuration space for device #0 (applicable to the entire 830 Chipset family). An "s" in the Default Value field means that a strap determines the power-up default value for that bit.

Table 25. Host-Hub I/F Bridge/SDRAM Controller Configuration Space (Device #0)

Address Offset	Register Symbol	Register Name	Default Value	Access
00-01h	VID	Vendor Identification	8086h	RO
02-03h	DID	Device Identification	3575h	RO
04-05h	PCICMD	PCI Command Register	0006h	R/W
06-07h	PCISTS	PCI Status Register	0010h	RO, R/WC
08h	RID	Revision Identification	00h	RO
09h	-	Intel Reserved	-	-
0Ah	SUBC	Sub-Class Code	00h	RO
0Bh	BCC	Base Class Code	06h	RO
0Ch	-	Intel Reserved	-	-
0Dh	MLT	Master Latency Timer	00h	RO
0Eh	HDR	Header Type	00h	RO
0Fh	-	Intel Reserved	-	-
10-13h	APBASE	Aperture Base Configuration	0000008h	R/W, RO
14-2Bh	-	Intel Reserved	-	-
2C-2Dh	SVID	Subsystem Vendor Identification	00h	R/WO
2E-2Fh	SID	Subsystem Identification	00h	R/WO
30-33h	-	Intel Reserved	-	-
34h	CAPPTR	Capabilities Pointer	40h	RO
35-3Fh	-	Intel Reserved	-	-
40-44h	-	Intel Reserved	-	-
45-47h	-	Intel Reserved	-	-
48-4Bh	RRBAR	Register Range Base Address	00000000h	R/W, RO
4C-4Fh	-	Intel Reserved	-	-
50-51h	GCC0	GMCH Control Register 0	A072h	R/W, RO
52-53h	GCC1	GMCH Control Register 1	0000h	R/W
54-55h	-	Intel Reserved	-	-
56-57h	-	Intel Reserved	-	-
58h	FDHC	Fixed DRAM Hole Control	00h	R/W
59-5Fh	PAM[6:0]	Programmable Attribute Map (7	00h	R/W

		registers)		
60-67h	DRB[7:0]	DRAM Row Boundary Register	00h	R/W/L
68-6Fh	-	Intel Reserved	-	-
70-71h	DRA[1:0]	DRAM Row Attributes	FFh	R/W/L
72-77h	-	Intel Reserved	-	-
78-7Bh	DRT	DRAM Timing Register	00000010h	R/W
7C-7Fh	DRC	DRAM Control	00000000h	R/W
80-8Bh	-	Intel Reserved	-	-
8C-8Fh	DTC	DRAM Throttling Control Register	00000000h	R/W/L
90h	SMRAM	System Management RAM Control Reg.	02h	R/W/L
91h	ESMRAMC	Extended System Management RAM Control Register	38h	R/W
92-93h	ERRSTS	Error Status Register	0000h	R/W
94-95h	ERRCMD	Error Command Register	0000h	R/W
96h	-	Intel Reserved	-	-
97h	-	Intel Reserved	-	-
98-9F	-	Intel Reserved	-	-
A0-A3h	ACAPID	AGP Capability Identifier	00200002h	RO*
A4-A7h	AGPSTAT	AGP Status Register	1F000217h	RO*
A8-ABh	AGPCMD	AGP Command Register	00000000h	RW*
AC-AFh	-	Intel Reserved	-	-
B0-B1h	AGPCTRL	AGP Control Register	0000h	R/W*
B2-B3h	AFT	AGP Functional Test Register	0000h	R/W*
B4h	APSIZE	AGP Aperture Size	00h	R/W*
B5-B7h	-	Intel Reserved	-	-
B8-BBh	ATTBASE	Aperture Translation Table	00000000h	R/W*
BCh	AMTT	AGP Interface Multi-Transaction Timer Register	00h	R/W*
BDh	LPTT	Low Priority Transaction Timer Register	00h	R/W*
BE-BFh	-	Intel Reserved	-	-
C2-EBh	-	Intel Reserved	-	-
EC-EFh	BUFF_SC	System Memory Buffer Strength Control Register	00000000h	R/W
F0-FFh	-	Intel Reserved	-	-

NOTE: *Register is READ ONLY (RO) when internal graphics device is used with the Intel 830MG Chipset is used. Register will have no functionality when internal graphics device is used with Intel 830M Chipset.

intel

4.5.1.1 VID - Vendor Identification Register - Device #0

Address Offset:	00 - 01h
Default Value:	8086h
Attribute:	Read Only
Size:	16 bits

The VID Register contains the vendor identification number. This 16-bit register combined with the Device Identification Register uniquely identifies any PCI device. Writes to this register have no effect.

Bit	Description
15:0	Vendor Identification Number. This is a 16-bit value assigned to Intel. Intel VID = 8086h.
	Default Value=1000/0000/1000/0110.

4.5.1.2 DID - Device Identification Register - Device #0

Address Offset:	02 - 03h
Default Value:	3575h
Attribute:	Read Only
Size:	16 bits

This 16-bit register combined with the Vendor Identification register uniquely identifies any PCI device. Writes to this register have no effect.

Bit	Description
15:0	Device Identification Number . This is a 16-bit value assigned to the GMCH-M Host-hub interface Bridge, Device #0. Default Value=0011/0101/0111/0101.

4.5.1.3 PCICMD - PCI Command Register - Device #0

Address Offset:	04-05h
Default Value:	0006h
Access:	Read/Write
Size	16 bits

Since GMCH-M Device #0 is the host-to-Hub Interface bridge, many of the PCI specific bits in this register don't apply.

Bit	Description
15:10	Reserved
9	Fast Back-to-Back . This bit controls whether or not the master can do fast back-to-back write. Since device #0 is strictly a target this bit is not implemented and is hardwired to 0. Writes to this bit position have no effect. Default Value=0.
8	SERR Enable (SERRE) . This bit is a global enable bit for Device #0 SERR messaging. The GMCH-M does not have an SERR# signal. The GMCH-M communicates the SERR# condition by sending an SERR message to the ICH3-M. If this bit is set to a 1, the GMCH-M is enabled to generate SERR messages over Hub Interface for specific Device #0 error conditions that are individually enabled in the ERRCMD register. The error status is reported in the ERRSTS and PCISTS registers. If SERRE is reset to 0, then the SERR message is not generated by the GMCH-M for Device #0.
	NOTE : This bit only controls SERR messaging for the Device #0. Device #1 has its own SERRE bit to control error reporting for error conditions occurring on Device #1. The two control bits are used in a logical OR manner to enable the SERR Hub Interface message mechanism. Default Value=0.
7	Address/Data Stepping. Address/data stepping is not implemented in the GMCH-M, and this bit is hardwired to 0. Writes to this bit position have no effect. Default Value=0.
6	Parity Error Enable (PERRE) . PERR# is not implemented by the GMCH-M, and this bit is hardwired to 0. Writes to this bit position have no effect. Default Value=0.
5	VGA Palette Snoop. The GMCH-M does not implement this bit and it is hardwired to a 0. Writes to this bit position have no effect. Default Value=0.
4	Memory Write and Invalidate Enable . The GMCH-M will never use this command and this bit is hardwired to 0. Writes to this bit position have no effect. Default Value=0.
3	Special Cycle Enable . The GMCH-M does not implement this bit and it is hardwired to a 0. Writes to this bit position have no effect. Default Value=0.
2	Bus Master Enable (BME) . The GMCH-M is always enabled as a master on Hub Interface. This bit is hardwired to a 1. Writes to this bit position have no effect. Default Value=1.
1	Memory Access Enable (MAE) . The GMCH-M always allows access to main memory. This bit is not implemented and is hardwired to 1. Writes to this bit position have no effect. Default Value=1.
0	I/O Access Enable (IOAE). This bit is not implemented in the GMCH-M and is hardwired to a 0. Writes to this bit position have no effect. Default Value=0.
4.5.1.4 PCISTS - PCI Status Register - Device #0

Address Offset:	06-07h
Default Value:	0010h
Access:	Read Only, Read/Write Clear
Size:	16 bits

PCISTS is a 16-bit status register that reports the occurrence of error events on Device #0's Hub Interface. Bit 14 is read/write clear. All other bits are Read Only. Since GMCH-M Device #0 is the host-to-Hub Interface bridge, many of the PCI specific bits in this register do not apply.

Bit	Description
15	Detected Parity Error (DPE) . This bit is hardwired to a 0. Writes to this bit position have no effect. Default Value=0.
14	Signaled System Error (SSE). This bit is set to 1 when GMCH-M Device #0 generates an SERR message over Hub Interface for any enabled Device #0 error condition. Device #0 error conditions are enabled in the PCICMD and ERRCMD registers. Device #0 error flags are read/reset from the PCISTS or ERRSTS registers. Software sets SSE to 0 by writing a 1 to this bit. Default Value=0.
13	Received Master Abort Status (RMAS). This bit is set when the GMCH-M generates a Hub Interface request that receives a Master Abort completion packet. Software clears this bit by writing a 1 to it. Default Value=0.
12	Received Target Abort Status (RTAS) . This bit is set when the GMCH-M generates a Hub Interface request that receives a Target Abort completion packet. Software clears this bit by writing a 1 to it. Default Value=0.
11	Signaled Target Abort Status (STAS) . The GMCH-M will not generate a Target Abort Hub Interface completion packet. This bit is not implemented in the GMCH-M and is hardwired to a 0. Writes to this bit position have no effect. Default Value=0.
10:9	DEVSEL# Timing (DEVT). Hub Interface does not comprehend DEVSEL# protocol. These bits are hardwired to "00". Writes to these bits have no effect. Default Value=00.
8	Data Parity Detected (DPD) . GMCH-M does not support parity on Hub Interface. This bit is hardwired to a 0. Writes to this bit position have no effect. Default Value=0.
7	Fast Back-to-Back (FB2B). Hub Interface does not comprehend PCI Fast Back-to-Back protocol. This bit is hardwired to 0. Writes to this bit position have no effect. Default Value=0.
6:5	Reserved
4	Capability List (CLIST) . This bit is hardwired to 1 to indicate to the configuration software that this device/function implements a list of new capabilities.
	A list of new capabilities is accessed via register CAPPTR at configuration address offset 34h. Register CAPPTR contains an offset pointing to the start address within configuration space of this device where the Capabilities linked list begins.
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4.5.1.5 RID - Revision Identification Register - Device #0

Address Offset:	08h
Default Value:	03h (A5 silicon)
	04h (A6 silicon)
Access:	Read Only
Size:	8 bits

This register contains the revision number of the GMCH-M Device #0. These bits are read only and writes to this register have no effect.

Bit	Description	
7:0	Revision Identification Number . This is an 8-bit value that indicates the revision identification number for the GMCH-M Device #0. Please see spec update for the latest silicon revision.	
	Silicon Revision	Default Value
	A5	0000/0011 (03h)
	A6	0000/0100 (04h)

4.5.1.6 SUBC - Sub-Class Code Register - Device #0

Address Offset:	0Ah
Default Value:	00h
Access:	Read Only
Size:	8 bits

This register contains the Sub-Class Code for the GMCH-M Device #0. This code is 00h indicating a Host Bridge device. The register is read only.

Bit	Description
7:0	Sub-Class Code (SUBC). This is an 8-bit value that indicates the category of Bridge into which the GMCH- M falls. The code is 00h indicating a Host Bridge.
	Default Value=0000/0000.

4.5.1.7 BCC - Base Class Code Register - Device #0

Address Offset:	0Bh
Default Value:	06h
Access:	Read Only
Size:	8 bits

This register contains the Base Class Code of the GMCH-M Device #0. This code is 06h indicating a Bridge device. This register is read only.

Bit	Description
7:0	Base Class Code (BASEC). This is an 8-bit value that indicates the Base Class Code for the GMCH-M. This code has the value 06h.
	Default Value=0000/0110.

4.5.1.8 MLT - Master Latency Timer Register - Device #0

0Dh
00h
Read Only
8 bits

Hub Interface does not comprehend the concept of a Master Latency Timer. Therefore the functionality of this register is not implemented and the register is hardwired to 0.

Bit	Description
7:0	These bits are hardwired to 0. Writes have no effect.
	Default Value=0000/0000.

4.5.1.9 HDR - Header Type Register - Device #0

0Eh
00h
Read Only
8 bits

This register identifies the header layout of the configuration space. No physical register exists at this location.

Bit	Descriptions
7:0	This read only field always returns 0 when read and writes have no effect.
	Default Value=0000/0000.

INt

4.5.1.10 APBASE - Aperture Base Configuration Register - Device #0

Address Offset:	10-13h
Default Value:	0000008h
Access:	Read/Write, Read Only
Size:	32 bits

The APBASE is a standard PCI Base Address register that is used to set the base of the Graphics Aperture. The standard PCI Configuration mechanism defines the base address configuration register such that only a fixed amount of space can be requested (dependent on which bits are hardwired to "0" or behave as hardwired to "0").

To allow for flexibility (of the aperture) an additional register called APSIZE is used as a "back-end" register to control which bits of the APBASE will behave as hardwired to "0". This register will be programmed by the GMCH-M specific BIOS code that will run before any of the generic configuration software is run.

Note that bit 9 of the GCC0 register at 51-50h is used to prevent accesses to the aperture range before the configuration software initializes this register and the appropriate translation table structure has been established in the main memory.

Bit	Descr	iption		
31:28	Upper via low Defaul	Programm ver bits 27:4 t Value = 00	able Base A 000.	ddress bits (R/W). These bits are used to locate the range size selected
27:25	27:25 Lower "Hardwired"/Programmable Base Address bits. These bits behave as a "hardwired" or as a programmable depending on the contents of the APSIZE register as defined below:			ble Base Address bits. These bits behave as a "hardwired" or as a ne contents of the APSIZE register as defined below:
	<u>27</u>	26	25	Aperture Sizer/w
	r/w	r/w	r/w	32 MB
	r/w	r/w	r/w	64 MB
	r/w	0	0	128 MB
	0	0	0	256 MB
	"hardwired" to 0). This provides a default to the maximum aperture size of 256MB. The GMCH-M specific BIOS is responsible for selecting smaller size (if required) before PCI configuration software runs and establishes the system address map. Default Value=000.			
24:4	Hardw	vired to "0"	. This forces	minimum aperture size selected by this register to be 32 MB.
3	Prefet i.e. the and the	chable (RO rre are no si e GMCH-M). This bit is h de effects on may merge p	hardwired to "1" to identify the Graphics Aperture range as a prefetchable, n reads, the device returns all bytes on reads regardless of the byte enables, processor writes into this range without causing errors.
2:1	Type (range	RO). These defined by t	bits determir he upper bits	ne addressing type and they are hardwired to "00" to indicate that address of this register can be located anywhere in the 32-bit address space.
	Defaul	t value=00.		
0	Memo	ry Space Ir	dicator (RO)). Hardwired to "0" to identify aperture range as a memory range.

4.5.1.11 SVID - Subsystem Vendor ID - Device #0

Address Offset:	2C-2Dh
Default Value:	0000h
Access:	Read/Write Once
Size:	16 bits

This value is used to identify the vendor of the subsystem.

Bit	Description
15:0	Subsystem Vendor ID (R/WO). The default value is 00h. This field should be programmed during boot-up. After this field is written once, it becomes read only.
	Default Value=0000/0000/0000.

4.5.1.12 SID - Subsystem ID - Device #0

Address Offset:	2E-2Fh
Default Value:	0000h
Access:	Read/Write Once
Size:	16 bits

This value is used to identify a particular subsystem.

Bit	Description
15:0	Subsystem ID (R/WO). The default value is 00h. This field should be programmed during boot-up. After this field is written once, it becomes read only.
	Default Value=0000/0000/0000.

4.5.1.13 CAPPTR - Capabilities Pointer - Device #0

34h
40h
Read Only
8 bits

The CAPPTR provides the offset that is the pointer to the location where the first capability register set is located.

Bit	Description
7:0	Pointer to the start of Capabilities Register Block. The value in this field is 40h.

INto

4.5.1.14 RRBAR - Register Range Base Address Register - Device #0

Address Offset:48-4BhDefault Value:0000000hAccess:Read/Write, Read OnlySize:32 bits

This register requests a 256-KB allocation for the Device registers. The base address is defined by bits 31 to 18 and can be used to access device configuration registers. Only Dword aligned writes are allowed to this space. See Table below for address map within the 512-KB space.

This addressing mechanism may be used to write to registers that modify the device address map (includes all the BARs, PAMs, SMM registers, Pre-Allocated Memory registers etc). However, before using or allowing the use of the modified address map the BIOS must synchronize using an IO or Read cycle.

Note that bit 8 of the GCC0 register at 51-50h is used to prevent accesses to this range before the configuration software initializes this register.

Bit	Description
31:18	Memory Base Address-R/W . Set by the OS, these bits correspond to address signals [31:18]. Default Value=0000/0000/0000/0.
17:15	Address Mask-RO. Hardwired to 0s to indicate 512-KB address range. The Minimum size that can be requested by converting all these bits to R/W would be 64 KB. Default Value=000.
15:8	Reserved. Hardwired to 00h.
7:0	Scratch Pad Size-RO, Hardwired to "00h". 00h = 256B FFh = 64 KB Default Value=0000/0000.

Address Range		Description
	Sub Ranges	Description
00000h to 3FFFFhDevice 0 Space	00000h to 0003Fh	Read Only: Maps to 00-3Fh of Device #0 P&P register space.
	00040h to 000FFh	Read/Write: Maps to 40-FFh of Device #0 P&P register space.
	00100h to 3FEFFh	Read/Write: Extended Register Space. Reserved.
	3FF00h to 3FFFFh	Scratch Pad Registers: 256 B, D-word read/write-able.

4.5.1.15 GCC0 - GMCH Control Register #0 - Device #0

50-51h
A072h
Read/Write, Read Only
16 bits

Bit	Descriptions
15	Reserved
14:12	Low Priority Grace Period. This value is loaded in SDRAM Arbiter when a request is ongoing and a higher priority request is presented to the Arbiter. The arbiter continues to grant the first request for this specified number of page hits (1 KB). If the first requester causes a page miss or stops requesting the arbiter will switch to the higher priority requester. (A request equals an Oct-word also known as dual-oct byte). 000 = 00 001 = 04 010 = 08 (Default) 011 = 16 100 = 24 111 = Reserved
	Default Value=010.
	Recommended Value with Internal Graphics = $010 \rightarrow 8$
	Recommended Value without Internal Graphics = $011 \rightarrow 16$
11	 Scratch Pad Enable. This bit when set to a "1", allows the upper 256 Bytes of Device #0 RRBAR space to be mapped to Scratch Pad Ram in the device. Once D_LCK is set, this bit becomes read only. NOTE: The BIOS can use the scratch pad area when devices on the AGP bus are inactive (Not capable of using the AGP Pipe or Side-Band command bus to issue read cycles to Main Memory). Default Value=0.
10	Reserved.
9	Aperture Access Global Enable (R/W). This bit is used to prevent access to the aperture from any port (CPU, PCI0 or AGP/PCI1) before the aperture range is established by the configuration software and appropriate translation table in the main SDRAM has been initialized. It must be set after system is fully configured for aperture accesses. Default Value=0.
8	RRBAR Access Enable . This bit when set to a "1", enables the RRBAR space. When "0", accesses will not decode to register range. Default Value=0.
7	Reserved
6:4	 IOQ request Grant Ceiling. This value is loaded in SDRAM Arbiter when an IOQ request is granted. It provides a grant for the duration specified for as long as the request is active or until a fixed higher priority request needs to be serviced. 111 = Infinite Ceiling (Default)
	11 U = 64
	101 = 40 100 - 32
	011 = 24
	-

	010 10					
	001 = 08					
	000 = 04					
	Default Value=	111.				
	Please contact	your Int	el Field Representative for more information.			
3:1	Reserved	,				
0	MDA Present	(MDAP)	(R/W).			
	This bit works initiated transa set when the V	with the ctions ta 'GA Ena	VGA Enable bit in the BCTRL register of device 1 to control the routing of CPU argeting MDA compatible I/O and memory address ranges. This bit should not be ble bit is not set.			
	If the VGA ena Interface.	ble bit is	s set, then accesses to IO address range x3BCh-x3BFh are forwarded to Hub			
	If the VGA enable bit is not set then accesses to IO address range x3BCh-x3BFh are treated just like any other IO accesses i.e. the cycles are forwarded to AGP if the address is within IOBASE and IOLIMIT and ISA enable bit is not set, otherwise they are forwarded to Hub Interface. MDA resources are defined as the following:					
	Memory: 0B00	000h - 0	7FFFhl/O:			
	I/O: 3B4h, 3B5h, 3B8h, 3B9h, 3BAh, 3BFh, (including ISA address aliases, A[15:10] are not used in decode)					
	Any I/O reference that includes the I/O locations listed above, or their aliases, will be forwarded to Hub Interface even if the reference includes I/O locations not listed above. The following table shows the behavior for all combinations of MDA and VGA:					
	VGA MDA Behavior					
	Default 0	0 All References to MDA and VGA go to Hub Interface				
	0	1	Illegal Combination (DO NOT USE)			
	1	0	All References to VGA go to AGP/PCI.			
			MDA-only references (I/O address 3BF and aliases) will go to Hub Interface.			
	1	1	VGA References go to AGP/PCI; MDA References go to Hub Interface			
	Default Value=	:0.	-			

4.5.1.16 GCC1—GMCH Control Register #1 - Device #0

Address Offset:	52-53h
Default Value:	0000h
Access:	Read/Write
Size:	16 bits

Bit	Descriptions
15:7	Reserved
6:4	Graphics Mode Select (GMS). This field is used to select the amount of Main Memory that is pre- allocated to support the Internal Graphics device in VGA (non-linear) and Native (linear) modes. These 3 bits are valid only when Internal graphics is enabled. 000 = No memory pre-allocated (Graphics memory Disabled) [RESERVED] 001 = No memory pre-allocated (Graphics memory Enabled) [RESERVED] 010 = DVMT (UMA) mode, 512K of memory pre-allocated for frame buffer 011 = DVMT (UMA) mode, 1M of memory pre-allocated for frame buffer 100 = DVMT (UMA) mode, 8M of memory pre-allocated for frame buffer 100 = DVMT (UMA) mode, 8M of memory pre-allocated for frame buffer Note This register is locked and becomes Read Only when the D_LCK bit in the SMRAM register is set.
2	
5	When set to "1" this bit disables Device #2 and all associated spaces. Default Value = 0 NOTE : Device#2(IGD) is only available with Intel 830M and 830MG Chipset.
2	Device #2 Function 1 Enable
	When set to "1", enables the second function within Device #2. Default Value = 0
	Note: Device#2(IGD) is only available with Intel 830M and 830MG Chipset.
1	IGD VGA Disable (IVD). When set to a "1", the IGD will not claim VGA cycles (Mem and I/O), and the Sub-Class Code field within Device #2 Class Code register is 80h. When set to a "0", the IGD will claim VGA memory and I/O cycles, the Sub-Class Code within Device#2 Class Code register is 00h Default Value = 0 Note: Device#2(IGD) is only available with Intel 830M and 830MG Chipset.
0	Pavice 2: Graphics Memory Aparture Size (Controls GMADR register in Davice#2)
0	0 = 128 MB 1 = 64 MB Default Value = 0 Note: Device#2(IGD) is only available with Intel 830M and 830MG Chipset.

NOTE: Notes on Pre-allocated Memory for Graphics (applicable only when internal graphics is used).

These Register Bits control the theft of memory from Main Memory space for use as Graphics memory. The memory for TSEG is pre-allocated first and then the Graphics memory is pre-allocated. An example of this theft mechanism is:

TOM equal 64 MB, TSEG selected as 512 KB in size, Graphics memory selected as 1 MB in size General System RAM available in system = 62.5 MB General System RAM Range TSEG Address Range TSEG pre-allocated from Graphics memory pre-allocated from

00000000h to 03E7FFFFh 03F80000h to 03FFFFFFh 03F80000h to 03FFFFFFh 03E80000h to 03F7FFFFh

VGA Memory and IO Space decode priority: Integrated Graphics Device (IGD), Device #2. PCI-PCI bridge, Device #1. Hub Interface.

VGA Memory Space decode to IGD:

IF IGE = '1' AND IVD = '0' AND Device # 2 Mem_Access_En = '1' AND MSRb1 = '1' AND \rightarrow

Additional Qualification Within IGD Decode (Comprehends MDA Requirements)

Mem Access→ GR06(3:2)	A0000h - AFFFFh	B0000h - B7FFFh	B8000h-BFFFFh
"00"	IGD	IGD	IGD
"01"	IGD	P2P Bridge or Hub Interface	P2P Bridge or Hub Interface
"10"	P2P Bridge or Hub Interface	IGD	P2P Bridge or Hub Interface
"11"	P2P Bridge or Hub Interface	P2P Bridge or Hub Interface	IGD

ELSE VGA Mem space Legacy Decode:

IF Device # 1 Mem_Access_En = '1'.VGA Mem RangexA0000 - xBFFFFMDA Mem RangexB0000 - xB7FFF

VGA_en	MDAP	Range	Destination	Exceptions/Notes
0	0	VGA, MDA	Hub Interface	-
0	1	Illegal	Illegal	Illegal
1	0	VGA, MDA	AGP	-
1	1	VGAMDA	AGPHub Interface	-

ELSE defaults to Hub Interface.

VGA IO space decode to IGD:

IF IGE = '1' AND IVD = '0' AND Device # 2 IO_Access_En = '1' AND

Additional Qualification within IGD decode (comprehends MDA requirements).

IO Access →MSRb0	3CX	3DX	3B0-3BB	3BC-3BF
"0"	IGD	P2P Bridge or Hub Interface	IGD	P2P Bridge or Hub Interface
"1"	IGD	IGD	P2P Bridge or Hub Interface	P2P Bridge or Hub Interface

ELSE VGA IO space Legacy Decode:

IF Device # 1 IO_Access_En = '1'.

VGA I/O	x3B0 - x3BB & x3C0 - x3DF
MDA I/O	x3B4, x3B5, x3B8, x3B9, x3BA, x3BF

VGA_en	MDAP	Range	Destination	Exceptions/Notes
0	0	VGA, MDA	Hub Interface	x3BC - x3BF goes to AGP if ISA enabled bit is not set in Device #1
0	1	Illegal	Illegal	lllegal
1	0	VGA MDA only (x3BF)	AGPHub Interface	Note : x3BC - x3BE will also go to Hub Interface
1	1	VGAMDA	AGPHub Interface	Note : x3BC - x3BE will also go to Hub Interface

ELSE defaults to Hub Interface.

4.5.1.17 FDHC - Fixed DRAM Hole Control Register - Device #0

Address Offset:	58h
Default Value:	00h
Access:	Read/Write
Size:	8 bits

This 8-bit register controls a single fixed SDRAM hole: 15-16 MB.

Bit	Description					
7	Hole Enable (HEN). This field enables a memory hole in SDRAM space. Host cycles matching an enabled hole are passed on to ICH3-M through Hub Interface. Hub Interface cycles matching an enabled hole will be ignored by the GMCH-M. Note that a selected hole is not re-mapped.					
	Bit 7	Bit 7 Hole Enabled				
	0 None					
	1 15M-16M (1M bytes)					
	Default Value=0.					
6:0	Reserved					

4.5.1.18 PAM(6:0) - Programmable Attribute Map Registers - Device #0

Address Offset:	59 - 5Fh
Default Value:	00h
Attribute:	Read/Write
Size:	4 bits/register, 14 registers

The GMCH-M allows programmable memory attributes on 13 Legacy memory segments of various sizes in the 640-KB to 1-MB address range. Seven Programmable Attribute Map (PAM) Registers are used to support these features. Cacheability of these areas is controlled via the MTRR registers in the P6 processor. Two bits are used to specify memory attributes for each memory segment. These bits apply to host, AGP/PCI, and Hub Interface initiator accesses to the PAM areas.

Note: AGP is available only with the Intel 830M and 830MP Chipset.

These attributes are:

RE - Read Enable. When RE = 1, the CPU read accesses to the corresponding memory segment are claimed by the GMCH-M and directed to main memory. Conversely, when RE = 0, the host read accesses are directed to PCI0.

WE - Write Enable. When WE = 1, the host write accesses to the corresponding memory segment are claimed by the GMCH-M and directed to main memory. Conversely, when WE = 0, the host write accesses are directed to PCI0.

The RE and WE attributes permit a memory segment to be Read Only, Write Only, Read/Write, or disabled. For example, if a memory segment has RE = 1 and WE = 0, the segment is Read Only.

Each PAM Register controls two regions, typically 16 KB in size. Each of these regions has a 4-bit field. The 4 bits that control each region have the same encoding and are defined in the following table.

Bits [7, 3] Reserved	Bits [6, 2] Reserved	Bits [5, 1] WE	Bits [4, 0] RE	Description
X	X	0	0	Disabled . SDRAM is disabled and all accesses are directed to Hub Interface. The GMCH-M does not respond as an AGP/PCI or Hub Interface target for any read or write access to this area.
x	Х	0	1	Read Only . Reads are forwarded to SDRAM and writes are forwarded to Hub Interface for termination. This write protects the corresponding memory segment. The GMCH-M will respond as an AGP/PCI or Hub Interface target for read accesses but not for any write accesses.
X	х	1	0	Write Only . Writes are forwarded to SDRAM and reads are forwarded to the Hub Interface for termination. The GMCH-M will respond as an AGP/PCI or Hub Interface target for write accesses but not for any read accesses.
X	Х	1	1	Read/Write . This is the normal operating mode of main memory. Both read and write cycles from the host are claimed by the GMCH-M and forwarded to SDRAM. The GMCH-M will respond as an AGP/PCI or Hub Interface target for both read and write accesses.

Table 26. Attribute Bit Assignment

NOTE: AGP is available only with the Intel 830M and 830MP Chipset.

As an example, consider a BIOS that is implemented on the expansion bus. During the initialization process, the BIOS can be shadowed in main memory to increase the system performance. When BIOS is shadowed in main memory, it should be copied to the same address location. To shadow the BIOS, the attributes for that address range should be set to write only. The BIOS is shadowed by first doing a read of that address. This read is forwarded to the expansion bus. The host then does a write of the same address, which is directed to main memory. After the BIOS is shadowed, the attributes for that memory area are set to read only so that all writes are forwarded to the expansion bus. Figure 12 and Table 27 show the PAM registers and the associated attribute bits:





•				
PAM Reg	Attribute Bits	Memory Segment	Comments	Offset
PAM0[3:0]	Reserved			59h
PAM0[7:4]	R R WE RE	0F0000h - 0FFFFFh	BIOS Area	59h
PAM1[3:0]	R R WE RE	0C0000h - 0C3FFFh	ISA Add-on BIOS	5Ah
PAM1[7:4]	R R WE RE	0C4000h - 0C7FFFh	ISA Add-on BIOS	5Ah
PAM2[3:0]	R R WE RE	0C8000h - 0CBFFFh	ISA Add-on BIOS	5Bh
PAM2[7:4]	R R WE RE	0CC000h- 0CFFFFh	ISA Add-on BIOS	5Bh
PAM3[3:0]	R R WE RE	0D0000h- 0D3FFFh	ISA Add-on BIOS	5Ch
PAM3[7:4]	R R WE RE	0D4000h- 0D7FFFh	ISA Add-on BIOS	5Ch
PAM4[3:0]	R R WE RE	0D8000h- 0DBFFFh	ISA Add-on BIOS	5Dh
PAM4[7:4]	R R WE RE	0DC000h- 0DFFFFh	ISA Add-on BIOS	5Dh
PAM5[3:0]	R R WE RE	0E0000h- 0E3FFFh	BIOS Extension	5Eh
PAM5[7:4]	R R WE RE	0E4000h- 0E7FFFh	BIOS Extension	5Eh
PAM6[3:0]	R R WE RE	0E8000h- 0EBFFFh	BIOS Extension	5Fh
PAM6[7:4]	R R WE RE	0EC000h- 0EFFFFh	BIOS Extension	5Fh

Table 27. PAM Registers and Associated Memory Segments

For details on overall system address mapping scheme see the Address Decoding Section of this document.

DOS Application Area (00000h-9FFFh)

The DOS area is 640 KB in size and it is further divided into two parts. The 512-KB area at 0 to 7FFFFh is always mapped to the main memory controlled by the GMCH-M, while the 128-KB address range from 080000 to 09FFFFh can be mapped to PCI0 or to main SDRAM. By default, this range is mapped to main memory and can be declared as a main memory hole (accesses forwarded to PCI0) via GMCH-M's FDHC configuration register.

Video Buffer Area (A0000h-BFFFFh)

This 128-KB area is not controlled by attribute bits. The host -initiated cycles in this region are always forwarded to either PCI0 or AGP/PCI1 or PCI2 unless this range is accessed in SMM mode. *Routing of accesses is controlled by the Legacy VGA control mechanism of the "virtual" PCI-PCI bridge device embedded within the GMCH-M*.

This area can be programmed as SMM area via the SMRAM register. When used as an SMM space, this range cannot be accessed from Hub Interface or AGP.

Expansion Area (C0000h-DFFFFh)

This 128-KB area is divided into eight 16-KB segments that can be assigned with different attributes via PAM control register as defined by Table 27.

Extended System BIOS Area (E0000h-EFFFFh)

This 64-KB area is divided into four 16-KB segments that can be assigned with different attributes via PAM control register as defined by the Table 27.

System BIOS Area (F0000h-FFFFFh)

This area is a single 64-KB segment that can be assigned with different attributes via PAM control register as defined by the Table 27.

4.5.1.19 DRB — DRAM Row Boundary Register - Device #0

Address Offset:	60-67h
Default Value:	00h
Access:	Read/Write (Read_Only if D_LCK = 1)
Size:	8 bits

Row Boundary Register defines the upper boundary address of each SDRAM row in 32-MB granularity.

Each row has its own DRB register. Contents of these 8-bit registers represent the boundary address in 32-MB granularity. For example, a value of 1 indicates 32 MB.

Row0: 60h Row1: 61h 62h Row2: 63h Row3: 64h: Reserved Row4: Row5: 65h: Reserved 66h: Reserved Row6: Row7: 67h: Reserved

DRB0 = Total memory in row0 (in 32 Mbytes)

DRB1 = Total memory in row0 + row1 (in 32 Mbytes)

DRB4 = Total memory in row0 + row1 + row2 + row3 + (in 32 Mbytes)

Note: The number of DRB registers and number of bits per DRB register are system dependent. For example, a system that supports 4 rows of SDRAM and a max memory of 1.0 GB needs only 4 DRB registers and 4 bits per DRB.

GMCH-M supports four physical rows of Single data rate SDRAM in 2 SO-DIMMs. The width of a row is 64 bits. Each SO-DIMM/Row is represented by a byte. Each byte has the following format.

GMCH-M supported maximum memory size: 1.0 GB.

Bit	Description
7:0	SDRAM Row Boundary Address : This 8-bit value defines the upper and lower addresses for each SDRAM row.
	Bits 6:0 of this field are compared against the address lines A[31:25] to determine the upper address limit of a particular row.
	Bit 7 must be Zero.
	Default Value=0000/0000.

4.5.1.20 DRA — DRAM Row Attribute Register - Device #0

70-71h
FFh
Read/Write (Read_Only if D_LCK = 1)
8 bits
70h
71h

Row Attribute Register defines the page size of each row.

7	6		4	3	2		0
R		Row attribute for Row1		R		Row Attribute for Row0	

76	4	3	2 0
R	Row attribute for Row3	R	Row Attribute for Row2

Bit	Descriptio	n			
3:0(7:4)	Row Attribute: This 4-bit filed defines the page size of the row. Page Size is dependent on the technology as shown in the table below.				
	Bits 3:0	Page Size			
	"0000"	2 KB			
	"0001"	4 KB			
	"0010"	8 KB			
	"0011"	16 KB.			
	"1111"	Empty Row.			
	All Other (Combinations are Reserved.			
	Default Val	ue=1111.			

4.5.1.21 DRT—DRAM Timing Register - Device #0

Address Offset:	
Default Value:	
Access:	
Size:	

78-7Bh 00000010h Read/Write 32 bits

This register controls the timing of the SDRAM Controller.

Bit	Description	1			
31:19	Reserved				
18:16	DRAM Idle Timer: This field determines the number of clocks the SDRAM controller allows a row in the idle state (un-accessed) before pre-charging all pages in that row; or powering down that row based on the settings of bit 28 and bit 14 of DRC.				
	Bit[18:16]	Idle clocks befo	ore Action		
	000	Ir	finite (Counter is disabled and no action is taken)		
	001	0	(Not Supported on GMCH-M as this setting requires auto precharge)		
	010	8			
	011	1	6		
	100	6	4		
	101	2	56		
	110	5	12		
	111	10)24		
	DRC 28	DRC 14	Action on Counter Expiration.		
	(Pwr Dwn Er	nbl) (Page Cls Er	ldı)		
	0	0	None (Counter Disabled)		
	0	1	Pre-Charge All		
	1	0	Power Down and Deassert CKE, Pages open.		
	1	1	Pre-charge All, Power Down and Deassert CKE		
	Default Valu	e=000.			
	Recommend	led settings for D	RC 28=1, DRC 14=1 and DRT 18:16 =010.		
15:11	Reserved				
10	Activate to Precharge delay (tRAS). This bit controls the number of CLKs for tRAS.				
	0 = tRAS = 7	7 CLKs			
	1 = tRAS = 5	5 CLKs.			
	Default Valu	e=0.			
9:6	Reserved				
5:4	CAS# Laten sampled by 00 = Reser 01 = 3 10 = 2 11 = Reser Default Valu	rved rved rved rved	t controls the number of CLKs between when a read command is when GMCH-M samples read data from the SDRAM.		
3	Reserved				

Bit	Description
2	DRAM RAS# to CAS# Delay (tRCD). This bit controls the number of CLKs from a Row Activate command to a read or write command.
	0 = 3 clocks will be inserted between a row activate command and either a read or write command.
	1 = 2 clocks will be inserted between a row activate command and either a read or write command.
	Default Value=0.
1	Reserved
0	DRAM RAS# Precharge (tRP). This bit controls the number of CLKs for RAS# pre-charge.
	0 = 3 clocks of RAS# pre-charge are provided.
	1 = 2 clocks of RAS# pre-charge are provided
	Default Value=0.

4.5.1.22 DRC - DRAM Controller Mode Register - Device #0

7C-7Fh
0000000h
Read/Write
32 bits

Bit	Description
31:30	Specification Revision Number. Hardwired to "00" on GMCH-M.
29	Initialization Complete (IC): Setting this bit to a "1" enables SDRAM refreshes. On power up and S3 exit, the BIOS initializes the SDRAM array and sets this bit to a "1". This bit works in combination with the RMS bits in controlling refresh state:
	IC RMS Refresh State
	0 XXX OFF
	X 000 OFF
	1 001 ON
	1 010 ON
	1 011 ON
	1 111 ON
	Default Value=0.
28	DRAM Row Power- Mgmt Enable: When this bit is set to a 1, a SDRAM row is powered down (issued a power down command and CKE deasserted) after the SDRAM idle timer (as programmed in DRT) expires.
	During a refresh, rows in the low power state are powered up and refreshed. Hence, coming out of a refresh all rows will be powered up.
	Default Value=0.
27	Reserved.
26:24	Active Row Count: This field determines the number of rows the SDRAM controller allows in the active state if SDRAM row power management is enabled (bit 28). All populated rows not in the active state are in power down. An access to a row in power down will cause that row to exit power down, following that the LRU row is placed into power down if the number of active rows is greater than that allowed by this register (see BIOS specification for the latest value. To receive the BIOS specification, contact your Intel Field Representative).
	Bit[26:24] Maximum number of Active Rows
	0 0 0 All rows allowed to be in active state.
	0 0 1 1 Row
	0 1 0 2 Rows
	0 1 1 3 Rows
	1 0 0 4 Rows
	1 0 1 Reserved
	1 1 0 Reserved
	1 1 1 Reserved
	Default Value=000.
23:20	Reserved
19:15	Reserved
14	Page Close Enable: When this bit is set to a 1, SDRAM row pages are closed after the SDRAM idle timer (as programmed in DRT) expires.
	Default Value=0.
13:11	Reserved

10:8 Refresh Mode Select (RMS): Bits Determine if Refresh is enabled and Refresh Rate. 000: Refresh Enabled. Refresh interval 15.6 µs. 010: Refresh Enabled. Refresh interval 15.6 µs. 011: Reserved 111: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode) All Other Combinations are reserved. Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode. CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/31/33 this register is parameted to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = AII Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 = AII Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 = AII Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 = AII Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interfac	Bit	Description		
000: Refresh Disabled. 001: Refresh Enabled. Refresh interval 15.6 µs. 001: Refresh Enabled. Refresh interval 7.8 µs. 011: Reserved 111: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode) All Other Combinations are reserved. Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 his register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 = Mode Register Set Enable: In this mode. MA3 must be driven to 1 for interfave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011	10:8	Refresh Mode Select (RMS): Bits Determine if Refresh is enabled and Refresh Rate.		
001: Refresh Enabled. Refresh interval 15.6 μs. 010: Refresh Enabled. Refresh interval 7.8 μs. 011: Refresh Enabled. Refresh interval 7.8 μs. 011: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode) All Other Combinations are reserved. Default Value=000. 7 Reserved 6.4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/81/83 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 011 = MOP Command Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set down the 010 for burst of 4 mode. MA3 must be driven to 1 for interfeave wrap type. MA[6:4] needs to be driven based on the value programm		000: Refresh Disabled.		
010: Refresh Enabled. Refresh interval 7.8 µs. 011: Reserved 111: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode) All Other Combinations are reserved. Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 011 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a the deriven to 010 for burst of 4 mode. MA3 must be driven to 1 for interleave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks		001: Refresh Enabled. Refresh interval 15.6 μs.		
011: Reserved 111: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode) All Other Combinations are reserved. Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interfeave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 011 MA[12:7] must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 111 = Normal Operation. Default Value		010: Refresh Enabled. Refresh interval 7.8 μs.		
111: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode) All Other Combinations are reserved. Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/51/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: 011 in this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 = All Banks Pre-charge Command is driven to 1 for interleave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 <th></th> <th>011: Reserved</th>		011: Reserved		
All Other Combinations are reserved. Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/5/153 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 & Clocks 010 3 Clocks 011 MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive		111: Refresh Enabled. Refresh interval 128 Clocks. (Fast Refresh Mode)		
Default Value=000. 7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in a MI Banks Pre-charge Command on the SDRAM interface. 011 Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 Mode Register Set Enable: In this mode all CPU cycles to a the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is drive on on the MA[12:0] lines. 100 <th></th> <th>All Other Combinations are reserved.</th>		All Other Combinations are reserved.		
7 Reserved 6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interfeave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. <		Default Value=000.		
6:4 Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM Interface. The special modes are intended for initialization at power up. 000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interleave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface.	7	Reserved		
000 = Self refresh (Default): In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. 012 = Cacks 010 013 Clocks 011 MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 110 = CBR Ref	6:4	Mode Select (SMS). These bits select the special operational mode of the GMCH-M SDRAM interface. The special modes are intended for initialization at power up.		
In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in CX351/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted. 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interfeave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 011 MA[6:4] 2 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 102 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved		000 = Self refresh (Default):		
001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interfeave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 = Max[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		In this mode, CKEs are deasserted. All other values cause CKE assertion. The exception is in C3/S1/S3 this register is programmed to "normal operation", the DRAMs are in self-refresh, and CKEs are deasserted.		
010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interleave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. <u>CAS Latency</u> <u>MA[6:4]</u> 2 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		 001 = NOP Command Enable: In this mode all CPU cycles to SDRAM result in a NOP Command on the SDRAM interface. 010 = All Banks Pre-charge Enable: In this mode all CPU cycles to SDRAM result in an All Banks Pre-charge Command on the SDRAM interface. 		
011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interleave wrap type. MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved				
MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field. CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		 011 = Mode Register Set Enable: In this mode all CPU cycles to SDRAM result in a mode register set command on the SDRAM interface. The Command is driven on the MA[12:0] lines. MA[2:0] must always be driven to 010 for burst of 4 mode. MA3 must be driven to 1 for interleave wrap type. 		
CAS Latency MA[6:4] 2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		MA[6:4] needs to be driven based on the value programmed in the CAS# Latency field.		
2 Clocks 010 3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		CAS Latency MA[6:4]		
3 Clocks 011 MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0		2 Clocks 010		
MA[12:7] must be driven to 00000. BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		3 Clocks 011		
BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines. 100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		MA[12:7] must be driven to 00000.		
100 = Reserved. 101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		BIOS must calculate and drive the correct host address for each row of memory such that the correct command is driven on the MA[12:0] lines.		
101 = Reserved. 110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		100 = Reserved.		
110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface. 111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		101 = Reserved.		
111 = Normal Operation. Default Value=000. 3:2 Reserved 1:0 Reserved		110 = CBR Refresh Enable. In this mode all CPU cycles to SDRAM result in a CBR cycle on the SDRAM interface.		
Default Value=000. 3:2 Reserved 1:0 Reserved		111 = Normal Operation.		
3:2 Reserved 1:0 Reserved		Default Value=000.		
1:0 Reserved	3:2	Reserved		
	1:0	Reserved		

4.5.1.23 DTC - DRAM Throttling Control Register - Device #0.

Offset Address:	8C-8Fh
Default Value:	0000_0000h
Access:	Read/Write/Lock
Size:	32 bits

Throttling is independent for Reads and Writes. If the number of Oct-Words (16 bytes) read/written during this window exceeds the DRAM Bandwidth Threshold defined below, then the DRAM throttling mechanism will be invoked to limit DRAM reads/writes to a lower bandwidth checked over smaller time windows. The throttling will be active for the remainder of the current GDWS and for the next GDSW after which it will return to non-throttling mode. The throttling mechanism accounts for the actual bandwidth consumed during the sampling window, by reducing the allowed bandwidth within the smaller throttling window based on the bandwidth consumed during the sampling period.

Bits	Description		
31	Throttle Lock (TLOCK): This bit secures the SDRAM throttling control register. Once a '1' is written to this bit, all of the configuration register bits in DTC (including TLOCK) documented below become read-only. Default Value=0.		
30	Intel Reserved		
29:28	DRAM Throttle Mode (TMODE):		
	Bits Mode 0 0 Throttling turned off. 0 1 Bandwidth Counter mechanism is enabled. When bandwidth exceeds threshold set in the r/w PTC field, DRAM read/write throttling begins. 1 0 Thermal Sensor based throttling enabled. When the device's thermal sensor is tripped DRAM Write throttling begins based on settings programmed in WPTC. Read throttling is disabled. 1 1 With this setting Thermal Sensor and DRAM Counter mechanisms are both enabled. However, read throttling is bandwidth counter triggered only while write throttling is thermal sensor or counter triggered. Both read and write throttling mechanisms use programmed values in the throttle control registers. Default Value=00 1		
27:26	Reserved		
25:24	Read Power Throttle Control. These bits select the Power Throttle Bandwidth Limits for Read operations to System Memory. R/W, RO if Throttle Lock.		
	Bits Power Throttle Bandwidth Limit		
	00 No Limit (Default)		
	01 Limit at 65%		
	10 Limit at 55%		
	11 Limit at 45%		
	Default Value=00		
23:22	Reserved		
21:20	Write Power Throttle Control. These bits select the Power Throttle Bandwidth Limits for Write operations to System Memory.		

Bits	Description		
	R/W, RO if Throttle Lock.		
	Bits Power Thro	ttle Bandwidth Limit	
	00	No Limit (Default)	
	01	Limit at 65%	
	10	Limit at 55%	
	11	Limit at 45%	
	Default Value=00		
19:16	Reserved		
15:8	Global DRAM Sampling Window (GDSW) : This eight bit value is multiplied by 4 to define the length of time in milliseconds (0-1020) over which the number of OctWords (16 bytes) read/written is counted and Throttling is imposed. Default Value=00000000.		
7:0	Reserved		

4.5.1.24 SMRAM - System Management RAM Control Register - Device #0

Address Offset:90hDefault Value:02hAccess:Read/Write/Lock, Read OnlySize:8 bits

The SMRAM register controls how accesses to Compatible and Extended SMRAM spaces are treated. The Open, Close, and Lock bits function only when G_SMRAME bit is set to a 1. Also, the OPEN bit must be reset before the LOCK bit is set.

Bit	Description
7	Reserved
6	SMM Space Open (D_OPEN): When D_OPEN=1 and D_LCK=0, the SMM space SDRAM is made visible even when SMM decode is not active. This is intended to help BIOS initialize SMM space. Software should ensure that D_OPEN=1 and D_CLS=1 are not set at the same time. When D_LCK is set to a 1, D_OPEN is reset to 0 and becomes read only. Default Value=0.
5	SMM Space Closed (D_CLS) : When D_CLS = 1 SMM space DRAM is not accessible to data references, even if SMM decode is active. Code references may still access SMM space SDRAM. This will allow SMM software to reference "through" SMM space to update the display even when SMM is mapped over the VGA range. Software should ensure that D_OPEN=1 and D_CLS=1 are not set at the same time. Default Value=0.
4	SMM Space Locked (D_LCK): When D_LCK is set to 1 then D_OPEN is reset to 0 and D_LCK, D_OPEN, G_SMRAME, C_BASE_SEG, GMS, DRB, DRA, H_SMRAM_EN, TSEG_SZ and TSEG_EN become read only. GBA[15:0] and GAR[15:0] associated with the SDRAM controller also become read only after D_LCK is set. D_LCK can be set to 1 via a normal configuration space write but can only be cleared by a Full Reset. The combination of D_LCK and D_OPEN provide convenience with security. The BIOS can use the D_OPEN function to initialize SMM space and then use D_LCK to "lock down" SMM space in the future so that no application software (or BIOS itself) can violate the integrity of SMM space, even if the program has knowledge of the D_OPEN function.
3	Global SMRAM Enable (G_SMRAME). If set to a 1, then Compatible SMRAM functions is enabled, providing 128 KB of SDRAM accessible at the A0000h address while in SMM (ADS# with SMM decode). To enable Extended SMRAM function this bit has be set to 1. Refer to the section on SMM for more details. Once D_LCK is set, this bit becomes read only. Default Value=0.
2:0	Compatible SMM Space Base Segment (C_BASE_SEG) (RO). This field indicates the location of SMM space. "SMM DRAM" is not remapped. It is simply "made visible" if the conditions are right to access SMM space, otherwise the access is forwarded to Hub Interface. C_BASE_SEG is hardwired to 010 to indicate that the GMCH-M supports the SMM space at A0000h-BFFFFh. Default Value=010.

4.5.1.25 ESMRAMC - Extended System Management RAM Control Register -Device #0

Address Offset:91hDefault Value:38hAccess:Read/WriteSize:8 bits

The Extended SMRAM register controls the configuration of Extended SMRAM space. The Extended SMRAM (E_SMRAM) memory provides a write-back cacheable SMRAM memory space that is above 1 MB.

Bit	Description		
7	 H_SMRAM_EN (H_SMRAME): Controls the SMM memory space location (i.e. above 1 MB or below 1 MB). When G_SMRAME is 1 and H_SMRAME this bit is set to 1, the high SMRAM memory space is enabled. SMRAM accesses from 0FEDA0000h to 0FEDBFFFFh are remapped to SDRAM address 000A0000h to 000BFFFFh. Once D_LCK is set, this bit becomes read only. 		
0			
6	E_SMRAM_ERR (E_SMERR): This bit is set when CPU accesses the defined memory ranges in Extended SMRAM (High Memory and T-segment) while not in SMM space and with the D-OPEN bit = 0. It is software's responsibility to clear this bit. The software must write a 1 to this bit to clear it		
	Default Value=0.		
5	SMRAM_Cache (SM_CACHE): This bit is <u>forced to '1'</u> by the GMCH-M . Default Value=1.		
4	SMRAM_L1_EN (SM_L1): This bit is <u>forced to '1'</u> by the GMCH-M.		
2	CNDAM LO EN (CM LO). This hit is formed to (4) hushe CMC/LM		
3	Default Value=1.		
2	Reserved		
1	TSEG_SZ(T_SZ): Selects the size of the TSEG memory block if enabled. This memory is taken from the top of SDRAM space (i.e. TOM - TSEG_SZ), which is no longer claimed by the memory controller. This field decodes as follows: TSEG_SZ Description 0 (TOM-512K) to TOM 1 (TOM 4M) to TOM		
	Once D_LCK is set, this bit becomes read only.		
	Default Value=0.		
0	TSEG_EN (T_EN): Enabling of SMRAM memory (TSEG, 512 Kbytes or 1 Mbytes of additional SMRAM memory) for Extended SMRAM space only. When G_SMRAME =1 and TSEG_EN = 1, the TSEG is enabled to appear in the appropriate physical address space.		
	Once D_LCK is set, this bit becomes read only.		
	Default Value=U.		

4.5.1.26 ERRSTS – Error Status Register – Device #0

Address Offset: 92-93h Default Value: 0000h Access: Read/Write Clear Size: 16 bits

This register is used to report various error conditions via Hub interface special cycles. An SERR, SMI, or SCI Error Hub interface special cycle may be generated on a zero to one transition of any of these flags when enabled in the PCICMD/ERRCMD, SMICMD, or SCICMD registers respectively.

Bit	Description
15:13	Reserved
12	GMCH Software Generated Event for SMI. This indicates the source of the SMI was a Device#2 Software Event for the Local Memory Interface. Software must write a "1" to clear this bit. (Local memory no longer supported.)
11	Reserved
10	Reserved
9	LOCK to non-DRAM Memory Flag (LCKF). (R/WC) When this bit is set it indicates that a CPU initiated LOCK cycle targeting non-DRAM memory space occurred. Software must write a "1" to clear this status bit.
8	Received Refresh Timeout.
	This Bit is set when 1024 memory core refresh are Queued up.
	Software must write a "1" to clear this status bit.
7	DRAM Throttle Flag (DTF) (R/WC). When this bit is set it indicates that the DRAM Throttling condition occurred. Software must write a "1" to clear this status bit.
6	Reserved
5	Received Unimplemented Special Cycle Hub interface Completion Packet FLAG (UNSC) (R/WC). When this bit is set, it indicates that the GMCH initiated a Hub interface request that was terminated with an Unimplemented Special Cycle completion packet. Software must write a "1" to clear this status bit.
4	AGP Access Outside of Graphics Aperture Flag (OOGF). (R/WC) When this bit is set it indicates that an AGP access occurred to an address that is outside of the graphics aperture range. Software must write a "1" to clear this status bit.
	Note: AGP is available only with the Intel 830M and 830MP Chipset.
3	 Invalid AGP Access Flag (IAAF). (R/WC) When this bit is set to "1" it indicates that an AGP access was attempted outside of the graphics aperture and either to the 640k - 1M range or above the top of memory. Software must write a "1" to clear this status bit. NOTE: AGP is available only with the Intel 830M and 830MP Chipset.
2	Invalid Graphics Aperture Translation Table Entry Flag (ITTEF). (R/WC) When this bit is set to "1", it indicates that an invalid translation table entry was returned in response to an AGP access to the graphics aperture. Software must write a "1" to clear this status bit. Invalid translation table entries include the following: Invalid bit set in table entry. Translated address hits PAM region.
	Translated address hits enabled physical SMM space.
	NOTE: AGP is available only with the Intel 830M and 830MP Chipset.
1-0	Reserved

4.5.1.27 ERRCMD - Error Command Register - Device #0

Address Offset:	94-95h
Default Value:	0000h
Access:	Read/Write
Size:	16 bits

This register enables various errors to generate an SERR Hub Interface special cycle. Since the GMCH-M does not have an SERR# signal, SERR messages are passed from the GMCH-M to the ICH3-M over the Hub Interface. The actual generation of the SERR message is globally enabled for Device #0 via the PCI Command register.

Note: An error can generate one and only one Hub Interface error special cycle. The software is responsible to ensure that when an SERR error message is enabled for an error condition, SMI and SCI error messages are disabled for that same error condition.

Bit	Description
15:10	Reserved
9	SERR on LOCK to non-SDRAM Memory . When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when a CPU initiated LOCK transaction targeting non-SDRAM memory space occurs. If this bit is "0" then reporting of this condition is disabled. Default Value=0.
8	SERR on SDRAM Refresh timeout . When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when a SDRAM Refresh timeout occurs.
	If this bit is "0" then reporting of this condition is disabled.
	Default Value=0.
7	SERR on SDRAM Throttle Condition. When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when a SDRAM Read or Write Throttle condition occurs.
	If this bit is "0" then reporting of this condition is disabled.
	Default Value=0.
6	SERR on Receiving Target Abort on Hub Interface . When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when a GMCH-M originated Hub Interface cycle is terminated with a Target Abort.
	If this bit is "0" then reporting of this condition is disabled.
	Default Value=0.
5	SERR on Receiving Unimplemented Special Cycle Hub Interface Completion Packet. When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when a GMCH-M initiated Hub Interface request is terminated with a Unimplemented Special Cycle completion packet.
	If this bit is "0" then reporting of this condition is disabled.
	Default Value=0.
4	SERR on AGP Access Outside of Graphics Aperture . When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when an AGP access occurs to an address outside of the graphics aperture.
	If this bit is "0" then reporting of this condition is disabled.
	Default Value=0.
	NOTE: AGP is available only with the Intel 830M and 830MP Chipset.
3	SERR on Invalid AGP Access . When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when an AGP access occurs to an address outside of the graphics aperture and either to the 640K - 1M range or above the top of memory.

	Default Value=0.
	NOTE: AGP is available only with the Intel 830M and 830MP Chipset.
2	SERR on Access to Invalid Graphics Aperture Translation Table Entry . When this bit is set to "1", the GMCH-M generates an SERR Hub Interface special cycle when an invalid translation table entry was returned in response to a AGP access to the graphics aperture.
	If this bit is "0" then reporting of this condition via SERR messaging is disabled.
	Default Value=0.
	NOTE: AGP is available only with the Intel 830M and 830MP Chipset.
1-0	Reserved

Table 28. Summary of GMCH-M Error Sources, Enables and Status Flags

Error Event	Hub I/F Message	Enable Bits Required to be Set	Status Flags Set
SDRAM Refresh Timeout	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 8	ERRSTS bit 8
CPU LOCK to non-SDRAM memory	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 9	ERRSTS bit 9
SDRAM Throttle	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 7	ERRSTS bit 7
Received Hub Interface Target Abort	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 6	PCISTS bit 12
Unimplemented Special Cycle	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 5	ERRSTS bit 5
AGP Access Outside of Graphics Aperture	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 4	ERRSTS bit 4
Invalid AGP Access	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 3	ERRSTS bit 3
Access to Invalid GTLB Entry	SERR	PCICMD bit 8	PCISTS bit 14
		ERRCMD bit 2	ERRSTS bit 2
AGP PCI Parity Error Detected	SERR	PCICMD1 bit 8	PCISTS1 bit 14
		BCTRL bit 0	SSTS bit 15
AGP PCI Received Target Abort	SERR	PCICMD1 bit 8	PCISTS1 bit 14
		ERRCMD1 bit 0	SSTS bit 12

4.5.1.28 ACAPID - AGP Capability Identifier Register - Device #0

Address Offset:	A0-A3h
Default Value:	00200002h
Access:	Read Only
Size:	32 bits

This register provides standard identifier for AGP capability. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
31:24	Reserved
23:20	Major AGP Revision Number : These bits provide a major revision number of AGP specification to which this version of GMCH-M conforms. These bits are set to the value 0010 to indicate AGP Rev. 2.x. Default Value=0010.
19:16	Minor AGP Revision Number : These bits provide a minor revision number of AGP specification to which this version of GMCH-M conforms. This number is hardwired to value of 0000 (i.e. implying Rev x.0). Together with major revision number, this field identifies GMCH-M as an AGP REV 2.0 compliant device.
	Default Value=0000.
15:8	Next Capability Pointer : AGP capability is the last capability described via the capability pointer mechanism and therefore these bits are hardwired to 00h to indicate the end of the capability linked list. Default Value=0000/0000.
7:0	AGP Capability ID: This field identifies the linked list item as containing AGP registers. This field has the value 02h as assigned by the PCI SIG. Default Value=0000/0010.

4.5.1.29 AGPSTAT - AGP Status Register - Device #0

Address Offset:A4-A7hDefault Value:1F000217hAccess:Read OnlySize:32 bits

This register reports AGP device capability/status. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
31:24	Request Queue . This field is hardwired to 1Fh to indicate a maximum of 32 outstanding AGP command requests can be handled by the GMCH-M. Default =1Fh to allow a maximum of 32 outstanding AGP command requests.
23:10	Reserved
9	SBA. This bit indicates that the GMCH-M supports side band addressing. It is hardwired to 1.
8:6	Reserved
5	4G . This bit indicates that the GMCH-M does not support addresses greater than 4 GB. It is hardwired to 0.
4	Fast Writes The GMCH-M supports Fast Writes from the CPU to the AGP master. Fast Writes are disabled. Default Value=1.
3	Reserved
2:0	 RATE. After reset the GMCH-M reports its data transfer rate capability. Bit 0 identifies if AGP device supports 1x data transfer mode Bit 1 identifies if AGP device supports 2x data transfer mode Bit 2 identifies if AGP device supports 4x data transfer mode. 1x, 2x, and 4x data transfer modes are supported by the GMCH-M. NOTE: The selected data transfer mode applies to both AD bus and SBA bus. Default Value=111.

4.5.1.30 AGPCMD - AGP Command Register - Device #0

Address Offset:	A8-ABh
Default Value:	00000000h
Access:	Read/Write
Size:	32 bits

This register provides control of the AGP operational parameters. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
31:10	Reserved
9	SBA Enable. When this bit is set to 1, the side band addressing mechanism is enabled.
	Default Value=0.
8	AGP Enable. When this bit is reset to 0, the GMCH-M will ignore all AGP operations, including the sync cycle.
	Any AGP operations received while this bit is set to 1 will be serviced even if this bit is reset to 0.
	If this bit transitions from a 1 to a 0 on a clock edge in the middle of an SBA command being delivered in 1X mode the command will be issued.
	When this bit is set to 1 the GMCH-M will respond to AGP operations delivered via PIPE#, or to operations delivered via SBA if the AGP Side Band Enable bit is also set to 1.
	Default Value=0.
7:6	Reserved
5	4G . The GMCH-M as an AGP target does not support addressing greater than 4 GB. This bit is hardwired to 0.
4	Fast Write Enable
	When set to "1" GMCH-M AGP master supports Fast Writes.
	When set to "0" Fast Writes are disabled.
	Default Value=0.
3	Reserved
2:0	Data Rate : The settings of these bits determine the AGP data transfer rate. One (and only one) bit in this field must be set to indicate the desired data transfer rate.
	001 = 1X (Bit 0)
	010 = 2X (Bit 1)
	100 = 4x (Bit 2)
	The same bit must be set on both master and target. Configuration software will update this field by setting only one bit that corresponds to the capability of AGP master (after that capability has been verified by accessing the same functional register within the AGP masters configuration space.)
	Note that the selected data transfer mode applies to both AD bus and SBA bus.
	Default Value=000

4.5.1.31 AGPCTRL - AGP Control Register - Device #0

Address Offset:B0-B1hDefault Value:00000000hAccess:Read/WriteSize:32 bits

This register provides for additional control of the AGP interface. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
31:8	Reserved
7	GTLB Enable (and GTLB Flush Control) (R/W):
	NOTE: This bit can be changed dynamically (i.e. while an access to GTLB occurs).
	Default Value=0.
6:0	Reserved

4.5.1.32 AFT – AGP Functional Test Register – Device #0

Address Offset: B2-B3h Default Value: 0000h Access: Read/Write Size: 16 bits

This register provides for additional control of the AGP interface. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
15:10	Reserved
9	PCI Read Buffer Disable. (RW) When set to "1" is disabled. In this mode all data pre-fetched and buffered for a PCI-to-DRAM read will be discarded when that read transaction terminates. This bit defaults to "0".
8:4	AGP PCI1 Discard Timer Time-out Count. (RW) These bits control the length of AGP/PCI1 Delayed Transaction discard time-out for the purpose of enhancing the system testability. Default value is 11111b (31d) for a discard count of 1024d ((value+1)*32).
3:0	Reserved

4.5.1.33 APSIZE— Aperture Size - Device #0

Address Offset:	B4h
Default Value:	00h
Access:	Read/Write
Size:	8 bits

This register determines the effective size of the Graphics Aperture. This register can be updated by the GMCH-M-specific BIOS configuration sequence before the PCI standard bus enumeration sequence. If the register is not updated then a default value will select an aperture of maximum size (i.e. 256 MB). The size of the table that will correspond to a 256 MB aperture is not practical for most applications and therefore these bits must be programmed to a smaller practical value that will force adequate address range to be requested via APBASE register from the PCI configuration software. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description	
7:6	Reserved	
5:3	Graphics Aperture Size (APSIZE) (R/W): Each bit in APSIZE[5:3] operates on similarly ordered bits in APBASE[27:25] of the Aperture Base configuration register.	
	When a particular bit of this field is "0", it forces the similarly ordered bit in APBASE[27:25] to behave as "hardwired" to 0.	
	When a particular bit of this field is set to "1", it allows the corresponding bit of the APBASE[27:25] to be read/write accessible. Only the following combinations are allowed when the Aperture is enabled:	
	Bits[5:3] Aperture Size	
	1 1 1 32 MB	
	1 1 0 64 MB	
1 0 0 128 MB	1 0 0 128 MB	
	0 0 0 256 MB	
	Default for APSIZE[5:3]=000b forces default APBASE[27:25] =000b (i.e. all bits respond as "hardwired" to 0). This provides maximum aperture size of 256 MB. As another example, programming APSIZE[5:3]=111b enables APBASE[27:25] as read/write programmable.	
2:0	Reserved	

INT

4.5.1.34 ATTBASE— Aperture Translation Table Base Register - Device #0

Address Offset:	B8-BBh
Default Value:	00000000h
Access:	Read/Write
Size:	32 bits

This register provides the starting address of the Graphics Aperture Translation Table Base located in the main DRAM. This value is used by the GMCH-M's Graphics Aperture address translation logic (including the GTLB logic) to obtain the appropriate address translation entry required during the translation of the aperture address into a corresponding physical DRAM address. The ATTBASE register may be dynamically changed. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Note: The address provided via ATTBASE is 4-KB aligned.

Bit	Description
31: 12	This field contains a pointer to the base of the translation table used to map memory space addresses in the aperture range to addresses in main memory.
11:0	Reserved

4.5.1.35 AMTT—AGP Interface Multi-Transaction Timer Register - Device #0

Address Offset:	BCh
Default Value:	00h
Access:	Read/Write
Size:	8 bits

AMTT is an 8-bit register that controls the amount of time that the GMCH-M's arbiter allows the AGP/PCI master to perform multiple back-to-back transactions. The GMCH-M's AMTT mechanism is used to optimize the performance of the AGP master (using PCI semantics) that performs multiple back-to-back transactions to fragmented memory ranges (and as a consequence cannot use long burst transfers). The AMTT mechanism applies to the CPU-AGP/PCI transactions as well and it guarantees to the CPU a fair share of the AGP/PCI interface bandwidth.

The number of clocks programmed in the AMTT represents the guaranteed time slice (measured in 66-MHz clocks) allotted to the current agent (either AGP PCI master or Host bridge) after which the AGP arbiter may grant the bus to another agent. The default value of AMTT is 00h and disables this function. The AMTT value can be programmed with 8-clock granularity. For example, if the AMTT is programmed to 18h, then the selected value corresponds to the time period of 24 AGP (66-MHz) clocks. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
7:3	Multi-Transaction Timer Count Value . The number programmed in these bits represents the guaranteed time slice (measured in eight 66-MHz clock granularity) allotted to the current agent (either AGP PCI master or Host bridge) after which the AGP arbiter may grant the bus to another agent.
2:0	Reserved

4.5.1.36 LPTT—Low Priority Transaction Timer Register - Device #0

BDh
00h
Read/Write
8 bits

LPTT is an 8-bit register similar in a function to AMTT. This register is used to control the minimum tenure on the AGP for low priority data transaction (both reads and writes) issued using PIPE# or Sideband mechanisms.

The number of clocks programmed in the LPTT represents the guaranteed time slice (measured in 66-MHz clocks) allotted to the current low priority AGP transaction data transfer state. This does not necessarily apply to a single transaction but it can span over multiple low-priority transactions of the same type. After this time expires the AGP arbiter may grant the bus to another agent if there is a pending request. The LPTT does not apply in the case of high-priority request where ownership is transferred directly to the high-priority requesting queue.

The default value of LPTT is 00h and disables this function. The LPTT value can be programmed with 8-clock granularity. For example, if the LPTT is programmed to 10h, then the selected value corresponds to the time period of 16 AGP (66-MHz) clocks. This register is Read Only when either the Intel 830M or Intel 830MG internal graphics device is used.

Bit	Description
7:3	Low Priority Transaction Timer Count Value . The number of clocks programmed in these bits represents the guaranteed time slice (measured in eight 66-MHz clock granularity) allotted to the current low priority AGP transaction data transfer state.
2:0	Reserved

4.5.1.37 BUFF_SC – System Memory Buffer Strength Control Register - Device #0

Address Offset:	
Default Value:	
Access:	
Size	

EC-EFh 00000000h Read/Write 32 bits

4.5.1.37.1 SDR Drive Strength Register Description

The System Memory Buffer Strength Control Register programs drive strengths and slew rate and for each buffer category based on loading detected by SPD. CS#, CKE, and CLK buffers have independent control for each SO-DIMM and are programmed to the same strength for front and back side of each SO-DIMM. If the BIOS detects different loading on the backside of the SO-DIMM (i.e. 96 MB), it should ignore the devices on the backside of the SO-DIMM.

Bit	Descriptions
31	Reserved
30	 CLK[3:2] Slew Rate. This field sets the slew rate of the CLK[3:2] pins. 0 = Normal slew rate. 1 = Fast slew rate for reduced Tco. Default Value=0.
29	 CLK[1:0] Slew Rate. This field sets the slew rate of the CLK[1:0] pins. 0 = Normal slew rate. 1 = Fast slew rate for reduced Tco. Default Value=0.
28	Reserved
27	 CS[3:2]#, CKE[3:2] Slew Rate. This field sets the slew rate of the CS[3:2]#, CKE[3:2] pins. 0 = Normal slew rate. 1 = Fast slew rate for reduced Tco. Default Value=0.
26	 CS[1:0]#, CKE[1:0] Slew Rate. This field sets the slew rate of the CS[1:0]#, CKE[1:0] pins. 0 = Normal slew rate. 1 = Fast slew rate for reduced Tco. Default Value=0.
25	 DQ[63:0], DQM[7:0] Slew Rate. This field sets the slew rate of the DQ[63:0], DQM[7:0] pins. 0 = Normal slew rate. 1 = Fast slew rate for reduced Tco. Default Value=0.
24	 MA[12:0], BA[1:0], RAS#, CAS#, WE# Slew Rate. This field sets the slew rate of the MA[12:0], BA[1:0], RAS#, CAS#, WE# pins. 0 = Normal slew rate. 1 = Fast slew rate for reduced Tco. Default Value=0.
23:21	Reserved
20:18	CLK[3:2] Buffer Strength. This field sets the buffer strength of the CLK[3:2] pins.
int_el.

	000 = 0.75X
	001 = 1X
	010 = 1.25X
	011 = 1.5X
	100 = 2X
	101 = 2.5X
	110 = 3X
	111 = 4X
	Default Value=000.
17:15	CLK[1:0] Buffer Strength. This field sets the buffer strength of the CLK[1:0] pins.
	000 = 0.75X
	001 = 1X
	010 = 1.25X
	011 = 1.5X
	100 = 2X
	101 = 2.5X
	110 = 3X
	111 = 4X
	Default Value=000.
14:12	RESERVED
11.0	CS[2,2]# CVE[2,2] Duffer Strength This field acts the buffer strength of the CS[2,2]# CVE[2,2]
11.9	pins.
	000 = 0.75X
	001 = 1X
	010 = 1.25X
	011 = 1.5X
	100 = 2X
	101 = 2.5X
	110 = 3X
	111 = invalid
	Default Value=000.
8:6	CS[1:0]#, CKE[1:0] Buffer Strength . This field sets the buffer strength of the CS[1:0]#, CKE[1:0] pins.
	000 = 0.75X
	001 = 1X
	010 = 1.25X
	011 = 1.5X
	100 = 2X
	101 = 2.5X
	110 = 3X
	111 = invalid
	Default Value=000.
5:3	DQ[63:0], DQM[7:0] Buffer Strength. This field sets the buffer strength of the DQ[63:0], DQM[7:0] pins.
	000 = 0.75X
	001 = 1X
	010 = 1.25X

	011 = 1.5X
	100 = 2X
	101 = 2.5X
	110 = 3X
	111 = invalid
	Default Value=000.
2:0	MA[12:0], BA[1:0], RAS#, CAS#, WE# Buffer Strength . This field sets the buffer strength of the MA[12:0], BA[1:0], RAS#, CAS#, WE# pins.
	000 = 0.75X
	001 = 1X
	010 = 1.25X
	011 = 1.5X
	100 = 2X
	101 = 2.5X
	110 = 3X
	111 = invalid
	Default Value=000.

4.5.2 830M and 830MP Chipset HOST-AGP Bridge Registers - Device #1

Table 29 summarizes the GMCH-M configuration space for device #1. Device 1 applies to both the Intel 830MP and 830M Chipset.

	-	-	1	
Address Offset	Register Symbol	Register Name	Default Value	Access
00-01h	VID1	Vendor Identification	8086h	RO
02-03h	DID1	Device Identification	3576h	RO
04-05h	PCICMD1	PCI Command Register	0000h	RO, R/W
06-07h	PCISTS1	PCI Status Register	0020h	RO, R/WC
08	RID1	Revision Identification	00h	RO
09	-	Intel Reserved	-	-
0Ah	SUBC1	Sub-Class Code	04h	RO
0Bh+	BCC1	Base Class Code	06h	RO
0Ch	-	Intel Reserved	-	-
0Dh	MLT1	Master Latency Timer	00h	R/W
0Eh	HDR1	Header Type	01h	RO
0F-17h	-	Intel Reserved	-	-
18h	PBUSN	Primary Bus Number	00h	RO
19h	SBUSN	Secondary Bus Number	00h	R/W
1Ah	SUBUSN	Subordinate Bus Number	00h	R/W
1Bh	SMLT	Secondary Bus Master Latency Timer	00h	R/W
1Ch	IOBASE	I/O Base Address Register	F0h	R/W
1Dh	IOLIMIT	I/O Limit Address Register	00h	R/W
1E-1Fh	SSTS	Secondary Status Register	02A0h	RO, R/WC
20-21h	MBASE	Memory Base Address Register	FFF0h	R/W
22-23h	MLIMIT	Memory Limit Address Register	0000h	R/W
24-25h	PMBASE	Prefetchable Memory Base Address Reg.	FFF0h	R/W
26-27h	PMLIMIT	Prefetchable Memory Limit Address Reg.	0000h	R/W
28-3Dh	-	Intel Reserved	-	-
3Eh	BCTRL	Bridge Control Register	00h	R/W
3Fh	-	Intel Reserved	-	-
40h	ERRCMD1	Error Command	00h	R/W
41-FFh	-	Intel Reserved	-	-

Table 29. Host-AGP Bridge Configuration Space (Device #1)

4.5.2.1 VID1 - Vendor Identification Register - Device #1

00 - 01h
8086h
Read Only
16 bits

The VID Register contains the vendor identification number. This 16-bit register combined with the Device Identification Register uniquely identifies any PCI device. Writes to this register have no effect.

Bit	Description	
15:0	Vendor Identification Number. This is a 16-bit value assigned to Intel. Intel VID = 8086h.	
	Default Value=1000/0000/1000/0110.	

4.5.2.2 DID1 - Device Identification Register - Device #1

Address Offset:	02 - 03h
Default Value:	3576h
Attribute:	Read Only
Size:	16 bits

This 16-bit register combined with the Vendor Identification register uniquely identifies any PCI device. Writes to this register have no effect.

Bit	Description
15:0	Device Identification Number. This is a 16-bit value assigned to the GMCH-M device #1.GMCH-M device #1 DID =3576h.
	Default Value=0011/0101/0111/0110.

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4.5.2.3 PCICMD1 - PCI-PCI Command Register - Device #1

Address Offset:	04-05h
Default Value:	0000h
Access:	Read/Write, Read Only
Size	16 bits

Bit	Descriptions
15:10	Reserved
9	Fast Back-to-Back: Not Applicable-hardwired to 0. Default Value=0.
8	SERR Message Enable (SERRE1) . This bit is a global enable bit for Device #1 SERR messaging. The GMCH-M does not have an SERR# signal. The GMCH-M communicates the SERR# condition by sending an SERR message to the ICH3-M.
	If this bit is set to a 1, the GMCH-M is enabled to generate SERR messages over Hub Interface for specific Device #1 error conditions that are individually enabled in the BCTRL register. The error status is reported in the PCISTS1 register.
	If SERRE1 is reset to 0, then the SERR message is not generated by the GMCH-M for Device #1.
	NOTE : This bit only controls SERR messaging for the Device #1. Device #0 has its own SERRE bit to control error reporting for error conditions occurring on Device #0. The two control bits are used in a logical OR manner to enable the SERR Hub Interface message mechanism.
	Default Value=0.
7	Address/Data Stepping: Not applicable. Hardwired to 0.
6	Parity Error Enable (PERRE1): PERR# is not supported on AGP/PCI1. Hardwired to 0.
5	Reserved
4	Memory Write and Invalidate Enable: (RO) This bit is implemented as Read Only and returns a value of "0" when read.
	Default Value=0.
3	Special Cycle Enable: (RO) This bit is implemented as Read Only and returns a value of "0" when read.
	Default Value=0.
2	Bus Master Enable (BME1): (R/W) When the Bus Master Enable is set to "0" (default), AGP Master initiated FRAME# cycles will be ignored by the GMCH-M resulting in a Master Abort. Ignoring incoming cycles on the secondary side of the P2P bridge effectively disables the bus master on the primary side.
	When Bus Master Enable is set to "1", AGP Master initiated FRAME# cycles will be accepted by the GMCH-M if they hit a valid address decode range This bit has no effect on AGP Master originated SBA or PIPE# cycles.
	Default Value=0.
1	Memory Access Enable (MAE1): (R/W) This bit must be set to "1" to enable the Memory and Prefetchable memory address ranges defined in the MBASE, MLIMIT, PMBASE, and PMLIMIT registers.
	When set to "0", all of device #1's memory space is disabled.
	Default Value=0.
0	I/O Access Enable (IOAE1): (R/W) This bit must be set to "1" to enable the I/O address range defined in the IOBASE, and IOLIMIT registers.
	When set to "0" all of device #1's I/O space is disabled.
	Default Value=0.

4.5.2.4 PCISTS1 - PCI-PCI Status Register - Device #1

Address Offset:	06-07h
Default Value:	0020h
Access:	Read Only, Read/Write Clear
Size:	16 bits

PCISTS1 is a 16-bit status register that reports the occurrence of error conditions associated with primary side of the "virtual" PCI-PCI bridge embedded within the GMCH-M. Since this device does not physically reside on PCI0 it reports the optimum operating conditions so that it does not restrict the capability of PCI0.

Bit	Descriptions
15	Detected Parity Error (DPE1): Not Applicable - hardwired to "0".
14	Signaled System Error (SSE1). This bit is set to 1 when GMCH-M Device #1 generates an SERR message over Hub Interface for any enabled Device #1 error condition. Device #1 error conditions are enabled in the PCICMD1 and BCTRL registers. Device #1 error flags are read/reset from the SSTS register. Software clears this bit by writing a 1 to it. Default Value=0.
13	Received Master Abort Status (RMAS1): Not Applicable - hardwired to "0".
12	Received Target Abort Status (RTAS1): Not Applicable - hardwired to "0".
11	Signaled Target Abort Status (STAS1): Not Applicable - hardwired to "0".
10:9	DEVSEL# Timing (DEVT1): Not Applicable - hardwired to "00".
8	Data Parity Detected (DPD1): Not Applicable - hardwired to "0".
7	Fast Back-to-Back (FB2B1): Not Applicable - hardwired to "0".
6	Reserved
5	66/60 MHz Capability: Not Applicable - Hardwired to "1".
4:0	Reserved

4.5.2.5 RID1 - Revision Identification Register - Device #1

Address Offset:	08h
Default Value:	03h (A5 silicon)
	04h (A6 silicon)
Access:	Read Only
Size:	8 bits

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This register contains the revision number of the GMCH-M device #1. These bits are read only and writes to this register have no effect. For the A-5 Stepping, this value is 03h.

Bit	Description	
7:0	Revision Identification Number . This is an 8-bit value that indicates the revision identification number for the GMCH-M device #1. Please see spec update for the latest silicon revision.	
	Silicon Revision	Default Value
	A5	0000/0011 (03h)
	A6	0000/0100 (04h)

4.5.2.6 SUBC1 - Sub-Class Code Register - Device #1

Address Offset:	0Ah
Default Value:	04h
Access:	Read Only
Size:	8 bits

This register contains the Sub-Class Code for the GMCH-M device #1. This code is 04h indicating a PCI-PCI Bridge device. The register is read only.

Bit	Description
7:0	Sub-Class Code (SUBC1). This is an 8-bit value that indicates the category of Bridge into which the GMCH-M falls. The code is 04h indicating a Host Bridge. Default Value=0000/0100.

4.5.2.7 BCC1 - Base Class Code Register - Device #1

Address Offset:0BhDefault Value:06hAccess:Read OnlySize:8 bits

This register contains the Base Class Code of the GMCH-M device #1. This code is 06h indicating a Bridge device. This register is read only.

Bit	Description
7:0	Base Class Code (BASEC). This is an 8-bit value that indicates the Base Class Code for the GMCH-M device #1. This code has the value 06h, indicating a Bridge device. Default Value=00000110.

4.5.2.8 MLT1 - Master Latency Timer Register - Device #1

Address Offset:	0Dh
Default Value:	00h
Access:	Read/Write
Size:	8 bits

This functionality is not applicable. It is described here since these bits should be implemented as a read/write to prevent standard PCI-PCI bridge configuration software from getting "confused".

Bit	Description
7:3	Not applicable but support read/write operations. (Reads return previously written data.) Default Value=00000.
2:0	Reserved

4.5.2.9 HDR1 - Header Type Register - Device #1

Address Offset:0EhDefault Value:01hAccess:Read OnlySize:8 bits

This register identifies the header layout of the configuration space. No physical register exists at this location.

Bit	Descriptions
7:0	This read only field always returns 01h when read. Writes have no effect.
	Default Value=00000001.

4.5.2.10 PBUSN - Primary Bus Number Register - Device #1

Address Offset:	18h
Default Value:	00h
Access:	Read Only
Size:	8 bits

This register identifies that "virtual" PCI-PCI bridge is connected to bus #0.

Bit	Descriptions	
7:0	Bus Number. Hardwired to "0".	

4.5.2.11 SBUSN - Secondary Bus Number Register - Device #1

Address Offset:	19h
Default Value:	00h
Access:	Read /Write
Size:	8 bits

This register identifies the bus number assigned to the second bus side of the "virtual" PCI-PCI bridge i.e. to PCI1/AGP. This number is programmed by the PCI configuration software to allow mapping of configuration cycles to PCI1/AGP.

Bit	Descriptions
7:0	Bus Number. Programmable
	Default Value=00000000.

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4.5.2.12 SUBUSN - Subordinate Bus Number Register - Device #1

Address Offset:	1Ah
Default Value:	00h
Access:	Read /Write
Size:	8 bits

This register identifies the subordinate bus (if any) that resides at the level below PCI1/AGP. This number is programmed by the PCI configuration software to allow mapping of configuration cycles to PCI1/AGP.

Bit	Descriptions
7:0	Bus Number. Programmable
	Default Value=00000000.

4.5.2.13 SMLT - Secondary Master Latency Timer Register - Device #1

Address Offset:1BhDefault Value:00hAccess:Read/WriteSize:8 bits

This register controls the bus tenure of the GMCH-M on AGP/PCI. SMLT is an 8-bit register that controls the amount of time the GMCH-M, as an AGP/PCI bus master, can burst data on the AGP/PCI Bus. The Count Value is an 8-bit quantity, however SMLT[2:0] are reserved and assumed to be 0 when determining the Count Value. The GMCH-M's SMLT is used to guarantee to the AGP master a minimum amount of the system resources. When the GMCH-M begins the first PCI bus cycle after being granted the bus, the counter is loaded and enabled to count from the assertion of FRAME#. If the count expires while the GMCH-M's grant is removed (due to AGP master request), then the GMCH-M will lose the use of the bus, and the AGP master agent may be granted the bus. If GMCH-M's bus grant is not removed, the GMCH-M will continue to own the AGP/PCI bus regardless of the SMLT expiration or idle condition.

Note: The GMCH-M must always properly terminate an AGP/PCI transaction, with FRAME# negation prior to the final data transfer.

The number of clocks programmed in the SMLT represents the guaranteed time slice (measured in 66-MHz PCI clocks) allotted to the GMCH-M, after which it must complete the current data transfer phase and then surrender the bus as soon as its bus grant is removed. For example, if the SMLT is programmed to 18h, then the value is 24 AGP clocks. The default value of SMLT is 00h and disables this function. When the SMLT is disabled, the burst time for the GMCH-M is unlimited (i.e. the GMCH-M can burst forever).

Bit	Description
7:3	Secondary MLT counter value. Default Value=00000.
2:0	Reserved

4.5.2.14 IOBASE - I/O Base Address Register - Device #1

Address Offset:	1Ch
Default Value:	F0h
Access:	Read/Write
Size:	8 bits

This register control the CPU to PCI1/AGP I/O access routing based on the following formula:

IO_BASE =< address =< IO_LIMIT

Only upper 4 bits are programmable. For the purpose of address decode address bits A[11:0] are treated as 0. Thus the bottom of the defined I/O address range will be aligned to a 4-KB boundary.

Note: BIOS must not set this register to 00h otherwise 0CF8h/0CFCh accesses will be forwarded to AGP.

Bit	Description
7:4	I/O Address Base . Corresponds to A[15:12] of the I/O address. Default Value=1111.
3:0	I/O Addressing Capability . Hardwired to 0h indicating that only 16 bit I/O addressing is supported. Bits [31:16] of the I/O base address is assumed to be 0000h. Default Value=0000.

4.5.2.15 IOLIMIT - I/O Limit Address Register - Device #1

Address Offset:	1Dh
Default Value:	00h
Access:	Read/Write
Size:	8 bits

This register controls the CPU to PCI1/AGP I/O access routing based on the following formula:

IO_BASE=< address =<IO_LIMIT

Only upper 4 bits are programmable. For the purpose of address decode address bits A[11:0] are assumed to be FFFh. Thus, the top of the defined I/O address range will be at the top of a 4-KB aligned address block.

Bit	Description
7:4	I/O Address Limit . Corresponds to A[15:12] of the I/O address. Default Value=0000.
3:0	Reserved. (Only 16 bit addressing supported.)

4.5.2.16 SSTS - Secondary PCI-PCI Status Register - Device #1

Address Offset:1E-1FhDefault Value:02A0hAccess:Read Only, Read/Write ClearSize:16 bits

SSTS is a 16-bit status register that reports the occurrence of error conditions associated with secondary side (i.e. PCI1/AGP side) of the "virtual" PCI-PCI bridge embedded within GMCH-M.

Bit	Descriptions
15	Detected Parity Error (DPE1). This bit is set to a 1 to indicate GMCH-M's detection of a parity error in the address or data phase of PCI1/AGP bus transactions. Software sets DPE1 to 0 by writing a 1 to this bit. Note that the function of this bit is not affected by the PERRE1 bit.
	Also note that PERR# is not implemented in the GMCH-M.
	Default Value=0.
14	Received System Error (SSE1) . This bit is hardwired to 0 since the GMCH-M does not have an SERR# signal pin.
	Default Value=0.
13	Received Master Abort Status (RMAS1). When the GMCH-M terminates a Host-to-PCI1/AGP with an unexpected master abort, this bit is set to 1.
	Software resets this bit to 0 by writing a 1 to it.
	Default Value=0.
12	Received Target Abort Status (RTAS1). When a GMCH-M-initiated transaction on PCI1/AGP is terminated with a target abort, RTAS1 is set to 1.
	Software resets RTAS1 to 0 by writing a 1 to it.
	Default Value=0.
11	Signaled Target Abort Status (STAS1). STAS1 is hardwired to a 0, since the GMCH-M does not generate target abort on PCI1/AGP.
	Default Value=0.
10:9	DEVSEL# Timing (DEVT1). This 2-bit field indicates the timing of the DEVSEL# signal when the GMCH-M responds as a target on PCI1/AGP, and is hard-wired to the value 01b (medium) to indicate the time when a valid DEVSEL# can be sampled by the initiator of the PCI cycle. Default Value=01.
8	Data Parity Detected (DPD1) Hardwired to 0 GMCH-M does not implement G PERR# function
0	However, data parity errors are still detected and reported using SERR Hub Interface special cycles(if enabled by SERRE1 and the BCTRL register, bit 0).
	Default Value=0.
7	Fast Back-to-Back (FB2B1). This bit is hardwired to 1 since GMCH-M as a target supports fast back- to-back transactions on PCI1/AGP.
	Default Value=1.
6	Reserved
5	66/60 MHZ Capability: Hardwired to "1".
4:0	Reserved
1	

4.5.2.17 MBASE - Memory Base Address Register - Device #1

Address Offset:	20-21h
Default Value:	FFF0h
Access:	Read/Write
Size:	16 bits

This register controls the CPU to PCI1 non-prefetchable memory access routing based on the following formula:

MEMORY_BASE=< address =<MEMORY_LIMIT

The upper 12 bits of the register are read/write and correspond to the upper 12 address bits A[31:20] of the 32-bit address. The bottom 4 bits of this register are read-only and return zeroes when read. The configuration software must initialize this register. For the purpose of address decode, address bits A[19:0] are assumed to be 0. Thus, the bottom of the defined memory address range will be aligned to a 1-MB boundary.

Bit	Description
15: 4	Memory Address Base (MEM_BASE). Corresponds to A[31:20] of the memory address. Default Value=0000000000000.
3:0	Reserved

4.5.2.18 MLIMIT - Memory Limit Address Register - Device #1

Address Offset:	22-23h
Default Value:	0000h
Access:	Read/Write
Size:	16 bits

This register controls the CPU to PCI1 non-prefetchable memory access routing based on the following formula:

MEMORY_BASE =< address =< MEMORY_LIMIT

The upper 12 bits of the register are read/write and correspond to the upper 12 address bits A[31:20] of the 32-bit address. The bottom 4 bits of this register are read-only and return zeroes when read. The configuration software must initialize this register. For the purpose of address decode, address bits A[19:0] are assumed to be FFFFFh. Thus, the top of the defined memory address range will be at the top of a 1-MB aligned memory block.

Bit	Description
15: 4	Memory Address Limit (MEM_LIMIT). Corresponds to A[31:20] of the memory address. Default Value=0000000000000.
3:0	Reserved

- *Note:* Memory range covered by MBASE and MLIMIT registers are used to map non-prefetchable PCI1/AGP address ranges (typically where control/status memory-mapped I/O data structures of the graphics controller will reside). Memory range covered by PMBASE and PMLIMIT registers are used to map prefetchable address ranges (typically graphics memory). This segregation allows application of USWC space attribute to be performed in a true plug-and-play manner to the prefetchable address range for improved CPU-AGP memory access performance.
- *Note:* Configuration software is responsible for programming all address range registers (prefetchable, non-prefetchable) with the values that provide exclusive address ranges i.e. prevent overlap with each other and/or with the ranges covered with the main memory. There is no provision in the GMCH-M hardware to enforce prevention of overlap and operations of the system in the case of overlap are not guaranteed.

4.5.2.19 PMBASE - Prefetchable Memory Base Address Register - Device #1

Address Offset:24-25hDefault Value:FFF0hAccess:Read/WriteSize:16 bits

This register controls the CPU to PCI1 prefetchable memory accesses routing based on the following formula:

```
PREFETCHABLE_MEMORY_BASE=< address =< PREFETCHABLE_MEMORY_LIMIT
```

The upper 12 bits of the register are read/write and correspond to the upper 12 address bits A[31:20] of the 32-bit address. The bottom 4 bits of this register are read-only and return zeroes when read. The configuration software must initialize this register. For the purpose of address decode, address bits A[19:0] are assumed to be 0. Thus, the bottom of the defined memory address range will be aligned to a 1-MB boundary.

Bit	Description
15: 4	Prefetchable Memory Address Base (PMEM_BASE). Corresponds to A[31:20] of the memory address. Default Value=1111/1111/1111.
3:0	Reserved

4.5.2.20 PMLIMIT - Prefetchable Memory Limit Address Register - Device #1

Address Offset:	26-27h
Default Value:	0000h
Access:	Read/Write
Size:	16 bits

This register controls the CPU to PCI1 prefetchable memory accesses routing based on the following formula:

```
PREFETCHABLE_MEMORY_BASE=< address =<PREFETCHABLE_MEMORY_LIMIT
```

The upper 12 bits of the register are read/write and correspond to the upper 12 address bits A[31:20] of the 32-bit address. The bottom 4 bits of this register are read-only and return zeroes when read. The configuration software must initialize this register. For the purpose of address decode, address bits A[19:0] are assumed to be FFFFFh. Thus, the top of the defined memory address range will be at the top of a 1-MB aligned memory block.

Bit	Description
15: 4	Prefetchable Memory Address Limit (PMEM_LIMIT).Corresponds to A[31:20] of the memory address. Default Value=0000/0000/0000.
3:0	Reserved

Note that prefetchable memory range is supported to allow segregation by the configuration software between the memory ranges that must be defined as UC and the ones that can be designated as a USWC (i.e. prefetchable) from the CPU perspective.

4.5.2.21 BCTRL - PCI-PCI Bridge Control Register - Device #1

Address Offset:	3Eh
Default Value:	00h
Access:	Read/Write
Size	8 bits

This register provides extensions to the PCICMD1 register that are specific to PCI-PCI bridges. The BCTRL provides additional control for the secondary Interface (i.e. PCI1/AGP) as well as some bits that affect the overall behavior of the "virtual" PCI-PCI bridge embedded within GMCH-M, e.g. VGA compatible address ranges mapping.

Bit	Descript	ions		
7	Fast Bac	k-to-Back I wired to 0.	Enable: Since there is only one target allowed on AGP this bit is meaningless. This	
6	Secondary Bus Reset: GMCH-M does not support generation of reset via this bit on the AGP and therefore this bit is hardwired to 0.			
	Note that software of	the only wa	ay to perform a hard reset of the AGP is via the system reset either initiated by e via ICH3-M.	
5	Master A GMCH-M Default Va	bort Mode : will drop w alue=0.	This bit is hardwired to 0. This means when acting as a master on AGP/PCI1 the rites on the "floor" and return all 1 during reads when a Master Abort occurs.	
4	Reserved	1		
3	VGA Ena memory a the AGP:	ble . Contro address ran	Is the routing of CPU initiated transactions targeting VGA compatible I/O and ges. When this bit is set, the GMCH-M will forward the following CPU accesses to	
	1) Memory accesses in the range 0A0000h to 0BFFFFh			
	2) I/O addresses where A[9:0] are in the ranges 3B0h to 3BBh and 3C0h to 3DFh			
	(inclusive of ISA address aliases - A[15:10] are not decoded)			
	When this bit is set, forwarding of these accesses issued by the CPU is independent of the I/O address and memory address ranges defined by the previously defined base and limit registers. Forwarding of these accesses is also independent of the settings of the bit 2 (ISA Enable) of this register if this bit is 1.			
	If the VGA Interface.	A enable bit	is set, then accesses to IO address range x3BCh-x3BFh are forwarded to Hub	
	If the VGA other IO a ISA enabl	A enable bit accesses, i. le bit is not	is not set then accesses to IO address range x3BCh-x3BFh are treated just like any e. the cycles are forwarded to AGP if the address is within IOBASE and IOLIMIT and set, otherwise they are forwarded to Hub Interface.	
	If this bit i they are n defined al	s 0, then V0 napped to p bove (IOBA	GA compatible memory and I/O range accesses are not forwarded to AGP but rather primary PCI unless they are mapped to AGP via I/O and memory range registers SE, IOLIMIT, MBASE, MLIMIT, PMBASE, PMLIMIT)	
	The follow	ving table s	hows the behavior for all combinations of MDA and VGA:	
	VGA	MDA	Behavior	
	0	0	All References to MDA and VGA Go To Hub Interface (Default)	
	0	1	Illegal Combination (DO NOT USE)	
	1	0	All References To VGA Go To AGP MDA-only references (I/O Address 3BF and aliases) will go to Hub Interface.	
	1	1	VGA References Go To AGP; MDA references go to Hub Interface	
	Default Va	alue=0.		

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Bit	Descriptions
2	ISA Enable : Modifies the response by the GMCH-M to an I/O access issued by the CPU that target ISA I/O addresses. This applies only to I/O addresses that are enabled by the IOBASE and IOLIMIT registers. When this bit is set to 1, GMCH-M will not forward to PCI1/AGP any I/O transactions addressing the last 768 bytes in each 1KB block even if the addresses are within the range defined by the IOBASE and IOLIMIT registers. Instead of going to PCI1/AGP these cycles will be forwarded to Hub Interface where they can eventually be subtractive or positively claimed by the ISA bridge.
	will be mapped to PCI1/AGP.
	Default Value=0.
1	SERR# Enable . This bit normally controls forwarding SERR# on the secondary interface to the primary interface. The GMCH-M does not support the SERR# signal on the AGP PCI1 bus. Hardwired to a "0".
0	Parity Error Response Enable : Controls GMCH-M's response to data phase parity errors on PCI1/AGP G_PERR# is not implemented by the GMCH-M. However, when this bit is set to 1, address and data parity errors on PCI1 are reported via SERR messaging, if enabled by SERRE1.
	If this bit is reset to 0, then address and data parity errors on PCI1/AGP are not reported via the GMCH-M SERR# signal. Other types of error conditions can still be signaled via SERR messaging independent of this bit's state.
	Default Value=0.

4.5.2.22 ERRCMD1 - Error Command Register - Device #1

Address Offset:	40h
Default Value:	00h
Access:	Read/Write
Size	8 bits

Bit	Descriptions
7:1	Reserved.
0	SERR on Receiving Target Abort on AGP/PCI . When this bit is set to 1, the GMCH-M generates an SERR Hub Interface special cycle when an GMCH-M originated AGP/PCI cycle is terminated with a Target Abort.
	If this bit is 0, then reporting of this condition is disabled.
	Default Value=0.

4.5.3 830M and 830MG Chipset Integrated Graphics Device Registers – Device #2

This section contains the PCI configuration registers listed in order of ascending offset address. Device#2 applies to both the Intel 830M and 830MG Chipset.

Device #2 incorporates 2 functions, #0 and #1.

Table 30. Integrated Graphics Device Configuration Space (Device #2)

Address Offset	Register Symbol	Register Name	Default Value Function #0	Default Value Function #1	Access	Regs in Func #1*
00-01h	VID2	Vendor Identification	8086h	8086h	RO	COF0
02-03h	DID2	Device Identification	3577h	3577h	RO	COF0
04-05h	PCICMD2	PCI Command Register	0000h	0000h	RO,R/W	UIF1
06-07h	PCISTS2	PCI Status Register	0090h	0090h	RO,R/WC	UIF1
08h	RID2	Revision Identification	00h	00h	RO	COF0
09-0Bh	CC	Class Code	030000h	038000h	RO	UIF1
0Ch	CLS	Cache Line Size Register	00h	00h	RO	COF0
0Dh	MLT2	Master Latency Timer	00h	00h	RO	COF0
0Eh	HDR2	Header Type	00h	00h	RO	UIF1
0Fh	-	Intel Reserved	-	-	-	-
10-13h	GMADR	Graphics Memory Range Address	0000008h	0000008h	RO,R/W	UIF1
14-17h	MMADR	Memory Mapped Range Address	00000000h	00000000h	RO,R/W	UIF1
18-2Bh	-	Intel Reserved	-	-	-	-
2C-2Dh	SVID2	Subsystem Vendor ID	0000h	0000h	R/WO in F# 0	COF0
2E-2Fh	SID2	Subsystem ID	0000h	0000h	R/ WO in F# 0	COF0
30-33h	ROMADR	Video Bios ROM Base Address	00000000h	00000000h	RO,R/W	COF0
34h	CAPPOINT	Capabilities Pointer	D0h	D0h	RO	COF0
35-3Bh	-	Intel Reserved	-	-	-	-
3Ch	INTRLINE	Interrupt Line	00h	00h	R/W, RO in	-

		Register			F# 1	
3Dh	INTRPIN	Interrupt Pin Register	01h	00h	RO, Reserved In F #1	-
3Eh	MINGNT	Minimum Grant Register	00h	00h	RO	COF0
3Fh	MAXLAT	Maximum Latency Register	00h	00h	RO	COF0
40-CFh	-	Intel Reserved	-	-	-	-
D0-D1h	PMCAPID	Power Management Capabilities ID	0001h	0001h	RO	COF0
D2-D3h	PMCAP	Power Management Capabilities	0221h	0221h	RO	COF0
D4-D5h	PMCS	Power Management Control	0000h	0000h	RO,R/W	UIF1
D6-FFh	-	Intel Reserved	-	-	-	-

NOTES:

COF0: Copy of Function #0, No hardware implemented for this register in function #1.
 UIF1: Unique in Function #1, Hardware is implemented for this register in function #1, may be RO or R/W.

4.5.3.1 VID2 - Vendor Identification Register – Device #2

Address Offset:	00h-01h
Default Value:	8086h
Access:	Read Only
Size:	16 bits

The VID Register contains the vendor identification number. This 16-bit register combined with the Device Identification Register uniquely identifies any PCI device. Writes to this register have no effect.

Bit	Description
15:0	Vendor Identification Number. This is a 16-bit value assigned to Intel.
	Default Value=1000/0000/1000/0110.

4.5.3.2 DID2 - Device Identification Register - Device #2

Address Offset:02h-03hDefault Value:3577hAccess:Read OnlySize:16 bits

This 16-bit register combined with the Vendor Identification register uniquely identifies any PCI device. Writes to this register have no effect.

Bit	Description
15:0	Device Identification Number. This is a 16 bit value assigned to the GMCH-M IGD.
	Default Value=0011/0101/0111/0111.

4.5.3.3 PCICMD2 - PCI Command Register - Device #2

Address Offset:	04h-05h
Default Value:	0000h
Access:	Read Only, Read/Write
Size:	16 bits

This 16-bit register provides basic control over the IGD's ability to respond to PCI cycles. The PCICMD Register in the IGD disables the IGD PCI compliant master accesses to main memory.

Bit	Description
15:10	Reserved
9	Fast Back-to-Back (FB2B) - RO. (Not Implemented). Hardwired to 0.
8	SERR# Enable (SERRE) - RO. (Not Implemented). Hardwired to 0.
7	Address/Data Stepping - RO. (Not Implemented). Hardwired to 0.
6	Parity Error Enable (PERRE) - RO. (Not Implemented). Hardwired to 0.
	Since the IGD belongs to the category of devices that does not corrupt programs or data in system memory or hard drives, the IGD ignores any parity error that it detects and continues with normal operation.
5	Video Palette Snooping (VPS) - RO. This bit is hardwired to 0 to disable snooping.
4	Memory Write and Invalidate Enable (MWIE) - RO. Hardwired to 0.
	The IGD does not support memory write and invalidate commands.
3	Special Cycle Enable (SCE) - RO. This bit is hardwired to 0.
	The IGD ignores Special cycles.
2	Bus Master Enable (BME) - R/W . Set to 1 to enable the IGD to function as a PCI compliant master. Set to 0 to disable IGD bus mastering. Default Value=0.
1	Memory Access Enclos (MAE) DAV This hit controls the ICD's response to memory appear
I	accesses.
	0 = Disable
	1 = Enable
	Default Value=0.

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0	I/O Access Enable (IOAE) - R/W. This bit controls the IGD's response to I/O space accesses.
	0 = Disable
	1 = Enable.
	Default Value=0.

4.5.3.4 PCISTS2 - PCI Status Register - Device #2

Address Offset:06h-07hDefault Value:0090hAccess:Read Only, Read/Write ClearSize:16 bits

PCISTS is a 16-bit status register that reports the occurrence of a PCI compliant master abort and PCI compliant target abort. PCISTS also indicates the DEVSEL# timing that has been set by the IGD.

Bit	Description
15	Detected Parity Error (DPE) - RO . Since the IGD does not detect parity, this bit is always set to 0. Default Value=0.
14	Signaled System Error (SSE) - R/WC. The IGD never asserts SERR#, therefore this bit is hardwired to 0.
13	Received Master Abort Status (RMAS) - R/WC. The IGD never gets a Master Abort, therefore this bit is hardwired to 0.
12	Received Target Abort Status (RTAS) - R/WC . The IGD never gets a Target Abort, therefore this bit is hardwired to 0.
11	Signaled Target Abort Status (STAS). Hardwired to 0. The IGD does not use target abort semantics.
10:9	DEVSEL# Timing (DEVT) - RO. NA - Hardwired to 00.
8	Data Parity Detected (DPD) - R/WC . Since Parity Error Response is hardwired to disabled (and the IGD does not do any parity detection), this bit is hardwired to 0.
7	Fast Back-to-Back (FB2B). Hardwired to 1. The IGD accepts fast back-to-back when the transactions are not to the same agent.
6	User Defined Format (UDF). Hardwired to 0.
5	66 MHz PCI Capable (66C). NA - Hardwired to 0.
4	CAP LIST - RO . This bit is set to 1 to indicate that the register at 34h provides an offset into the function's PCI Configuration Space containing a pointer to the location of the first item in the list.
	Default Value=1.
3:0	Reserved

4.5.3.5 RID2 - Revision Identification Register - Device #2

Address Offset:	08h
Default Value:	03h (A5 silicon)
	04h (A6 silicon)
Access:	Read Only
Size:	8 bits

This register contains the revision number of the IGD. These bits are read only and writes to this register have no effect.

Bit	Description	
7:0	Revision Identification for the IGD. Please se	on Number. This is an 8-bit value that indicates the revision identification number be spec update for the latest silicon revision.
	Silicon Revision	Default Value
	A5	0000/0011 (03h)
	A6	0000/0100 (04h)

4.5.3.6 CC - Class Code Register - Device #2

Address Offset:	09h-0Bh
Default Value:	030000h
Access:	Read Only
Size:	24 bits

This register contains the device programming interface information related to the Sub-Class Code and Base Class Code definition for the IGD. This register also contains the Base Class Code and the function sub-class in relation to the Base Class Code.

Bit	Description
23:16	Base Class Code (BASEC). 03=Display controller Default Value=00000011.
15:8	Sub-Class Code (SCC). Function 0: 00h=VGA compatible; based on Device #0 GCC1 bit 1. Function 1: 80h=Non VGA; Default Value=00000000.
7:0	Programming Interface (PI) . 00h=Hardwired as a Display controller. Default Value=00000000.

4.5.3.7 CLS - Cache Line Size Register - Device #2

Address Offset:	0Ch
Default Value:	00h
Access:	Read only
Size:	8 bits

The IGD does not support this register as a PCI slave.

Bit	Description
7:0	Cache Line Size (CLS). This field is hardwired to 0's. The IGD as a PCI compliant master does not use the Memory Write and Invalidate command and, in general, does not perform operations based on cache line size.
	Default Value=00000000.

4.5.3.8 MLT2 - Master Latency Timer Register - Device #2

0Dh
00h
Read Only
8 bits

The IGD does not support the programmability of the master latency timer because it does not perform bursts.

Bit	Description
7:0	Master Latency Timer Count Value. Hardwired to 00000000.

4.5.3.9 HDR2 - Header Type Register - Device #2

Address Offset:	0Eh
Default Value:	00h
Access:	Read Only
Size:	8 bits

This register contains the Header Type of the IGD.

Bit	Description
7	Multi Function Status (MFunc). Indicates if the device is a Multi-Function Device. The Value of this register is determined by GCC1 bit 2. If GCC1 bit 2 is set this bit is a "1" indicating Device #2 to be multi-function. Default Value=0.
6:0	Header Code (H) . This is an 7-bit value that indicates the Header Code for the IGD. This code has the value 00h, indicating a type 0 configuration space format. Default Value=000000000.

4.5.3.10 GMADR - Graphics Memory Range Address Register - Device #2

Address Offset:10-13hDefault Value:0000008hAccess:Read/Write, Read OnlySize:32 bits

This register requests allocation for the IGD graphics memory. The allocation is for either 64 MB or 128 MB and the base address is defined by bits [31:27,26].

Bit	Description
31:27	Memory Base Address - R/W . Set by the OS, these bits correspond to address signals [31:26]. Default Value=00000.
26	128 MB Address Mask – RO, R/W. The operation of this bit is controlled via Device 0 register GCCR.
	If the signal is low this bit is Read Only with a value of 0, indicating a memory range of 128 MB.
	If the signal is high, this bit becomes R/W, indicating a memory range of 64MB (where system software will program the bit to the appropriate address bit value.
	Default Value=0.
25:4	Address Mask - RO. Hardwired to 0s to indicate (at least) a 32MB address range.
3	Prefetchable Memory - RO. Hardwired to 1 to enable prefetching.
2:1	Memory Type - RO. Hardwired to 0 to indicate 32-bit address.
0	Memory/IO Space - RO. Hardwired to 0 to indicate memory space.

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4.5.3.11 MMADR - Memory Mapped Range Address Register - Device #2

Address Offset:14-17hDefault Value:0000000hAccess:Read/Write, Read OnlySize:32 bits

This register requests allocation for the IGD registers and instruction ports. The allocation is for 512 KB and the base address is defined by bits [31:19].

Bit	Description
31:19	Memory Base Address - R/W. Set by the OS, these bits correspond to address signals [31:19].
	Default Value=0.
18:4	Address Mask - RO. Hardwired to 0s to indicate 512-KB address range.
3	Prefetchable Memory - RO. Hardwired to 0 to prevent prefetching.
2:1	Memory Type - RO. Hardwired to 0s to indicate 32-bit address.
0	Memory / IO Space - RO. Hardwired to 0 to indicate memory space.

4.5.3.12 SVID2 - Subsystem Vendor Identification Register - Device #2

Address Offset:	2C-2Dh
Default Value:	0000h
Access:	Read/Write Once
Size:	16 bits

Bit	Description
15:0	Subsystem Vendor ID. This value is used to identify the vendor of the subsystem. This register should be programmed by BIOS during boot-up. Once written, this register becomes Read_Only. This register can only be cleared by a Reset. Default Value=000000000000000000000000000000000000

4.5.3.13 SID2 - Subsystem Identification Register - Device #2

Address Offset:	2E-2Fh
Default Value:	0000h
Access:	Read/Write Once
Size:	16 bits

В	Bit	Description
15	5:0	Subsystem Identification . This value is used to identify a particular subsystem. This field should be programmed by BIOS during boot-up. Once written, this register becomes Read_Only. This register can only be cleared by a Reset.
		Default Value=000000000000000000000000000000000000

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4.5.3.14 ROMADR - Video BIOS ROM Base Address Registers - Device #2

Address Offset:	30-33h
Default Value:	00000000h
Access:	Read/Write, Read Only
Size:	32 bits

The IGD does not use a separate BIOS ROM, therefore this register is hardwired to 0's.

Bit	Description
31:18	ROM Base Address - R/W. Hardwired to 0's.
17:11	Address Mask - RO. Hardwired to 0s to indicate 256-KB address range.
10:1	Reserved. Hardwired to 0s.
0	ROM BIOS Enable - R/W . 0 = ROM not accessible.
	Default Value=0.

4.5.3.15 CAPPOINT - Capabilities Pointer Register - Device #2

Address Offset:	34h
Default Value:	D0h
Access:	Read Only
Size:	8 bits

Bit	Description
7:0	Capabilities Pointer Value . This field contains an offset into the function's PCI Configuration Space for the first item in the New Capabilities Linked List, the ACPI registers at address D0h. Default Value=11010000.

4.5.3.16 INTRLINE - Interrupt Line Register - Device #2

Address Offset:	3Ch
Default Value:	00h
Access:	Read/Write
Size:	8 bits

Bit	Description
7:0	Interrupt Connection . Used to communicate interrupt line routing information. POST software writes the routing information into this register as it initializes and configures the system. The value in this register indicates which input of the system interrupt controller that the device's interrupt pin is connected to. Default Value=00000000.

4.5.3.17 INTRPIN - Interrupt Pin Register - Device #2

Address Offset:3DhDefault Value:01h, 00h for Function #1Access:Read OnlySize:8 bits

Bit	Description
7:0	Interrupt Pin . As a single function device, the IGD specifies INTA# as its interrupt pin. 01h=INTA#. For Function #1, this register is set to 00h.
	Default Value=00000001.

4.5.3.18 MINGNT - Minimum Grant Register - Device #2

3Eh
00h
Read Only
8 bits

Bit	Description	
7:0	Minimum Grant Value. The IGD does not burst as a PCI compliant master. Bits[7:0]=00h.	
	Default Value=00000000.	

4.5.3.19 MAXLAT - Maximum Latency Register - Device #2

Address Offset:	3Fh
Default Value:	00h
Access:	Read Only
Size:	8 bits

Bit	Description	
7:0	Maximum Latency Value. PCI bus. Bits [7:0]=00h	The IGD has no specific requirements for how often it needs to access the
	Default Value=00000000.	

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4.5.3.20 PMCAPID - Power Management Capabilities ID Register - Device #2

Address Offset:	D0h-D1h
Default Value:	0001h
Access:	Read Only
Size:	16 bits

Bit	Description
15:8	NEXT_PTR. This contains a pointer to next item in capabilities list. This is the final capability in the list and must be set to 00h. Default Value=00000000.
7:0	CAP_ID. SIG defines this ID is 01h for power management. Default Value=00000001.

4.5.3.21 PMCAP - Power Management Capabilities Register - Device #2

Address Offset:	D2h-D3h
Default Value:	0221h
Access:	Read Only
Size:	16 bits

Bit	Description
15:11	PME Support . This field indicates the power states in which the IGD may assert PME#. Hardwired to 0 to indicate that the IGD does not assert the PME# signal.
10	D2 . The D2 power management state is not supported. This bit is hardwired to 0.
9	D1. Hardwired to 1 to indicate that the D1 power management state is supported.
8:6	Reserved. Read as 0s.
5	Device Specific Initialization (DSI). Hardwired to 1 to indicate that special initialization of the IGD is required before generic class device driver is to use it.
4	Auxiliary Power Source. Hardwired to 0.
3	PME Clock. Hardwired to 0 to indicate IGD does not support PME# generation.
2:0	Version. Hardwired to 001b to indicate there are 4 bytes of power management registers implemented.

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4.5.3.22 PMCS - Power Management Control/Status Register - Device #2

Address Offset:D4h-D5hDefault Value:0000hAccess:Read/Write, Read OnlySize:16 bits

Bit	Descriptio	on
15	PME_Status - RO . This bit is 0 to indicate that IGD does not support PME# generation from D3 (cold). Default Value=0.	
14:13	Reserved Default Value=0.	
12:9	Reserved Default Value=0.	
8	PME_En - RO . This bit is 0 to indicate that PME# assertion from D3 (cold) is disabled. Default Value=0.	
7:2	Reserved. Always returns 0 when read, write operations have no effect. Default Value=0.	
1:0	PowerState - R/W . This field indicates the current power state of the IGD and can be used to set the IGD into a new power state. If software attempts to write an unsupported state to this field, write operation must complete normally on the bus, but the data is discarded and no state change occurs.	
	Bits[1:0]	Power State
	00	D0
	00	D1
	10	D2 Not Supported
	11	D3
	Default Value=00.	

5 Functional Description

5.1 System Address Map

A Mobile Intel Pentium III Processor-M / Mobile Intel Celeron Processor system based on the Intel 830 Chipset family GMCH-M supports 4 GB of addressable memory space and 64 KB+3 of addressable I/O space. (The P6 bus I/O addressability is 64 KB + 3.) There is a programmable memory address space under the 1 MB region that is divided into regions which can be individually controlled with programmable attributes such as Disable, Read/Write, Write Only, or Read Only.

The Mobile Intel Pentium III Processor-M / Mobile Intel Celeron Processors support addressing of memory ranges larger than 4 GB. The GMCH-M claims any CPU access over 4 GB and terminates the transaction without forwarding it to hub interface or AGP. Simply dropping the data terminates writes and for reads the GMCH-M returns all zeros on the host bus. Note that the GMCH-M does not support the PCI Dual Address Cycle Mechanism (DAC) and therefore does not allow addressing of greater than 4 GB on either the hub interface or AGP interface.

In the following sections, it is assumed that all of the compatibility memory ranges reside on the hub interface/PCI. The exception to this rule is VGA ranges, which may be mapped to AGP or to IGD. In the absence of more specific references, cycle descriptions referencing PCI should be interpreted as the hub interface/PCI, while cycle descriptions referencing AGP are related to the AGP bus.

Note: Support for AGP is available on both the Intel 830MP and 830M Chipset. Support for internal graphics device (IGD) is available on both the Intel 830MG and 830M Chipset.

5.1.1 System Memory Address Ranges

The Intel 830 Chipset family GMCH-M provides a maximum PC133 address decode space of 1.0 GB. The GMCH-M does not re-map APIC memory space. The GMCH-M does not limit SDRAM space in hardware. It is the BIOS or system designer's responsibility to limit SDRAM population so that adequate PCI, AGP, High BIOS, and APIC memory space can be allocated. The following figure represents system memory address map in a simplified form. The following figure provides additional details on mapping specific memory regions as defined and supported by the Intel 830 Chipset family.



Figure 13. Memory System Address Map

NOTE: Note: Support for AGP is available on both the Intel 830MP and 830M Chipset.



Figure 14. Detailed Memory System Address Map

NOTE: Support for AGP is available on both the Intel 830MP and 830M Chipset.

5.1.2 Compatibility Area

This area is divided into the following address regions:

- 0 640 KB DOS Area
- 640 768 KB Video Buffer Area
- 768 896 KB in 16-KB sections (total of 8 sections) Expansion Area
- 896 -960 KB in 16-KB sections (total of 4 sections) Extended System BIOS Area
- 960 KB 1 MB Memory (BIOS Area) System BIOS Area

There are 16 memory segments in the compatibility area. Thirteen of the memory ranges can be enabled or disabled independently for both read and write cycles.

Memory Segments	Attributes	Comments
000000H - 09FFFFH	Fixed - always mapped to main SDRAM	0 to 640K – DOS Region
0A0000H - 0BFFFFH	Mapped to hub interface, or AGP - configurable as SMM space	Video Buffer (physical SDRAM configurable as SMM space)
0C0000H - 0C3FFFH	WE RE	Add-on BIOS
0C4000H - 0C7FFFH	WE RE	Add-on BIOS
0C8000H - 0CBFFFH	WE RE	Add-on BIOS
0CC000H - 0CFFFFH	WE RE	Add-on BIOS
0D0000H - 0D3FFFH	WE RE	Add-on BIOS
0D4000H - 0D7FFFH	WE RE	Add-on BIOS
0D8000H - 0DBFFFH	WE RE	Add-on BIOS
0DC000H - 0DFFFFH	WE RE	Add-on BIOS
0E0000H - 0E3FFFH	WE RE	BIOS Extension
0E4000H - 0E7FFFH	WE RE	BIOS Extension
0E8000H - 0EBFFFH	WE RE	BIOS Extension
0EC000H - 0EFFFFH	WE RE	BIOS Extension
0F0000H - 0FFFFFH	WE RE	BIOS Area

Table 31. Memory Segments and Attributes

5.1.2.1 DOS Area (00000h-9FFFh)

The DOS area is 640 KB in size and is always mapped to the main memory controlled by the Intel 830 Chipset family GMCH-M.

5.1.2.2 Legacy VGA Ranges (A0000h-BFFFFh)

The legacy 128-KB VGA memory range A0000h-BFFFFh (Frame Buffer) can be mapped to AGP/PCI1 (Device #1), to IGD (Device #2) and/or to the hub interface depending on the programming of the VGA steering bits. Priority for VGA mapping is constant in that the Intel 830 Chipset family GMCH-M always decodes internally mapped devices first. Internal to the GMCH-M, decode precedence is always given to IGD. The GMCH-M always positively decodes internally mapped device, namely the IGD and AGP/PCI1. Subsequent decoding of regions mapped to AGP/PCI1 or the hub interface depends on the Legacy VGA configurations bits (VGA Enable and MDAP). This region is also the default for SMM space.

5.1.2.3 Compatible SMRAM Address Range (A0000h-BFFFFh)

When compatible SMM space is enabled, SMM-mode CPU accesses to this range are routed to physical system SDRAM at this address. Non-SMM-mode CPU accesses to this range are considered to be to the Video Buffer Area as described above. AGP and hub interface originated cycles to enabled SMM space are not allowed and are considered to be to the Video Buffer Area.

5.1.2.4 Monochrome Adapter (MDA) Range (B0000h - B7FFFh)

Legacy support requires the ability to have a second graphics controller (monochrome) in the system. Accesses in the VGA range are forwarded to IGD, AGP/PC11 and the hub interface (depending on configuration bits). Since the monochrome adapter may be mapped to anyone of these devices, the GMCH-M must decode cycles in the MDA range and forward them either to IGD, AGP/PC11 or to the hub interface. This capability is controlled by a VGA steering bits and the legacy configuration bit (MDAP bit). In addition to the memory range B0000h to B7FFFh, the Intel 830 Chipset family GMCH-M decodes IO cycles at 3B4h, 3B5h, 3B8h, 3B9h, 3Bah, and 3BFh and forwards them to the either the IGD, AGP/PC11 and/or the hub interface.

5.1.2.5 Expansion Area (C0000h-DFFFFh)

This 128-KB ISA Expansion region is divided into eight 16- KB segments. Each segment can be assigned one of four Read/Write states: read-only, write-only, read/write, or disabled. Typically, these blocks are mapped through GMCH-M and are subtractively decoded to ISA space. Memory that is disabled is not remapped.

5.1.2.6 Extended System BIOS Area (E0000h-EFFFFh)

This 64-KB area is divided into four 16-KB segments. Each segment can be assigned independent read and write attributes so it can be mapped either to main SDRAM or to hub interface. Typically, this area is used for RAM or ROM. Memory segments that are disabled are not remapped elsewhere.

5.1.2.7 System BIOS Area (F0000h-FFFFFh)

This area is a single 64-KB segment. This segment can be assigned read and write attributes. It is by default (after reset) Read/Write disabled and cycles are forwarded to hub interface. By manipulating the Read/Write attributes, the GMCH-M can "shadow" BIOS into the main SDRAM. When disabled, this segment is not remapped.

5.1.3 Extended Memory Area

This memory area covers 100000h (1 MB) to FFFFFFFh (4 GB-1) address range and it is divided into the following regions:

- Main System SDRAM Memory from 1 MB to the Top of Memory; maximum of 1.0 GB.
- AGP or PCI Memory space from the Top of Memory to 4 GB with two specific ranges:
- APIC Configuration Space from FEC0_0000h (4 GB-20 MB) to FECF_FFFFh and FEE0_0000h to FEEF_FFFFh
- High BIOS area from 4 GB to 4 GB 2 MB

5.1.3.1 Main System SDRAM Address Range (0010_0000h to Top of Main Memory)

The address range from 1 MB to the top of main memory is mapped to main SDRAM address range controlled by the Intel 830 Chipset family GMCH-M. The Top of Memory (TOM) is limited to 1.0 GB. All accesses to addresses within this range will be forwarded by the GMCH-M to the SDRAM unless a hole in this range is created using the fixed hole as controlled by the FDHC register. Accesses within this hole are forwarded to hub interface.

The GMCH-M provides a maximum SDRAM address decode space of 4 GB. The GMCH-M does not re-map APIC memory space. The GMCH-M does not limit SDRAM address space in hardware. It is the BIOS or system designer's responsibility to limit SDRAM population so that adequate PCI, AGP, High BIOS, and APIC memory space can be allocated.

5.1.3.1.1 15 MB-16 MB Window

A hole can be created at 15 MB-16 MB as controlled by the fixed hole enable (FDHC register) in Device 0 space. Accesses within this hole are forwarded to the hub interface. The range of physical SDRAM memory disabled by opening the hole is not remapped to the Top of the memory – that physical SDRAM space is not accessible. This 15 MB-16 MB hole is an optionally enabled ISA hole. Video accelerators originally used this hole. Validation and customer SV teams also use it for some of their test cards. That is why it is being supported. There is no inherent BIOS request for the 15-16 hole.

5.1.3.1.2 Pre-allocated Memory

Physical addresses that are not accessible as general system memory and reside within system memory address range (less than TOM) are created for SMM-mode and legacy VGA graphics compatibility. The Intel 830M and 830MG Chipsets support an increased amount of pre-allocated memory to support up to 1600 x 1200 x 32 bpp. The pre-allocated memory allows sizes of 512 KB, 1 MB, or 8 MB. . The system BIOS must properly initialize these regions.

5.1.3.2 Extended SMRAM Address Range (HSEG and TSEG)

The HSEG and TSEG SMM transaction address spaces reside in this extended memory area.

5.1.3.2.1 HSEG

SMM-mode CPU accesses to enabled HSEG are remapped to 000A0000h-000BFFFFh. Non-SMMmode CPU accesses to enabled HSEG are considered invalid and are terminated immediately on the host interface. The exceptions to this rule are Non-SMM-mode Write Back cycles that are remapped to SMM space to maintain cache coherency. AGP and hub interface originated cycles to enabled SMM space are not allowed. Physical SDRAM behind the HSEG transaction address is not remapped and is not accessible.

5.1.3.2.2 TSEG

TSEG can be up to 1 MB in size and is at the top of physical memory. SMM-mode CPU accesses to enabled TSEG access the physical SDRAM at the same address. Non-SMM-mode CPU accesses to enabled TSEG is considered invalid and are terminated immediately on the host interface. The exceptions to this rule are Non-SMM-mode Write Back cycles that are directed to the physical SMM space to maintain cache coherency. AGP and hub interface originated cycles to enabled SMM space are not allowed.

The size of the SMRAM space is determined by the USMM value in the SMRAM register. When the extended SMRAM space is enabled, non-SMM CPU accesses and all other accesses in this range are forwarded to the hub interface. When SMM is enabled, the amount of memory available to the system is equal to the amount of physical SDRAM minus the value in the TSEG register.

5.1.3.3 Intel Dynamic Video Memory Technology (DVMT)

The IGD on both 830M and 830MG Chipsets supports DVMT in a non-graphics memory configuration. Intel's Dynamic Video Memory Technology is a mechanism that manages system memory and the
internal graphics device for optimal graphics performance. DVMT-enabled software drivers, working with the memory arbiter and the operating system, utilize the system memory to support graphics 2D and 3D applications. DVMT dynamically responds to application requirements by allocating the proper amount of display and texturing memory. DVMT is not available when discrete AGP device is used.

5.1.3.4 PCI Memory Address Range (Top of Main Memory to 4 GB)

The address range from the top of main SDRAM to 4 GB (top of physical memory space supported by the Intel 830 Chipset family GMCH-M is normally mapped via the hub interface to PCI.

As an internal graphics configuration, there is one exception to this rule.

1. Addresses decoded to the Memory Mapped Range of the Internal Graphics Device. These are forwarded to the Internal Graphics Device.

As an AGP configuration, there are two exceptions to this rule.

- 1. Addresses decoded to the AGP Memory Window defined by the MBASE, MLIMIT, PMBASE, and PMLIMIT registers are mapped to AGP.
- 2. Addresses decoded to the Graphics Aperture range defined by the APBASE and APSIZE registers are mapped to the main SDRAM.

There are two sub-ranges within the PCI Memory address range defined as APIC Configuration Space and High BIOS Address Range. As an IGD, the Memory Mapped Range of the IGD MUST NOT overlap with these two ranges. Similarly, as an AGP device, the AGP memory window and AGP Graphics Aperture Window MUST NOT overlap with these two ranges. These ranges are described in detail in the following paragraphs.

5.1.3.5 Configuration Space (FEC0_0000h -FECF_FFFFh, FEE0_0000h-FEEF_FFFh)

This range is reserved for APIC configuration space that includes the default I/O APIC configuration space. The default Local APIC configuration space is FEE0_0000h to FEEF_0FFFh.

CPU accesses to the Local APIC configuration space do not result in external bus activity since the Local APIC configuration space is internal to the CPU. However, an MTRR must be programmed to make the Local APIC range uncacheable (UC). The Local APIC base address in each CPU should be relocated to the FEC0_0000h (4 GB-20 MB) to FECF_FFFFh range so that one MTRR can be programmed to 64 KB for the Local and I/O APICs. The I/O APIC(s) usually resides in the ICH3-M portion of the chip-set or as a stand-alone component(s).

I/O APIC units will be located beginning at the default address FEC0_0000h. The first I/O APIC will be located at FEC0_0000h. Each I/O APIC unit is located at FEC0_x000h where x is I/O APIC unit number 0 through F(hex). This address range will be normally mapped to hub interface.

Note: There is no provision to support an I/O APIC device on AGP.

The address range between the APIC configuration space and the High BIOS (FED0_0000h to FFDF_FFFFh) is always mapped to the hub interface.

5.1.3.6 High BIOS Area (FFE0_0000h -FFFF_FFFh)

The top 2 MB of the Extended Memory Region is reserved for System BIOS (High BIOS), extended BIOS for PCI devices, and the A20 alias of the system BIOS. CPU begins execution from the High BIOS after reset. This region is mapped to hub interface so that the upper subset of this region aliases to

16 MB-256 KB range. The actual address space required for the BIOS is less than 2 MB but the minimum CPU MTRR range for this region is 2 MB so that full 2 MB must be considered.

5.1.4 AGP Memory Address Ranges

The Intel 830MP and 830M GMCH-M can be programmed to direct memory accesses to the AGP bus interface when addresses are within either of two ranges specified via registers in GMCH-M's Device #1 configuration space. The first range is controlled via the Memory Base Register (MBASE) and Memory Limit Register (MLIMIT) registers. The second range is controlled via the Prefetchable Memory Base (PMBASE) and Prefetchable Memory Limit (PMLIMIT) registers.

Conceptually, address decoding for each range follows the same basic concept. The top 12 bits of the respective Memory Base and Memory Limit registers correspond to address bits A[31:20] of a memory address. For the purpose of address decoding, the GMCH-M assumes that address bits A[19:0] of the memory base are zero and that address bits A[19:0] of the memory limit address are FFFFFh. This forces each memory address range to be aligned to 1-MB boundary and to have a size granularity of 1 MB.

The GMCH-M positively decodes memory accesses to AGP memory address space as defined by the following equations:

Memory_Base_Address * Address * Memory_Limit_Address

Prefetchable_Memory_Base_Address * Address * Prefetchable_Memory_Limit_Address

The window size is programmed by the plug-and-play configuration software. The window size depends on the size of memory claimed by the AGP device. Normally these ranges will reside above the Top-of-Main-SDRAM and below High BIOS and APIC address ranges. They normally reside above the top of memory (TOM) so they do not steal any physical SDRAM memory space.

It is essential to support a separate Prefetchable range in order to apply USWC attribute (from the processor point of view) to that range. The USWC attribute is used by the processor for write combining.

Note that the GMCH-M Device #1 memory range registers described above are used to allocate memory address space for any devices sitting on AGP that requires such a window. These devices would include the AGP device, PCI-66 MHz/1.5 V agents, and multifunctional AGP devices where one or more functions are implemented as PCI devices.

The PCICMD1 register can override the routing of memory accesses to AGP. In other words, the memory access enable bit must be set in the device 1, PCICMD1 register, to enable the memory base/limit and prefetchable base/limit windows.

5.2 Intel 830 Chipset Family Host Interface

5.2.1 Overview

The Intel 830 Chipset family GMCH-M is optimized for the Mobile Intel Pentium III Processor-M/ Mobile Intel Celeron Processors. The GMCH-M supports a PSB frequency of 133 MHz using 1.25 V AGTL signaling. The AGTL buffers support dual-ended termination. The GMCH-M supports 32-bit host addressing, decoding up to 4 GB of memory address space for the processor. CPU memory writes to address space above 4 GB will be immediately terminated and discarded. CPU memory reads to address space above 4 GB will be immediately terminated and will return the value of the pulled-up GTL host bus. Host initiated I/O cycles are decoded to AGP/PCI1, hub interface, or GMCH-M configuration space. Host initiated memory cycles are decoded to AGP/PCI1, hub interface, or system SDRAM, or graphics memory mapped registers. Host cycles to AGP/PCI, or the Integrated Graphics Device (IGD), or hub interface, are subject to dynamic deferring.

All memory accesses from the Host that hit the graphics aperture are translated using an AGP address translation table. GMCH-M accesses to AGP/PCI1 device accesses to non-cacheable system memory are not snooped on the host bus. Memory accesses initiated from AGP/PCI1 using PCI semantics, cacheable accesses from the IGD and from hub interface to SDRAM will be snooped on the host bus.

Note: Support for AGP is available on both the Intel 830MP and 830M Chipset. Support for internal graphics device (IGD) is available on both the Intel 830MG and 830M Chipset.

5.2.2 Processor Unique PSB Activity

The Intel 830 Chipset family GMCH-M recognizes and supports a large subset of the transaction types that are defined for the P6 bus interface. However, each of these transaction types has a multitude of response types, some of which are not supported by this controller. All transactions are processed in the order that they are received on the host bus. A summary of transactions supported by the GMCH-M is given in the following table.

Table 32. Host Bus Transactions Supported by GMCH-M

Transaction	REQa[4:0]#	REQb[4:0]#	GMCH-M Support
Deferred Reply	00000	x x x x x	The GMCH-M will initiate a deferred reply for a previously deferred transaction.
Reserved	00001	XXXXX	Reserved
Interrupt Acknowledge	01000	00000	Interrupt acknowledge cycles are forwarded to the hub interface bus.
Special Transactions	01000	00001	See Table 34 in Special Cycles section.
Reserved	01000	0 0 0 1 x	Reserved
Reserved	01000	0 0 1 x x	Reserved
Branch Trace Message	01001	00000	The GMCH-M will terminate a branch trace message without latching data.
Reserved	01001	00001	Reserved
Reserved	01001	0 0 0 1 x	Reserved
Reserved	01001	0 0 1 x x	Reserved
I/O Read	10000	0 0 x LEN#	I/O read cycles are forwarded to hub interface or AGP/PCI unless they target the GMCH-M configuration space (this includes the IGD). In this case, the GMCH- M picks up the transaction.
I/O Write	10001	0 0 x LEN#	I/O write cycles are forwarded to hub interface or AGP/PCI unless they target the GMCH-M configuration space (this includes the IGD). In this case, the GMCH- M picks up the transaction.
Reserved	1100x	0 0 x x x	Reserved
Memory Read & Invalidate	00010	0 0 x LEN#	Host initiated memory read and invalidate cycles are forwarded to system SDRAM, hub interface, AGP/PCI, or Graphics Memory Mapped Registers. The GMCH- M will initiate an MRI (LEN=0) cycle to snoop a hub interface, AGP/PCI, or cacheable IGD initiated write cycle to system SDRAM.
Reserved	00011	0 0 x LEN#	Reserved
Memory Code Read	00100	0 0 x LEN#	Memory code read cycles are forwarded to system SDRAM, hub interface, or AGP/PCI.
Memory Data Read	00110	0 0 x LEN#	Host initiated memory read cycles are forwarded to system SDRAM, hub interface, AGP/PCI, or Graphics Memory Mapped Registers. The GMCH-M will initiate a memory read cycle to snoop a hub interface, AGP/PCI, or cacheable IGD initiated read cycle to system SDRAM.
Memory Write (no retry)	00101	0 0 x LEN#	This memory write is a writeback cycle and cannot be retried. The GMCH-M will forward the write to system SDRAM.
Memory Write (can be retried)	00111	0 0 x LEN#	The memory write cycle will be forwarded to system SDRAM, hub interface, AGP/PCI, or Graphics Memory Mapped Registers.

NOTES:

For Memory cycles, REQa[4:3]# = ASZ#. The GMCH-M only supports ASZ# = 00 (32 bit address).
 REQb[4:3]# = DSZ#. For the Pentium Pro Processor, DSZ# = 00 (64 bit data bus size).

3.	LEN# =	data	transfer	length	as	follows:
----	--------	------	----------	--------	----	----------

- LEN# Data length 00
 - <= 8 bytes (BE[7:0]# specify granularity) 01
 - Length = 16 bytes BE[7:0]# all active
 - Length = 32 bytes BE[7:0]# all active
- 4. Reserved.

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Table 33. Host Bus Responses Supported by GMCH-M

RS2#	RS1#	RS0#	Description	GMCH-M Support
0	0	0	Idle	
0	0	1	Retry Response	This response is generated if an access is to a resource that cannot be accessed by the processor at this time and the logic must avoid deadlock.
				Hub Interface directed reads and writes, SDRAM locked reads, AGP/PCI, and IGD reads and writes can be retried.
				Unless there is an attempt to establish LOCK, the GMCH- M will never Retry a cycle that targets system memory.
0	1	0	Deferred Response	This response can be returned for all transactions that can be executed 'out of order.'
				Hub Interface directed reads (memory, I/O and Interrupt Acknowledge) and writes (I/O only), AGP/PCI directed reads (memory and I/O) and writes (I/O only), and IGD directed reads (memory and I/O) and writes (I/O only) can be deferred.
				Unless there is an attempt to establish LOCK, the GMCH- M will never Defer a cycle that targets system memory.
0	1	1	Reserved	Reserved
1	0	0	Hard Failure	Not supported
1	0	1	No Data Response	This is for transactions where the data has already been transferred or for transactions where no data is transferred.
				Writes and zero length reads receive this response.
1	1	0	Implicit Writeback	This response is given for those transactions where the initial transactions snoop hits on a modified cache line.
1	1	1	Normal Data Response	This response is for transactions where data accompanies the response phase. Reads receive this response.

5.2.3 Host Addresses Above 4 GB

CPU memory writes to address space above 4 GB will be terminated and discarded immediately. CPU memory reads to address space above 4 GB will also be immediately terminated and will return the value of the pulled-up GTL host bus.

5.2.4 Host Bus Cycles

The following transaction descriptions illustrate the various operations in their most straightforward representation. The diagrams do not attempt to show the transaction phase relationships when multiple transactions are active on the CPU bus. For a full description of the CPU Bus functionality please refer to the latest *P6 Family of Processor Hardware Developer's Manual*.

5.2.4.1 Partial Reads

Partial Read transactions include: I/O reads and memory read operations of less than or equal to eight bytes (four consecutive bytes for I/O) within an aligned 8-byte span. The byte enable signals, BE#[7:0], select which bytes in the span to read.

5.2.4.2 Part-Line Read and Write Transactions

The Intel 830 Chipset family GMCH-M does not support a part-line, i.e. 16-byte transactions.

5.2.4.3 Cache Line Reads

A read of a full cache line (as indicated by the LEN[1:0]=10 during request phase) requires 32 bytes of data to be transferred, which translates into four data transfers for a given request. If selected as a target, the Intel 830 Chipset family GMCH-M will determine if the address is directed to system SDRAM, graphics SDRAM, hub interface, or AGP/PCI, and provide the corresponding command and control to complete the transaction.

5.2.4.4 Partial Writes

Partial Write transactions include: I/O and memory write operations of eight bytes or less (maximum of four bytes for I/O) within an aligned 8-byte span. The byte enable signals, BE#[7:0], select which bytes in the span to write. I/O writes crossing a 4-byte boundary are broken into two separate transactions by the CPU.

5.2.4.5 Cache Line Writes

A write of a full cache line requires 32 bytes of data to be transferred, which translates into four data transfers for a given request.

5.2.4.6 Memory Read and Invalidate (Length > 0)

A Memory Read and Invalidate (MRI) transaction is functionally equivalent to a cache line read. The purpose this special transaction is to support write allocation (write miss case) of cache lines in the processors. When a processor issues an MRI, the cache line is read as in a normal cache line read operation; however, all other caching agents must invalidate this line if they have it in a shared or exclusive state. If a caching agent has this line in the Modified State, then it must be written back to memory and invalidated. The Intel 830 Chipset family GMCH-M snarfs the write-back data.

5.2.4.7 Memory Read and Invalidate (Length = 0)

A Memory Read and Invalidate transaction of length zero, MRI(0) does not have an associated Data Response. Executing the transaction will inform other agents in the system that the agent issuing this request wants exclusive ownership of a cache line that is in the Shared State (write hit to a shared line).

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Agents with this cache line will invalidate the line. If this line is in the modified state an implicit writeback cycle is generated and the Intel 830 Chipset family GMCH-M snarfs the data.

The Intel 830 Chipset family GMCH-M generates length=0 Memory Read and Invalidate transactions for hub interface, AGP/PCI, or IGD memory write cycles to system SDRAM.

5.2.4.8 Memory Read (Length = 0)

A Memory Read of length zero, MR(0), does not have an associated Data Response. This transaction is used by the GMCH-M to snoop for the hub interface to system SDRAM, AGP/PCI snoopable system SDRAM read accesses, and IGD snoopable system SDRAM read accesses. The Intel 830 Chipset family GMCH-M snoop request policy is identical for hub interface and AGP/PCI, and IGD memory read transactions.

Note that the GMCH-M will perform single MR(0) cycles for hub interface reads less than or equal to 32 bytes, for AGP/PCI master reads or read lines directed to System SDRAM, and for IGD cacheable reads or read lines (which can only be directed to System SDRAM). The GMCH-M will do multiple snoop ahead cycles for hub interface burst reads greater than 32 bytes and for AGP/PCI master burst reads (i.e. memory read multiple) to SDRAM. Multiple snoop ahead cycles by the GMCH-M are not necessary for the IGD as burst reads are not supported by the IGD.

5.2.4.9 Host Initiated Zero-Length R/W Cycles

Streaming SIMD Extension (SSE) new instructions can result in zero-length read and write cycles to the Chipset.

The Intel 830 Chipset family GMCH-M supports a zero-length processor write cycle by executing a 1 QW write cycle to the targeted destination with all 8 byte enables turned off. The following destinations for host initiated zero-length writes are supported:

- 1. Coherent system memory
- 2. Aperture mapped to system memory
- 3. Aperture mapped to graphics memory
- 4. GMCH-M internal memory-mapped I/O registers
- 5. PCI (via hub Interface)
- 6. AGP

The GMCH-M only supports zero-length processor read cycles that target coherent system memory or AGP/PCI1. When targeting coherent system memory, the GMCH-M forwards the cycle as a 1 QW read from system SDRAM. The data is returned to the GMCH-M. The GMCH-M then returns a "no data" response to the host and empties the returned data from its buffer.

5.2.4.10 Cache Coherency Cycles

The Intel 830 Chipset family GMCH-M generates an implicit writeback response during host bus read and write transactions when a CPU asserts HITM# during the snoop phase. The CPU initiated write case has two data transfers, the requesting agents data followed by the snooping agents writeback data.

The GMCH-M will perform a memory read and invalidate cycle of length = 0 (MRI[0]) on the CPU bus when a hub interface, AGP/PCI, or IGD snoopable system SDRAM write cycle occurs.

The GMCH-M will perform a memory read cycle with length = 0 (MR[0]) on the CPU bus when a hub interface, AGP/PCI, or IGD snoopable system SDRAM read cycle occurs.

5.2.4.11 Interrupt Acknowledge Cycles

A processor agent issues an Interrupt Acknowledge cycle in response to an interrupt from an 8259compatible interrupt controller. The Interrupt Acknowledge cycle is similar to a partial read transaction, except that the address bus does not contain a valid address.

Interrupt Acknowledge cycle is always directed to the hub interface (never to AGP/PCI, or the IGD).

5.2.4.12 Locked Cycles

The Intel 830 Chipset family GMCH-M supports resource locking due to the assertion of the LOCK# line on the CPU bus as follows.

5.2.4.12.1 CPU<->System SDRAM Locked Cycles

The Intel 830 Chipset family GMCH-M supports CPU to SDRAM locked cycles. The host bus may not execute any other transactions until the locked cycle is complete. The GMCH-M arbiter may grant another hub interface or AGP device, but any "Coherent" cycles to SDRAM will be blocked. CPU Lock operations DO NOT block any "Non_Coherent" accesses to SDRAM.

5.2.4.12.2 CPU<->Hub Interface Locked Cycles

Any CPU-to-hub interface locked transaction will initiate a hub interface locked sequence. The P6 bus implements the bus lock mechanism, which means that no change of bus ownership can occur from the time one agent, has established a locked transaction (i.e., the initial read cycle of a locked transaction has completed) until the locked transaction is completed. Note that for CPU-to-hub interface lock transactions, a bit in the request packet indicates a lock transaction.

Any concurrent cycle that requires snooping on the host bus is not processed while a LOCK transaction is occurring on the host bus.

Hub interface-to-SDRAM locked cycles are not supported.

5.2.4.12.3 CPU<->AGP/PCI Locked Cycles

The AGP/PCI1 interface does not support locked operations and therefore both CPU locked and nonlocked transactions destined to AGP/PCI1 are propagated in the same manner. However, note that any concurrent cycle that requires snooping on the host bus is not processed while a LOCK transaction is occurring on the host bus.

5.2.4.12.4 CPU<->IGD (Graphics Memory)

The IGD does not support locked operations and therefore both CPU locked and non-locked transactions destined to IGD Graphics Memory are propagated in the same manner. Note however, that any concurrent cycle that requires snooping on the host bus is not processed while a LOCK transaction is occurring on the host bus.

5.2.4.13 Branch Trace Cycles

An agent issues a Branch Trace Cycle for taken branches if execution tracing is enabled. Address Aa[35:3]# is reserved and can be driven to any value. D[63:32]# carries the linear address of the instruction causing the branch and D[31:0]# carries the target linear address. The GMCH-M will respond

and retire this transaction but will not latch the value on the data lines or provide any additional support for this type of cycle.

5.2.4.14 Special Cycles

A Special Cycle is defined when REQa[4:0] = 01000 and REQb[4:0] = xx001. In the first address phase Aa[35:3]# is undefined and can be driven to any value. In the second address phase, Ab[15:8]# defines the type of Special Cycle issued by the processor. All Host initiated Special Cycles are routed to hub interface.

Special Cycles are "posted" into the Intel 830 Chipset family GMCH-M. The host bus transaction is terminated immediately. It does not wait for the cycle to propagate or terminate on hub interface.

Table 34 specifies the cycle type and definition as well as the action taken by the GMCH-M when the corresponding cycles are identified. Note that none of the host bus special cycles are propagated to the AGP interface.

BE[7:0}#	Special Cycle Type	Action Taken
0000 0000	NOP	This transaction has no side effects.
0000 0001	Shutdown	This transaction is issued when an agent detects a severe software error that prevents further processing.
		This cycle is claimed by the GMCH-M and propagated as a Shutdown special cycle over the hub interface bus.
		This cycle is retired on the CPU bus after the associated hub interface special cycle request packet is successfully broadcast over hub interface.
0000 0010	Flush	This transaction is issued when an agent has invalidated its internal caches without writing back any modified lines.
		The GMCH-M claims this cycle and simply retires it.
0000 0011	Halt	This transaction is issued when an agent executes a HLT instruction and stops program execution.
		This cycle is claimed by the GMCH-M and propagated over hub interface as a Halt special cycle.
		This cycle is retired on the CPU bus after the associated hub interface special cycle request packet is successfully broadcast over hub interface.
0000 0100	Sync	This transaction is issued when an agent has written back all modified lines and has invalidated its internal caches.
		The GMCH-M claims this cycle and simply retires it.
0000 0101	Flush Acknowledge	This transaction is issued when an agent has completed a cache sync and flush operation in response to an earlier FLUSH# signal assertion.
		The GMCH-M claims this cycle and simply retires it.
0000 0110	Stop Clock Acknowledge	This transaction is issued when an agent enters Stop Clock mode.
		This cycle is claimed by the GMCH-M and propagated over hub interface as a Stop Grant special cycle.
		This cycle is retired on the CPU bus after the associated hub interface special cycle request packet is successfully broadcast over hub interface.
0000 0111	SMI Acknowledge	This transaction is first issued when an agent enters the System Management Mode (SMM). Ab[7]# is also set at this entry point.

Table 34. Intel 830 Chipset Family GMCH-M Responses to Host Initiated Special Cycles

		All subsequent transactions from the CPU with Ab[7]# set are treated by the GMCH-M as accesses to the SMM space. No corresponding cycle is propagated to the hub interface.
		To exit the System Management Mode the CPU issues another one of these cycles with the Ab[7]# bit deasserted. The SMM space access is closed by the GMCH-M at this point.
All others	Reserved	

5.2.5 In-Order Queue Pipelining

All agents on the CPU bus track the number of pipelined bus transaction with an in-order queue (IOQ). The GMCH-M can support an IOQ depth of 8 and uses BNR# to guarantee that limit is not exceeded.

5.2.6 Write Combining

To allow for high speed write capability for graphics, the USWC (uncacheable, speculative, writecombining) memory type provides a write-combining buffering mechanism for write operations. A high percentage of graphics transactions are writes to the memory-mapped graphics region, normally known as the linear frame buffer. Reads and writes to USWC are non-cached and can have no side effects.

In the case of graphics, current 32-bit drivers (without modifications) would use Partial Write protocol to update the frame buffer. The highest performance write transaction on the CPU bus is the Line Write. By combining several back-to-back Partial write transactions (internal to the CPU) into a Line write transaction on the CPU bus, the performance of frame buffer accesses would be greatly improved. To this end, the CPU supports the USWC memory. Writes to USWC memory can be buffered and combined in the processor's write-combining buffers (WCB). The WCB is flushed after executing a serializing, locked, I/O instruction, or the WCB is full (32 bytes). The WCB can be flushed under different situations*. In order to extend this capability to the current drivers, it is necessary to set up the linear frame buffer address range to be USWC memory type. This can be done by programming the MTRR registers in the CPU.

If the number of bytes in the WCB is < 32 then a series of <= 8 byte writes are performed upon WCB flushing. The GMCH-M further optimizes this by providing write combining for CPU-to-hub interface, CPU-to-AGP/PCI, and CPU-to-IGD Write transactions. If the target of CPU writes is hub interface memory, then the data is combined and sent to the hub interface bus as a single write burst. The same concept applies to CPU writes to AGP/PCI and IGD memory. The USWC writes that target system SDRAM are handled as regular system SDRAM writes.

Note that the application of USWC memory attribute is not limited only to the frame buffer support and that the GMCH-M implements write combining for any CPU-to-hub interface or CPU-to-AGP/PCI posted write.

*Please refer to the following documents on how to implement write combining buffers:

Intel[®] Write Combining Memory Implementation Guidelines (24422) <<u>http://developer.intel.com/design/PentiumII/applnots/244422.htm</u>

Intel[®] Architecture Software Developer's Manual Volume 3 System Programming Guide (245572) <<u>http://developer.intel.com/design/Pentium4/manuals/24547203.pdf>.</u>

5.3 Intel 830 Chipset Family System Memory Interface

5.3.1 SDRAM Interface Overview

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The Intel 830 Chipset GMCH-M integrates a main memory SDRAM controller with a 64-bit wide interface. The GMCH-M memory buffers support LVTTL (SDRAM) signaling at 133 MHz.

- Configured for Single Data Rate SDRAM, the GMCH memory interface includes support for:
- Up to 1.0 GB of 133-MHz SDRAM using 512-Mb technology
- PC133 SO-DIMMs
- Maximum of 2 SO-DIMMs, Single-sided and/or Double-sided
- The Intel 830MP/830M/830MG Chipset only support 4 bank memory technologies.
- Four Integrated Clock buffers

The 2-bank select lines SM_BA[1:0] and the 13 Address lines SM_MA[12:0] allow each member of the Intel 830 Chipset family to support 64 bit wide SO-DIMMs using 64-Mb, 128-Mb, 256-Mb, and 512-Mb SDRAM technology. While address lines SM_MA[9:0] determine the starting address for a burst, burst lengths are fixed at 4. Six chip selects SM_CS# lines allow maximum of three rows of single-sided SO-DIMMs and six rows of double-sided SDRAM SO-DIMMs.

The Intel 830 Chipset family GMCH-M main memory controller targets CAS latencies of 2 and 3 for SDRAM. Each member of the Chipset family provides refresh functionality with programmable rate (normal SDRAM rate is 1 refresh/15.6 ms). For write operations of less than a Qword in size, a bytewise write will be performed.

5.3.2 SDRAM Organization and Configuration

In the following discussion the term row refers to a set of memory devices that are simultaneously selected by a SM_CS# signal. The Intel 830 Chipset family will support a maximum of 4 rows of memory. For the purposes of this discussion, a "side" of a SO-DIMM is equivalent to a "row" of SDRAM devices.

The 2-bank select lines SM_BA[1:0] and the 13 Address lines SM_MA[12:0] allow the Intel 830 Chipset family to support 64-bit wide SO-DIMMs using x16 64-Mb, 128-Mb, 256-Mb, and 512-Mb SDRAM technologies.

	Technology Density	Device Depth	Device Width	Devices Per Side	Capacity Per Side	# of Row Addr Bits	# of Column Addr Bits	# of Bank Addr Bits	Page Size	Max Capacity SDR(2 SO- DIMMs)
6	64 Mb	4M	X16	4	32 MB	12	8	2	2 KB	128 MB
1:	28 Mb	8M	X16	4	64 MB	12	9	2	4 KB	256 MB
2	56 Mb	16M	X16	4	128 MB	13	9	2	4 KB	512 MB
5	12 Mb	32M	X16	4	256 MB	13	10	2	8 KB	1.0 GB

Table 35. System Memory SO-DIMM Configurations

5.3.2.1 Configuration Mechanism for SO-DIMMs

Detection of the type of SDRAM installed on the SO-DIMM is supported via Serial Presence Detect mechanism as defined in the JEDEC SO-DIMM specification. This uses the SCL, SDA and SA[2:0] pins on the SO-DIMMs to detect the type and size of the installed SO-DIMMs. No special programmable modes are provided on the Intel 830 Chipset family for detecting the size and type of memory installed. Type and size detection must be done via the serial presence detection pins.

5.3.2.1.1 Memory Detection and Initialization

Before any cycles to the memory interface can be supported, the Intel 830 Chipset family SDRAM registers must be initialized. The Intel 830 Chipset family must be configured for operation with the installed memory types. Detection of memory type and size is done via the System Management Bus (SMB) interface on the ICH3-M. This two-wire bus is used to extract the SDRAM type and size information from the serial presence detect port on the SDRAM SO-DIMMs. SDRAM SO-DIMMs contain a 5-pin serial presence detect interface, including SCL (serial clock), SDA (serial data) and SA[2:0]. Devices on the SMBus have a 7-bit address. For the SDRAM SO-DIMMs, the upper 4 bits are fixed at 1010. The lower three bits are strapped on the SA[2:0] pins. SCL and SDA are connected directly to the System Management Bus on the ICH3-M. Thus data is read from the Serial Presence Detect port on the SO-DIMMs via a series of IO cycles to the south bridge. BIOS essentially needs to determine the size and type of memory used for each of the rows of memory in order to properly configure the Intel 830 Chipset family memory interface.

5.3.2.1.2 SDRAM Register Programming

This section provides an overview of how the required information for programming the SDRAM registers is obtained from the Serial Presence Detect ports on the SO-DIMMs. The Serial Presence Detect ports are used to determine Refresh Rate, MA and MD Buffer Strength, Row Type (on a row by row basis), SDRAM Timings, Row Sizes, and Row Page Sizes. The following table lists a subset of the data available through the on board Serial Presence Detect ROM on each SO-DIMM.

Byte	Function				
2	Memory Type (EDO, SDR SDRAM)				
3	# of Row Addresses, not counting Bank Addresses				
4	# of Column Addresses				
5	# of banks of SDRAM (Single or Double sided SO-DIMM)				
11	ECC, no ECC				
12	Refresh Rate				
17	# Banks on each Device				
36-41	Access Time from Clock for CAS# Latency 1 through 7				
42	Data Width of SDRAM Components				
126	Memory Frequency				

Table 36. Data Bytes on SO-DIMM Used for Programming SDRAM Registers

Table 36 is only a subset of the defined SPD bytes on the SO-DIMMs. These bytes collectively provide enough data for programming the Intel 830 Chipset family SDRAM registers.

5.3.3 SDRAM Address Translation and Decoding

The Intel 830 Chipset family contains address decoders that translate the address received on the host bus, or the hub interface to an effective memory address. Decoding and Translation of these addresses vary with the three SDRAM types. Also, the number of pages, page sizes, and densities supported vary with the 4 SDRAM types. In general, the Intel 830 Chipset family supports 64-Mb, 128-Mb, 256-Mb, and 512-Mb SDRAM devices. The multiplexed row/column address to the SDRAM memory array is provided by the SM_BA[1:0] and SM_MA[12:0] signals. These addresses are derived from the host address bus as defined by the table above for SDRAM devices.

Table 37. Address	Franslation and	l Decoding
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Tech	Donth	Width	Addr	ess l	Jsage	Row	Page	BS	BS	MA	MA	MA	MA	MA	ма	ма	MA	MA	MA	MA	MA	MA
recii	Deptil	width	Row	Col	Bank	Size		1	0	12	11	10	9	8	7	6	5	4	3	2	1	0
64 Mb	4M	16	12	8	2	32 MB	2K	12 12	11 11	x x	15 X	14 PA	13 X	24 X	23 10	22 9	21 8	20 7	19 6	18 5	17 4	16 3
128 Mb	8M	16	12	9	2	64 MB	4K	13 13	12 12	x x	15 X	14 PA	25 X	24 11	23 10	22 9	21 8	20 7	19 6	18 5	17 4	16 3
256 Mb	16M	16	13	9	2	128 MB	4K	13 13	12 12	15 X	14 X	26 PA	25 X	24 11	23 10	22 9	21 8	20 7	19 6	18 5	17 4	16 3
512 Mb	16M	16	13	10	2	256 MB	8K	14 14	13 13	15 X	27 X	26 PA	25 12	24 11	23 10	22 9	21 8	20 7	19 6	18 5	17 4	16 3

5.3.4 SDRAM Performance Description

The overall SDRAM performance is controlled by the SDRAM timing register, pipelining depth used in the Intel 830 Chipset family, SDRAM speed grade, and the type of SDRAM used in the system. Besides this, the exact performance in a system is also dependent on the total memory supported, external buffering and memory array layout. The most important contribution to overall performance by the System Memory controller is to minimize the latency required to initiate and complete requests to memory, and to support the highest possible bandwidth (full streaming, quick turn-arounds). One measure of performance is the total flight time to complete a cache line request. A true discussion of performance really involves the entire chipset, not just the System Memory controller.

5.4 Intel 830M and 830MG Chipset Internal Graphics Description

The Intel 830M and 830MG Chipset GMCH-M provides a highly integrated graphics accelerator and PCIset while allowing a flexible Integrated System Graphics solution.



Figure 15. Intel 830M and 830MG Chipset GMCH-M Graphics Block Diagram

High bandwidth access to data is provided through the system memory port. The Intel 830M and 830MG Chipset GMCH-M can access UMA memory located in system memory at 1.06 GB/s. The Intel 830M and 830MG Chipset uses a tiling architecture to minimize page miss latencies and thus maximize effective rendering bandwidth.

5.4.1 3D/2D Instruction Processing

The Intel 830M and 830MG GMCH-M contain an extensive set of instructions that control various functions including 3D rendering, BLT operations, display, MPEG decode acceleration, and overlay. The 3D instructions set 3D pipeline states and control the processing functions. The 2D instructions provide an efficient method for invoking BLT operations.

5.4.2 3D Engine

The 3D engine of the Intel 830M and 830MG Chipset GMCH-M has been designed with a deep pipelined architecture, where performance is maximized by allowing each stage of the pipeline to simultaneously operate on different primitives or portions of the same primitive. GMCH-M supports Perspective-correct Texture Mapping, Multitextures, Bump-Mapping, Cubic Environment Maps, Bilinear, Trilinear & Anisotropic MIP mapped filtering, Gouraud shading, Alpha-blending, Vertex and Per Pixel Fog, and Z/W Buffering. These features are independently enabled (disabled) via a set of 3D instructions.

The 3D pipeline subsystem performs the 3D rendering acceleration. The main blocks of the pipeline are the Setup Engine, Scan Converter, Texture Pipeline, and Raster Pipeline. A typical programming

sequence would be to send instructions to set the state of the pipeline followed by rendering instructions containing 3D primitive vertex data.

5.4.2.1 Setup Engine

The Intel 830M and 830MG Chipset GMCH-M 3D setup engine takes the input data associated with each vertex of a 3D primitive and computes the various parameters required for scan conversion. In formatting this data, GMCH-M maintains sub-pixel accuracy. The per-vertex data is converted into gradients that can be used to interpolate the data at any pixel within a polygon (colors, alpha, Z depth, fog, and texture coordinates). The pixels covered by a polygon are identified and per-pixel texture addresses are calculated.

5.4.2.2 Viewport Transform and Perspective Divide

The 3D-geometry pipeline involves transformation of vertices from model space to clipping space followed by clip test and clipping. Lighting can be performed during the transformation or at any other point in the pipeline. After clipping, the next stage involves perspective divide followed by transformation to the viewport or screen space. The Intel 830M and 830MG Chipset GMCH-M can support Viewport Transform and Perspective Divide portion of the 3D Geometry Pipeline in hardware.

5.4.2.3 3D Primitives and Data Formats Support

The 3D primitives rendered by the Intel 830M and 830MG Chipset GMCH-M are points, lines, discrete triangles, line strips, triangle strips, triangle fans, and polygons. In addition to this, GMCH-M supports DirectX6's Flexible Vertex Format (FVF), which enables the application to specify a variable length of parameter list obviating the need for sending unused information to the hardware. Strips, Fans, and Indexed Vertices as well as FVF improves delivered vertex rate to the setup engine significantly.

5.4.2.4 Pixel Accurate Fast Scissoring and Clipping Operation

The Intel 830M and 830MG Chipset GMCH-M supports clipping to a scissoring rectangle within the drawing window. GMCH-M 's clipping and scissoring in hardware reduce the need for software to process polygons, and thus improves performance. During the setup stage, GMCH-M clips polygons to the drawing window. The scissor rectangle accelerates the clipping process by allowing the driver to clip to a bigger region than the hardware renders to. The scissor rectangle needs to be pixel accurate, and independent of line and point width. GMCH-M supports a single scissor box rectangle.

5.4.2.5 Backface Culling

As part of the setup, the Intel 830M and 830MG Chipset GMCH-M discards polygons from further processing, if they are facing away from or towards the user's viewpoint. This operation, referred to as "Back Face Culling" is accomplished based on the "clockwise" or "counter-clockwise" orientation of the vertices on a primitive. This can be enabled or disabled by the driver.

5.4.2.6 Scan Converter

The Scan Converter takes the vertex and edge information is used to identify all pixels that are affected by features being rendered. It works on a per-polygon basis, and one polygon may be entering the pipeline while calculations finish on another.

5.4.2.7 Texture Engine

As texture sizes increase beyond the bounds of graphics memory, executing textures from graphics memory becomes impractical. The Intel 830M and MG Chipset GMCH-M, using Intel's Direct Memory Execution model, simplifies this process by rendering each scene using the texture located in system memory. The 830M and 830MG Chipsets include a cache controller to avoid frequent memory fetches of recently used texture data.

The 830M and 830MG Chipsets allow an image, pattern, or video to be placed on the surface of a 3D polygon. The texture engine performs texture color or chromakey matching, texture filtering (anisotropic, trilinear, and bilinear interpolation), and YUV to RGB conversions.

5.4.2.8 Perspective Correct Texture Support

Textured polygon is generated by mapping a 2D texture pattern onto each pixel of the polygon. A texture map is like wallpaper pasted onto the polygon. Since polygons are rendered in perspective, it is important that texture be mapped in perspective as well. Without perspective correction, texture is distorted when an object recedes into the distance. Perspective correction involves a compute-intensive "per-pixel-divide" operation on each pixel. Perspective correction is necessary for realistic 3D graphics.

5.4.2.8.1 Texture Decompression

DirectX7.0 supports Texture Compression to reduce the bandwidth required to deliver textures. As the textures' average sizes (512x512) get larger with higher color depth and multiple textures become the norm, it becomes increasingly important to provide a mechanism compress textures. The Intel 830M and 830MG Chipset GMCH-M supports DX7 decompression. Texture decompression formats supported include DXT1, DXT2, DXT3, DXT4, DXT5.

5.4.2.9 Texture ColorKey and ChromaKey

ColorKey and ChromaKey describe two methods of removing a specific color or range of colors from a texture map before it is applied to an object. For "nearest" texture filter modes, removing a color simply makes those portions of the object transparent (the previous contents of the back buffer show through). For "linear" texture filtering modes, the texture filter is modified if only the non-nearest neighbor texels match the key (range).

ColorKeying occurs with paletted textures and removes colors according to an index (before the palette is accessed). When a color palette is used with indices to indicate a color in the palette, the indices can be compared against a state variable "ColorKey Index Value" and if a match occurs and ColorKey is enabled, then this value's contribution is removed from the resulting pixel color. The Intel 830M and 830MG Chipset GMCH-M defines index matching as ColorKey.

ChromaKeying can be performed for both paletted and non-paletted textures, and removes texels that fall within a specified color range. The ChromaKey mode refers to testing the ARGB or YUV components to see if they fall between high and low state variable values. If the color of a texel contribution is in this range and chromakey is enabled, then this contribution is removed from the resulting pixel color.

5.4.2.10 Anti-aliasing

Aliasing is one of the artifacts that degrade image quality. In its simplest manifestation, aliasing causes the jagged staircase effects on sloped lines and polygon edges. Another artifact is the moiré patterns, which occur as a result of the fact that there is very small number of pixels available on screen to contain the data of a high-resolution texture map.

Full Scene Anti-Aliasing uses supersampling, which means that the image is rendered internally at a higher resolution than it is displayed on screen. The Intel 830M and 830MG GMCH-M can render internally at 1600x1200 and then this image is downsampled (via a Bilinear filter) to the screen resolution of 640x480 and 800x600. Full Scene Anti-aliasing removes jaggies at the edges as well as moiré patterns. The GMCH-M renders the supersampled image up to 2Kx2K pixel dimensions. The GMCH-M then reads it as a texture and bilinear filters it to the final resolution.

5.4.2.11 Texture Map Filtering

Many texture-mapping modes are supported. Perspective correct mapping is always performed. As the map is fitted across the polygon, the map can be tiled, mirrored in either the U or V directions, or mapped up to the end of the texture and no longer placed on the object (this is known as clamp mode). The way a texture is combined with other object attributes is also definable.

- 830M/830MG GMCH-M supports up to 12 Levels-of-Detail (LODs) ranging in size from 2048x2048 to 1x1 texels. (A texel is defined as a texture map element). Included in the texture processor is a texture cache, which provides efficient MIP-mapping.
- 830M/830MG GMCH-M supports 7 types of texture filtering:
- Nearest (also known as Point Filtering): Texel with coordinates nearest to the desired pixel is used. (This is used if only one LOD is present).
- Linear (also known as Bilinear Filtering): A weighted average of a 2x2 area of texels surrounding the desired pixel are used. (This is used if only one LOD is present).
- Nearest MIP Nearest (also known as Point Filtering): This is used if many LODs are present. The nearest LOD is chosen and the texel with coordinates nearest to the desired pixel are used.
- Linear MIP Nearest (Bilinear MIP Mapping): This is used if many LODs are present. The nearest LOD is chosen and a weighted average of a 2x2 area of texels surrounding the desired pixel are used (four texels). This is also referred to as Bilinear MIP Mapping.
- Nearest MIP Linear (Point MIP Mapping): This is used if many LODs are present. Two appropriate LODs are selected and within each LOD the texel with coordinates nearest to the desired pixel are selected. The Final texture value is generated by linear interpolation between the two texels selected from each of the MIP Maps.
- Linear MIP Linear (Trilinear MIP Mapping): This is used if many LODs are present. Two appropriate LODs are selected and a weighted average of a 2x2 area of texels surrounding the desired pixel in each MIP Map is generated (four texels per MIP Map). The Final texture value is generated by linear interpolation between the two texels generated for each of the MIP Maps. Trilinear MIP Mapping is used minimize the visibility of LOD transitions across the polygon.
- Anisotropic MIP Nearest (Anisotropic Filtering): This is used if many LODs are present. The nearest LOD-1 level will be determined for each of four sub-samples for the desired pixel. These four sub-samples are then bilinear filtered and averaged together.
- Both D3D (DirectX 6.0) and OGL (Rev.1.1) allows support for all these filtering modes.

5.4.2.12 Multiple Texture Composition

830M/830MG GMCH-M also performs multiple texture composition. This allows the combination of two or greater MIP maps to produce a new one with new LODs and texture attributes in a single or iterated pass. The setup engine supports up to four texture map coordinates in as single pass. GMCH-M allows up to two Bilinear MIP Maps or a single Trilinear MIP Map to be composited in a single pass. Greater than two Bilinear MIP Maps or more than one Trilinear MIP Map would require multiple passes.

The actual blending or composition of the MIP Maps is done in the raster engine. The texture engine provides the required texels including blending information.

Flexible vertex format support allows multi-texturing because it makes it possible to pass more than one texture in the vertex structure.

5.4.2.13 Cubic Environment Mapping

Environment maps allow applications to render scenes with complex lighting and reflections while significantly decreasing CPU load. There are several methods to generate environment maps such as spherical, circular, and cubic. 830M/830MG GMCH-M has selected to support cubic reflection mapping over spherical and circular since it is the best choice to provide real-time environment mapping for complex lighting and reflections.

Cubic Mapping requires a texture map for each of the 6 cube faces. These can be generated by pointing a camera with a 90-degree field-of-view in the appropriate direction. Per-vertex vectors (normal, reflection or refraction) are interpolated across the polygon and the intersection of these vectors with the cube texture faces is calculated. Texel values are then read from the intersection point on the appropriate face and filtered accordingly.

5.4.2.14 Bump Mapping

Bump mapping is a feature in the 830M/830MG GMCH-M that enables a surface to appear wrinkled or dimpled without the need to model these depressions geometrically. By perturbing environment map texture coordinates on a per pixel basis using delta values read from the bump map, non-uniform lighting effects (reflections, etc.) can be applied. This can give flat objects a bumpy or raised appearance. Embossing, a simpler form of bump mapping, is achieved by layering two identical texture maps. It can be supported through software to give the appearance of depth.

5.4.3 Raster Engine

The Raster Engine is where the color data such as fogging, specular RGB, texture map blending, etc. is processed. The final color of the pixel is calculated and the RGBA value combined with the corresponding components resulting from the Texture Engine. These textured pixels are modified by the specular and fog parameters. These specular highlighted, fogged, textured pixels are color blended with the existing values in the frame buffer. In parallel, stencil, alpha and depth buffer tests are conducted which will determine whether the Frame and Depth Buffers will be updated with the new pixel values.

5.4.3.1 Texture Map Blending

Multiple Textures can be blended together in an iterative process and applied to a primitive. 830M/830MG GMCH-M allows up to four distinct or shared texture coordinates and texture maps to be specified onto the same polygon. Also, GMCH-M supports using a texture coordinate set to access multiple texture maps. State variables in multiple texture are bound to texture coordinates, texture map or texture blending.

5.4.3.2 Combining Intrinsic and Specular Color Components

The Intel 830M and 830MG GMCH-M allows an independently specified and interpolated "specular RGB" attribute to be added to the post-texture blended pixel color. This feature provides a full RGB specular highlight to be applied to a textured surface, permitting a high quality reflective colored lighting effect not available in devices, which apply texture after the lighting components have been combined. If specular-add state variable is disabled, only the resultant colors from the map blending are used. If this

state variable is enabled, RGB values from the output of the map blending are added to values for RS, GS, BS on a component by component basis.

5.4.3.3 Color Shading Modes

The Raster Engine will support the flat and Gouraud shading modes. These shading modes are programmed by the appropriate state variables issued through the command stream.

Flat shading is performed by smoothly interpolating the vertex intrinsic color components (Red, Green, Blue), Specular (R,G,B), Fog, and Alpha to the pixel, where each vertex color has the same value. The setup engine substitutes one of the vertex's attribute values for the other two vertices attribute values thereby creating the correct flat shading terms. This condition is set up by the appropriate state variables issued prior to rendering the primitive.

Gouraud shading is performed by smoothly interpolating the vertex intrinsic color components (Red, Green, Blue). Specular (RGB), Fog, and Alpha to the pixel, where each vertex color has a different value.

All the attributes can be selected independently to one of the shading mode by setting the appropriate value state variables.

5.4.3.4 Color Dithering

Color Dithering in the GMCH-M helps to hide color quantization errors. Color Dithering takes advantage of the human eye's propensity to "average" the colors in a small area. Input color, alpha, and fog components are converted from 8-bit components to 5-bit or 6- bit component by dithering. Dithering is performed on blended textured pixels. In 32-bit mode, dithering is not performed on the components

5.4.3.5 Vertex and Per Pixel Fogging

Fogging is used to create atmospheric effects such as low visibility conditions in flight simulator-type games. It adds another level of realism to computer-generated scenes. Fog can be used for depth cueing or hiding distant objects. With fog, distant objects can be rendered with fewer details (less polygons), thereby improving the rendering speed or frame rate. Fog is simulated by attenuating the color of an object with the fog color as a function of distance, and the greater the distance, the higher the density (lower visibility for distant objects). There are two ways to implement the fogging technique: per-vertex (linear) fogging and per-pixel (non-linear) fogging. The per-vertex method interpolates the fog value at the vertices of a polygon to determine the fog factor at each pixel within the polygon. This method provides realistic fogging as long as the polygons are small. With large polygons (such as a ground plane depicting an airport runway), the per-vertex technique results in unnatural fogging

GMCH-M supports both types of fog operations, vertex and per pixel or table fog. If fog is disabled, the incoming color intensities are passed unchanged to the destination blend unit.

If fog is enabled, the incoming pixel color is blended with the fog color based on a fog coefficient on a per pixel basis using the following equation before sending to the destination blend unit.

5.4.3.6 Alpha Blending (Frame Buffer)

Alpha Blending in the Intel 830M and 830MG GMCH-M adds the material property of transparency or opacity to an object. Alpha blending combines a source pixel color (RsGsBs) and alpha (As) component with a destination pixel color (RdGdBd) and alpha(Ad) component. For example, this is so that a glass

surface on top (source) of a red surface (destination) would allow much of the red base color to show through.

Blending allows the source and destination color values to be multiplied by programmable factors and then combined via a programmable blend function. The combined and independent selection of factors and blend functions for color and alpha is supported.

5.4.3.7 Color Buffer Formats: (Destination Alpha)

The Raster Engine will support 8-bit, 16-bit, and 32-bit Color Buffer Formats. The 8-bit format is used to support planar YUV420 format, which used only in Motion Compensation and Arithmetic Stretch format. The bit format of Color and Z will be allowed to mix.

The Intel 830M and 830MG GMCH-M will support an 8-bit destination alpha in 32-bit mode. Destination alpha will be supported in 16-bit mode in 1555 or 4444 format.

GMCH-M does not support general 3D rendering to 8-bit surfaces. 8-bit destinations are supported for operations on planar YUV surfaces (e.g., stretch Blts) where each 8-bit color component is written in a separate pass. GMCH-M also supports a mode where both U and V planar surfaces can be operated on simultaneously.

The frame buffer of GMCH-M contains at least two hardware buffers-the Front Buffer (display buffer) and the Back Buffer (rendering buffer). While the back buffer may actually coincide with (or be part of) the visible display surface, a separate (screen or window-sized) back buffer is typically used to permit double-buffered drawing. That is, the image being drawn is not visible until the scene is complete and the back buffer made visible or copied to the front buffer via a 2D BLT operation. Rendering to one buffer and displaying from the other buffer removes image tearing artifacts. Additionally, more than two back buffers (e.g., triple-buffering) can be supported.

5.4.3.8 Depth Buffer

The Raster Engine will be able to read and write from this buffer and use the data in per fragment operations that determine resultant color and depth value of the pixel for the fragment are to be updated or not.

Typical applications for entertainment or visual simulations with exterior scenes require far/near ratios of 1000 to 10000. At 1000, 98 percent of the range is spent on the first 2 percent of the depth. This can cause hidden surface artifacts in distant objects, especially when using 16-bit depth buffers. A 24-bit Z-buffer provides 16 million Z-values as opposed to only 64K with a 16-bit Z-buffer. With lower Z-resolution, two distant overlapping objects may be assigned the same Z-value. As a result, the rendering hardware may have a problem resolving the order of the objects, and the object in the back may appear through the object in the front.

By contrast, when w (or eye-relative z) is used, the buffer bits can be more evenly allocated between the near and far clip planes in world space. The key benefit is that the ratio of far and near is no longer an issue, allowing applications to support a maximum range of miles, yet still get reasonably accurate depth buffering within inches of the eye point. The selection of depth buffer size is relatively independent of the color buffer. A 16 bit Z/W or 24 bit Z/W buffer can be selected with a 16-bit color buffer. Z buffer is not supported in 8-bit mode.

5.4.3.9 Stencil Buffer

The Raster Engine will provide 8-bit stencil buffer storage in 32-bit mode and the ability to perform stencil testing. Stencil testing controls 3D drawing on a per pixel basis, which conditionally eliminates a

pixel on the outcome of a comparison between a stencil reference value and the value in the stencil buffer at the location of the source pixel being processed. They are typically used in multipass algorithms to achieve special effects, such as decals, outlining, shadows and constructive solid geometry rendering.

One of three possible stencil operations is performed when stencil testing is enabled. The stencil operation specifies how the stencil buffer is modified when a fragment passes or fails the stencil test. The selection of the stencil operation to be performed is based upon the result of the stencil test and the depth test. A stencil write mask is also included that controls the writing of particular bits into the stencil buffer. It selects between the destination value and the updated value on a per-bit basis. The mask is 8-bit wide.

5.4.3.10 Projective Textures

830M/830MG GMCH-M will support two simultaneous projective textures at full rate processing. These textures require 3 floating-point texture coordinates to be included in the FVF format. Projective textures enable special effects such as projecting spot light textures obliquely onto walls, etc.

5.4.4 2D Engine

The 830M and 830MG Chipset GMCH-M provide an extensive set of 2D instructions and 2D HW acceleration for block transfers of data (BLTs). The BLT engine provides the ability to copy a source block of data to a destination and perform operations (e.g., ROP1, ROP2, and ROP3) on the data using a pattern, and/or another destination. The Stretch BLT engine is used to move source data to a destination that need not be the same size, with source transparency. Performing these common tasks in hardware reduces CPU load, and thus improves performance.

5.4.4.1 GMCH-M VGA Registers and Enhancements

The 2D registers are a combination of registers defined by IBM* when the Video Graphics Array (VGA) was first introduced and others that Intel has added to support graphics modes that have color depths, resolutions, and hardware acceleration features that go beyond the original VGA standard.

5.4.4.2 256-Bit Pattern Fill and BLT Engine

Use of this BLT engine accelerates the Graphical User Interface (GUI) of Microsoft* Windows*. The GMCH-M BLT Engine provides hardware acceleration of block transfers of pixel data for many common Windows operations. The term BLT refers to a block transfer of pixel data between memory locations. The BLT engine can be used for the following:

- Move rectangular blocks of data between memory locations
- Data Alignment
- Perform logical operations (raster ops)

The rectangular block of data does not change as it is transferred between memory locations. Data to be transferred can consist of regions of memory, patterns, or solid color fills. A pattern will always be 8x8 pixels wide and may be 8, 16, or 32 bits per pixel.

The 830M/830MG GMCH-M BLT engine has the ability to expand monochrome data into a color depth of 8, 16, or 32 bits. BLTs can be either opaque or transparent. Opaque transfers, move the data specified to the destination. Transparent transfers compare destination color to source color and write according to the mode of transparency selected.

Data is horizontally and vertically aligned at the destination. If the destination for the BLT overlaps with the source memory location, GMCH-M can specify which area in memory to begin the BLT transfer. Hardware is included for all 256 raster operations (Source, Pattern, and Destination) defined by Microsoft, including transparent BLT.

GMCH-M has instructions to invoke BLT operations, permitting software to set up instruction buffers and use batch processing as described in the Instruction Processing Section. GMCH-M can perform hardware clipping during BLTs.

5.4.4.3 Alpha Stretch BLT

The stretch BLT function can stretch source data in the X and Y directions to a destination larger or smaller than the source. Stretch BLT functionality expands a region of memory into a larger or smaller region using replication and interpolation. The stretch BLT function also provides format conversion and data alignment.

5.4.5 Planes and Engines

Intel 830M and 830MG GMCH display can be functionality delineated into: Planes and Engines (Pipes and Ports). A plane consists of rectangular shaped image that has characteristics such as source, size, position, method, and format. These planes get attached to source surfaces, which are rectangular memory surfaces with a similar set of characteristics. They are also associated with a particular destination pipe.

A pipe consists of a set of planes that will be combined and a timing generator. A port is the destination for the result of the pipe. Therefore, planes are associated with pipes and pipes are associated with ports.

5.4.5.1 Dual Display Functionality

The display consists of two display pipes. Pipes have a set of planes that are assigned to them as sources. The analog display port is restricted to Pipe A, while any of the DVOs may use either Pipe A or Pipe B. This limits the resolutions available on a digital display when an analog CRT is active. Please refer to the *Intel*[®] 830M PC10 Product Requirements (Please contact local Intel representative).

Display Pipe A	Display Pipe B			
CRT	LCD			
CRT	DVI			
CRT	TV			
CRT	LCD (DVOB+DVOC)			
CRT	DVI (DVOB+DVOC)			
LCD	TV			
LCD	DVI (DVOB+DVOC)			
LCD (DVOB+DVOC)	DVI			
LCD (DVOB+DVOC)	TV			
DVI	τv			

Table 38. Dual Display Usage Model

5.4.6 Hardware Cursor Plane

The Intel 830M and 830MG Chipsets support two hardware cursors. The cursor plane is one of the simplest display planes. With a few exceptions, has a fixed size of 64x64 and a fixed Z-order (top). In legacy modes, cursor can cause the display data below it to be inverted. In the alpha blend mode, true color cursor data can be alpha blended into the display stream. It can be assigned to either display pipe A or display pipe B and dynamically flipped from one to the other when both are running.

5.4.6.1 Cursor Color Formats

Color data can be in an indexed format or a true color format. Indexed data uses the entries in the fourentry cursor palette to convert the two-bit index to a true color format before being passed to the blenders. The index can optionally specify that a cursor pixel be transparent or cause an inversion of the pixel value below it or one of two colors from the cursor palette. Blending of YUV or RGB data is only supported with planes that have data of the same format.

5.4.6.2 Cursor Hot Spot

There is the additional function of defining a cursor hot spot. This hot spot is the pixel that is positioned over the user selection. This is accomplished by allowing negative XY offset values and ones that exceed the size of the underlying active region and trimming the excess display data.

5.4.6.3 Popup Plane

The popup plane is used for control functions in mobile applications. This is not used for typical desktop applications. Only the hardware cursor has a higher Z-order precedence over the hardware icon. In standard modes (non-VGA) either cursor A or cursor B can be used as a Popup Icon. For VGA modes, 32-bpp data format is not supported.

5.4.6.4 **Popup Color Formats**

Source color data for the popup is in an indexed format. Indexed data uses the entries in the four-entry cursor palette to convert the two-bit index to a true color format before being passed to the blenders. Blending of color data is only supported with data of the same format.

5.4.7 Overlay Plane

The overlay engine provides a method of merging either video capture data (from an external Video Capture device) or data delivered by the CPU, with the graphics data on the screen.

5.4.7.1 Multiple Overlays

A single overlay plane and scalar is implemented. This overlay plane can be connected to the primary display, secondary display or in bypass mode. In the default mode, it appears on the primary display. The overlay may be displayed in a multi-monitor scenario for single-pipe simultaneous displays only.

Picture-in-Picture Feature is supported via software through the arithmetic stretch blitter.

5.4.7.2 Source/Destination Color-/Chroma-Keying

Overlay source/destination chroma-keying enables blending of the overlay with the underlying graphics background. Destination color-/chroma-keying can be used to handle occluded portions of the overlay window on a pixel-by-pixel basis that is actually an underlay. Destination color keying supports a specific color (8 or 15 bit) mode as well as 32 bit alpha blending.

Source color-/chroma-keying is used to handle transparency based on the overlay window on a pixel-bypixel basis. This is used when "blue screening" an image to overlay the image on a new background later.

5.4.7.3 Gamma Correction

To compensate for overlay color intensity loss, the overlay engine supports independent gamma correction. This allows the overlay data to be converted to linear data or corrected for the display device when not blending.

5.4.7.4 YUV to RGB Conversion

The format conversion can be bypassed in the case of RGB source data.

5.4.7.5 Color Control

Color control provides a method of changing the color characteristics of the pixel data. It is applied to the data while in YUV format and uses input parameters such as brightness, saturation, hue (tint) and contrast. This feature is supplied for the overlay only and works in YUV formats only.

5.4.7.6 X/Y Mirroring

Both X or Y mirroring in the overlay is supported for video conferencing applications.

5.4.7.7 Dynamic Bob and Weave

Interlaced data that originates from a video camera creates two fields that are temporally offset by 1/60 of a second. There are several schemes to de-interlace the video stream: line replication, vertical filtering, field merging and vertical temporal filtering. Field merging takes lines from the previous field and inserts them into the current field to construct the frame – this is known as Weaving. This is the best solution for images with little motion; however, showing a frame that consists of the two fields will have serration or feathering of moving edges when there is motion in the scene. Vertical filtering or "Bob" interpolates adjacent lines rather replicating the nearest neighbor. This is the best solution for images with motion however, it will have reduced spatial resolution in areas that have no motion and introduces jaggies. In absence of any other de-interlacing, these form the baseline and are supported by Intel 830 M and MG Chipset GMCH-M.

5.4.8 Video Functionality

5.4.8.1 MPEG-2 Decoding

GMCH-M MPEG2 Decoding supports Hardware Motion Compensation (MC).

GMCH-M can accelerate video decoding for the following video coding standards:

- MPEG-2: Full feature support
- MPEG-1: Full feature support
- H.261: Full feature support
- H.263: Full feature support
- H.263+: Most of features with some exceptions of H.263+ optional features
- MPEG-4: Only supports some features in the simple profile.

The Intel 830M and 830MG Chipset HWMC interface is optimized for Microsoft's VA API. Hardware Video Acceleration API (HVA) is a generic DirectDraw and DirectShow interface supported in Windows 2000 and Windows 98 Millennium to provide video decoding acceleration. Direct VA is the open standard implementation of HVA, which is natively supported by the Intel 830M and 830MG Chipset's hardware.

5.4.8.2 Hardware Motion Compensation

The Motion Compensation (MC) process consists of reconstructing a new picture by predicting (either forward, backward, or bi-directional) the resulting pixel colors from one or more reference pictures. The Intel 830M and 830MG GMCH-M receives the video stream and implements Motion Compensation and subsequent steps in hardware. Performing Motion Compensation in hardware reduces the processor demand of software-based MPEG-2 decoding, and thus improves system performance.

5.5 Intel 830M and 830MG Chipset Internal Graphics Display Interface

830M/830MG GMCH-M has two dedicated display ports, the analog port and digital display port A (DVOA). Digital display port B (DVOB) and port C (DVOC) are multiplexed with the AGP interface and are compromised if an external AGP graphics device is in use. Examples of this are TV encoders, external DACs, LVDS transmitters, and TMDS transmitters. Each display port has control signals that

may be used to control, configure and/or determine the capabilities of an external device. The data that is sent out the display port is selected from one of the two possible sources; display pipe A or display pipe B. DVOB & DVOC can also operate in a "gang" mode, where the data bus is connected to both display ports, allowing a single device to take data at twice the pixel rate.

GMCH-M's digital display ports are capable of driving a 165-MHz pixel clock. When in dual channel mode (DVOB + DVOC), GMCH-M can be configured in gang mode to drive larger digital displays.

The Intel 830M and 830MG Chipset has three digital interfaces through display port (DVOA, DVOB, and DVOC). Each interface is capable of driving a 165-MHz pixel clocks up to 165 MHz. The DVO interface can support a variety of TV encoders, external DACs, LVDS transmitters, and TMDS transmitters. Each display port has control signals that may be used to control, configure and/or determine the capabilities of an external device. The data that is sent out the display port is selected from one of the two possible sources; display pipe A or display pipe B. DVOB & DVOC can also operate in a "gang" mode, where the data bus is connected to both display ports, allowing a single device to take data at twice the pixel rate. When in dual channel mode (DVOB + DVOC), GMCH-M can be configured in gang mode to drive larger digital displays.

In addition, the Intel 830M Chipset can also support a discrete AGP graphics device by multiplexing an AGP interface with the DVOB and DVOC interfaces.

5.5.1 Analog Display Port Characteristics

The analog display port provides a RGB signal output along with a HSYNC and VSYNC signal. There is an associated DDC signal pair that is implemented using GPIO pins dedicated to the analog port. The intended target device is for a CRT based monitor with a VGA connector.

5.5.1.1 Integrated RAMDAC

The display function contains a RAM-based Digital-to-Analog Converter (RAMDAC) that transforms the digital data from the graphics and video subsystems to analog data for the CRT monitor. Three 8-bit DACs provide the R, G, and B signals to the monitor.

5.5.1.2 DDC (Display Data Channel)

DDC is defined by VESA. Its purpose is to allow communication between the host system and display. Both configuration and control information can be exchanged allowing plug-and-play systems to be realized. Support for DDC 1 and 2 is implemented.

5.5.2 DVO Display Interface

The Intel 830M and MG GMCH-M has several options for driving digital displays. The Intel 830M and 830MG Chipset GMCH-M contains a dedicated digital display channel that can support DVO devices. The Intel 830M Chipset also has two digital display channels that are multiplexed on the AGP interface. When an external AGP graphics accelerator is not present, the Intel 830M Chipset can use the multiplexed DVOs to provide extra DVO display options.

5.5.2.1 Dedicated Digital Display Channel - DVOA

The Intel 830M and 830MG GMCH-M has a dedicated port for digital display support. It will consist of a 12-bit digital data bus with accompanying clocks and control signals. Please refer to Section 3.6.1 for a detailed description of these signals. This port utilizes a 1.5-V interface for high speed signaling,

supporting a pixel clock up to 165 MHz. The port is designed to connect to a transmission device capable of TMDS or TV-Out type signaling. For more details on the functionality of this interface, please refer to the latest DVO specification.

5.5.2.2 Multiplexed Digital Display Channels – DVOB and DVOC

The Intel 830M GMCH-M also has the capability to support additional digital display devices through two digital visual ports muxed with the AGP signals. When an external graphics accelerator is utilized via AGP, these digital display capabilities are compromised. The two multiplexed DVOs are very similar to the dedicated DVO.

The muxed DVOs each support a pixel clock up to 165 MHz and can support a variety of transmission devices. When using a 24-bit external transmitter, it will be possible to pair the two DVOs to support a single digital display with higher resolutions and refresh rates.

5.5.2.2.1 Optional High Speed (Dual Channel) Interface

The multiplexed digital display ports can operate in either two 12-bit port mode or a single 24-bit mode. The 24-bit mode uses the 12-bit DVOB data pins combined with the DVOC data pins to make a 24-bit bus. This doubles the transfer rate capabilities of the port. In the single port case, horizontal periods have a granularity of a single pixel clock; in the double case horizontal periods have a granularity of two pixel clocks. In both cases, data is transferred on both edges of the differential clock.

5.5.2.3 DDC (Display Data Channel)

The dedicated digital display interface (DVOA) uses the DDC2_CLK/DDC2_DATA or I2C_CLK /I2C_DATA to interrogate the panel. GMCH-M supports the DDC2B protocol to initiate the transfer of EDID information. The dedicated digital display interface uses the I2C bus to interrogate the external transmitter.

The multiplexed digital display interface (DVOB & DVOC) uses the M_I2C_CLK/M_I2C_DATA or M_DDC1_CLK/M_DDC1_DATA to interrogate the panel. GMCH-M supports the DDC2B protocol to initiate the transfer of EDID data. The multiplexed digital display interface uses the M_I2C bus to interrogate the external transmitter.

5.5.2.4 Third Party TMDS/LVDS Support Capabilities

The Intel 830M and 830MG Chipset GMCH-M is compliant with the DVI Specification 1.0. When combined with a DVI compliant device, the GMCH-M DVO port can drive a flat panel or a digital CRT.

5.5.2.5 TV Encoder Capabilities

The Intel 830M and 830MG Chipset GMCH-M supports TV encoders through the digital video output (DVO) interface. GMCH-M will generate the proper timing for the external encoder. The external encoder is responsible for generation of the proper format signal. Since the GMCH-M DVO interface is 1.5 V, care should be taken to ensure that the TV encoder is operational at that signaling voltage.

The TV-out interface on GMCH-M is addressable as a master device. This allows an external TV encoder device to drive a pixel clock signal on DVOx_CLKIN that the Intel 830M and 830MG Chipset will use as a reference frequency. The frequency of this clock is dependent on the output resolution required. Data is driven to the encoder across 12 data lines, along with clock pair and sync signals. The encoder can expect a continuous flow of data from GMCH-M because data will not be throttled.

5.5.2.5.1 Flicker Filter and Overscan Compensation

Overscan compensation scaling and the flicker filter is done in the external TV encoder chip. Care must be taken to allow for support of TV sets with high performance de-interlacers and progressive scan displays connected to by way of a non-interlaced signal. Timing will be generated with pixel granularity to allow more overscan ratios to be supported.

5.5.2.5.2 Direct YUV From Overlay

When source material is in the YUV format and is destined for a device that can take YUV format data in, it is desired to send the data without converting it to RGB. This avoids the truncation errors associated with multiple color conversion steps. The common situation will be that the overlay source data is in the YUV format and will bypass the conversion to RBG as it is sent to the TV port directly.

5.5.2.5.3 Analog Content Protection

Analog content protection will be provided through the external encoder using Macrovision 7.01. DVD software must verify the presence of a Macrovision TV encoder before playback continues. Simple attempts to disable the Macrovision operation must be detected.

5.5.2.5.4 Support of Progressive Scan SDTV TVs

Support will be included for progressive scan TV devices through the TV port. This support will include the resolutions of 480p and 1080i using both a YUV analog signal with sync on Y and a RGB HV connection for TVs with that connection.

DVOA	DVOB	DVOC			
LCD	DVI	TV			
LCD	TV	DVI			
LCD	DVI (DVOB+DVOC)				
DVI or TV	LCD (DVOB+DVOC)				
DVI or TV	LCD	DVI or TV			
DVI or TV	DVI or TV	LCD			

Table 39. DVO Usage Model

The Intel 830M and 830MG Chipset GMCH-M do not support two TV encoders devices at a time.

5.5.3 **Concurrent and Simultaneous Display**

The Intel 830M and 830MG Chipset GMCH-M has two independent pipes, each with its own timing generator and dot clock, and thus is able to support two displays concurrently. Windows* 98 and Windows* 2000 have enabled support for multi-monitor display. There are two types of multi-monitor solutions: Concurrent and Simultaneous. Concurrent displays different data on two screens whereas Simultaneous displays the same information on both displays. The GMCH-M also supports a combination of concurrent and simultaneous displays.

5.6 Intel 830M and 830MP Discrete AGP Interface

The 830M and 830MP Chipset will support 1.5-V AGP 1x/2x/4x devices. The AGP signal buffers will have one mode of operation; 1.5-V drive/receive (not 3.3-V tolerant). The GMCH-M will support 4x (266MT/s) clocking transfers for read and write data, and sideband addressing. The GMCH-M has a 32-deep AGP request queue. The GMCH-M integrates a fully associative 16 entry Translation Look-aside Buffer.

AGP semantic transactions to system SDRAM do not get snooped and are therefore not coherent with the CPU caches. PCI semantic transactions on AGP to system SDRAM are snooped. AGP semantic accesses to hub interface/PCI are not supported. PCI semantic access from an AGP master to hub interface is not supported.

5.6.1 AGP Target Operations

As an initiator, the 830M and 830MP GMCH-M does not initiate cycles using AGP enhanced protocols. The GMCH-M supports AGP target interface to main memory only. The GMCH-M supports interleaved AGP and PCI transactions.

The following table summarizes target operation support of GMCH-M for AGP masters.

Table 40. AGP Commands Supported by GMCH-M When Acting as an AGP Target

AGP Command	C/BE[3:0]#	GMCH-M Host Bridge				
	Encoding	Cycle Destination	Response as AGP Target			
Read	0000	Main Memory	Low Priority Read			
	0000	Hub interface	Complete with random data			
Hi-Priority Read	0001	Main Memory	High Priority Read			
	0000	hub interface	Complete with random data			
Reserved	0010	N/A	No Response			
Reserved	0011	N/A	No Response			
Write	0100	Main Memory	Low Priority Write			
	0100	hub interface	Cycle goes to SDRAM with BE's inactive			
Hi-Priority Write	0101	Main Memory	High Priority Write			
	0101	hub interface	Cycle goes to SDRAM with BE's inactive - does not go to hub interface			
Reserved	0110	N/A	No Response			
Reserved	0111	N/A	No Response			
Long Read	1000	Main Memory	Low Priority Read			
		Hub interface	Complete locally with random data - does not go to hub interface			
Hi-Priority Long Read	1001	Main Memory	High Priority Read			
		Hub interface	Complete with random data			
Flush	1010	GMCH-M	Complete with QW of Random Data			
Reserved	1011	N/A	No Response			

Fence	1100	GMCH-M	No Response – Flag inserted in GMCH- M request queue
Reserved	1101	N/A	No Response
Reserved	1110	N/A	No Response
Reserved	1111	N/A	No Response

NOTE: N/A refers to a function that is not applicable.

As a target of an AGP cycle, the GMCH-M supports all the transactions targeted at main memory and summarized in the table above. The GMCH-M supports both normal and high priority read and write requests. The GMCH-M will not support AGP cycles to hub interface. AGP cycles do not require coherency management and all AGP initiator accesses to main memory using AGP protocol are treated as non-snoopable cycles. These accesses are directed to the AGP aperture in main memory that is programmed as either uncacheable (UC) memory or write combining (WC) in the processor's MTRRs.

5.6.2 AGP Transaction Ordering

The Intel 830M and 830MP Chipset GMCH-M observes transaction ordering rules as defined by the AGP 2.0 specification.

5.6.3 AGP Electricals

4x/2x/1x and PCI data transfers use 1.5V signaling levels as described in the AGP 2.0 specification.

5.6.4 Support for PCI-66 Devices

The Intel 830M and 830MP Chipset GMCH-M's AGP interface may be used as a PCI-66 MHz interface with the following restrictions:

- Support for 1.5-V operation only.
- Support for only one device. GMCH-M will not provide arbitration or electrical support for more than one PCI-66 device.
- The PCI-66 device must meet the AGP 2.0 electrical specification.
- The GMCH-M does not provide full PCI-to-PCI bridge support between AGP/PCI and hub interface. Traffic between AGP and hub interface is limited to hub interface-to-AGP memory writes.
- LOCK# signal is not present. Neither inbound nor outbound locks are supported.
- SERR#/PERR# signals are not present.
- 16-clock Subsequent Data Latency timer (instead of 8)

5.6.5 4x AGP Protocol

In addition to the 1x and 2x AGP protocol the Intel 830M and 830MP GMCH-M supports 4x AGP read and write data transfers, and 4x sideband address generation. 4x operation will be compliant with the 4x AGP spec as currently described in AGP 2.0.

The 4x data transfer protocol provides 1.06 GB/s transfer rates. The control signal protocol for the 4x data transfer protocol is identical to 1x/2x protocol. In 4x mode 16 bytes of data are transferred during

each 66-MHz clock period. The minimum throttle-able block size remains four 66-MHz clocks which means 64 bytes of data is transferred per block. Three additional signal pins are required to implement the 4x data transfer protocol. These signal pins are complementary data transfer strobes for the AD bus (2) and the SBA bus (1).

5.6.6 Fast Writes

The Fast Write (FW) transaction is from the core logic to the AGP master acting as a PCI target. This type of access is required to pass data/control directly to the AGP master instead of placing the data into main memory and then having the AGP master read the data. For 1x transactions, the protocol simply follows the PCI bus specification. However, for higher speed transactions (2x or 4x), FW transactions will follow a combination for PCI and AGP bus protocols for data movement.

5.6.7 AGP-to-Memory Read Coherency Mechanism

The Global Write Buffer (GWB) in the Intel 830MPand 830M Chipset is used to post write data from the CPU, AGP/PCI, and hub interfaces prior to the data actually being written to system SDRAM. Reads to system SDRAM are allowed to pass writes in the GWB. This policy requires that all reads to SDRAM be checked against the writes in the GWB to maintain data coherency. If an AGP read hits a write in the GWB, that particular write in the GWB and all writes queued in front of it are written to SDRAM prior to the read. After the data hit by the AGP read is written to SDRAM the AGP read cycle is generated to the SDRAM.

5.6.8 PCI Semantic Transactions on AGP

The Intel 830M and 830MP Chipset GMCH-M accepts and generates PCI semantic transactions on the AGP bus. The GMCH-M guarantees that PCI semantic accesses to SDRAM are kept coherent with the CPU caches by generating snoops to the CPU bus.

5.6.8.1 PCI Read Snoop-Ahead and Buffering

The Intel 830M and 830MP Chipset GMCH-M issues snoops dynamically for the various types of memory read transactions and retains the contents of the AGP/PCI-to-SDRAM read buffers between AGP/PCI transactions.

For Memory Reads the GMCH-M will issue one snoop and the entire cache line of read data will be buffered. If a Memory Read bursts across the cache line, another snoop will be issued. Subsequent Memory Read transaction hitting the cache line buffer will return data from the buffer.

For Memory Read Line and Memory Read Multiple the GMCH-M issues two snoops (a snoop followed by a snoop-ahead) on the host bus and releases the CPU bus for other traffic. When the first DW of the first cache line is delivered and FRAME# is still asserted, the GMCH-M will issue another snoop-ahead on the host bus. This allows the GMCH-M to continuously supply data during Memory Read Line and Memory Read Multiple bursts. When the transaction terminates there may be a minimum of 2 cache lines and a maximum of 2 cache line plus 7 Dwords buffered. Subsequent Memory Reads hitting the buffers will return data from the buffer.

5.6.8.2 Intel 830M and 830MP Chipset GMCH-M Initiator and Target Operations

The following table summarizes target operation support of the Intel 830M and 830MP Chipset GMCH-M for AGP/PCI1 bus initiators. The cycles can be destined to either main memory or the hub interface bus.

PCI Command	C/BE[3:0]# Encoding	GMCH-M	
		Cycle Destination	Response as PCI Target
Interrupt Acknowledge	0000	N/A	No Response
Special Cycle	0001	N/A	No Response
I/O Read	0010	N/A	No Response
I/O Write	0011	N/A	No Response
Reserved	0100	N/A	No Response
Reserved	0101	N/A	No Response
Memory Read	0110	Main Memory	Read
	0110	hub interface	No Response
Memory Write	0111	Main Memory	Posts Data
	0111	hub interface	No Response
Reserved	1000	N/A	No Response
Reserved	1001	N/A	No Response
Configuration Read	1010	N/A	No Response
Configuration Write	1011	N/A	No Response
Memory Read Multiple	1100	Main Memory	Read
	1100	hub interface	No Response
Dual Address Cycle	1101	N/A	No Response
Memory Read Line	1110	Main Memory	Read
	1110	hub interface	No Response
lemory Write and Invalidate	1111	Main Memory	Posts Data
	1111	hub interface	No Response

Table 41. PCI Commands Supported by GMCH-M When Acting as a PCI Target

NOTE: N/A refers to a function that is not applicable.

As a target of an AGP/PCI cycle, GMCH-M only supports the following transactions:

- *Memory Read* The GMCH-M will issue one snoop and the entire cache line of read data will be buffered. If a Memory Read bursts across the cache line another snoop will be issued but the transaction will be disconnected on the cache line boundary. Subsequent Memory Read transaction hitting the cache line buffer will return data from the buffer.
- *Memory Read Line, and Memory Read Multiple* These commands are supported identically by the GMCH-M. The GMCH-M issues two snoops (a snoop followed by a snoop-ahead) on the host bus and releases the CPU bus for other traffic. When the first DW of the first cache line is delivered and FRAME# is still asserted, the GMCH-M will issue another snoop-ahead on the host bus. This allows the GMCH-M to continuously supply data during Memory Read Line and Memory Read Multiple bursts. When the transaction terminates there may be a minimum of 2 cache lines and a maximum of 2 cache line plus 7 Dwords buffered. Subsequent Memory Reads hitting the buffers will return data from the buffer.
- Memory Write and Memory Write and Invalidate These commands are aliased and processed identically. The GMCH-M supports data streaming for PCI-to-SDRAM writes based on its

ability to buffer up to 128 bytes (16 Qwords) of data before a snoop cycle must be completed on the host bus. The GMCH-M is typically able to support longer write bursts, with the maximum length dependent upon concurrent host bus traffic during PCI-SDRAM write data streaming.

Fast Back-to-Back Transactions - GMCH-M as a target supports fast back-to-back cycles from a PCI initiator.

As a PCI initiator the GMCH-M is responsible for translating host cycles to AGP/PCI1 cycles. The GMCH-M also transfers hub interface to AGP/PCI1 write cycles. The following table shows all the cycles that need to be translated.

Source Bus	Other Encoded Information	GMCH-M Host Bridge					
Command		Corresponding PCI1 Command	C/BE[3:0]# Encoding				
Source Bus: Host							
Deferred Reply	Don't Care	None	N/A				
Interrupt Acknowledge	Length ≤ 8 Bytes	None	N/A				
Special Cycle	Shutdown	None	N/A				
	Halt	None	N/A				
	Stop Clock Grant	None	N/A				
	All other combinations	None	N/A				
Branch Trace Message	None	None	N/A				
I/O Read	Length \leq 8 Bytes up to 4 Bex asserted	I/O Read	0010				
I/O Write	Length ≤ 8 Bytes up to 4 Bex asserted	I/O Write	0011				
I/O Read to 0CFCh	Length ≤ 8 Bytes up to 4 Bex asserted	Configuration Read	1010				
I/O Write to 0CFCh	Length ≤ 8 Bytes up to 4 Bex asserted	Configuration Write	1011				
	Length < 8 Bytes without all Bes asserted	Memory Read	0110				
Memory Read (Code or Data)	Length = 8 Bytes with all Bes asserted	Memory Read	1110				
Memory Read Invalidate	Length = 16 Bytes	None	N/A				
	Length = 32 Bytes Code Only	Memory Read	1110				
	Length < 8 Bytes without all Bes asserted	Memory Write	0111				
Memory Write	Length = 16 Bytes	None	N/A				
	Length = 32 Bytes	Memory Write	0111				
Locked Access	All combinations	Unlocked Access ¹	As Applicable				
Reserved Encodings	All Combinations	None	N/A				
EA Memory Access	Address ≥ 4 GB	None	N/A				
	Source Bus: hub interfa	ace					
Memory Write	-	Memory Write	0111				

Table 42. PCI Commands Supported by GMCH-M When Acting as an AGP/PCI1 Initiator

NOTES:

CPU to AGP/PCI1 bus can result in deadlocks. Locked access to AGP/PCI1 bus is strongly discouraged
 N/A refers to a function that is not applicable. Not Supported refers to a function that is available but specifically not implemented on GMCH-M.

As an initiator of AGP/PCI1 cycle, the GMCH-M only supports the following transactions:

Memory Read - All CPU to AGP/PCI1 reads will use the Memory Read command.

- *Memory Write* GMCH-M initiates AGP/PCI1 cycles on behalf of the CPU or hub interface. GMCH-M does not issue Memory Write and Invalidate as an initiator. GMCH-M does not support write merging or write collapsing. GMCH-M will combine CPU-to-PCI writes (Dword or Qword) to provide bursting on the AGP/PCI1 bus. GMCH-M allows non-snoopable write transactions from hub interface to the AGP/PCI1 bus.
- *I/O Read and Write* I/O read and write from the CPU are sent to the AGP/PCI1 bus. I/O base and limit address range for PCI1 bus are programmed in AGP/PCI1 configuration registers. All other accesses that do not correspond to this programmed address range are forwarded to hub interface.
- *Exclusive Access* GMCH-M will not issue a locked cycle on AGP/PCI1 bus on the behalf of either the CPU or hub interface. Hub interface and CPU locked transactions to AGP/PCI1 will be initiated as unlocked transactions by the GMCH-M on the AGP/PCI1 bus.
- *Configuration Read and Write* Host Configuration accesses to internal GMCH-M registers are driven onto AGP/PCI1 as Type 1 Configuration Cycles where they are then claimed by the GMCH-M. This is done to support co-pilot mode. Host Configuration cycles to AGP/PCI1 are forwarded as Type 1 Configuration Cycles.

5.6.8.3 GMCH-M Retry/Disconnect Conditions

The Intel 830M and 830MP GMCH-M generates retry/disconnect according to the AGP Specification rules when being accessed as a target from the AGP interface (using PCI semantics).

5.6.8.4 Delayed Transaction

When an AGP/PCI-to-SDRAM read cycle is retried by the GMCH-M it will be processed internally as a Delayed Transaction.

The Intel 830M and 830MP GMCH-M supports the Delayed Transaction mechanism on the AGP target interface for the transactions issued using PCI semantics. This mechanism is compatible with the PCI 2.2 Specification. The process of latching all information required to complete the transaction, terminating with Retry, and completing the request without holding the master in wait-states is called a Delayed Transaction. The GMCH-M latches the Address and Command when establishing a Delayed Transaction. The GMCH-M generates a Delayed Transaction on the AGP only for SDRAM read accesses.

5.7 Intel 830 Chipset Family GMCH-M Power and Thermal Management

The following list provides the GMCH-M Power and Thermal Management Features:

- ACPI 1.0b & 2.0 support
- Mobile Power Reduction operating modes (C3, S1)
- System States: S0, S1, S3, S4, S5
- CPU States: C0, C1, C2, C3

- Graphics States: D0, D1, D3
- Compatible with Intel 815EM AGP Busy/Stop protocol
- Enhanced Intel SpeedStep[™] technology support
- Thermal Throttling for Main memory, and Graphics

5.7.1 ACPI 2.0 Support

Advanced Configuration and Power Management Interface (ACPI) primarily describes and runs motherboard devices. It is completely controlled by the operating system that OS drivers directly power down PCI/AGP devices. System or SMI BIOS plays a part of waking the system, however. Device drivers save and restore state while bus drivers change the physical power state of the device.

The Intel 830 Chipset family GMCH-M power management architecture is designed to allow single systems to support multiple suspend modes and to switch between those modes as required. A suspended system can be resumed via a number of different events. The system returns to full operation where it can continue processing or be placed into another suspend mode (potentially a lower power mode than it resumed from).

GMCH-M supports the minimum requirements for ACPI support. GMCH-M must support the minimum requirements for both system logic and for graphics controllers, as well as be capable of controlling monitors minimum functions. The transition sequences of entering and exiting system, CPU and graphics states are described in respective sections below.

5.7.2 ACPI States Supported

5.7.2.1 Intel 830M and 830MP Chipset ACPI Supported States

When a discrete AGP interface is used, the Intel 830M and 830MP Chipset supports the following ACPI states:

- 1. System States
 - G0/S0 Full On
 - G1/S1 Power On Suspend (POS). System Context Preserved.
 - G1/S3 Suspend to RAM (STR). Power and context lost to Chipset.
 - G1/S4 Suspend to Disk (STD). All power lost (except wakeup on ICH3-M)
 - G2/S5 Hard off. Total reboot.
- 2. CPU States
 - C0 Full On
 - C1 Auto Halt
 - C2 Quick Start
 - C3 Deep Sleep. Clock to CPU stopped Clock to CPU stopped or CPU DPSLP# pin asserted
5.7.2.2 Intel 830M and 830MG Chipset ACPI Supported States

When internal graphics device is used, the Intel 830M and 830MG Chipset support the following ACPI States:

1. System States

int_{el}.

G0/S0	Full On
G1/S1	Power On Suspend (POS). System Context Preserved.
G1/S3	Suspend to RAM (STR). Power and context lost to Chipset.
G1/S4	Suspend to Disk (STD). All power lost (except wakeup on ICH3-M)
G2/S5	Hard off. Total reboot.
CPU St	ates
CO	

2.

C0	Full On
C1	Auto Halt
C2	Quick Start
C3	Deep Sleep. Clock to CPU stopped Clock to CPU stopped or CPU DPSLP# pin asserted

3. Internal Graphics (IGD) States:

D0	Full on, display active
D1	Low power state, low latency recovery.
D3Hot	All state lost other than PCI configuration. Memory lost (optionally).
D3Cold	Power off

5.7.3 Intel 830 Chipset Family System and CPU States

Table 43 shows the state combinations that the Intel 830 Chipset family supports.

Global (G) State	Sleep (S) State	CPU (C) State	Processor State	Description
G0	S0	CO	Full On	Full On
G0	S0	C1	Auto-Halt	Auto Halt
G0	S0	C2	Quick Start	Quick Start
G0	S0	C3	Deep Sleep	Deep Sleep
G1	S1	C3	Deep Sleep	Power On Suspend
G1	S3	Power off	Power off	Suspend to RAM
G1	S4	Power off	Power off	Suspend to Disk
G2	S5	Power off	Power off	Hard Off.
G3	NA	Power off	Power off	Mechanical Off.

Table 43. Intel 830 Chipset Family System and CPU States

5.7.4 Intel 830 Chipset Family CPU "C" States

5.7.4.1 Full-On (C0)

This is the only state that runs software. All clocks are running, STPCLK# is deasserted and the processor core is active. The processor can service snoops and maintain cache coherency in this state.

5.7.4.2 Auto-Halt (C1)

The first level of power reduction occurs when the processor executes an Auto-Halt instruction. This stops the execution of the instruction stream and greatly reduces the processors power consumption. The processor can service snoops and maintain cache coherency in this state.

5.7.4.3 **Quickstart (C2)**

The next level of power reduction occurs when the processor is placed into the Quick start state by the assertion of STPCLK#. Mobile Quickstart state is a lower power version of the desktop Stop Grant state. The processor can service snoops and maintain cache coherency in this state.

The system can transition from the C0 state to the C2 state for several reasons.

- *Software*. C2 is entered when software reads the Level 2 Register. This is an ACPI defined register but BIOS or APM (via BIOS) can use this facility when entering a low power state.
- *Throttling*. This function can be enabled or disabled via a configuration bit. When this function is enabled STPCLK# will be asserted to place the processor into the C2 state with a programmable duty cycle. This is an ACPI defined function but BIOS or APM (via BIOS) can use this facility.
- *Thermal Override*. The Chipset will detect thermal events via an input to the ICH3-M. When a thermal threshold has been exceeded, a thermal sensor will assert a signal to the ICH3-M. If the signal

remains asserted for more than 2 seconds the Chipset will initiate thermal throttling. STPCLK# will be asserted to place the processor into the C2 state with a programmable duty cycle. This function can be enabled or disabled via a configuration bit. The Thermal Override condition is handled by the ICH3-M.

5.7.4.4 Deep Sleep (C3)

The Deep Sleep and Deeper Sleep states are identical as far as the Intel 830 Chipset family GMCH-M is concerned. The only difference externally is that the CPU voltage is lowered for Deeper Sleep state to enable even more power saving. Deeper Sleep is supported on the Mobile Intel Pentium III Processor-M but not on the Mobile Celeron processors. The C3 entry and exit sequence is also followed by an Enhanced Intel SpeedStepTM technology transition. C3 entry will generally occur when the system is idle, and no bus master activity has taken place recently as indicated by PCI REQ# signals and AGP_BUSY# (although AGP_BUSY# being active does not guarantee C3 will not be entered). Enhanced Intel SpeedStep technology transitions may occur at any time, while the system is busy and bus master activity is occurring. There will be no attempt to wait for the system to be idle for an Enhanced Intel SpeedStep technology transition.

C3 may be entered even if AGP_BUSY# is active, since there is a delay from the time AGP_BUSY# is sampled by the OS and C3 is actually entered. AGP_BUSY# does not prevent C3 entry in hardware, it only indicates to the OS that activity is present. The OS will choose C2 rather than C3 in this case. AGP_BUSY# active will cause a C3 exit, however, so the C3 mode will be brief if AGP_BUSY# is active. An Enhanced Intel SpeedStep technology transition, which appears to the GMCH-M exactly as a C3 entry/exit, will occur regardless of the state of AGP_BUSY#.

The GMCH-M can assume that no AGP, AGP/PCI, or Hub Interface cycle (except special cycles) will occur while the GMCH-M is in the C3 state. The processor cannot snoop its caches to maintain coherency while in the C3 state.

5.7.5 Intel 830MP and 830M Chipset AGP_BUSY# Protocol With External Graphics

The AGP_BUSY# and STP_AGP# signals allow power management signaling between an external AGP graphics controller and the ICH3-M. AGP_BUSY# indicates that the AGP device is busy. C3_STAT# (STP_AGP#) is the signal, which used for indicating to the AGP device that a C3 state transition is beginning or ending. AGP_BUSY# (ICH3-M signal) and STP_AGP# (AGP graphics controller signal) are not directly connected to the GMCH-M. For proper implementations, please consult Intel Field Application Engineers.

5.7.6 Intel 830M and 830MG Internal Graphics Device AGP_BUSY# Protocol

In IGD mode, AGP_BUSY# pin is a 3.3-V open drain output which indicates to the ICH3-M that C3 should be entered, or it should be exited if already in C3. When internal graphics device (IGD) is used, C3 must be entered without stopping the Chipset clock or the memory controller.

5.7.7 Enhanced Intel SpeedStep™ Technology (Applicable With Mobile Intel Pentium III Processor-M only)

Enhanced Intel SpeedStep technology allows the system to operate in multiple performance states. Enhanced Intel SpeedStep technology offers two CPU/system operational modes:

- *Maximum Performance Mode*: Maximum CPU Core Frequency, requiring a higher CPU Core voltage.
- *Battery Optimized Mode*: Reduced CPU core frequency to extend battery life. Allows for lower CPU Core voltage for additional power savings.

Enhanced Intel SpeedStep technology allows the processor switch to between two core frequencies automatically based on CPU demand, without having to reset the processor or change the system bus frequency. The processor has two bus ratios programmed into it instead of one and the GHI# signal controls which one is used. After reset, the processor will start in the lower of its two core frequencies, the "Battery Optimized" mode. An operating mode transition to the high core frequency can be made by putting the processor into the Deep Sleep state, raising the core voltage, setting GHI# low, and returning to the Normal state. This puts the processor into the "Maximum performance" mode. Reversing these steps transitions the processor back to the low-core frequency.

Most of the control for is done in the ICH3-M. However, the Intel 830 Chipset family GMCH-M must cooperate on certain functions.

5.7.8 Intel 830 Chipset Family System "S" States

5.7.8.1 Powered-On-Suspend (POS) (S1)

The deepest level of power savings that can be achieved by only shutting down clocks occurs in the S1 State. The only clock remaining active in the system in the S1 State is the RTC clock. This clock is used to detect wake events and to run the hardware in the resume well in the ICH3-M used to reactivate the system.

During the S1 State the CPU and the Intel 830 Chipset family GMCH-M power is on, however there is no activity, so the only power consumed is the leakage power. The Clock synthesizer) is powered off, this shuts the clocks off in the Host, Memory, and I/O clock groups. If the D1 State is used for internal graphics, a clock must be provided to GMCH-M for DPMS signaling to the CRT.

5.7.8.2 Suspend-To-RAM (STR) (S3)

The final level of power savings for the Intel 830 Chipset family GMCH-M is achievable when the Host Clock, Memory Group, and I/O clock group clocks are shutdown and the GMCH-M is powered down. This occurs when the system transitions to the S3 state. During transition to the S3 state, first the STPCLK# is asserted and the Stop Grant cycle snooped by the GMCH-M and forwarded over Hub interface where it is received by the ICH3-M. At this point the GMCH-M is functioning in the C2 State. The GMCH-M places all of the SDRAM components into the self-refresh mode. After the GMCH-M has placed all of the SDRAM components in self refresh, it is safe to enter the STR State. The ICH3-M will then assert a signal, SLP_S1#, to the clock synthesizer to shutdown all of the clocks in the Host and Memory Clock Groups.

The GMCH-M will assume that no AGP, AGP/PCI, or hub interface cycle (except special cycles) will occur while the GMCH-M is in the C3 State. The processor cannot snoop its caches to maintain coherency while in the C3 State.

GMCH-M contains no isolation circuitry and MUST be powered down once STR is reached. If GMCH-M is powered up and driving outputs to devices that are powered down, component damage will result.

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5.7.8.3 S4 (SUSPEND TO DISK), S5 (Soft Off) State

The Intel 830 Chipset family does not distinguish between Suspend to Ram (S3), Suspend to Disk (S4) and Soft Off (S5) states. From the 830 Chipset family perspective, entry and exit to S4 or S5 states, is the same as entry and exit to S3 state.

5.7.9 Intel 830M and 830MG Chipset Internal Graphics "D" States

PC9x implies that D0 and D3 are obligatory for graphics controllers. D0, D2, and D3 are obligatory for monitors. Intel 830M and 830MG GMCH-M also implements D1 for the graphics controller and monitors. System SDRAM state is generally controlled by S-States and C-States rather than D-States. With internal graphics the system SDRAM will remain available when the CPU is in C3.

5.7.9.1 D0 Graphics Adapter State – Active State

In the D0 Power State, everything is operating. This is the normal ON State for the ICD graphics functions. The GMCH-M graphics functions enter this state out of power-on-reset.

5.7.9.2 The D1 Graphics Adapter State

In the D1 Power State, the graphics must go to a lower power state. The displays are blank, but memory and registers must be maintained. The emphasis is on a fast recovery in this mode.

5.7.9.3 The D3 Graphics Adapter State

The D3 Power State is the lowest power mode. Displays are off, and the registers and memory need not be maintained. The PCI config space must be accessible, in order to write the power state back to D0.

When the OS decides to put the IGD graphics functions into D3 power state, it calls the IGD graphics driver so that the driver saves the device context. Device context consists of the IGD graphics mode as well as non-local video memory context. External parts context must also be stored.

5.7.9.4 Monitor [Analog CRT] States

The monitor is considered a child device of the graphics controller. It's ACPI states are controlled through the graphics controller. DPMS (Display Power Management Signaling) is a VESA (Video Electronics Standards Association) specification that provides a method for the graphics controller to put the monitor in a particular power management state by controlling the presence or absence of pulses on the HSYNC and VSYNC signals. The D state of the CRT monitor can be set independently of the graphics controller, but will always be equal to or higher (in number, lower in power) than the graphics controller. The monitor is considered a "child device" to the graphics controller. Table 44 lists each combination.

Graphics Controller	CRT State	HSYNC/VSYNC Status
D0	D0 = On	Pulse HSYNC and VSYNC
D0	D1 = Standby	Pulse VSYNC
D0	D2 = Suspend	Pulse HSYNC
D0	D3 = Off	No pulse on HSYNC and VSYNC
D1	D1	Pulse VSYNC
D1	D2	Pulse HSYNC
D1	D3	No pulse on HSYNC and VSYNC
D3	D3	No pulse on HSYNC and VSYNC

Table 44. Combinations of CRT and Graphics Power Down States

In D1 state, the graphics controller must be able to toggle either HSYNC or VSYNC, depending on the CRT state.

5.7.9.5 DPMS Clock Signaling in S1 (D1) State

When the Intel 830M and 830MG GMCH-M graphics controller is in the D1 State, the graphics core clock and dot clocks are stopped, causing HSYNC and VSYNC generation to stop. If the system is configured to allow the graphics controller to be in D1 while the system is in mobile S1, all clocks in the system, including the clock generator chip are shut off. Potentially the only clock running is the 32 kHz of the Real Time Clock. The DPMS clock signal is muxed with GAD30 provides clock source to generate pulses on HSYNC and VSYNC in the D1 State. The DPMS clock signal requires an external clock source, which may be 32 kHz or a 33/66 MHz clock. DPMS_CLK is NOT required if S1 states is NOT supported.

5.7.10 System Memory Dynamic CKE support

To reduce EMI and preserve battery life, clocks to unpopulated SO-DIMMs are turned off. The DRB registers are read to determine if the row is populated. Clocks are turned off in pairs because SM_CLK[1:0] go to one SO-DIMM, SM_CLK[3:2] go to another SO-DIMM.. The main memory SDRAMs are power managed during normal operation and in low power modes. Each row has a separate CKE (clock enable) pin that is used for power management. CKE is used to put the SDRAM rows into power down mode. Active power management is employed during normal operation. The memory setting is determined by the thermals of the system and the number of chips in a row. Following refresh, all SDRAMs are powered down except the one for which there is the first pending request, if any.

5.7.11 Intel 830 Chipset Family GMCH-M Thermal Management

With the addition of integrated graphics device, passive heat dissipation may not be enough and active cooling may reach its limit. Counter based throttling does not correlate well with the actual environment, especially in a notebook where the outside ambient temperature varies greatly, along with internal conditions, such as heavy 3D content.

The Intel 830 Chipset family GMCH-M has several methods for monitoring and/or handling thermal issues. GMCH-M contains an on-die thermal sensor is used for emergency throttling and shutdown. GMCH-M contains a bandwidth monitor on the IGD and the SDRAM interfaces. If the bandwidth

exceeds a programmed amount, the GMCH-M will automatically stall to avoid thermal problems. Intel will provide a CMTI software suite to profile system for optimal thermal management. Please contact local FAE for support.

5.7.11.1 Thermal Sensor

The Intel 830 Chipset family GMCH-M has an on-die thermal sensor for emergency throttling and shutdown. A thermal sensor provides a closed loop feedback path, and an emergency indicator. This sensor has two programmable trip points. The following will occur:

- 1. Software should cause an Intel SpeedStep technology transition to lower power/frequency.
- 2. The thermal sensor provides throttling either by hardware or a combination of hardware and software.
- 3. Hardware may reduce the temperature by:
 - a. Throttling the 3D rendering
 - b. Throttling the main memory
- 4. Software may reduce the temperature by:
 - a. Changing the 3D throttling parameters.
 - b. Shutting off functions.
 - c. Driver Throttling

5.7.11.2 Graphic Thermal Throttling

The Intel 830M and 830MG Chipset 3D engine contains throttling mechanism between 3D engine and the memory interface. In non-throttled-state, the 3D pipe has two signals that control the flow of data to and from the local cache. There are three programmable values for the 3D pipe duty cycle, of which one (at most) is in use at any given time.

5.7.11.3 System and Graphics Memory Bandwidth Monitoring and Throttling

The Intel 830 Chipset family has the capability for bandwidth monitoring/throttle mechanism for the system memory interface (applicable to the entire Chipset family). If the counter window exceeds the bandwidth threshold, then the SDRAM throttling mechanism will be invoked to limit the memory reads/writes to a lower bandwidth.

The bandwidth monitoring mechanism consists of a counter to measure SDRAM bandwidth being used. Depending on what is being monitored, reads, and writes or both, a counter is incremented. If the number of read/writes during the monitoring period exceeds the value programmed, the throttling mechanism is invoked.

If the Intel 830 Chipset family GMCH-M detects an idle cycle where no traffic is encountered during the throttling window, the counter decrements and no throttling takes place. Once the bandwidth reaches the determined bandwidth, the GMCH will start to throttle and continue throttling determined by the activity percentage. If the bandwidth never exceeds the set value, no throttling will take place. The GMCH will exit the throttling mechanism and return to monitoring traffic where the process starts over again.

5.8 Clocking

The Intel 830 Chipset Family GMCH-M has the following clocks:

- 133 MHz, Spread spectrum, Low voltage Differential HTCLK(#) for Processor Side Bus
- 66.666 MHz 3.3 V, Spread spectrum, GBOUT Output Clock for external Hub/AGP/PCI buffer

- 66.666 MHz 3.3 V, Spread spectrum, GBIN from external buffer for AGP/Hub interface
- 48-MHz, Spread spectrum, 3.3 V DREFCLK for the Display frequency syntheses (applicable only when internal graphics device is used)
- 75-85 MHz DVOx_CLKIN for TV encoder mode (applicable only when discrete AGP device is used)

The Intel 830 Chipset family has inputs for a low voltage, differential pair of clocks called HTCLK and HTCLK#. These pins receive a buffered host clock from the external clock synthesizer. This clock is used by all of the GMCH-M logic. This clock is also the reference clock for the graphics core PLL.

The Graphic core and Display interfaces are asynchronous to the rest of the GMCH-M. The Graphics core runs at 100-166 MHz. The Display PLLs uses the Non-Spread Spectrum 48-MHz input to generate frequency range of 12-350 MHz.

5.9 XOR Test Chains

Another feature of the Intel 830 Chipset family is the support for XOR Chain test modes. The XOR Chain test mode is used by product engineers during manufacturing and OEMs during board level connectivity tests. The main purpose of this test mode is to detect connectivity shorts between adjacent pins and to check proper bonding between I/O pads and I/O pins. There are 11 XOR test chains built into the chipset.

5.9.1.1 Test Mode Entry

Excluding the RAC chain, all that is required to prepare the GMCH-M for XOR chain testing is to pull DVOA_D[7] and G_PAR/ADD_DETECT high prior to deasserting PCIRST#. The following event sequence will put the GMCH-M into XOR testability mode:

- 1. Deassert PCIRST# high, deassert DVOA_D[11;8:6;4:3] low, assert G_PAR/ADD_DETECT high.
- 2. Assert PCIRST# low; assert DVOA_D[7:6] high and maintain G_PAR/ADD_DETECT high
- 3. Deassert PCIRST# high.
- 4. XOR chain patterns can be applied to all GMCH-M interfaces (except for RAC) after PCIRST# is deasserted.
- 5. DVOA_D[11;8:6;4:3] and G_PAR/ADD_DETECT can be "Don't care". See Figure 16 for more details.



Figure 16. XOR Chain Test Mode Entry Events Diagram

The assertion of DVOA_D[6] high in Figure 16 is optional. The 830 Chipset family supports dual ended termination for the CPU but only single ended termination is necessary when using the XOR test chains.

5.9.1.2 RAC Chain Initialization

On the RAC chain, special timing requirements need to be followed in order to use it. The event sequence (see Section 5.9.1.2) to enter test mode for the RAC chain is identical to that for all other chains and is shown in Figure 16 above. The application of test patterns to the inputs of the RAC chain must adhere to the timing requirements shown in Figure 17. Table 45 lists the minimum and maximum timings for the time parameters in Figure 17. This includes the maximum test enable (t1) and output propagation delays (t2), and minimum period for the application of a test pattern (t3).

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Figure 17. RAC Chain Timing Diagram



Table 45. RAC Chain Timing Descriptions

Symbol	Description	Min	Мах	Unit
t1	IOCT test enable delay	0	100	ns
t2	I/O to IOCT Output delay	0	25	ns
t3	I/O connectivity sequence period	30		ns

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5.9.1.3 XOR Chain Test Pattern Consideration for Differential Pairs

Below are the differential signals in the XOR chains that must be treated as pairs. Pin1 and Pin2 as shown below must always be complementary to each other. For example, if a 1 is driven on ADSTB0, a 0 must be driven on ADSTB0# and vice versa. This will need to be considered when applying test patterns to these chains.

Table 46. XOR Chain Differential Pairs

Pin1	Pin2	XOR Chain
ADSTB0	ADSTB0#	AGP1
ADSTB1	ADSTB1#	AGP1
SBSTB	SBSTB#	AGP2
DVOADATA(0)	DVOADATA(1)	DVO
PSTRB	PSTRB#	Hublink

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5.9.1.4 XOR Chain Exclusion List

Please see below for a list of pins that are not included in the XOR chains (excluding all VCC/VSS):

- 1. GTL_REF0
- 2. GTL_REF1
- 3. CPURST#
- 4. GTL_RCOMP
- 5. HTCLK#
- 6. HTCLK
- 7. DREFCLK
- 8. DVOA_RCOMP
- 9. BLUE#
- 10. BLUE
- 11. GREEN
- 12. GREEN#
- 13. RED
- 14. RED#
- 15. GBIN
- 16. GBOUT
- 17. RESET#
- 18. AGP_RCOMP
- 19. AGPREF
- 20. HLREF
- 21. HL_RCOMP
- 22. SM_REF0
- 23. SM_REF1

5.9.1.5 NC Balls

The 830 Chipset family contains four NC (No Connect) balls that are not used in any chipset features. However, these four NC balls are used as input and/or output to some of the XOR test chains. The following table lists the balls and associated XOR chain.

	Ball	XOR Chain
1	E11	PSB2
2	E20	SM1
3	F20	SM1
4	F12	RAC

5.9.1.6 XOR Chain Connectivity/Ordering

The following tables contain the ordering for all of the 830 Chipset family XOR chains and pin to ball mapping information:

Table 48. XOR Chain AGP1

	Ball	Pin
XOR OUT	A19	SMA5
1	W25	GAD29
2	Y29	GAD31
3	V25	GAD27
4	W26	GAD28
5	W27	GAD30
6	W29	GAD26
7	V27	GAD22
8	V28	GAD23
9	V29	GAD25
10	U26	GAD24
11	U27	GAD21
12	U29	GDSTB1
13	U28	GDSTBB1
14	T25	GCBE3
15	T26	GAD20
16	T27	DVOC_D0
17	T29	GAD18
18	R24	GAD17
19	R25	GAD16
20	P29	GCBE1
21	N29	GAD12
22	N27	GAD15
23	N26	GAD14
24	M29	GAD8
25	M28	GAD9
26	M27	GAD11
27	M25	GAD13
28	L29	GDSTB0
29	L28	GDSTBB0
30	L27	GCBE0
31	L26	GAD4

32	K29	GAD6
33	K27	GAD7
34	K26	DVOB_D1
35	L24	GAD10
36	J29	GAD0
37	K25	GAD3
38	J28	GAD1
39	J27	GAD5

Table 49. XOR Chain AGP2

	Ball	Pin
XOR OUT	A17	SMA9
1	AD29	GGNTB
2	AB25	GRBFB
3	AC27	GREQB
4	AC28	GST0
5	AC29	GST1
6	AA25	GSBA2
7	AB26	GPIPEB
8	AB27	GST2
9	AB29	GWBFB
10	Y24	GSBA3
11	AA27	GSBSTB
12	AA28	GSBSTBB
13	W24	GSBA6
14	AA24	GSBA1
15	Y26	GSBA5
16	AA29	GSBA0
17	Y27	GSBA4
18	Y28	GSBA7
19	R29	GFRAMEB
20	R27	GCBE2
21	R28	GDEVSELB
22	P28	GPAR
23	P27	GTRDYB
24	P26	GIRDYB
25	N25	GSTOPB

Table 50. XOR Chain DVO

	Ball	Pin
XOR OUT	C16	SMBA1
1	AD20	DVO CLKIN
2	AE21	DVO INTR
3	AJ22	DVOD0
4	AH22	DVOD1
5	AG22	DVOD2
6	AF22	DVO HSYNC
7	AJ23	DVOD3
8	AE22	DVO FIELD
9	AH23	DVOD4
10	AG23	DVOD5
11	AF23	DVO VSYNC
12	AD21	DVO BLANK
13	AJ24	DVO CLK
14	AG24	DVO CLKB
15	AE23	DVOD6
16	AJ25	DVOD8
17	AE24	DVOD7
18	AH25	DVOD9
19	AG25	DVOD10
20	AJ26	DVOD11

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Table 51. XOR Chain PSB1

	Ball	Pin
XOR OUT	E17	SMCS0
1	G6	H_RS2B
2	D3	H_HITB
3	C1	H_ADSB
4	H6	H_RS0B
5	G5	H_DBSYB
6	F4	H_DRDYB
7	E3	H_A4
8	G4	H_TRDYB
9	J6	H_LOCKB
10	D1	H_HITMB
11	H4	H_RS1B
12	G3	H_A5
13	K6	H_REQ0B
14	E1	H_BNRB
15	K5	H_REQ2B
16	F2	H_A9
17	F1	H_A8
18	L6	H_REQ4B
19	K4	H_REQ3B
20	H2	H_A3
21	M6	H_A7
22	L4	H_BPRIB
23	M4	H_REQ1B
24	N4	H_A6
25	Y2	H_D32
26	AA1	H_D34
27	AA2	H_D38
28	AA4	H_D33
29	AB1	H_D36
30	AB3	H_D39
31	AC1	H_D45
32	AC2	H_D42
33	AC3	H_D49
34	AC4	H_D37
35	AA6	H_D35

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36	AD1	H_D41
37	AD2	H_D40
38	AD4	H_D47
39	AE1	H_D59
40	AE3	H_D52
41	AF1	H_D63
42	AF2	H_D55
43	AC6	H_D44
44	AE4	H_D57
45	AB6	H_D43
46	AF3	H_D46
47	AG1	H_D58
48	AG2	H_D53
49	AE5	H_D51
50	AD6	H_D48
51	AF4	H_D54
52	AG3	H_D62
53	AH3	H_D50
54	AG4	H_D60
55	AH4	H_D61
56	AJ3	H_D56

Table 52. XOR Chain PSB2

	Ball	Pin
XOR OUT	E11	NC
1	F3	H_A11
2	J4	H_DEFERB
3	H3	H_A28
4	G1	H_A13
5	J3	H_A10
6	H1	H_A15
7	КЗ	H_A31
8	L3	H_A23
9	J2	H_A19
10	J1	H_A25
11	N5	H_A14
12	М3	H_A29
13	K1	H_A22
14	L2	H_A20
15	L1	H_A24
16	M2	H_A18
17	P6	H_A12
18	N3	H_D6
19	M1	H_A30
20	P4	H_A16
21	P3	H_D9
22	N1	H_A26
23	P2	H_D15
24	P1	H_D1
25	R4	H_A21
26	R3	H_D10
27	R2	H_D17
28	R1	H_D5
29	Т5	H_A27
30	T4	H_A17
31	Т3	H_D14
32	T1	H_D18
33	U4	H_D0
34	U6	H_D4
35	U3	H_D20

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36	U2	H_D3
37	U1	H_D11
38	V4	H_D8
39	V3	H_D16
40	V2	H_D30
41	V1	H_D24
42	W4	H_D13
43	W3	H_D19
44	V6	H_D12
45	W1	H_D23
46	W5	H_D7
47	Y3	H_D31
48	Y4	H_D21
49	W6	H_D2
50	Y6	H_D26
51	Y1	H_D25
52	AA3	H_D22
53	AB4	H_D28
54	AD3	H_D27
55	AB5	H_D29

Table 53. XOR Chain GPIO

	Ball	Pin
XOR OUT	C15	SMA11
1	AD28	HSYNC
2	AC24	AGP BUSY
3	AD27	DDC1 DATA
4	AC25	I2C DATA
5	AD26	DDC2 DATA
6	AE29	VSYNC
7	AE27	DDC1 CLK
8	AE26	DDC2 CLK
9	AD25	I2C CLK

Table 54. XOR Chain HUB

	Ball	Pin
XOR OUT	A18	SMA4
1	E28	HLD7
2	G25	HLRQM
3	E29	HLD6
4	F27	HLD5
5	G26	HLD0
6	F28	HLSTBB
7	G29	HLSTB
8	G27	HLRQI
9	F29	HLD4
10	H26	HLSTOP
11	H27	HLD3
12	H28	HLD1
13	H29	HLD2

Table 55. XOR Chain SM1

	Ball	Pin
XOR OUT	A20	SMA0
1	C24	SMRCLK
2	A24	SMOCLK
3	G22	SMD42
4	A23	SMD44
5	D22	SMD43
6	F21	SMD45
7	D21	SMD46
8	E20	NC
9	F20	NC
10	A22	SMD47
12	B20	SMA1
14	D19	SMCAS
15	F18	SMDQM0
16	B19	SMA2
17	C17	SMA6
18	B17	SMA8
20	D15	SMCS3
22	F13	SMDQM7
23	A15	SMCLK0
24	B14	SMCLK2
26	D13	SMDQM2
27	C13	SMCKE2
28	A13	SMCKE0
32	D12	SMDQM3
33	A11	SMD49
34	B11	SMD50
35	B10	SMD52
36	F11	SMD48
37	A9	SMCKE3
38	C9	SMCKE1
39	D9	SMD54
40	F10	SMD51
42	B8	SMD53
43	F9	SMD56
44	B7	SMD55

45	D7	SMD59
46	A6	SMD57
47	C6	SMD58
48	E6	SMD61
49	B5	SMD60
50	A4	SMD62
51	A3	SMCLK3
53	B2	SMCLK1
54	D4	SMD63

Table 56. XOR Chain SM2

	Ball	Pin
XOR OUT	C19	SMA3
1	D29	SMD0
2	C29	SMD1
3	C28	SMD33
4	B28	SMD34
5	E27	SMD32
6	D27	SMD2
7	E26	SMD35
8	C27	SMD3
9	A27	SMD4
10	C26	SMD36
11	B26	SMD5
12	E24	SMD6
13	A26	SMD38
14	D25	SMD37
15	C25	SMD7
16	B25	SMD9
17	E23	SMD8
18	D24	SMD39
19	A25	SMD41
20	F23	SMD40
21	C23	SMD10
22	B23	SMD12
23	F22	SMD11
24	C22	SMD13

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25	E21	SMD14
26	B22	SMD15
27	A21	SMWE
28	C20	SMRAS
29	E18	SMDQM4
30	D18	SMDQM1
31	F17	SMDQM5
32	C18	SMA7
33	D16	SMCS2
34	B16	SMBA0
35	A16	SMA10
36	C14	SMA12
37	F14	SMDQM6
38	C12	SMD16
39	C11	SMD18
40	A10	SMD19
41	C10	SMD20
42	D10	SMD17
43	F8	SMD27
44	E9	SMD23
45	C8	SMD21
46	A7	SMD22
47	C7	SMD24
48	E8	SMD25
49	D6	SMD29
50	A5	SMD26
51	C5	SMD28
52	B4	SMD30
53	C4	SMD31

Table 57. XOR Chain CMOS

	Ball	Pin
XOR OUT	F16	SMCS1
1	AG6	GCLK
2	AJ6	RCLK
3	AF7	SCK
4	AH7	CMD
5	AJ7	SIO

Table 58. XOR Chain RAC

	Ball	Pin
XOR OUT	F12	NC
1	AJ20	DQA7
2	AG20	DQA6
3	AJ19	DQA5
4	AG19	DQA4
5	AJ18	DQA3
6	AG18	DQA2
7	AJ17	DQA1
8	AG17	DQA0
9	AH15	СТМ
10	AJ16	CFM
11	AJ15	CTM_B
12	AH16	CFM_B
13	AJ14	RQ7
14	AG14	RQ6
15	AJ13	RQ5
16	AG13	RQ4
17	AH13	RQ3
18	AG12	RQ2
19	AJ12	RQ1
20	AG11	RQ0
21	AJ11	DQB0
22	AH10	DQB1
23	AJ10	DQB2
24	AG10	DQB3
25	AJ9	DQB4

26	AG9	DQB5
27	AJ8	DQB6
28	AG8	DQB7

6 Intel 830 Chipset Family Performance

The system performance for the Intel 830 Chipset family GMCH-M described below is a breakdown of the data streams that complement the Mobile Intel Pentium III Processor-M. This section describes the overall performance of the GMCH-M. Following categories of performance are examined:

- CPU/830 Chipset family GMCH-M: Intel 830 Chipset family supports Mobile Intel Pentium III Processor-M
- System Memory: Intel 830 Chipset GMCH-M supports PC133 main memory
- AGP only available with 830M and 830MP Chipset
- DVO only available with 830M and 830MG Chipset

Table 59. System Bandwidths

Interface	Clock Speed (MHz)	Samples Per Clock	Data Rate (Mega-samples/s)	Data Width (Bytes)	Bandwidth (MB/s)
CPU Bus	133	1	133	8	1066
SDRAM	133	1	133	8	1064
AGP 2.0	66	4	266	4	1066
DVO	165	2	330	1.5	495
DVO Gang mode	165	2	330	3	990
PCI 2.2	33	1	33	4	133

NOTE: *Theoretical Bandwidths only.

7 Mechanical Specification

7.1 Intel 830MP Chipset GMCH-M Ballout Diagram

Figure 18 and Figure 19 show the ballout of the Intel 830MP Chipset.

	1	2	3 SM CLK3	4 SMD62	5 SMD26	6 SMD57	7 SMD22	8 VCC SM	9 SM CKE3	10 SMD19	11 SMD49	12 VCC SM	13 SM CKE0	14 vss
4		SM CLEI	vee	SMD20	SMD40	vec	SMD22	SMD52	VCC	SMD52	SMD50	vec_am	Vec	SM CLF2
В		SM_CLKI	V55	SMD30	SMD60	V55	55055	SMD55	V55	SMD52	SMD50	v 55	v55	SM_CLK2
С	H_ADS#	GTL_ RCOMP	VSS	SMD31	SMD28	SMD58	SMD24	SMD21	SM_CK E1	SMD20	SMD18	SMD16	SM_CKE2	SMA12
D	H_HITM#	vss	H_HIT#	SMD63	VCC_SM	SMD29	SMD59	VCC_SM	SMD54	SMD17	VCC_SM	SM_DQM3	SM_DQM2	VCC_SM
Е	H_BNR#	VTT	H_A4#	vss	SM_VREF1	SMD61	vss	SMD25	SMD23	vss	NC	VCC_SM	vss	vss
F	H_A8#	H_A9#	H_A11#	H_DRDY#	VTT	SM_RCOMP	VCCQ_SM	SMD27	SMD56	SMD51	SMD48	NC	SM_DQM7	SM_DQM6
G	H_A13#	vss	H_A5#	H_TRDY#	H_DBSY#	H_RS2#	VCCA_ CPLL	VSSA_CPLL	vss	VCC_SM	VCC_SM		·	
Н	H_A15#	H_A3#	H_A28#	H_RS1#	vss	H_RS0#	vcc					1		
J	H_A25#	H_A19#	H_A10#	H_DEFER#	VTT	H_LOCK#	GTL_REFA							
K	H_A22#	vss	H_A31#	H_REQ3#	H_REQ2#	H_REQ0#	vcc	Í						
L	H_A24#	H_A20#	H_A23#	H_BPRI#	vss	H_REQ4#	vcc	İ						
М	H_A30#	H_A18#	H_A29#	H_REQ1#	VTT	H_A7#		÷				vss	vss	vcc
N	H_A26#	vss	H_D6#	H_A6#	H_A14#	vcc						vss	vss	vss
Р	H_D1#	H_D15#	H_D9#	H_A16#	vss	H_A12#						vcc	vss	vss
R	H_D5#	H_D17#	H_D10#	H_A21#	VTT	CPU_RST#	Ī					vcc	vss	vss
Т	H_D18#	vss	H_D14#	H_A17#	H_A27#	vcc						vcc	vss	vss
U	H_D11#	H_D3#	H_D20#	H_D0#	vss	H_D4#						vss	vss	vss
v	H_D24#	H_D30#	H_D16#	H_D8#	VTT	H_D12#						vss	vss	VDD_LM
W	H_D23#	vss	H_D19#	H_D13#	H_D7#	H_D2#	vcc	Ī						
Y	H_D25#	H_D32#	H_D31#	H_D21#	vss	H_D26#	vcc							
AA	H_D34#	H_D38#	H_D22#	H_D33#	VTT	H_D35#	GTL_REFB							
AB	H_D36#	vss	H_D39#	H_D28#	H_D29#	H_D43#	vcc	-						
AC	H_D45#	H_D42#	H_D49#	H_D37#	vss	H_D44#	vss	VCC_CMOS	VCC_CMOS	VCC_LM	VCC_LM	1		
AD	H_D41#	H_D40#	H_D27#	H_D47#	VTT	H_D48#	VSSA_HPLL	vss	vss	VSS	VCC_LM	VCC_LM	VCC_LM	RAMREF [0] RESERVED
AE	H_D59#	vss	H_D52#	H_D57#	H_D51#	VCCA_ HPLL	VCC_CMOS	vss	vss	vss	vss	vss	vss	RAMREF [1] RESERVED
AF	H_D63#	H_D55#	H_D46#	H_D54#	vss	VCC_CM OS	SCK RESERVED	vss	VSS	VSS	vss	vss	vss	vss
AG	H_D58#	H_D53#	H_D62#	H_D60#	VTT	GCLK	VSS	DQB7 RESERVED	DQB5 RESERVED	DQB3 RESERVED	RQ0	RQ2 RESERVED	RQ4 RESERVED	RQ6 RESERVED
AH		vss	H_D50#	H_D61#	HTCLK#	vss	CMD RESERVED	vss	vss	DQB1 RESERVED	VSS	vss	RQ3	vss
AJ		I	H_D56#	HTCLK	vss	GM_RCLK RESERVED	SIO	DQB6	DQB4	DQB2	DQB0	RQ1 RESERVED	RQ5 RESERVED	RQ7 RESERVED
	1	2	3	4	5	6	7	RESERVED 8	9	10	11	12	13	14

Figure 18. Intel 830MP Ballout Diagram (Left)

Figure 19. Intel 830MP Ballout (Right)

15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	
SM_ CLK0	SMA10	SMA9	SMA4	SMA5	SMA0	SMWE	SMD47	SMD44	SM_OCLK	SMD41	SMD38	SMD4			A
vss	SMBA0	SMA8	vss	SMA2	SMA1	vss	SMD15	SMD12	vss	SMD9	SMD5	vss	SMD34	I	В
SMA11	SMBA1	SMA6	SMA7	SMA3	SMRAS	vss	SMD13	SMD10	SM_R CLK	SMD7	SMD36	SMD3	SMD33	SMD1	С
SM_CS3#	SM_CS2#	VCC_SM	SMDQM1	SMCAS	VCC_SM	SMD46	SMD43	VCC_SM	SMD39	SMD37	VCC_SM	SMD2	vss	SMD0	D
VCCQ_ SM	vss	SM_CS0#	SMDQM4	vss	NC	SMD14	vss	SMD8	SMD6	vss	SMD35	SMD32	HL7	HL6	Е
VCCQ_ SM	SM_CS1#	SMDQM5	SMDQM0	vss	NC	SMD4 5	SMD11	SMD40	SM_VREF0	VCCA_ PLL1 RESERVED	VCC_HUB	HL5	HLSTRB#	HL4	F
				VCCQ_SM	VCCQ_SM	vss	SMD42	VCC_SM	VSSA_ DPLL1	HL8	HL0	HL9	vss	HLSTRB	G
				ļ	1			vcc	HLREF	vss	HL10	HL3	HL1	HL2	н
								HRCOMP	VCC_HUB	AGPREF	VCC_ AGP	G_AD5	G_AD1	G_AD0	J
								vcc	AGP_ RCOMP	G_AD3	G_AD2	G_AD7	vss	G_AD6	К
								VCC_AGP	G_AD10	vss	G_AD4	G_CBE0#	AD_STB0#	AD_STB0	L
vcc	vcc	vss	vss						VCC	G_AD13	VCC_ AGP	G_AD11	G_AD9	G_AD8	М
vss	vss	vss	VSS						VCCQ_AGP	G_STOP#	G_AD14	G_AD15	vss	G_AD12	N
VSS	vss	vss	VCC						vcc	vss	G_IRDY#	G_TRDY#	G_PAR	G_CBE1#	Р
vss	vss	vss	VCC						G_AD17	G_AD16	VCC_ AGP	G_CBE2#	G_DEVSEL#	G_FRAME#	R
vss	vss	vss	VCC						vcc	G_CBE3#	G_AD20	G_AD19	vss	G_AD18	Т
vss	vss	vss	vss						VCC_AGP	vss	G_AD24	G_AD21	AD_STB1#	AD_STB1	U
VDD_LM	VDD_LM	vss	vss						vcc	G_AD27	VCC_ AGP	G_AD22	G_AD23	G_AD25	v
	•			•				VDDQ_AGP	SBA6	G_AD29	G_AD28	G_AD30	vss	G_AD26	w
								vcc	SBA3	vss	SBA5	SBA4	SBA7	G_AD31	Y
								VCC_AGP	SBA1	SBA2	VCC_ AGP	SB_STB	SB_STB#	SBA0	AA
								vss	RESET#	RBF#	PIPE#	ST2	vss	WBF#	AB
				DREFCLK RESERVED	VCCA_ DPLL0 RESERVED	VCC_DVO	DVOA_ RCOMP RESERVED	vss	AGPBUSY#	I2C_ DATA RESERVED	vss	REQ#	ST0	ST1	AC
VDD_LM	VDD_LM	VCC_LM	VCC_LM	VCC_LM	DVOA_CLK INT RESERVED	DVOA_ BLANK#	vss	VCC_GPIO	GBOUT	I2C_CLK RESERVED	DDC2_DA	DDC1_DA	HSYNC	G_GNT#	AD
	VDD_LM	vss	VCC_LM	vss	VSSA_DPLL 0	RESERVED DVOA_ INTR# RESERVED	DVOA_FLD /STL RESERVED	DVOA_D6 RESERVED	DVOA_D7 RESERVED	VCC_ GPIO	DDC2_CK RESERVED	DDC1_CK RESERVED	vss	VSYNC RESERVED	AE
VDD_LM	1	vss	vss	vss	vss	VCC_DVO	DVOA_HSYNC	DVOA_VSYNC	VCC_DVO	vss	VCCA_ DAC	vss	RED#	RED	AF
VDD_LM	vss				ļ	VSS	RESERVED DVOA D2	RESERVED DVOA_D5	DVOA_CLK	DVO_D10	GBIN	VCCA_	RESERVED GREEN#	RESERVED GREEN	AC
VDD_LM VSS VSS	vss vss	DQA0	DQA2	DQA4	DQA6				#	1		DAC	PROPERTY		AU
VDD_LM VSS VSS	vss vss	DQA0 RESERVED	DQA2 RESERVED	DQA4 RESERVED	DQA6 RESERVED		RESERVED	RESERVED	RESERVED	RESERVED			RESERVED	RESERVED	
VDD_LM VSS VSS CTM RESERVED	VSS VSS CFM# RESERVED	DQA0 RESERVED VSS	DQA2 RESERVED VSS	DQA4 RESERVED VSS	DQA6 reserved VSS	vss	RESERVED DVOA_D1 RESERVED	RESERVED DVOA_D4 RESERVED	RESERVED	RESERVED DVO_D9 RESERVED	VSSA_DAC	BLUE# RESERVED	BLUE RESERVED	RESERVED	AH

7.2 Intel 830M Chipset GMCH-M Ballout Diagram

Figure 20 and Figure 21 show the ballout of the Intel 830M Chipset.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14
A			SM_CLK3	SMD62	SMD26	SMD57	SMD22	VCC_SM	SM_CKE3	SMD19	SMD49	VCC_SM	SM_CKE0	vss
В		SM_CLK1	vss	SMD30	SMD60	vss	SMD55	SMD53	vss	SMD52	SMD50	vss	vss	SM_CLK2
С	H_ADS#	GTL_ RCOMP	vss	SMD31	SMD28	SMD58	SMD24	SMD21	SM_CK E1	SMD20	SMD18	SMD16	SM_CKE2	SMA12
D	H_HITM#	vss	H_HIT#	SMD63	VCC_SM	SMD29	SMD59	VCC_SM	SMD54	SMD17	VCC_SM	SM_DQM3	SM_DQM2	VCC_SM
E	H_BNR#	VTT	H_A4#	vss	SM_VREF1	SMD61	vss	SMD25	SMD23	vss	NC	VCC_SM	vss	vss
F	H_A8#	H_A9#	H_A11#	H_DRDY#	VTT	SM_RCOMP	VCCQ_SM	SMD27	SMD56	SMD51	SMD48	NC	SM_DQM7	SM_DQM6
G	H_A13#	vss	H_A5#	H_TRDY#	H_DBSY#	H_RS2#	VCCA_ CPLL	VSSA_CPLL	vss	VCC_SM	VCC_SM		•	
Н	H_A15#	H_A3#	H_A28#	H_RS1#	vss	H_RS0#	vcc			•	+	+		
J	H_A25#	H_A19#	H_A10#	H_DEFER#	VTT	H_LOCK#	GTL_REFA							
K	H_A22#	vss	H_A31#	H_REQ3#	H_REQ2#	H_REQ0#	vcc	Ĩ						
L	H_A24#	H_A20#	H_A23#	H_BPRI#	vss	H_REQ4#	vcc	+						
М	H_A30#	H_A18#	H_A29#	H_REQ1#	VTT	H_A7#		+				vss	vss	vcc
N	H_A26#	vss	H_D6#	H_A6#	H_A14#	vcc						vss	vss	vss
Р	H_D1#	H_D15#	H_D9#	H_A16#	vss	H_A12#	Ī					vcc	vss	vss
R	H_D5#	H_D17#	H_D10#	H_A21#	VTT	CPU_RST#	Ī					vcc	vss	vss
Т	H_D18#	vss	H_D14#	H_A17#	H_A27#	vcc	İ					vcc	vss	vss
U	H_D11#	H_D3#	H_D20#	H_D0#	vss	H_D4#						vss	vss	vss
v	H_D24#	H_D30#	H_D16#	H_D8#	VTT	H_D12#						vss	vss	VDD_LM
W	H_D23#	vss	H_D19#	H_D13#	H_D7#	H_D2#	vcc	1						•
Y	H_D25#	H_D32#	H_D31#	H_D21#	vss	H_D26#	vcc	-						
AA	H_D34#	H_D38#	H_D22#	H_D33#	VTT	H_D35#	GTL_REFB							
AB	H_D36#	vss	H_D39#	H_D28#	H_D29#	H_D43#	vcc	-						
AC	H_D45#	H_D42#	H_D49#	H_D37#	vss	H_D44#	vss	VCC_CMOS	VCC_CMOS	VCC_LM	VCC_LM	Ī		
AD	H_D41#	H_D40#	H_D27#	H_D47#	VTT	H_D48#	VSSA_HPLL	vss	vss	vss	VCC_LM	VCC_LM	VCC_LM	RAMREF [0] RESERVED
AE	H_D59#	vss	H_D52#	H_D57#	H_D51#	VCCA_ HPLL	VCC_CMOS	vss	vss	vss	vss	vss	vss	RAMREF [1] RESERVED
AF	H_D63#	H_D55#	H_D46#	H_D54#	vss	VCC_CM OS	SCK RESERVED	vss	vss	vss	vss	vss	vss	vss
AG	H_D58#	H_D53#	H_D62#	H_D60#	VTT	GCLK RESERVED	vss	DQB7 RESERVED	DQB5 RESERVED	DQB3 RESERVED	RQ0 RESERVED	RQ2 RESERVED	RQ4 RESERVED	RQ6 RESERVED
ΑH		vss	H_D50#	H_D61#	HTCLK#	vss	CMD RESERVED	vss	vss	DQB1 RESERVED	vss	vss	RQ3 RESERVED	vss
AJ			H_D56#	HTCLK	vss	GM_RCLK RESERVED	SIO RESERVED	DQB6 RESERVED	DQB4 RESERVED	DQB2 RESERVED	DQB0 RESERVED	RQ1 reserved	RQ5 RESERVED	RQ7 RESERVED
	1	2	3	4	5	6	7	8	9	10	11	12	13	. 14

Figure 20. Intel 830M Chipset Ballout Diagram (Left)

15	16	17	18	19	20	21	22	23	24	25	26	27	28	29	
SM_ CLK0	SMA10	SMA9	SMA4	SMA5	SMA0	SMWE	SMD47	SMD44	SM_OCLK	SMD41	SMD38	SMD4			А
VSS	SMBA0	SMA8	vss	SMA2	SMA1	VSS	SMD15	SMD12	vss	SMD9	SMD5	vss	SMD34	I	В
SMA11	SMBA1	SMA6	SMA7	SMA3	SMRAS	vss	SMD13	SMD10	SM_R CLK	SMD7	SMD36	SMD3	SMD33	SMD1	С
SM_CS3#	SM_CS2#	VCC_SM	SMDQM1	SMCAS	VCC_SM	SMD46	SMD43	VCC_SM	SMD39	SMD37	VCC_SM	SMD2	VSS	SMD0	D
VCCQ_ SM	vss	SM_CS0#	SMDQM4	vss	NC	SMD14	vss	SMD8	SMD6	vss	SMD35	SMD32	HL7	HL6	E
VCCQ_ SM	SM_CS1#	SMDQM5	SMDQM0	vss	NC	SMD4 5	SMD11	SMD40	SM_VREF0	VCCA_ PLL1	VCC_HUB	HL5	HLSTRB#	HL4	F
			1	VCCQ_SM	VCCQ_SM	VSS	SMD42	VCC_SM	VSSA_ DPLL1	HL8	HL0	HL9	vss	HLSTRB	G
				ł	•		L	vcc	HLREF	vss	HL10	HL3	HL1	HL2	Н
								HRCOMP	VCC_HUB	AGPREF/ DVOBC_REF	VCC_ AGP	G_AD5/ DVOB_D2	G_AD1/ DVOB_VSYNC	G_AD0/ DVOB_HSYNC	J
								vcc	AGP_ RCOMP	G_AD3/ DVOB_D0	G_AD2/ DVOB_D1	G_AD7/ DVOB_D4	vss	G_AD6/ DVOB_D5	K
								VCC_AGP	G_AD10/ DVOB_D8	vss	G_AD4/ DVOB_D3	G_CBE0#/ DVOB_D7	AD_STB0#/ DVOB_CLK#	AD_STB0/ DVOB_CLK	L
vcc	vcc	vss	vss						vcc	G_AD13/ DVOBC_C LKINT#	VCC_ AGP	G_AD11/ DVOB_D11	G_AD9/ DVOB_D9	G_AD8/ DVOB_D6	М
vss	vss	vss	vss						VCCQ_AGP	G_STOP#	G_AD14/ DVOB_FL D/STL	G_AD15	vss	G_AD12/ DVOB_D10	N
VSS	VSS	vss	vcc						vcc	vss	G_IRDY#/ M_I2C_C LK	G_TRDY#/ M_DDC1_ CLK	G_PAR	G_CBE1#/ DVOB_BL ANK#	Р
VSS	VSS	vss	vcc						G_AD17/ DVOC_ HSYNC	G_AD16/ DVOC_ VSYNC	VCC_ AGP	G_CBE2#	G_DEVSEL#/ M_I2C_ DATA	G_FRAME#/ M_DDC1_ DATA	R
VSS	VSS	vss	vcc						vcc	G_CBE3#/ DVOC_D5	G_AD20/ DVOC_D1	G_AD19/ DVOC_D0	vss	G_AD18/ DVOC_BL ANK#	Т
VSS	vss	vss	vss						VCC_AGP	vss	G_AD24/ DVOC_D7	G_AD21/ DVOC_D2	AD_STB1#/ DVOC_CLK#	AD_STB1/ DVOC_CLK	U
VDD_LM	VDD_LM	vss	vss						vcc	G_AD27/ DVOC_D8	VCC_ AGP	G_AD22/ DVOC_D3	G_AD23/ DVOC_D4	G_AD25/ DVOC_D6	v
								VDDQ_AGP	SBA6	G_AD29/ DVOC_D10	G_AD28/ DVOC_D11	G_AD30/ DVOBC_INTR#/ DPMS_CLK	vss	G_AD26/ DVOC_D9	W
								VCC	SBA3	vss	SBA5	SBA4	SBA7	G_AD31/ DVOC_FLD/ STL	Y
								VCC_AGP	SBA1	SBA2	VCC_ AGP	SB_STB	SB_STB#	SBA0	AA
				,	,			vss	RESET#	RBF#	PIPE#	ST2	vss	WBF#	AF
				DREFCLK RESERVED	VCCA_ DPLL0	VCC_DVO	DVOA_ RCOMP	vss	AGPBUSY#	I2C_ DATA	vss	REQ#	ST0	STI	AC
VDD_LM	VDD_LM	VCC_LM	VCC_LM	VCC_LM	DVOA_CLK INT	DVOA_ BLANK#	vss	VCC_GPIO	GBOUT	I2C_CLK	DDC2_DA	DDC1_DA	HSYNC	G_GNT#	AI
VDD_LM	VDD_LM	vss	VCC_LM	vss	VSSA_DPLL 0	DVOA_ INTR#	DVOA_FLD /STL	DVOA_D6	DVOA_D7	VCC_ GPIO	DDC2_CK	DDC1_CK	vss	VSYNC	AF
vss	VSS	vss	vss	vss	vss	VCC_DVO	DVOA_HSYNC	DVOA_VSYNC	VCC_DVO	vss	VCCA_ DAC	vss	RED#	RED	AF
vss	VSS	DQA0 RESERVED	DQA2 RESERVED	DQA4 reserved	DQA6 reserved	VSS	DVOA_D2	DVOA_D5	DVOA_CLK #	DVOA_D10	GBIN	VCCA_ DAC	GREEN#	GREEN	AC
CTM RESERVED	CFM# RESERVED	vss	vss	vss	VSS	VSS	DVOA_D1	DVOA_D4	vss	DVOA_D9	VSSA_DAC	BLUE#	BLUE		Ał
CTM#	CFM	DQA1	DQA3	DQA5	DQA7	vss	DVOA_D0	DVOA_D3	DVOA_CLK	DVOA_D8	DVOA_D11	REFSET		-	A.

Figure 21. Intel 830M Chipset Ballout Diagram (Right)

7.3 Intel 830MG GMCH-M Ballout Diagram

Figure 22 and Figure 23 show the ballout of the Intel 830MG Chipset.

	1	2	3	4	5	6	7	8	9	10	11	12	13	14
А			SM_CLK3	SMD62	SMD26	SMD57	SMD22	VCC_SM	SM_CKE3	SMD19	SMD49	VCC_SM	SM_CKE0	vss
В		SM_CLK1	vss	SMD30	SMD60	vss	SMD55	SMD53	vss	SMD52	SMD50	vss	vss	SM_CLK2
С	H_ADS#	GTL_ RCOMP	vss	SMD31	SMD28	SMD58	SMD24	SMD21	SM_CK E1	SMD20	SMD18	SMD16	SM_CKE2	SMA12
D	H_HITM#	vss	H_HIT#	SMD63	VCC_SM	SMD29	SMD59	VCC_SM	SMD54	SMD17	VCC_SM	SM_DQM3	SM_DQM2	VCC_SM
Е	H_BNR#	VTT	H_A4#	vss	SM_VREF1	SMD61	vss	SMD25	SMD23	vss	NC	VCC_SM	vss	vss
F	H_A8#	H_A9#	H_A11#	H_DRDY#	VTT	SM_RCOMP	VCCQ_SM	SMD27	SMD56	SMD51	SMD48	NC	SM_DQM7	SM_DQM6
G	H_A13#	VSS	H_A5#	H_TRDY#	H_DBSY#	H_RS2#	VCCA_ CPLL	VSSA_CPLL	VSS	VCC_SM	VCC_SM	-		
н	H_A15#	H_A3#	H_A28#	H_RS1#	vss	H_RS0#	vcc				•	÷		
J	H_A25#	H_A19#	H_A10#	H_DEFER#	VTT	H_LOCK#	GTL_REFA	Ť						
к	H_A22#	vss	H_A31#	H_REQ3#	H_REQ2#	H_REQ0#	vcc	t						
L	H_A24#	H_A20#	H_A23#	H_BPRI#	vss	H_REQ4#	vcc	t						
М	H_A30#	H_A18#	H_A29#	H_REQ1#	VTT	H_A7#		ł				vss	vss	vcc
N	H_A26#	vss	H_D6#	H_A6#	H_A14#	vcc	1					vss	vss	vss
Р	H_D1#	H_D15#	H_D9#	H_A16#	vss	H_A12#	-					vcc	vss	vss
R	H_D5#	H_D17#	H_D10#	H_A21#	VTT	CPU_RST#						vcc	vss	vss
т	H_D18#	vss	H_D14#	H_A17#	H_A27#	vcc	t					vcc	vss	vss
U	H_D11#	H_D3#	H_D20#	H_D0#	vss	H_D4#						vss	vss	vss
v	H_D24#	H_D30#	H_D16#	H_D8#	VTT	H_D12#						vss	vss	VDD_LM
w	H_D23#	VSS	H_D19#	H_D13#	H_D7#	H_D2#	vcc	Ī						
Y	H_D25#	H_D32#	H_D31#	H_D21#	vss	H_D26#	vcc	-						
AA	H_D34#	H_D38#	H_D22#	H_D33#	VTT	H_D35#	GTL_REFB	-						
AB	H_D36#	vss	H_D39#	H_D28#	H_D29#	H_D43#	vcc							
AC	H_D45#	H_D42#	H_D49#	H_D37#	vss	H_D44#	vss	VCC_CMOS	VCC_CMOS	VCC_LM	VCC_LM	I		
AD	H_D41#	H_D40#	H_D27#	H_D47#	VTT	H_D48#	VSSA_HPLL	vss	vss	vss	VCC_LM	VCC_LM	VCC_LM	RAMREF [0] RESERVED
AE	H_D59#	vss	H_D52#	H_D57#	H_D51#	VCCA_ HPLL	VCC_CMOS	vss	vss	vss	vss	vss	vss	RAMREF [1] RESERVED
AF	H_D63#	H_D55#	H_D46#	H_D54#	vss	VCC_CM OS	SCK RESERVED	vss	vss	vss	vss	vss	vss	vss
AG	H_D58#	H_D53#	H_D62#	H_D60#	VTT	GCLK RESERVED	vss	DQB7 RESERVED	DQB5 RESERVED	DQB3 RESERVED	RQ0 RESERVED	RQ2 RESERVED	RQ4 RESERVED	RQ6 RESERVED
AH		vss	H_D50#	H_D61#	HTCLK#	vss	CMD RESERVED	vss	vss	DQB1 RESERVED	vss	vss	RQ3 RESERVED	vss
AJ			H_D56#	HTCLK	vss	GM_RCLK RESERVED	SIO RESERVED	DQB6 RESERVED	DQB4 RESERVED	DQB2 RESERVED	DQB0 RESERVED	RQ1 RESERVED	RQ5 RESERVED	RQ7 RESERVED
1					·	·	. 7	0	0	10	11	10	12	1.4

Figure 22. Intel 830MG Chipset Ballout Diagram (Left)

Figure 23. Intel 830MG Chipset Ballout Diagram (Right)

	29	28	27	26	25	24	23	22	21	20	19	18	17	16	15
А			SMD4	SMD38	SMD41	SM_OCLK	SMD44	SMD47	SMWE	SMA0	SMA5	SMA4	SMA9	SMA10	SM_ CLK0
В		SMD34	vss	SMD5	SMD9	vss	SMD12	SMD15	vss	SMA1	SMA2	vss	SMA8	SMBA0	vss
С	SMD1	SMD33	SMD3	SMD36	SMD7	SM_ICLK	SMD10	SMD13	vss	SMRAS	SMA3	SMA7	SMA6	SMBA1	SMA11
D	SMD0	vss	SMD2	VCC_SM	SMD37	SMD39	VCC_SM	SMD43	SMD46	VCC_SM	SMCAS	SMDQM1	VCC_SM	SM_CS2#	SM_CS3#
Е	HL6	HL7	SMD32	SMD35	VSS	SMD6	SMD8	vss	SMD14	NC	VSS	SMDQM4	SM_CS0#	vss	VCCQ_ SM
F	HL4	HLSTRB#	HL5	VCC_HUB	VCCA_ PLL1	SM_VREF0	SMD40	SMD11	SMD4	NC	vss	SMDQM0	SMDQM5	SM_CS1#	VCCQ_ SM
G	HLSTRB	vss	HL9	HL0	HL8	VSSA_ DPLL1	VCC_SM	SMD42	VSS	VCCQ_SM	VCCQ_SM				
н	HL2	HL1	HL3	HL10	vss	HLREF	vcc					l			
J	DVOB_ HSYNC	DVOB_ VSYNC	DVOB_ D2	VCC_AGP	DVOBC_REF	VCC_HUB	HRCOMP								
К	DVOB_ D5	VSS	DVOB_ D4	DVOB_ D1	DVOB_ D0	DVOBC_ RCOMP	VCC								
L	DVOB_ CLK	DVOB_ CLK#	DVOB_ D7	DVOB_ D3	vss	DVOB_ D8	VCC_AGP								
М	DVOB_ D6	DVOB_ D9	DVOB_ D11	VCC_AGP	DVOBC_ CLKINT#	VCC						vss	vss	vcc	vcc
N	DVOB_ D10	vss	G_AD15	DVOB_ FLD/ STL	G_STOP#	VCCQ_AGP						vss	vss	vss	vss
Р	DVOB_ BLANK#	G_PAR	M_DDC1_ CLK	M_I2C _CLK	VSS	VCC						vcc	vss	vss	vss
R	M_DDC1_ DATA	M_I2C_ DATA	G_CBE2#	VCC_ AGP	DVOC_ VSYNC	DVOC_ HSYNC						vcc	vss	vss	vss
Т	DVOC_ BLANK#	vss	DVOC_ D0	DVOC_ D1	DVOC_ D5	VCC						vcc	vss	vss	vss
U	DVOC_ CLK	DVOC_ CLK#	DVOC_ D2	DVOC_ D7	VSS	VCC_AGP						vss	vss	vss	vss
v	DVOC_ D6	DVOC_ D4	DVOC_ D3	VCC_AGP	DVOC_ D8	vcc						vss	vss	VDD_LM	VDD_LM
w	DVOC_ D9		DVOBC_IN R# / DPMS_CLF	DVOC_ D11	DVOC_ D10	SBA6	VDDQ_AGP								
Y	DVOC_ FLD/ STL	SBA7	SBA4	SBA5	vss	SBA3	VCC								
AA	SBA0	SB_STB#	SB_STB	VCC_AGP	SBA2	SBA1	VCC_AGP								
AB	WBF#	vss	ST2	PIPE#	RBF#	RESET#	vss								
AC	ST1	ST0	REQ#	VSS	I2C_ DATA	AGPBUSY#	P VSS	DVOA_RCOM	VCC_DVO	VCCA_ DPLL0	DREFCLK				
AD	G_GNT#	HSYNC	DDC1_DA	DDC2_DA	12C_CLK	GBOUT	VCC_GPIO	vss	DVOA_ BLANK#	DVOA_ CLKINT	VCC_LM	VCC_LM	VCC_LM	VDD_LM	VDD_LM
AE	VSYNC	VSS	DDC1_CK	DDC2_CK	VCC_ GPIO	DVOA_D7	DVOA_D6	#DVOA_FLD/ STL	DVOA_INT	VSSA_DPLI 0	VSS	VCC_LM	VSS	VDD_LM	VDD_LM
AF	RED	RED#	VSS	VCCA_ DAC	VSS	C VCC_DVO	DVOA_VSYN	DVOA_HSYNO	VCC_DVO	VSS	VSS	vss	VSS	vss	vss
AG	GREEN	GREEN#	VCCA_ DAC) GBIN	#DVOA_D10	DVOA_CLK#	DVOA_D5	DVOA_D2	vss	DQA6 reserved	DQA4 reserved	DQA2 reserved	DQA0 reserved	vss	vss
AH		BLUE	BLUE#	VSSA_DAC	DVOA_D9	VSS	DVOA_D4	DVOA_D1	VSS	vss	VSS	VSS	vss	CFM# RESERVED	CTM reserved
	•	•	REFSET	DVO_D11	DVOA_D8	DVOA CLK	DVOA D3	DVOA D0	VSS	DQA7	DQA5	DQA3	DQA1	CFM	CTM#
7.4 Intel 830MP GMCH-M Signal List

Table 60 provides an alphabetical signal listing of 830MP Chipset GMCH-M ballouts.

Table 60. Intel 830MP Chipset Ballout Signal Name List

Ball #	Signal Name
L29	AD_STB0
L28	AD_STB0#
U29	AD_STB1
U28	AD_STB1#
C1	ADS#
AC24	AGPBUSY#
K24	AGP_RCOMP
J25	AGPREF
AH28	BLUE [RESERVED]
AH27	BLUE# [RESERVED]
E1	BNR#
L4	BPRI#
AJ16	CFM [RESERVED]
AH16	CFM# [RESREVED]
AH7	CMD [RESERVED]
R6	CPURST#
AH15	CTM [RESERVED]
AJ15	CTM# [RESERVED]
G5	DBSY#
AE27	DDC1_CLK [RESREVED]
AD27	DDC1_DATA [RESERVED]
AE26	DDC2_CLK [RESREVED]
AD26	DDC2_DATA [RESREVED]
J4	DEFER#
AG17	DQ_A0 [RESERVED]
AJ17	DQ_A1 [RESERVED]
AG18	DQ_A2 [RESERVED]
AJ18	DQ_A3 [RESERVED]

Ball #	Signal Name
AG19	DQ_A4 [RESERVED]
AJ19	DQ_A5 [RESERVED]
AG20	DQ_A6 [RESERVED]
AJ20	DQ_A7 [RESERVED]
AJ11	DQ_B0 [RESERVED]
AH10	DQ_B1 [RESERVED]
AJ10	DQ_B2 [RESERVED]
AG10	DQ_B3 [RESERVED]
AJ9	DQ_B4 [RESERVED]
AG9	DQ_B5 [RESERVED]
AJ8	DQ_B6 [RESERVED]
AG8	DQ_B7 [RESERVED]
F4	DRDY#
AC19	DREFCLK [RESERVED]
AD20	DV0A_CLKINT [RESERVED]
AD21	DVOA_BLANK# [RESERVED]
AG24	DVOA_CLK# [RESERVED]
AJ24	DVOA_CLK [RESERVED]
AJ22	DVOA_D0 [RESERVED]
AH22	DVOA_D1 [RESERVED]
AG25	DVOA_D10 [RESERVED]
AJ26	DVOA_D11 [RESERVED]
AG22	DVOA_D2 [RESERVED]

intel

Ball #	Signal Name
AJ23	DVOA_D3 [RESERVED]
AH23	DVOA_D4 [RESERVED]
AG23	STRAP[0]]
AE23	DVOA_D6 [RESERVED]
AE24	STRAP[1]
AJ25	STRAP[2]
AH25	DVOA_D9 [RESERVED]
AE22	DVOA_FLD/STL [RESERVED]
AF22	DVOA_HSYNC [RESERVED]
AE21	DVOA_INTR# [RESERVED]
AC22	DVOA_RCOMP [RESERVED]
AF23	DVOA_VSYNC [RESERVED]
J29	G_AD0
J28	G_AD1
L24	G_AD10
M27	G_AD11
N29	G_AD12
M25	G_AD13
N26	G_AD14
N27	G_AD15
R25	G_AD16
R24	G_AD17
T29	G_AD18
T27	G_AD19
K26	G_AD2
T26	G_AD20
U27	G_AD21
V27	G_AD22
V28	G_AD23
U26	G_AD24
V29	G_AD25

Ball #	Signal Name
W29	G_AD26
V25	G_AD27
W26	G_AD28
W25	G_AD29
K25	G_AD3
W27	G_AD30
Y29	G_AD31
L26	G_AD4
J27	G_AD5
K29	G_AD6
K27	G_AD7
M29	G_AD8
M28	G_AD9
L27	G_C/BE0#
P29	G_C/BE1#
R27	G_C/BE2#
T25	G_C/BE3#
R28	G_DEVSEL#
R29	G_FRAME#
AD29	G_GNT#
P26	G_IRDY#
P28	G_PAR
AC27	G_REQ#
N25	G_STOP#
P27	G_TRDY#
AG26	GBIN
AD24	GBOUT
AG6	GM_GCLK [RESERVED]
AJ6	GM_RCLK [RESERVED]
AG29	GREEN [RESERVED]
AG28	GREEN# [RESERVED]
C2	GTL_RCOMP
J7	GTL_REFA
AA7	GTL_REFB

J3HA10#F3HA11#F3HA12#G1HA13#N5HA14#H1HA15#P4HA16#T4HA17#M2HA19#L2HA20#R4HA21#L1HA25#N1HA26#T5HA27#H3HA28#M3HA29#H2HA3#M1HA20#K3HA21#K3HA27#H2HA3#M1HA28#M3HA29#H2HA3#M1HA30#K3HA1#G3HA4#G3HA4#G3HA1#K3HA1#K3HA1#K4HO#V4HD1#V6HD12#W4HD13#T3HD14#	Ball #	Signal Name
F3 HA11# P6 HA12# G1 HA13# N5 HA14# H1 HA15# P4 HA16# T4 HA17# M2 HA19# L2 HA20# R4 HA21# K1 HA22# L3 HA23# L1 HA26# J1 HA26# J1 HA26# M3 HA29# H2 HA3# M3 HA29# K3 HA45# G3 HA4# G3 HA4# G3 HA5# F1 HA8# F2 HA9# U4 HD0# P1 HD1# K3 HD10# V6 HD12# W4 HD13#	J3	HA10#
P6 HA12# G1 HA13# N5 HA14# N5 HA14# H1 HA15# P4 HA16# T4 HA17# M2 HA19# L2 HA20# R4 HA21# K1 HA22# L3 HA23# L1 HA26# J1 HA26# J1 HA26# M3 HA28# M3 HA29# H2 HA3# G3 HA4# G3 HA4# G3 HA5# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# M6 HA7# F2 HA9# U4 HD1# W4 HD13# W4 HD13#	F3	HA11#
G1HA13#N5HA14#H1HA15#P4HA16#T4HA17#M2HA19#L2HA20#R4HA21#L1HA24#J1HA26#T5HA27#H3HA28#M3HA29#H2HA3#M1HA29#K3HA41#G3HA4#G3HA4#F1HA6#M6HA7#F1HA8#F2HA9#U4HD1#R3HD10#W4HD13#Y4HD13#	P6	HA12#
N5HA14#H1HA15#P4HA16#T4HA17#M2HA18#J2HA19#L2HA20#R4HA21#L3HA23#L1HA25#N1HA26#T5HA27#H3HA28#M3HA29#H2HA3#K3HA4#G3HA4#G3HA4#F1HA6#M6HA7#F2HA9#U4HD1#R3HD1#W4HD13#T3HD14#	G1	HA13#
H1HA15#P4HA16#T4HA17#M2HA18#J2HA19#L2HA20#R4HA21#K1HA22#L3HA23#L1HA26#J1HA26#T5HA27#H3HA28#M3HA29#H2HA3#K3HA21#G3HA29#K3HA29#F1HA30#F2HA4#G3HA5#F1HA8#F2HA9#U4HD0#P1HD1#R3HD14#	N5	HA14#
P4HA16#T4HA17#M2HA18#J2HA19#L2HA20#R4HA21#K1HA22#L3HA23#L1HA26#T5HA27#H3HA28#M3HA29#H2HA3#K3HA3#G3HA5#N4HA6#F1HA8#F2HA9#U4HD1#R3HD10#V4HD13#V4HD13#V4HD14#	H1	HA15#
T4HA17#M2HA18#J2HA19#L2HA20#R4HA21#K1HA23#L3HA24#J1HA26#T5HA27#H3HA28#M3HA29#H2HA3#M1HA30#K3HA4#G3HA5#N4HA6#M6HA7#F1HA8#F2HA9#U4HD1#R3HD10#V4HD13#V4HD13#T3HD14#	P4	HA16#
M2 HA18# J2 HA19# L2 HA20# R4 HA21# K1 HA22# L3 HA23# L1 HA26# J1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V4 HD1# W4 HD1# W4 HD1# W4 HD1# W4 HD1# W4 HD1#	T4	HA17#
J2 HA19# L2 HA20# R4 HA21# K1 HA22# L3 HA23# L1 HA24# J1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# W4 HD13# W4 HD13#	M2	HA18#
L2 HA20# R4 HA21# K1 HA22# L3 HA23# L1 HA24# J1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA1# G3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V6 HD12# W4 HD13#	J2	HA19#
R4 HA21# K1 HA22# L3 HA23# L1 HA24# J1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V6 HD12# W4 HD13#	L2	HA20#
K1HA22#L3HA23#L1HA24#J1HA25#N1HA26#T5HA27#H3HA28#M3HA29#H2HA3#M1HA30#K3HA4#G3HA5#N4HA6#M6HA7#F1HA8#F2HA9#U4HD0#P1HD1#K3HD10#W4HD13#T3HD14#	R4	HA21#
L3 HA23# L1 HA24# J1 HA26# N1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V6 HD12# W4 HD13#	K1	HA22#
L1 HA24# J1 HA25# N1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA1# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# W4 HD13# T3 HD14#	L3	HA23#
J1 HA25# N1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA1# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V6 HD12# W4 HD13#	L1	HA24#
N1 HA26# T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V6 HD13# T3 HD14#	J1	HA25#
T5 HA27# H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# V6 HD12# W4 HD13#	N1	HA26#
H3 HA28# M3 HA29# H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD13# T3 HD14#	T5	HA27#
M3 HA29# H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD13# T3 HD14#	H3	HA28#
H2 HA3# M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD13# T3 HD14#	M3	HA29#
M1 HA30# K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# K3 HD10# U1 HD1# V6 HD13# T3 HD14#	H2	HA3#
K3 HA31# E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD12# W4 HD13# T3 HD14#	M1	HA30#
E3 HA4# G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD13# T3 HD14#	K3	HA31#
G3 HA5# N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD12# W4 HD13# T3 HD14#	E3	HA4#
N4 HA6# M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD1# V6 HD12# W4 HD13# T3 HD14#	G3	HA5#
M6 HA7# F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD12# V6 HD13# T3 HD14#	N4	HA6#
F1 HA8# F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD11# V6 HD12# W4 HD13# T3 HD14#	M6	HA7#
F2 HA9# U4 HD0# P1 HD1# R3 HD10# U1 HD11# V6 HD12# W4 HD13# T3 HD14#	F1	HA8#
U4 HD0# P1 HD1# R3 HD10# U1 HD11# V6 HD12# W4 HD13# T3 HD14#	F2	HA9#
P1 HD1# R3 HD10# U1 HD11# V6 HD12# W4 HD13# T3 HD14#	U4	HD0#
R3 HD10# U1 HD11# V6 HD12# W4 HD13# T3 HD14#	P1	HD1#
U1 HD11# V6 HD12# W4 HD13# T3 HD14#	R3	HD10#
V6 HD12# W4 HD13# T3 HD14#	U1	HD11#
W4 HD13# T3 HD14#	V6	HD12#
T3 HD14#	W4	HD13#
	Т3	HD14#

Ball #	Signal Name
P2	HD15#
V3	HD16#
R2	HD17#
T1	HD18#
W3	HD19#
W6	HD2#
U3	HD20#
Y4	HD21#
AA3	HD22#
W1	HD23#
V1	HD24#
Y1	HD25#
Y6	HD26#
AD3	HD27#
AB4	HD28#
AB5	HD29#
U2	HD3#
V2	HD30#
Y3	HD31#
Y2	HD32#
AA4	HD33#
AA1	HD34#
AA6	HD35#
AB1	HD36#
AC4	HD37#
AA2	HD38#
AB3	HD39#
U6	HD4#
AD2	HD40#
AD1	HD41#
AC2	HD42#
AB6	HD43#
AC6	HD44#
AC1	HD45#
AF3	HD46#
AD4	HD47#

Ball #	Signal Name
AD6	HD48#
AC3	HD49#
R1	HD5#
AH3	HD50#
AE5	HD51#
AE3	HD52#
AG2	HD53#
AF4	HD54#
AF2	HD55#
AJ3	HD56#
AE4	HD57#
AG1	HD58#
AE1	HD59#
N3	HD6#
AG4	HD60#
AH4	HD61#
AG3	HD62#
AF1	HD63#
W5	HD7#
V4	HD8#
P3	HD9#
D3	HIT#
D1	HITM#
J23	HL_RCOMP
H24	HLREF
G26	HL0
H28	HL1
H26	HL10
H29	HL2
H27	HL3
F29	HL4
F27	HL5
E29	HL6
E28	HL7
G25	HL8
G27	HL9

Ball #	Signal Name
J6	HLOCK#
G29	HLSTRB
F28	HLSTRB#
K6	HREQ0#
M4	HREQ1#
K5	HREQ2#
K4	HREQ3#
L6	HREQ4#
AD28	HSYNC [RESERVED]
AJ4	HTCLK
AH5	HTCLK#
G4	HTRDY#
AD25	I2C_CLK [RESERVED]
AC25	I2C_DATA [RESERVED]
E11	NC
E20	NC
F12	NC
F20	NC
AB26	PIPE#
AD14	RAM_REFA
AE14	RAM_REFB
AB25	RBF#
AF29	RED
AF28	RED#
AJ27	REFSET
AB24	RESET#
AG11	RQ0 [RESERVED]
AJ12	RQ1 [RESERVED]
AG12	RQ2 [RESERVED]
AH13	RQ3 [RESERVED]
AG13	RQ4 [RESERVED]
AJ13	RQ5 [RESERVED]
AG14	RQ6 [RESERVED]
AJ14	RQ7 [RESERVED]
H6	RS0#

Ball #	Signal Name
H4	RS1#
G6	RS2#
AA27	SB_STB
AA28	SB_STB#
AA29	SBA0
AA24	SBA1
AA25	SBA2
Y24	SBA3
Y27	SBA4
Y26	SBA5
W24	SBA6
Y28	SBA7
AF7	SCK [RESERVED]
AJ7	SIO [RESERVED]
B16	SM_BA0
C16	SM_BA1
D19	SM_CAS#
A13	SM_CKE0
C9	SM_CKE1
C13	SM_CKE2
A9	SM_CKE3
A15	SM_CLK0
B2	SM_CLK1
B14	SM_CLK2
A3	SM_CLK3
E17	SM_CS0#
F16	SM_CS1#
D16	SM_CS2#
D15	SM_CS3#
F18	SM_DQM0
D18	SM_DQM1
D13	SM_DQM2
D12	SM_DQM3
E18	SM_DQM4
F17	SM_DQM5
F14	SM_DQM6

Ball #	Signal Name
F13	SM_DQM7
A20	SM_MA0
B20	SM_MA1
A16	SM_MA10
C15	SM_MA11
C14	SM_MA12
B19	SM_MA2
C19	SM_MA3
A18	SM_MA4
A19	SM_MA5
C17	SM_MA6
C18	SM_MA7
B17	SM_MA8
A17	SM_MA9
D29	SM_MD0
C29	SM_MD1
C23	SM_MD10
F22	SM_MD11
B23	SM_MD12
C22	SM_MD13
E21	SM_MD14
B22	SM_MD15
C12	SM_MD16
D10	SM_MD17
C11	SM_MD18
A10	SM_MD19
D27	SM_MD2
C10	SM_MD20
C8	SM_MD21
A7	SM_MD22
E9	SM_MD23
C7	SM_MD24
E8	SM_MD25
A5	SM_MD26
F8	SM_MD27
C5	SM_MD28

Ball #	Signal Name
D6	SM_MD29
C27	SM_MD3
B4	SM_MD30
C4	SM_MD31
E27	SM_MD32
C28	SM_MD33
B28	SM_MD34
E26	SM_MD35
C26	SM_MD36
D25	SM_MD37
A26	SM_MD38
D24	SM_MD39
A27	SM_MD4
F23	SM_MD40
A25	SM_MD41
G22	SM_MD42
D22	SM_MD43
A23	SM_MD44
F21	SM_MD45
D21	SM_MD46
A22	SM_MD47
F11	SM_MD48
A11	SM_MD49
B26	SM_MD5
B11	SM_MD50
F10	SM_MD51
B10	SM_MD52
B8	SM_MD53
D9	SM_MD54
B7	SM_MD55
F9	SM_MD56
A6	SM_MD57
C6	SM_MD58
D7	SM_MD59
E24	SM_MD6
B5	SM_MD60

Ball #	Signal Name
E6	SM_MD61
A4	SM_MD62
D4	SM_MD63
C25	SM_MD7
E23	SM_MD8
B25	SM_MD9
A24	SM_OCLK
C20	SM_RAS#
C24	SM_RCLK
F6	SM_RCOMP
E5	SM_REFA
F24	SM_REFB
A21	SM_WE#
AC28	ST0
AC29	ST1
AB27	ST2
N6	VCC
T6	VCC
H7	VCC
K7	VCC
L7	VCC
W7	VCC
Y7	VCC
AB7	VCC
P12	VCC
R12	VCC
T12	VCC
M14	VCC
M15	VCC
M16	VCC
P18	VCC
R18	VCC
T18	VCC
H23	VCC
K23	VCC
Y23	VCC

Ball #	Signal Name
M24	VCC
P24	VCC
T24	VCC
V24	VCC
L23	VCC_AGP
U24	VCC_AGP
J26	VCC_AGP
M26	VCC_AGP
R26	VCC_AGP
V26	VCC_AGP
AA23	VCC_AGP
AA26	VCC_AGP
AC8	VCC_CMOS
AC9	VCC_CMOS
AE7	VCC_CMOS
AF6	VCC_CMOS
AC21	VCC_DVO
AF21	VCC_DVO
AF24	VCC_DVO
AD23	VCC_GPIO
AE25	VCC_GPIO
J24	VCC_HUB
F26	VCC_HUB
AC10	VCC_LM
AC11	VCC_LM
AD11	VCC_LM
AD12	VCC_LM
AD13	VCC_LM
AD17	VCC_LM
AD18	VCC_LM
AD19	VCC_LM
AE18	VCC_LM
D5	VCC_SM
D8	VCC_SM
D11	VCC_SM
G11	VCC_SM

Ball #	Signal Name
D14	VCC_SM
D17	VCC_SM
D20	VCC_SM
D23	VCC_SM
G23	VCC_SM
D26	VCC_SM
G10	VCC_SM
E12	VCC_SM
A8	VCC_SM
A12	VCC_SM
G7	VCCA_CPLL
AF26	VCCA_DAC
AG27	VCCA_DAC
AC20	VCCA_DPLL0
F25	VCCA_DPLL1
AE6	VCCA_HPLL
W23	VCCQ_AGP
N24	VCCQ_AGP
E15	VCCQ_SM
F7	VCCQ_SM
F15	VCCQ_SM
G19	VCCQ_SM
G20	VCCQ_SM
V14	VDD_LM
V15	VDD_LM
V16	VDD_LM
AD15	VDD_LM
AD16	VDD_LM
AE15	VDD_LM
AE16	VDD_LM
A14	VSS
B13	VSS
C3	VSS
C21	VSS
E14	VSS
F19	VSS

Ball #	Signal Name
D2	VSS
G2	VSS
K2	VSS
N2	VSS
T2	VSS
W2	VSS
AB2	VSS
AE2	VSS
AH2	VSS
B3	VSS
E4	VSS
H5	VSS
L5	VSS
P5	VSS
U5	VSS
Y5	VSS
AC5	VSS
AF5	VSS
AJ5	VSS
B6	VSS
AH6	VSS
E7	VSS
AC7	VSS
AG7	VSS
AD8	VSS
AE8	VSS
AF8	VSS
AH8	VSS
B9	VSS
G9	VSS
AD9	VSS
AE9	VSS
AF9	VSS
AH9	VSS
E10	VSS
AD10	VSS

Ball #	Signal Name
AE10	VSS
AF10	VSS
AE11	VSS
AF11	VSS
AH11	VSS
B12	VSS
M12	VSS
N12	VSS
U12	VSS
V12	VSS
AE12	VSS
AF12	VSS
AH12	VSS
E13	VSS
M13	VSS
N13	VSS
P13	VSS
R13	VSS
T13	VSS
U13	VSS
V13	VSS
AE13	VSS
AF13	VSS
N14	VSS
P14	VSS
R14	VSS
T14	VSS
U14	VSS
AF14	VSS
AH14	VSS
B15	VSS
N15	VSS
P15	VSS
R15	VSS
T15	VSS
U15	VSS

Ball #	Signal Name
AF15	VSS
AG15	VSS
E16	VSS
N16	VSS
P16	VSS
R16	VSS
T16	VSS
U16	VSS
AF16	VSS
AG16	VSS
M17	VSS
N17	VSS
P17	VSS
R17	VSS
T17	VSS
U17	VSS
V17	VSS
AE17	VSS
AF17	VSS
AH17	VSS
B18	VSS
M18	VSS
N18	VSS
U18	VSS
V18	VSS
AF18	VSS
AH18	VSS
E19	VSS
AE19	VSS
AF19	VSS
AH19	VSS
AF20	VSS
AH20	VSS
B21	VSS
G21	VSS
AG21	VSS

Ball #	Signal Name
AH21	VSS
AJ21	VSS
E22	VSS
AD22	VSS
AB23	VSS
AC23	VSS
B24	VSS
AH24	VSS
E25	VSS
H25	VSS
L25	VSS
P25	VSS
U25	VSS
Y25	VSS
AF25	VSS
AC26	VSS
B27	VSS
AF27	VSS
D28	VSS
G28	VSS
K28	VSS
N28	VSS
T28	VSS
W28	VSS
AB28	VSS
AE28	VSS
G8	VSSA_CPLL
AH26	VSSA_DAC
AE20	VSSA_DPLL0
G24	VSSA_DPLL1
AD7	VSSA_HPLL
AE29	VSYNC
E2	VTT
F5	VTT
J5	VTT
M5	VTT

Ball #	Signal Name
R5	VTT
V5	VTT
AA5	VTT
AD5	VTT
AG5	VTT
AB29	WBF#

7.5 Intel 830M GMCH-M Signal List

Table 61. Intel 830M Chipset Ballout Signal Name List

Ball #	Signal Name
L29	AD_STB0 / DVOB_CLK
L28	AD_STB0#/ DVOB_CLK#
U29	AD_STB1/ DVOC_CLK
U28	AD_STB1#/ DVOC_CLK#
C1	ADS#
AC24	AGPBUSY#
K24	AGP_RCOMP/ DVOBC_RCOMP
J25	AGPREF/ DVOBC_REF
AH28	BLUE
AH27	BLUE#
E1	BNR#
L4	BPRI#
AJ16	CFM [RESERVED]
AH16	CFM# [RESERVED]
AH7	CMD [RESERVED]
R6	CPURST#
AH15	CTM [RESERVED]
AJ15	CTM# [RESERVED]
G5	DBSY#
AE27	DDC1_CLK
AD27	DDC1_DATA
AE26	DDC2_CLK
AD26	DDC2_DATA
J4	DEFER#
AG17	DQ_A0 [RESERVED]

Ball #	Signal Name
AJ17	DQ_A1 [RESERVED]
AG18	DQ_A2 [RESERVED]
AJ18	DQ_A3 [RESERVED]
AG19	DQ_A4 [RESERVED]
AJ19	DQ_A5 [RESERVED]
AG20	DQ_A6 [RESERVED]
AJ20	DQ_A7 [RESERVED]
AJ11	DQ_B0 [RESERVED]
AH10	DQ_B1 [RESERVED]
AJ10	DQ_B2 [RESERVED]
AG10	DQ_B3 [RESERVED]
AJ9	DQ_B4 [RESERVED]
AG9	DQ_B5 [RESERVED]
AJ8	DQ_B6 [RESERVED]
AG8	DQ_B7 [RESERVED]
F4	DRDY#
AC19	DREFCLK
AD20	DV0A_CLKINT
AD21	DVOA_BLANK#
AG24	DVOA_CLK#
AJ24	DVOA_CLK
AJ22	DVOA_D0
AH22	DVOA_D1
AG25	DVOA_D10

Ball #	Signal Name
AJ26	DVOA_D11
AG22	DVOA_D2
AJ23	DVOA_D3
AH23	DVOA_D4
AG23	DVOA_D5 /STRAP[0]
AE23	DVOA_D6
AE24	DVOA_D7 /STRAP[1]
AJ25	DVOA_D8 /STRAP[2]
AH25	DVOA_D9
AE22	DVOA_FLD/STL
AF22	DVOA_HSYNC
AE21	DVOA_INTR#
AC22	DVOA_RCOMP
AF23	DVOA_VSYNC
J29	G_AD0/ DVOB_HSYNC
J28	G_AD1/ DVOB_VSYNC
L24	G_AD10/ DVOB_D8
M27	G_AD11/ DVOB_D11
N29	G_AD12/ DVOB_D10
M25	G_AD13/ DVOBC_CLKINT#
N26	G_AD14/ DVOB_FLD/STL
N27	G_AD15
R25	G_AD16/ DVOC_VSYNC
R24	G_AD17/ DVOC_HSYNC
T29	G_AD18/ DVOC_BLANK#
T27	G_AD19
K26	G_AD2
T26	G_AD20/ DVOC_D1

Ball #	Signal Name
U27	G_AD21/ DVOC_D2
V27	G_AD22/ DVOC_D3
V28	G_AD23/ DVOC_D4
U26	G_AD24/ DVOC_D7
V29	G_AD25/ DVOC_D6
W29	G_AD26/ DVOC_D9
V25	G_AD27/ DVOC_D8
W26	G_AD28/ DVOC_D11
W25	G_AD29/ DVOC_D10
K25	G_AD3/ DVOC_D0
W27	G_AD30/ DVOBC_INTR# /DPRMS_CLK
Y29	G_AD31/ DVOC_FLD/STL
L26	G_AD4/ DVOB_D3
J27	G_AD5/ DVOB_D2
K29	G_AD6/ DVOB_D5
K27	G_AD7/ DVOB_D4
M29	G_AD8/ DVOB_D6
M28	G_AD9/ DVOB_D9
L27	G_C/BE0#/ DVOB_D7
P29	G_C/BE1#/ DVOB_BLANK#
R27	G_C/BE2#
T25	G_C/BE3#/ DVOC_D5
R28	G_DEVSEL#/

Ball #	Signal Name
	M_I2C_DATA
R29	G_FRAME#/ M_DDC1_DATA
AD29	G_GNT#
P26	G_IRDY#/ M_I2C_CLK
P28	G_PAR
AC27	G_REQ#
N25	G_STOP#
P27	G_TRDY#/ M_DDC1_CLK
AG26	GBIN
AD24	GBOUT
AG6	GM_GCLK
AJ6	GM_RCLK
AG29	GREEN
AG28	GREEN#
C2	GTL_RCOMP
J7	GTL_REFA
AA7	GTL_REFB
J3	HA10#
F3	HA11#
P6	HA12#
G1	HA13#
N5	HA14#
H1	HA15#
P4	HA16#
Τ4	HA17#
M2	HA18#
J2	HA19#
L2	HA20#
R4	HA21#
K1	HA22#
L3	HA23#
L1	HA24#
J1	HA25#
N1	HA26#
Т5	HA27#

Ball #	Signal Name
	1
R29	G_FRAME#/ M_DDC1_DATA
AD29	G_GNT#
P26	G_IRDY#/
	M_I2C_CLK
P28	G_PAR
AC27	G_REQ#
N25	G_STOP#
P27	G_TRDY#/ M_DDC1_CLK
AG26	GBIN
AD24	GBOUT
AG6	GM_GCLK
AJ6	GM_RCLK
AG29	GREEN
AG28	GREEN#
C2	GTL_RCOMP
J7	GTL_REFA
AA7	GTL_REFB
J3	HA10#
F3	HA11#
P6	HA12#
G1	HA13#
N5	HA14#
H1	HA15#
P4	HA16#
T4	HA17#
M2	HA18#
J2	HA19#
L2	HA20#
R4	HA21#
K1	HA22#
L3	HA23#
L1	HA24#
J1	HA25#
N1	HA26#
Т5	HA27#

Ball #	Signal Name
H3	HA28#
М3	HA29#
H2	HA3#
M1	HA30#
К3	HA31#
E3	HA4#
G3	HA5#
N4	HA6#
M6	HA7#
F1	HA8#
F2	HA9#
U4	HD0#
P1	HD1#
R3	HD10#
U1	HD11#
V6	HD12#
W4	HD13#
Т3	HD14#
P2	HD15#
V3	HD16#
R2	HD17#
T1	HD18#
W3	HD19#
W6	HD2#
U3	HD20#
Y4	HD21#
AA3	HD22#
W1	HD23#
V1	HD24#
Y1	HD25#
Y6	HD26#
AD3	HD27#
AB4	HD28#
AB5	HD29#
U2	HD3#
V2	HD30#

Ball #	Signal Name
Y3	HD31#
Y2	HD32#
AA4	HD33#
AA1	HD34#
AA6	HD35#
AB1	HD36#
AC4	HD37#
AA2	HD38#
AB3	HD39#
U6	HD4#
AD2	HD40#
AD1	HD41#
AC2	HD42#
AB6	HD43#
AC6	HD44#
AC1	HD45#
AF3	HD46#
AD4	HD47#
AD6	HD48#
AC3	HD49#
R1	HD5#
AH3	HD50#
AE5	HD51#
AE3	HD52#
AG2	HD53#
AF4	HD54#
AF2	HD55#
AJ3	HD56#
AE4	HD57#
AG1	HD58#
AE1	HD59#
N3	HD6#
AG4	HD60#
AH4	HD61#
AG3	HD62#
AF1	HD63#

Ball #	Signal Name
W5	HD7#
V4	HD8#
P3	HD9#
D3	HIT#
D1	HITM#
J23	HL_RCOMP
H24	HLREF
G26	HL0
H28	HL1
H26	HL10
H29	HL2
H27	HL3
F29	HL4
F27	HL5
E29	HL6
E28	HL7
G25	HL8
G27	HL9
J6	HLOCK#
G29	HLSTRB
F28	HLSTRB#
K6	HREQ0#
M4	HREQ1#
K5	HREQ2#
K4	HREQ3#
L6	HREQ4#
AD28	HSYNC
AJ4	HTCLK
AH5	HTCLK#
G4	HTRDY#
AD25	I2C_CLK
AC25	I2C_DATA
E11	NC
E20	NC
F12	NC
F20	NC

Ball #	Signal Name
AB26	PIPE#
AD14	RAM_REFA
AE14	RAM_REFB
AB25	RBF#
AF29	RED
AF28	RED#
AJ27	REFSET
AB24	RESET#
AG11	RQ0 [RESERVED]
AJ12	RQ1 [RESERVED]
AG12	RQ2 [RESERVED]
AH13	RQ3 [RESERVED]
AG13	RQ4 [RESERVED]
AJ13	RQ5 [RESERVED]
AG14	RQ6 [RESERVED]
AJ14	RQ7 [RESERVED]
H6	RS0#
H4	RS1#
G6	RS2#
AA27	SB_STB
AA28	SB_STB#
AA29	SBA0
AA24	SBA1
AA25	SBA2
Y24	SBA3
Y27	SBA4
Y26	SBA5
W24	SBA6
Y28	SBA7
AF7	SCK [RESERVED]
AJ7	SIO [RESERVED]

Ball #	Signal Name
B16	SM_BA0
C16	SM_BA1
D19	SM_CAS#
A13	SM_CKE0
C9	SM_CKE1
C13	SM_CKE2
A9	SM_CKE3
A15	SM_CLK0
B2	SM_CLK1
B14	SM_CLK2
A3	SM_CLK3
E17	SM_CS0#
F16	SM_CS1#
D16	SM_CS2#
D15	SM_CS3#
F18	SM_DQM0
D18	SM_DQM1
D13	SM_DQM2
D12	SM_DQM3
E18	SM_DQM4
F17	SM_DQM5
F14	SM_DQM6
F13	SM_DQM7
A20	SM_MA0
B20	SM_MA1
A16	SM_MA10
C15	SM_MA11
C14	SM_MA12
B19	SM_MA2
C19	SM_MA3
A18	SM_MA4
A19	SM_MA5
C17	SM_MA6
C18	SM_MA7
B17	SM_MA8
A17	SM_MA9

Ball #	Signal Name
D29	SM_MD0
C29	SM_MD1
C23	SM_MD10
F22	SM_MD11
B23	SM_MD12
C22	SM_MD13
E21	SM_MD14
B22	SM_MD15
C12	SM_MD16
D10	SM_MD17
C11	SM_MD18
A10	SM_MD19
D27	SM_MD2
C10	SM_MD20
C8	SM_MD21
A7	SM_MD22
E9	SM_MD23
C7	SM_MD24
E8	SM_MD25
A5	SM_MD26
F8	SM_MD27
C5	SM_MD28
D6	SM_MD29
C27	SM_MD3
B4	SM_MD30
C4	SM_MD31
E27	SM_MD32
C28	SM_MD33
B28	SM_MD34
E26	SM_MD35
C26	SM_MD36
D25	SM_MD37
A26	SM_MD38
D24	SM_MD39
A27	SM_MD4
F23	SM_MD40

Ball #	Signal Name
A25	SM_MD41
G22	SM_MD42
D22	SM_MD43
A23	SM_MD44
F21	SM_MD45
D21	SM_MD46
A22	SM_MD47
F11	SM_MD48
A11	SM_MD49
B26	SM_MD5
B11	SM_MD50
F10	SM_MD51
B10	SM_MD52
B8	SM_MD53
D9	SM_MD54
B7	SM_MD55
F9	SM_MD56
A6	SM_MD57
C6	SM_MD58
D7	SM_MD59
E24	SM_MD6
B5	SM_MD60
E6	SM_MD61
A4	SM_MD62
D4	SM_MD63
C25	SM_MD7
E23	SM_MD8
B25	SM_MD9
A24	SM_OCLK
C20	SM_RAS#
C24	SM_RCLK
F6	SM_RCOMP
E5	SM_REFA
F24	SM_REFB
A21	SM_WE#
AC28	ST0

Ball #	Signal Name
AC29	ST1
AB27	ST2
N6	VCC
Т6	VCC
H7	VCC
K7	VCC
L7	VCC
W7	VCC
Y7	VCC
AB7	VCC
P12	VCC
R12	VCC
T12	VCC
M14	VCC
M15	VCC
M16	VCC
P18	VCC
R18	VCC
T18	VCC
H23	VCC
K23	VCC
Y23	VCC
M24	VCC
P24	VCC
T24	VCC
V24	VCC
L23	VCC_AGP
U24	VCC_AGP
J26	VCC_AGP
M26	VCC_AGP
R26	VCC_AGP
V26	VCC_AGP
AA23	VCC_AGP
AA26	VCC_AGP
AC8	VCC_CMOS
AC9	VCC_CMOS

Ball #	Signal Name
AE7	VCC_CMOS
AF6	VCC_CMOS
AC21	VCC_DVO
AF21	VCC_DVO
AF24	VCC_DVO
AD23	VCC_GPIO
AE25	VCC_GPIO
J24	VCC_HUB
F26	VCC_HUB
AC10	VCC_LM
AC11	VCC_LM
AD11	VCC_LM
AD12	VCC_LM
AD13	VCC_LM
AD17	VCC_LM
AD18	VCC_LM
AD19	VCC_LM
AE18	VCC_LM
D5	VCC_SM
D8	VCC_SM
D11	VCC_SM
G11	VCC_SM
D14	VCC_SM
D17	VCC_SM
D20	VCC_SM
D23	VCC_SM
G23	VCC_SM
D26	VCC_SM
G10	VCC_SM
E12	VCC_SM
A8	VCC_SM
A12	VCC_SM
G7	VCCA_CPLL
AF26	VCCA_DAC
AG27	VCCA_DAC
AC20	VCCA_DPLL0

Ball #	Signal Name
F25	VCCA_DPLL1
AE6	VCCA_HPLL
W23	VCCQ_AGP
N24	VCCQ_AGP
E15	VCCQ_SM
F7	VCCQ_SM
F15	VCCQ_SM
G19	VCCQ_SM
G20	VCCQ_SM
V14	VDD_LM
V15	VDD_LM
V16	VDD_LM
AD15	VDD_LM
AD16	VDD_LM
AE15	VDD_LM
AE16	VDD_LM
A14	VSS
B13	VSS
C3	VSS
C21	VSS
E14	VSS
F19	VSS
D2	VSS
G2	VSS
K2	VSS
N2	VSS
T2	VSS
W2	VSS
AB2	VSS
AE2	VSS
AH2	VSS
B3	VSS
E4	VSS
H5	VSS
L5	VSS
P5	VSS

Ball #	Signal Name
U5	VSS
Y5	VSS
AC5	VSS
AF5	VSS
AJ5	VSS
B6	VSS
AH6	VSS
E7	VSS
AC7	VSS
AG7	VSS
AD8	VSS
AE8	VSS
AF8	VSS
AH8	VSS
В9	VSS
G9	VSS
AD9	VSS
AE9	VSS
AF9	VSS
AH9	VSS
E10	VSS
AD10	VSS
AE10	VSS
AF10	VSS
AE11	VSS
AF11	VSS
AH11	VSS
B12	VSS
M12	VSS
N12	VSS
U12	VSS
V12	VSS
AE12	VSS
AF12	VSS
AH12	VSS
E13	VSS

Ball #	Signal Name
M13	VSS
N13	VSS
P13	VSS
R13	VSS
T13	VSS
U13	VSS
V13	VSS
AE13	VSS
AF13	VSS
N14	VSS
P14	VSS
R14	VSS
T14	VSS
U14	VSS
AF14	VSS
AH14	VSS
B15	VSS
N15	VSS
P15	VSS
R15	VSS
T15	VSS
U15	VSS
AF15	VSS
AG15	VSS
E16	VSS
N16	VSS
P16	VSS
R16	VSS
T16	VSS
U16	VSS
AF16	VSS
AG16	VSS
M17	VSS
N17	VSS
P17	VSS
R17	VSS

Ball #	Signal Name
T17	VSS
U17	VSS
V17	VSS
AE17	VSS
AF17	VSS
AH17	VSS
B18	VSS
M18	VSS
N18	VSS
U18	VSS
V18	VSS
AF18	VSS
AH18	VSS
E19	VSS
AE19	VSS
AF19	VSS
AH19	VSS
AF20	VSS
AH20	VSS
B21	VSS
G21	VSS
AG21	VSS
AH21	VSS
AJ21	VSS
E22	VSS
AD22	VSS
AB23	VSS
AC23	VSS
B24	VSS
AH24	VSS
E25	VSS
H25	VSS

Ball #	Signal Name
L25	VSS
P25	VSS
U25	VSS
Y25	VSS
AF25	VSS
AC26	VSS
B27	VSS
AF27	VSS
D28	VSS
G28	VSS
K28	VSS
N28	VSS
T28	VSS
W28	VSS
AB28	VSS
AE28	VSS
G8	VSSA_CPLL
AH26	VSSA_DAC
AE20	VSSA_DPLL0
G24	VSSA_DPLL1
AD7	VSSA_HPLL
AE29	VSYNC
E2	VTT
F5	VTT
J5	VTT
M5	VTT
R5	VTT
V5	VTT
AA5	VTT
AD5	VTT
AG5	VTT
AB29	WBF#

7.6 Intel 830MG GMCH-M Signal List

Table 62. Intel 830MG Chipset Ballout Signal Name List

Ball #	Signal Name
L29	DVOB_CLK
L28	DVOB_CLK#
U29	DVOC_CLK
U28	DVOC_CLK#
C1	ADS#
AC24	AGPBUSY#
K24	DVOBC_RCOMP
J25	DVOBC_REF
AH28	BLUE
AH27	BLUE#
E1	BNR#
L4	BPRI#
AJ16	CFM [RESERVED]
AH16	CFM# [RESERVED]
AH7	CMD [RESERVED]
R6	CPURST#
AH15	CTM [RESERVED]
AJ15	CTM# [RESERVED]
G5	DBSY#
AE27	DDC1_CLK
AD27	DDC1_DATA
AE26	DDC2_CLK
AD26	DDC2_DATA
J4	DEFER#
AG17	DQ_A0 [RESERVED]
AJ17	DQ_A1 [RESERVED]
AG18	DQ_A2 [RESERVED]
AJ18	DQ_A3 [RESERVED]
AG19	DQ_A4 [RESERVED]
AJ19	DQ_A5 [RESERVED]

Ball #	Signal Name
AG20	DQ_A6 [RESERVED]
AJ20	DQ_A7 [RESERVED]
AJ11	DQ_B0 [RESERVED]
AH10	DQ_B1 [RESERVED]
AJ10	DQ_B2 [RESERVED]
AG10	DQ_B3 [RESERVED]
AJ9	DQ_B4 [RESERVED]
AG9	DQ_B5 [RESERVED]
AJ8	DQ_B6 [RESERVED]
AG8	DQ_B7 [RESERVED]
F4	DRDY#
AC19	DREFCLK
AD20	DV0A_CLKINT
AD21	DVOA_BLANK#
AG24	DVOA_CLK#
AJ24	DVOA_CLK
AJ22	DVOA_D0
AH22	DVOA_D1
AG25	DVOA_D10
AJ26	DVOA_D11
AG22	DVOA_D2
AJ23	DVOA_D3
AH23	DVOA_D4
AG23	DVOA_D5/ STRAP[0]
AE23	DVOA_D6
AE24	DVOA_D7/ STRAP[7]
AJ25	DVOA_D8/ STRAP[8]
AH25	DVOA_D9
AE22	DVOA_FLD/STL
AF22	DVOA_HSYNC
AE21	DVOA_INTR#

Ball #	Signal Name
AC22	DVOA_RCOMP
AF23	DVOA_VSYNC
J29	DVOB_HSYNC
J28	DVOB_VSYNC
L24	DVOB_D8
M27	DVOB_D11
N29	DVOB_D10
M25	DVOBC_CLKINT#
N26	DVOB_FLD/STL
N27	G_AD15
R25	DVOC_VSYNC
R24	DVOC_HSYNC
T29	DVOC_BLANK#
T27	G_AD19
K26	G_AD2
T26	DVOC_D1
U27	DVOC_D2
V27	DVOC_D3
V28	DVOC_D4
U26	DVOC_D7
V29	DVOC_D6
W29	DVOC_D9
V25	DVOC_D8
W26	DVOC_D11
W25	DVOC_D10
K25	DVOB_D0
W27	DVOBC_INTR#/DPMS_CLK
Y29	DVOC_FLD/STL
L26	DVOB_D3
J27	DVOB_D2
K29	DVOB_D5
K27	DVOB_D4
M29	DVOB_D6
M28	DVOB_D9
L27	DVOB_D7
P29	DVOB_BLANK#
R27	G_C/BE2#
T25	DVOC_D5
R28	M_I2C_DATA
R29	M_DDC1_DATA
AD29	G_GNT#
P26	M_I2C_CLK

Ball #	Signal Name
P28	G_PAR
AC27	G_REQ#
N25	G_STOP#
P27	M_DDC1_CLK
AG26	GBIN
AD24	GBOUT
AG6	GM_GCLK
AJ6	GM_RCLK
AG29	GREEN
AG28	GREEN#
C2	GTL_RCOMP
J7	GTL_REFA
AA7	GTL_REFB
J3	HA10#
F3	HA11#
P6	HA12#
G1	HA13#
N5	HA14#
H1	HA15#
P4	HA16#
T4	HA17#
M2	HA18#
J2	HA19#
L2	HA20#
R4	HA21#
K1	HA22#
L3	HA23#
L1	HA24#
J1	HA25#
N1	HA26#
T5	HA27#
H3	HA28#
M3	HA29#
H2	HA3#
M1	HA30#
K3	HA31#
E3	HA4#
G3	HA5#
N4	HA6#
M6	HA7#
F1	HA8#
F2	HA9#

Ball #	Signal Name
U4	HD0#
P1	HD1#
R3	HD10#
U1	HD11#
V6	HD12#
W4	HD13#
Т3	HD14#
P2	HD15#
V3	HD16#
R2	HD17#
T1	HD18#
W3	HD19#
W6	HD2#
U3	HD20#
Y4	HD21#
AA3	HD22#
W1	HD23#
V1	HD24#
Y1	HD25#
Y6	HD26#
AD3	HD27#
AB4	HD28#
AB5	HD29#
U2	HD3#
V2	HD30#
Y3	HD31#
Y2	HD32#
AA4	HD33#
AA1	HD34#
AA6	HD35#
AB1	HD36#
AC4	HD37#
AA2	HD38#
AB3	HD39#
U6	HD4#
AD2	HD40#
AD1	HD41#
AC2	HD42#
AB6	HD43#
AC6	HD44#
AC1	HD45#
AF3	HD46#

Ball #	Signal Name
AD4	HD47#
AD6	HD48#
AC3	HD49#
R1	HD5#
AH3	HD50#
AE5	HD51#
AE3	HD52#
AG2	HD53#
AF4	HD54#
AF2	HD55#
AJ3	HD56#
AE4	HD57#
AG1	HD58#
AE1	HD59#
N3	HD6#
AG4	HD60#
AH4	HD61#
AG3	HD62#
AF1	HD63#
W5	HD7#
V4	HD8#
P3	HD9#
D3	HIT#
D1	HITM#
J23	HL_RCOMP
H24	HLREF
G26	HLO
H28	HL1
H26	HL10
H29	HL2
H27	HL3
F29	HL4
F27	HL5
E29	HL6
E28	HL7
G25	HL8
G27	HL9
J6	HLOCK#
G29	HLSTRB
F28	HLSTRB#
K6	HREQ0#
M4	HREQ1#

Ball #	Signal Name
K5	HREQ2#
K4	HREQ3#
L6	HREQ4#
AD28	HSYNC
AJ4	HTCLK
AH5	HTCLK#
G4	HTRDY#
AD25	I2C_CLK
AC25	I2C_DATA
E11	NC
E20	NC
F12	NC
F20	NC
AB26	PIPE#
AD14	RAM_REFA
AE14	RAM_REFB
AB25	RBF#
AF29	RED
AF28	RED#
AJ27	REFSET
AB24	RESET#
AG11	RQ0 [RESERVED]
AJ12	RQ1 [RESERVED]
AG12	RQ2 [RESERVED]
AH13	RQ3 [RESERVED]
AG13	RQ4 [RESERVED]
AJ13	RQ5 [RESERVED]
AG14	RQ6 [RESERVED]
AJ14	RQ7 [RESERVED]
H6	RS0#
H4	RS1#
G6	RS2#
AA27	SB_STB
AA28	SB_STB#
AA29	SBA0
AA24	SBA1

Ball #	Signal Name
AA25	SBA2
Y24	SBA3
Y27	SBA4
Y26	SBA5
W24	SBA6
Y28	SBA7
AF7	SCK [RESERVED]
AJ7	SIO [RESERVED]
B16	SM_BA0
C16	SM_BA1
D19	SM_CAS#
A13	SM_CKE0
C9	SM_CKE1
C13	SM_CKE2
A9	SM_CKE3
A15	SM_CLK0
B2	SM_CLK1
B14	SM_CLK2
A3	SM_CLK3
E17	SM_CS0#
F16	SM_CS1#
D16	SM_CS2#
D15	SM_CS3#
F18	SM_DQM0
D18	SM_DQM1
D13	SM_DQM2
D12	SM_DQM3
E18	SM_DQM4
F17	SM_DQM5
F14	SM_DQM6
F13	SM_DQM7
A20	SM_MA0
B20	SM_MA1
A16	SM_MA10
C15	SM_MA11
C14	SM_MA12
B19	SM_MA2
C19	SM_MA3
A18	SM_MA4
A19	SM_MA5
C17	SM_MA6

Ball #	Signal Name
C18	SM_MA7
B17	SM_MA8
A17	SM_MA9
D29	SM_MD0
C29	SM_MD1
C23	SM_MD10
F22	SM_MD11
B23	SM_MD12
C22	SM_MD13
E21	SM_MD14
B22	SM_MD15
C12	SM_MD16
D10	SM_MD17
C11	SM_MD18
A10	SM_MD19
D27	SM_MD2
C10	SM_MD20
C8	SM_MD21
A7	SM_MD22
E9	SM_MD23
C7	SM_MD24
E8	SM_MD25
A5	SM_MD26
F8	SM_MD27
C5	SM_MD28
D6	SM_MD29
C27	SM_MD3
B4	SM_MD30
C4	SM_MD31
E27	SM_MD32
C28	SM_MD33
B28	SM_MD34
E26	SM_MD35
C26	SM_MD36
D25	SM_MD37
A26	SM_MD38
D24	SM_MD39
A27	SM_MD4
F23	SM_MD40
A25	SM_MD41
G22	SM_MD42
D22	SM_MD43

Ball #	Signal Name
A23	SM_MD44
F21	SM_MD45
D21	SM_MD46
A22	SM_MD47
F11	SM_MD48
A11	SM_MD49
B26	SM_MD5
B11	SM_MD50
F10	SM_MD51
B10	SM_MD52
B8	SM_MD53
D9	SM_MD54
B7	SM_MD55
F9	SM_MD56
A6	SM_MD57
C6	SM_MD58
D7	SM_MD59
E24	SM_MD6
B5	SM_MD60
E6	SM_MD61
A4	SM_MD62
D4	SM_MD63
C25	SM_MD7
E23	SM_MD8
B25	SM_MD9
A24	SM_OCLK
C20	SM_RAS#
C24	SM_RCLK
F6	SM_RCOMP
E5	SM_REFA
F24	SM_REFB
A21	SM_WE#
AC28	ST0
AC29	ST1
AB27	ST2
N6	VCC
Т6	VCC
H7	VCC
K7	VCC
L7	VCC
W7	VCC
Y7	VCC

Ball #	Signal Name
AB7	VCC
P12	VCC
R12	VCC
T12	VCC
M14	VCC
M15	VCC
M16	VCC
P18	VCC
R18	VCC
T18	VCC
H23	VCC
K23	VCC
Y23	VCC
M24	VCC
P24	VCC
T24	VCC
V24	VCC
L23	VCC_AGP
U24	VCC_AGP
J26	VCC_AGP
M26	VCC_AGP
R26	VCC_AGP
V26	VCC_AGP
AA23	VCC_AGP
AA26	VCC_AGP
AC8	VCC_CMOS
AC9	VCC_CMOS
AE7	VCC_CMOS
AF6	VCC_CMOS
AC21	VCC_DVO
AF21	VCC_DVO
AF24	VCC_DVO
AD23	VCC_GPIO
AE25	VCC_GPIO
J24	VCC_HUB
F26	VCC_HUB
AC10	VCC_LM
AC11	VCC_LM
AD11	VCC_LM
AD12	VCC_LM
AD13	VCC_LM
AD17	VCC_LM

Ball #	Signal Name
AD18	VCC_LM
AD19	VCC_LM
AE18	VCC_LM
D5	VCC_SM
D8	VCC_SM
D11	VCC_SM
G11	VCC_SM
D14	VCC_SM
D17	VCC_SM
D20	VCC_SM
D23	VCC_SM
G23	VCC_SM
D26	VCC_SM
G10	VCC_SM
E12	VCC_SM
A8	VCC_SM
A12	VCC_SM
G7	VCCA_CPLL
AF26	VCCA_DAC
AG27	VCCA_DAC
AC20	VCCA_DPLL0
F25	VCCA_DPLL1
AE6	VCCA_HPLL
W23	VCCQ_AGP
N24	VCCQ_AGP
E15	VCCQ_SM
F7	VCCQ_SM
F15	VCCQ_SM
G19	VCCQ_SM
G20	VCCQ_SM
V14	VDD_LM
V15	VDD_LM
V16	VDD_LM
AD15	VDD_LM
AD16	VDD_LM
AE15	VDD_LM
AE16	VDD_LM
A14	VSS
B13	VSS
C3	VSS
C21	VSS
E14	VSS

Ball #	Signal Name
F19	VSS
D2	VSS
G2	VSS
K2	VSS
N2	VSS
T2	VSS
W2	VSS
AB2	VSS
AE2	VSS
AH2	VSS
B3	VSS
E4	VSS
H5	VSS
L5	VSS
P5	VSS
U5	VSS
Y5	VSS
AC5	VSS
AF5	VSS
AJ5	VSS
B6	VSS
AH6	VSS
E7	VSS
AC7	VSS
AG7	VSS
AD8	VSS
AE8	VSS
AF8	VSS
AH8	VSS
B9	VSS
G9	VSS
AD9	VSS
AE9	VSS
AF9	VSS
AH9	VSS
E10	VSS
AD10	VSS
AE10	VSS
AF10	VSS
AE11	VSS
AF11	VSS
AH11	VSS

Ball #	Signal Name
B12	VSS
M12	VSS
N12	VSS
U12	VSS
V12	VSS
AE12	VSS
AF12	VSS
AH12	VSS
E13	VSS
M13	VSS
N13	VSS
P13	VSS
R13	VSS
T13	VSS
U13	VSS
V13	VSS
AE13	VSS
AF13	VSS
N14	VSS
P14	VSS
R14	VSS
T14	VSS
U14	VSS
AF14	VSS
AH14	VSS
B15	VSS
N15	VSS
P15	VSS
R15	VSS
T15	VSS
U15	VSS
AF15	VSS
AG15	VSS
E16	VSS
N16	VSS
P16	VSS
R16	VSS
T16	VSS
U16	VSS
AF16	VSS
AG16	VSS
M17	VSS

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Ball #	Signal Name
N17	VSS
P17	VSS
R17	VSS
T17	VSS
U17	VSS
V17	VSS
AE17	VSS
AF17	VSS
AH17	VSS
B18	VSS
M18	VSS
N18	VSS
U18	VSS
V18	VSS
AF18	VSS
AH18	VSS
E19	VSS
AE19	VSS
AF19	VSS
AH19	VSS
AF20	VSS
AH20	VSS
B21	VSS
G21	VSS
AG21	VSS
AH21	VSS
AJ21	VSS
E22	VSS
AD22	VSS
AB23	VSS
AC23	VSS
B24	VSS
AH24	VSS
E25	VSS

Ball #	Signal Name
H25	VSS
L25	VSS
P25	VSS
U25	VSS
Y25	VSS
AF25	VSS
AC26	VSS
B27	VSS
AF27	VSS
D28	VSS
G28	VSS
K28	VSS
N28	VSS
T28	VSS
W28	VSS
AB28	VSS
AE28	VSS
G8	VSSA_CPLL
AH26	VSSA_DAC
AE20	VSSA_DPLL0
G24	VSSA_DPLL1
AD7	VSSA_HPLL
AE29	VSYNC
E2	VTT
F5	VTT
J5	VTT
M5	VTT
R5	VTT
V5	VTT
AA5	VTT
AD5	VTT
AG5	VTT
AB29	WBF#

7.7 Intel 830 Chipset Family Chipset Package Dimensions

Figure 24 outlines the mechanical dimensions for the Intel 830 Chipset family GMCH-M. The package is a 625-ball grid array (BGA) package.



